The right choice for the ultimate yield!

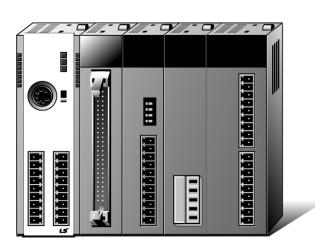
LS ELECTRIC strives to maximize your profits in gratitude for choosing us as your partner.

Programmable Logic Control

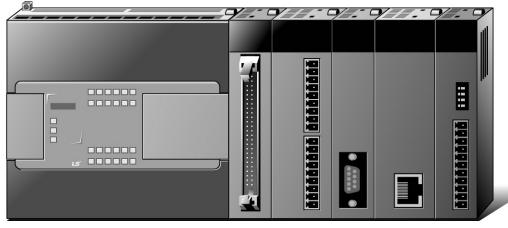
XGB Hardware

XGT Series

User Manual



XBM-DR16S XBM-DN16S XBM-DN32S XBC-DR32H XBC-DN32H XBC-DR64H XBC-DR64H XBC-DR32HL XBC-DN32H/DC XBC-DN64H/DC XBC-DR32H/DC XBC-DR32H/DC





Safety Instructions

- Read this manual carefully before installing, wiring, operating, servicing or inspecting this equipment.
- Keep this manual within easy reach for quick reference.



Before using the product ...

For your safety and effective operation, please read the safety instructions thoroughly before using the product.

- ► Safety Instructions should always be observed in order to prevent accident or risk with the safe and proper use the product.
- ► Instructions are separated into "Warning" and "Caution", and the meaning of the terms is as follows;

Warning

This symbol indicates the possibility of serious injury or death if some applicable instruction is violated

⚠ Caution

This symbol indicates the possibility of slight injury or damage to products if some applicable instruction is violated

The marks displayed on the product and in the user's manual have the following meanings.



Be careful! Danger may be expected.



/ႃဴ Be careful! Electric shock may occur.

The user's manual even after read shall be kept available and accessible to any user of the product.

Safety Instructions when designing

Warning

- Please, install protection circuit on the exterior of PLC to protect the whole control system from any error in external power or PLC module. Any abnormal output or operation may cause serious problem in safety of the whole system.
 - Install applicable protection unit on the exterior of PLC to protect the system from physical damage such as emergent stop switch, protection circuit, the upper/lowest limit switch, forward/reverse operation interlock circuit, etc.
 - If any system error (watch-dog timer error, module installation error, etc.) is detected during CPU operation in PLC, the whole output is designed to be turned off and stopped for system safety. However, in case CPU error if caused on output device itself such as relay or TR can not be detected, the output may be kept on, which may cause serious problems. Thus, you are recommended to install an addition circuit to monitor the output status.
- Never connect the overload than rated to the output module nor allow the output circuit to have a short circuit, which may cause a fire.
- ▶ Never let the external power of the output circuit be designed to be On earlier than PLC power, which may cause abnormal output or operation.
- In case of data exchange between computer or other external equipment and PLC through communication or any operation of PLC (e.g. operation mode change), please install interlock in the sequence program to protect the system from any error. If not, it may cause abnormal output or operation.

Safety Instructions when designing

⚠ Caution

► I/O signal or communication line shall be wired at least 100mm away from a high-voltage cable or power line. If not, it may cause abnormal output or operation.

Safety Instructions when designing

- ▶ Use PLC only in the environment specified in PLC manual or general standard of data sheet. If not, electric shock, fire, abnormal operation of the product or flames may be caused.
- ▶ Before installing the module, be sure PLC power is off. If not, electric shock or damage on the product may be caused.
- ▶ Be sure that each module of PLC is correctly secured. If the product is installed loosely or incorrectly, abnormal operation, error or dropping may be caused.
- ▶ Be sure that I/O or extension connecter is correctly secured. If not, electric shock, fire or abnormal operation may be caused.
- ▶ If lots of vibration is expected in the installation environment, don't let PLC directly vibrated. Electric shock, fire or abnormal operation may be caused.
- ▶ Don't let any metallic foreign materials inside the product, which may cause electric shock, fire or abnormal operation..

Safety Instructions when wiring

Warning

- Prior to wiring, be sure that power of PLC and external power is turned off. If not, electric shock or damage on the product may be caused.
- ▶ Before PLC system is powered on, be sure that all the covers of the terminal are securely closed. If not, electric shock may be caused

⚠ Caution

- ▶ Let the wiring installed correctly after checking the voltage rated of each product and the arrangement of terminals. If not, fire, electric shock or abnormal operation may be caused.
- Secure the screws of terminals tightly with specified torque when wiring. If the screws of terminals get loose, short circuit, fire or abnormal operation may be caused.
- ▶ Surely use the ground wire of Class 3 for FG terminals, which is exclusively used for PLC. If the terminals not grounded correctly, abnormal operation may be caused.
- ▶ Don't let any foreign materials such as wiring waste inside the module while wiring, which may cause fire, damage on the product or abnormal operation.

Safety Instructions for test-operation or repair

Warning

- ▶ Don't touch the terminal when powered. Electric shock or abnormal operation may occur.
- ▶ Prior to cleaning or tightening the terminal screws, let all the external power off including PLC power. If not, electric shock or abnormal operation may occur.
- ▶ Don't let the battery recharged, disassembled, heated, short or soldered. Heat, explosion or ignition may cause injuries or fire.

⚠ Caution

- ▶ Don't remove PCB from the module case nor remodel the module.
 Fire, electric shock or abnormal operation may occur.
- Prior to installing or disassembling the module, let all the external power off including PLC power. If not, electric shock or abnormal operation may occur.
- ▶ Keep any wireless installations or cell phone at least 30cm away from PLC. If not, abnormal operation may be caused.

Safety Instructions for waste disposal

∴ Caution

▶ Product or battery waste shall be processed as industrial waste.

The waste may discharge toxic materials or explode itself.

Revision History

2006.6	1. First Edition 1. Position and Special function contents separated (1) Position function contents separated (position part published) (2) PID control and Ch. 12 Analog IO module contents separated 2. Contents added (1) Naming standard added (2) Caution when selecting IO module added (3) IO wiring method by using Smart Link board added	- - - 2-3 ~ 2-6 7-1 ~ 7-6
2007.7	 (1) Position function contents separated (position part published) (2) PID control and Ch. 12 Analog IO module contents separated 2. Contents added (1) Naming standard added (2) Caution when selecting IO module added (3) IO wiring method by using Smart Link board added 	
	(1) Naming standard added(2) Caution when selecting IO module added(3) IO wiring method by using Smart Link board added	
	(4) Installation and wiring contents added	7-27 ~ 7-28 10-1 ~ 10-18
	 3. Content modified (1) Safety instruction modified (2) System Configuration modified (3) High speed counter function modified (4) External dimension modified 	1 ~ 6 2-7 ~ 2-10 8-6 ~ 8-8 App. 2-1 ~ 2-4
2008.3	1. XGB compact type 'H' type added	-
	Built-in communication content separated (1) Ch.9 built-in communication function separated (Cnet I/F user manual)	Ch. 9
2009.3	Specification of output for positioning added	7-13,14,17,18
2010.3	 "UL warranty voltage" word added RTC example program modified XBC input resistor modified and digital I/O mixed module added 	4-6 6-22 Chapter 7
	 Installation of module added DC power unit added DC power unit and expansion module added Error in high speed counter channel fixed Specification of TR output for positioning modified Error in figure fixed External memory module added 	9-10 Front cover 2-1 ~ 2-4 4-6 ~ 4-7 Chapter 7 Appendix 2 8-3 7-13, 14, 17, 18 4-4 Ch6.13
	2009.3	(2) System Configuration modified (3) High speed counter function modified (4) External dimension modified 2. Built-in communication content separated (1) Ch.9 built-in communication function separated (Cnet I/F user manual) 2009.3 1. Specification of output for positioning added 2. RTC example program modified 3. XBC input resistor modified and digital I/O mixed module added 4. Installation of module added 5. DC power unit added 6. DC power unit and expansion module added 7. DC power unit and expansion module added 8. DC power unit and expansion module added 9. DC power unit and expansion module added 10. Error in high speed counter channel fixed 11. Specification of TR output for positioning modified 12. Error in figure fixed

Version Date Remark		Page	
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V1.7	2014.3	 Data Back-up method added Module added (1) XBE-DC16B/RY08B (2) XBF-AD04C/DV04C/DC04C (3) XBL-EIMT/EIMF/EIMH/EIPT/CMEA/CSEA/PMEC Domain of Homepage Changed External Memory Module Modified	4-11 7-20,7-23 2-2~ 2-8 2-2~ 2-8 Front/Back Cover 6-23~6-30
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V1.9	2016.11	1. Module added (1) XBE-DN32A	Ch7
V 2.0	2020.06	LSIS to change its corporate name to LS ELECTRIC	Entire

About User's Manual

Congratulations on purchasing PLC of LS ELECTRIC Co.,Ltd.

Before use, make sure to carefully read and understand the User's Manual about the functions, performances, installation and programming of the product you purchased in order for correct use and importantly, let the end user and maintenance administrator to be provided with the User's Manual.

The Use's Manual describes the product. If necessary, you may refer to the following description and order accordingly. In addition, you may connect our website(http://www.lselectric.co.kr/) and download the information as a PDF file.

Relevant User's Manual

Title	Description	No. of User Manual
XG5000 User's Manual	It describes how to use XG5000 software especially about online functions such as programming, printing, monitoring and debugging by using XGT series products.	10310000512
XGK/XGB Series It describes how to use the instructions for programming using XGK/XGB series. Programming		10310000510
XGB Hardware User's Manual	It describes how to use the specification of power/input /output/expansion modules, system configuration and built-in High-speed counter for XGB basic unit.	10310000926
XGB Analog User's Manual	It describes how to use the specification of analog input/analog output/temperature input module, system configuration and built-in PID control for XGB basic unit.	10310000920
XGB Cnet I/F It describes how to use built-in communication function for User's Manual XGB basic unit and external Cnet I/F module.		10310000816
XGB Fast Ethernet I/F User's Manual It describes how to use XGB FEnet I/F module.		10310000873

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Chapter 1 Introduction

1.1 Guide to Use This Manual

This manual includes specifications, functions and handling instructions for the XGB series PLC. This manual is divided up into chapters as follows.

No.	Title	Contents		
Chapter 1	Introduction	Describes configuration of this manual, unit's features and		
<u>'</u>		terminology.		
Chapter 2	System Configurations	Describes available units and system configuration in the XGB series.		
Chapter 3	General Specifications	Describes general specifications of units used in the XGB series.		
Chapter 4	CPU Specifications			
Chapter 5	Program Configuration and Operation Method	Describes performances, specifications and operations.		
Chapter 6	CPU Module Functions			
Chapter 7	Input/Output Specifications	Describes operation of basic and input/output.		
Chapter 8	Built-in High-speed Counter Function	Describes built-in high-speed counter functions.		
Chapter 9	Installation and Wiring	Describes installation, wiring and handling instructions for reliability of the PLC system.		
Chapter 10	Maintenance	Describes the check items and method for long-term normal operation of the PLC system.		
Chapter 11	Troubleshooting	Describes various operation errors and corrective actions.		
Appendix 1	Flag List	Describes the types and contents of various flags.		
Appendix 2	Dimension	Shows dimensions of the main units and expansion modules.		
Appendix 3	Compatibility with MASTER-K	Describes the compatibility with MASTER-K.		
Appendix 4	Instruction List	Describes the special relay and instruction list.		

1.2 Features

The features of XGB system are as follows.

- (1) The system secures the following high performances.
 - (a) High Processing Speed
 - (b) Max. 384 I/O control supporting small & mid-sized system implementation

ltem	Туре		Reference	
item	XBM-DxxxS	XBC-DxxxH	Reference	
Operation processing speed	160ns / Step	120ns / Step	-	
Max IO contact point	256 points	384 points		
Program capacity	10Kstep	15Kstep	-	
Max. no. of expanded base	7	10	-	

- (c) Enough program capacity
- (d) Expanded applications with the support of floating point.
- (e) XBM-DxxxS is expressed "S" type and XBC-DxxxH is expressed "H" type.
- (2) Compact: the smallest size comparing to the same class model of competitors.
 - (a) Compact panel realized through the smallest size.

Item	Туре	Size (W * H * D)	Reference
	XBC-Dx32H	114 * 90 * 64	"H" type
Basic unit	XBC-Dx64H	180 * 90 * 64	
	XBM-DxxxS	30 * 90 * 64	"S" type
Extension module	XBE-,XBF-,XBL-	20 * 90 * 60	Basis of minimum size

- (3) Easy attachable/extensible system for improved user convenience.
 - (a) Easy attachable to European terminal board and convenient-to-use MIL connector method improving convenient wiring. ("S" type basic unit and expanded module)
 - (b) By adopting a removable terminal block connector (M3 X 6 screw), convenience of wiring may be increased.
 - (c) By adopting connector coupling method, modules may be easily connected and separated.
- (4) Improved maintenance ability with kinds of register, built-in RTC ("H" type), comment backup and etc
 - (a) Convenient programming environment by providing analogue register and index register.
 - (b) Improved maintenance ability by operating plural programs and task program through module program.
 - (c) Built-in Flash ROM enabling permanent backup of program without any separate battery.
 - (d) Improved maintenance ability by types of comment backup.
 - (e) Built-in RTC function enabling convenient history and schedule management

Chapter 1. Introduction

- (5) Optimized communication environment.
 - (a) With max. 2 channels of built-in COM (excl. loader), up to 2 channel communication is available without any expanded of module.
 - (b) Supporting various protocols to improve the convenience (dedicated, Modbus, user-defined communication)
 - (c) Communication module may be additionally increased by adding modules (up to 2 stages such as Cnet, Enet and etc).
 - (d) Convenient network-diagnostic function through network & communication frame monitoring.
 - (e) Convenient networking to upper systems through Enet or Cnet.
 - (f) High speed program upload and download by USB Port
- (6) Applications expanded with a variety of I/O modules.
 - (a) 8, 16, 32 points modules provided (if relay output, 8/16 points module).
 - (b) Single input, single output and combined I/O modules supported.
- (7) Applications expanded through analog-dedicated register design and full attachable mechanism.
 - (a) All analogue modules can be attachable on extension base. (H type: up to 10 stages available)
 - (b) With analog dedicated register(U) and monitoring dedicated function, convenient use for I/O is maximized (can designate operations using easy programming of U area and monitoring function)
- (8) Integrated programming environment
 - (a) XG 5000: intensified program convenience, diverse monitoring, diagnosis and editing function
 - (b) XG PD: COM/network parameters setting, frame monitoring, protocol analysis function
- (9) Built-in high speed counter function
 - (a) Providing High-speed counter 1 phase, 2 phase and more additional functions.
 - (b) Providing parameter setting, diverse monitoring and diagnosis function using XG5000.
 - (c) Monitoring function in XG5000 can inspect without program, inspecting external wiring, data setting and others.
- (10) Built-in position control function
 - (a) Supporting max 100Kpps 2 axes.
 - (b) Providing parameter setting, operation data collection, diverse monitoring and diagnosis by using XG5000.
 - (c) Commissioning by monitoring of XG5000, without program, inspecting external wiring and operation data setting.

(11) Built-in PID

- (a) Supporting max. 16 loops.
- (b) Setting parameters by using XG5000 and supporting loop status monitoring conveniently with trend monitor.
- (c) Control constant setting through the improved Auto-tuning function.
- (d) With many other additional functions including PWM output, Δ MV, Δ PV and SV Ramp, improving the control preciseness.
- (e) Supporting types of control modes such as forward/backward mixed operation, 2-stage SV PID control, cascade control and etc.
- (f) A variety of warning functions such as PV MAX and PV variation warning securing the safety.

1.3 Terminology

The following table gives definition of terms used in this manual.

Terms	Definition	Remark
Module	A standard element that has a specified function which configures the system. Devices such as I/O board, which inserted onto the mother board.	Example) Expansion module, Special module, Communication module
Unit	A single module or group of modules that perform an independent operation as a part of PLC systems.	Example) Main unit, Expansion unit
PLC System	A system which consists of the PLC and peripheral devices. A user program can control the system.	-
XG5000	A program and debugging tool for the MASTER-K series. It executes program creation, edit, compile and debugging. (PADT: Programming Added Debugging Tool)	-
XG - PD	Software to execute description, edition of basic parameter, high speed link, P2P parameter, and function of communication diagnosis	-
I/O image area	Internal memory area of the CPU module which used to hold I/O status.	
Cnet	Computer Network	-
FEnet	Fast Ethernet Network	-
Pnet	Profibus-DP Network	-
Dnet	DeviceNet Network	-
RTC	Abbreviation of 'Real Time Clock'. It is used to call general IC that contains clock function.	-
Watchdog Timer	Supervisors the pre-set execution times of programs and warns if a program is not competed within the pre-set time.	-

Terms	Definition	Remark
Sink Input	Current flows from the switch to the PLC input terminal if a input signal turns on. PLC A power source Common	Z: Input impedance
Source Input	Current flows from the PLC input terminal to the switch after a input signal turns on. PLC A power source Current Z	-
Sink Output	Current flows from the load to the output terminal and the PLC output turn on. PLC Output Contact A power source Common	-
Source Output	Current flows from the output terminal to the load and the PLC output turn on. PLC Common A power source Output Junction	-

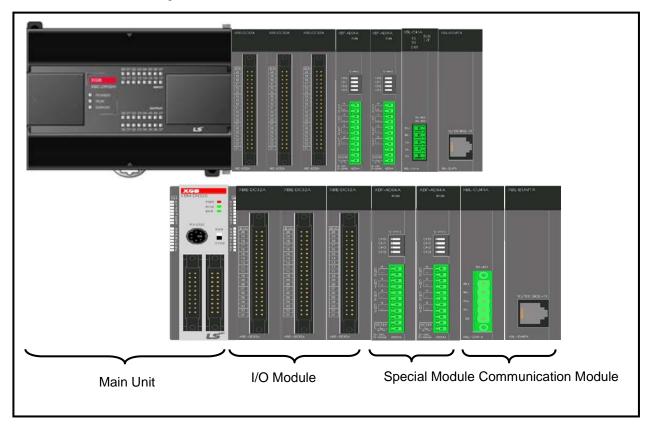
Chapter 2 System Configuration

The XGB series has suitable to configuration of the basic, computer link and network systems.

This chapter describes the configuration and features of each system.

2.1. XGB System Configuration

XGB series System Configuration is as follows. Expanded I/O module and special module are available to connect maximum 7 stages for "S" type and 10 stages for "H" type. Expanded communication module is available to connect maximum 2 stages.



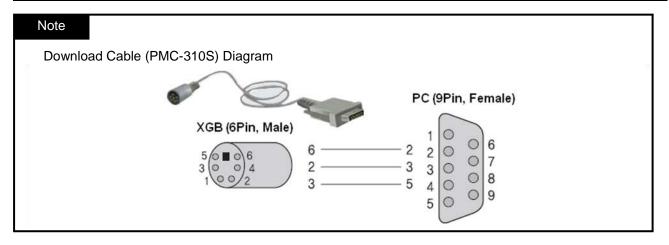
ltem			Description	
Total I/O	Total I/O points		XBC-DxxxH ("H" type): 32~384 points XBM-DxxxS ("S" type): 16~256 points	
	Digital I/O module		• "S" type: Max. 7 / "H" type: Max. 10	
Maximur	n number of	Special module	• "S" type: Max. 7 / "H" type: Max. 10	
modules		Communication I/F module	Maximum 2	
	NAsiait	"H" type		
	Main unit	"S" type		
Items		Digital I/O module	• refer to 2.2 Product List	
	Expansion module	A/D·D/A module		
		Communication I/F		
		module		

2.2. Product List

XGB series' product list is as follows.

Types	Model	Description	Remark				
	XBC-DR32H	AC100-220V power supply, DC24V input 16 point, Relay output 16 point					
	XBC-DN32H	AC100-220V power supply, DC24V input 16 point, Transistor output 16 point					
	XBC-DR64H	AC100-220V power supply, DC24V input 32 point, Relay output 32 point					
	XBC-DN64H	AC100-220V power supply, DC24V input 32 point, Transistor output 32 point					
	XBC-DR32HL	AC100-220V power supply, DC24V input 16 point, relay output 16 point	"H" type				
Main Unit	XBC-DR32H/DC	DC 24V power supply, DC24V input 16 point, relay output 16 point					
Main	XBC-DN32H/DC	DC 24V power supply, DC24V input 16 point, TR output 16 point					
	XBC-DR64H/DC DC 24V power supply, DC24V input 32 point, relay output 32 point						
	XBC-DN64H/DC	DC 24V power supply, DC24V input 32 point, TR output 32 point					
	XBM-DN16S	DC24V Power supply, DC24V Input 8 point, Transistor output 8 point					
	XBM-DN32S	DC24V Power supply, DC24V Input 16 point, Transistor output 16 point	"S" type				
	XBM-DR16S	DC24V Power supply, DC24V Input 8 point, Relay output 8 point					
	XBE-DC08A	DC24V Input 8 point					
	XBE-DC16A/B	DC24V Input 16 point	Input				
	XBE-DC32A	DC24V Input 32 point					
	XBE-RY08A	Relay output 8 point					
	XBE-RY08B	Relay output 8 point(isolated ouput)					
Unit	XBE-RY16A	KBE-RY16A Relay output 16 point					
Expansion Unit	XBE-TN08A	Transistor output 8 point (sink type)					
oans	XBE-TN16A	Transistor output 16 point (sink type)	Output				
Ä	XBE-TN32A	Transistor output 32 point (sink type)					
	XBE-TP08A	Transistor output 8 point (source type)					
	XBE-TP16A	Transistor output 16 point (source type)					
	XBE-TP32A	Transistor output 32 point (source type)					
	XBE-DR16A	DC24V Input 8 point, Relay output 8 point	la (Outaut				
	XBE-DN32A	DC24V Input 16 point, Transistor output 16 point (sink type)	In/Output				
	XBF-AD04A	Current/Voltage input 4 channel					
	XBF-AD04C	Current/Voltage input 4 channel, High resolution					
ale	XBF-AD08A	Current/Voltage input 8 channel					
Special Module	XBF-DC04A	Current output 4 channel	Analog				
ecial	XBF-DC04C	Current output 4 channel, High resolution	In/Out				
Spé	XBF-DV04A	Voltage output 4 channel					
	XBF-DV04C	Voltage output 4 channel, High resolution					
	XBF-AH04A	Current/Voltage input 2 channel, Current/Voltage output 2 channel,					

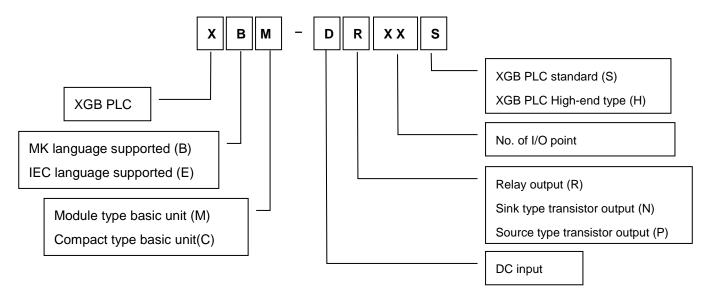
Types	Model	Description	Remark			
	XBF-RD04A	RTD (Resistance Temperature Detector) input 4 channel				
	XBF-RD01A	RTD (Resistance Temperature Detector) input 1 channel	Temperature			
ale	XBF-TC04S	TC (Thermocouple) input 4 channel				
Special Module	XBF-PD02A	Position 2Axis, Line Drive type	Position			
ecial	XBF-HD02A	High Speed Counter 2 channel, Line Drive Type	Occuptor			
Sp	XBF-HO02A	Counter				
	XBF-TC04RT	Temperature controller module (RTD input, 4 roof)	Temperature			
	XBF-TC04TT Temperature controller module (TC input, 4 roof)					
	XBL-C21A	Cnet (RS-232C/Modem) I/F	-			
	XBL-C41A	Cnet (RS-422/485) I/F	-			
on	XBL-EMTA	-				
Communication Module	XBL-EIMT	-				
mmu Moc	XBL-EIPT	-				
ပိ	XBL-EIPT EtherNet I/P Module XBL-CMEA CANopen MasterI/F					
	XBL-CSEA	CANopen Slave I/F	-			
	XBL-PMEC	Pnet I/F	-			
Option module	XBO-M1024A	Memory module	-			
wn ad ole	PMC-310S	Connection cable (PC to PLC), 9pin(PC)-6pin(PLC)	-			
Down load cable	USB-301A	Connection cable (PC to PLC), USB				



2.3. Classification and Type of Product Name

2.3.1 Classification and type of basic unit

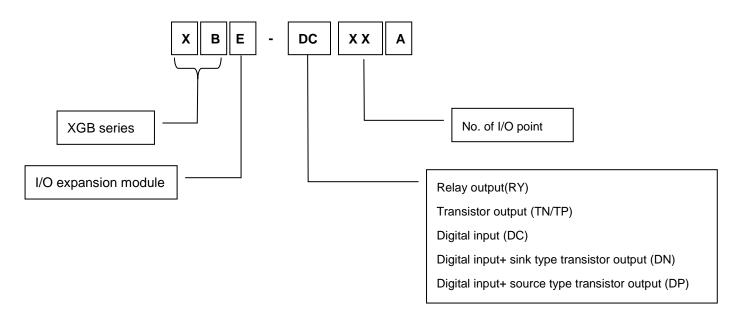
Name of basic unit is classified as follows.



Classification	Name	DC input	Relay output	Transistor output	Power
	XBM-DR16S	8 point	8 point	None	
Module type	XBM-DN16S	8 point	None	8 point	DC24V
basic unit	XBM-DN32S	16 point	None	16 point	
	XBC-DR32H	16 point	16 point	None	
Compact type	XBC-DN32H	16 point	None	16 point	
	XBC-DR64H	32 point	32 point	None	AC110V-220V
	XBC-DN64H	32 point	None	32 point	
	XBC-DR32HL	16 point	16 point	None	
basic unit	XBC-DR32H/DC	16 point	16 point	None	
	XBC-DN32H/DC	16 point	None	16 point	
	XBC-DR64H/DC	32 point	32 point	None	DC24V
	XBC-DN64H/DC	32 point	None	32 point	

2.3.2 Classification and type of expansion module

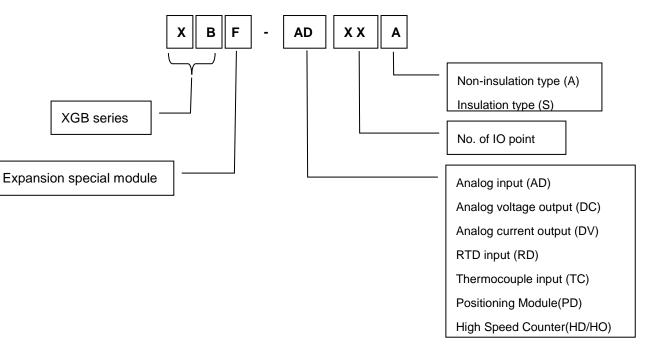
Name of expansion module is classified as follows.



Name	DC input	Relay output	Transistor output	Reference
XBE-DC08A	8 point	None	None	
XBE-DC16A/B	16 point	None	None	
XBE-DC32A	32 point	None	None	
XBE-RY08A/B	None	8 point	None	
XBE-RY16A	None	16 point	None	
XBE-TN08A	None	None	8 point (sink type)	
XBE-TN16A	None	None	16 point (sink type)	
XBE-TN32A	None	None	32 point (sink type)	
XBE-TP08A	None	None	8 point (source type)	
XBE-TP16A	None	None	16 point (source type)	
XBE-TP32A	None	None	32 point (source type)	
XBE-DR16A	8 point	8 point	None	
XBE-DN32A	16 point	None	16 point (sink type)	

2.3.3 Classification and type of special module

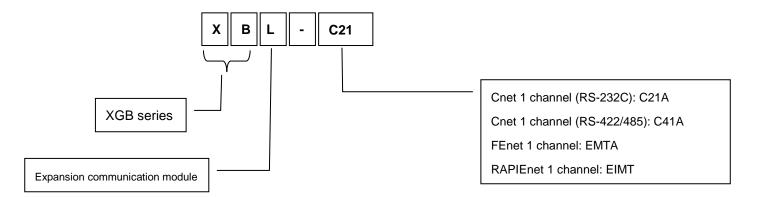
Special module is classified as follows.



Classification	Name	No. of input ch.	Input type	No. of output ch.	Output type
Analog input	XBF-AD04A/C	4	Voltage/Current	None	-
Analog input	XBF-AD08A	8	Voltage/Current	None	
Analog output	XBF-DC04A/C	None	-	4	Current
Analog output	XBF-DV04A/C	None	-	4	Voltage
RTD input	XBF-RD04A	4	PT100/JPT100	None	-
KTD IIIpat	XBF-RD01A	1	PT100/JPT100	None	-
	XBF-TC04S	4	K, J, T, R	None	-
TC input	XBF-TC04RT	4	PT100/JPT100	4	Transister
	XBF-TC04TT	4	K, J, T, R	4	Transister
Positioning	XBF-PD02A	-	Line Driver	2	Voltage
High Speed	XBF-HD02A	2	Line Driver		
Counter	XBF-HO02A	2	Open Collector		

2.3.4 Classification and type of communication module

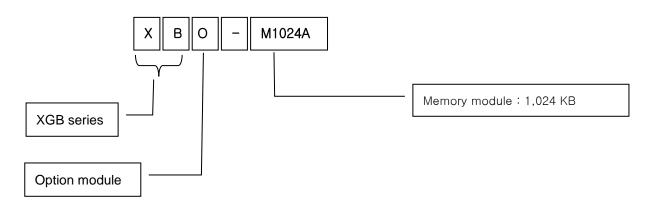
Name of communication module is classified as follows.



Classification	Name	Туре
Cnet Comm. Module	XBL-C21A	RS-232C, 1 channel
Criet Comm. Module	XBL-C41A	RS-422/485, 1 channel
FEnet Comm. Module XBL-EMTA Electricity, open type Etheri		Electricity, open type Ethernet
RAPIEnet Comm. Module	XBL-	Comm. Module between PLCs, electric media,
RAPIENEL COMM. Module	EIMT/EIMF/EIMH	100 Mbps industrial Ethernet supported
EtherNet Comm. Module XBL-EIPT Open EtherNet I/P		Open EtherNet I/P
CANonan Comm. Modulo	XBL-CMEA	CANopen Master
CANopen Comm. Module	XBL-CSEA	CANopen Slave
Pnet Comm. Module	XBL-PMEC	Profibus-DP

2.3.5 Classification and Type of Option Module

Name of option module is classified as follows.



Classification	Name	Туре
Memory module	XBO-M1024A	Memory module : 1,024 KB

2.4. System Configuration 2.4.1 Cnet I/F system

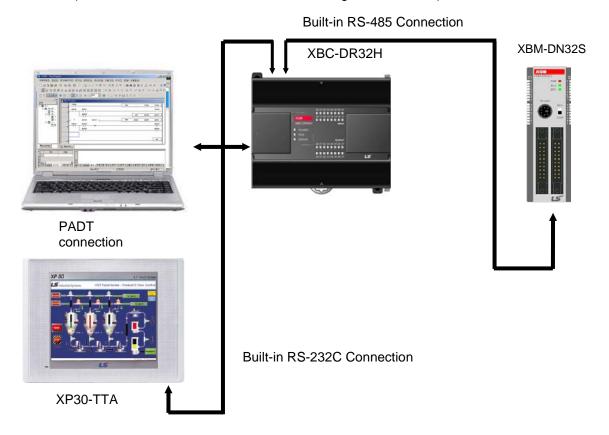
Cnet I/F System is used for communication between the main unit and external devices using RS-232C/RS-422 (485) Interface. The XGB series has a built-in RS-232C port, RS-485 port and has also XBL-C21A for RS-232C, XBL-C41A for RS-422/485. It is possible to construct communication systems on demand.

1) 1:1 communication system

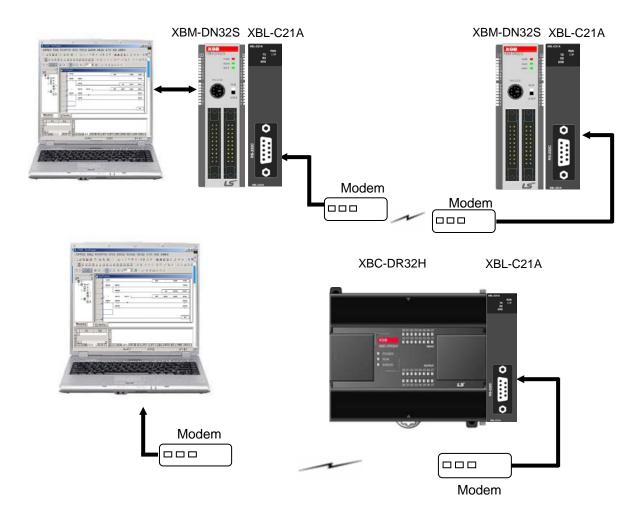
(1) 1:1 communication of an external device (computer) with main unit using a built-in port (RS-232C/RS-485)



(2) 1:1 communication with main unit using a built-in RS-485 port (In case of built-in RS-232C,it is for connecting to HMI device.)



(3) 1:1 RS-232C Communication with remote device via modem by Cnet I/F modules

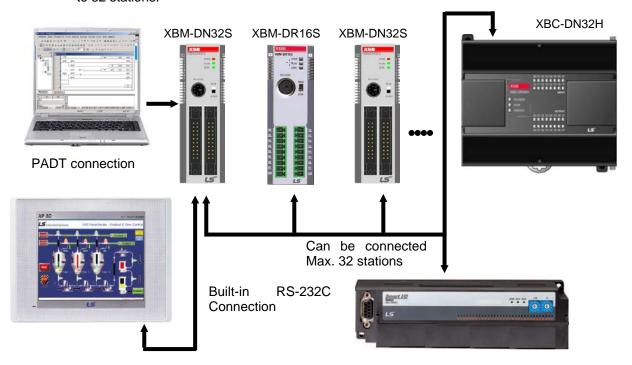


(4) 1:1 communication of an external device (monitoring unit) with main unit using a built-in RS-232C/485 port.

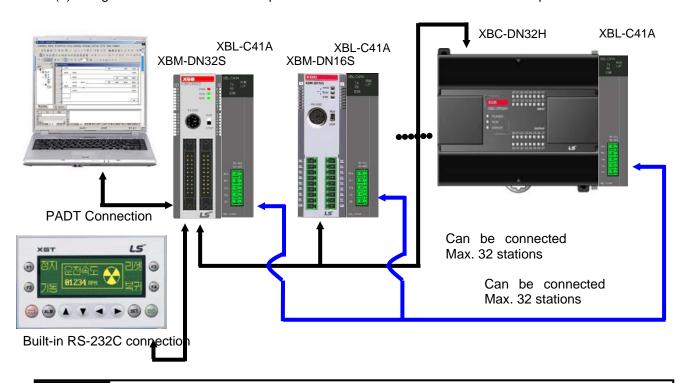


2) 1:n Communication system

(1) Using RS-485 built-in function can connect between one computer and multiple main units for up to 32 stations.



(2) Using RS-485 built-in function/expansion Cnet I/F module can be connect for up to 32 stations.

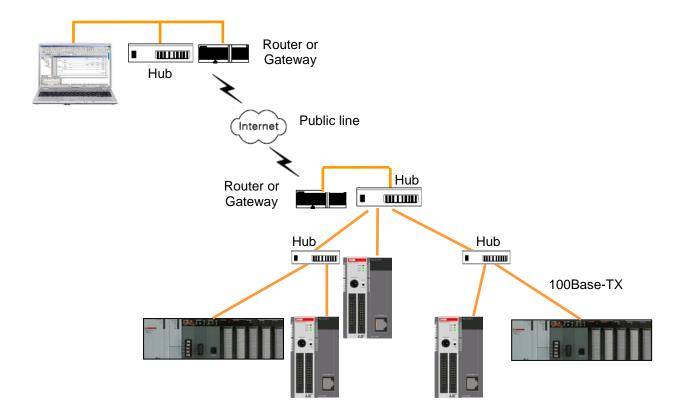


Note

1) Refer to 'XGB Cnet I/F user manual' for details

2.4.2 Ethernet system

Ethernet made by cooperation of Xerox, Intel, DEC is standard LAN connection method (IEEE802.3), which is network connection system using 1.5KB packet with 100Mbps transmission ability. Since Ethernet can combine a variety of computer by network, it is called as standard specification of LAN and diverse products. By adopting CSMA/CD method, it is easy to configure the network and collect large capacity data.



Note

1) Refer to 'XGB FEnet I/F user manual' for details

Chapter 3 General Specifications

3.1 General Specifications

The General specification of XGB series is as below.

nbient Temp. prage Temp. bient humidity rage humidity Vibration	Frequency $5 \le f < 8.4$ Hz $8.4 \le f \le 150$ Hz	5 ~ 95% 5 ~ 95% Occasional Accord z 9.8n	0 ~ 55 °C -25 ~ +70 ° BRH (Non-cost) RH (Non-cost) I vibration eleration	ondensing) ondensing) Pulse width	- Times	-
bient humidity rage humidity	Frequency $5 \le f < 8.4$ Hz $8.4 \le f \le 150$ Hz	5 ~ 95% 5 ~ 95% Occasional Accord z 9.8n	SRH (Non-co SRH (Non-co Vibration	ondensing) ondensing) Pulse width	- Times	-
rage humidity	Frequency $5 \le f < 8.4$ Hz $8.4 \le f \le 150$ Hz	5 ~ 95% Occasional Accord z 9.8n	RH (Non-co	ondensing) Pulse width	- Times	-
	Frequency $5 \le f < 8.4$ Hz $8.4 \le f \le 150$ Hz	Occasional Acco z 9.8n	vibration	Pulse width	- Times	
Vibration	Frequency $5 \le f < 8.4$ Hz $8.4 \le f \le 150$ Hz	Acce z 9.8n			- Times	
Vibration	$5 \le f < 8.4Hz$ $8.4 \le f \le 150Hz$	z 9.8n	eleration -		Times	
Vibration	8.4 ≤ f ≤ 150Hz		_			_
Vibration				3.5mm		
VIDIATION			n/s² (1G)	_	10 times	
	_	Continuous	vibration		each	
	Frequency	Acce	eleration	Pulse width	direction	IEC61131-2
	$5 \le f < 8.4Hz$		-	1.75mm	(X,Y and Z)	12001131-2
	$8.4 \leq f \leq 150Hz$	4.9m/	/s ² (0.5G)	_		
	• Peak acceleration :	147 m/s ² (1	15G)			
Shocks	Duration : 11ms					
		lalf-sine (3 t		•	ixis)	
	•					LS ELECTRIC
	•			DC: ±900 V		standard
			Voltage: 4k	κV (Contact dischar	rge)	IEC61131-2
						IEC61000-4-2
npulse noise			00 4			IEC61131-2,
	_		80 ~ 1	,000 MHz, 10V/m		IEC61000-4-3
	field noise	Cloosifi	Dower	Digital/Apolog	Innut/Output	
	Fast transient			•	• •	IEC61131-2
	/Burst noise	11.3		IEC61000-4-4		
Operation					v	
ambience	Free	from corros	sive gases a	and excessive dust		
Altitude		Le	ess than 2,0	00m		1 _
lution degree						
-	Air-cooling				1	
(pulse noise Operation ambience Altitude ution degree	Peak acceleration: Duration: 11ms Pulse wave type: Factorized acceleration: Pulse wave type: Factorized acceleration: Square wave impulse noise Electrostatic discharge Radiated electromagnetic field noise Fast transient /Burst noise Operation ambience Altitude	Peak acceleration: 147 m/s² (1	Peak acceleration : 147 m/s²(15G) Duration : 11ms Pulse wave type : Half-sine (3 times each of the second of the se	Peak acceleration : 147 m/s² (15G) Duration : 11ms Pulse wave type : Half-sine (3 times each direction per each a Square wave impulse noise Electrostatic discharge Radiated electromagnetic field noise Fast transient /Burst noise Altitude Peak acceleration : 147 m/s² (15G) Duration : 11ms Pulse wave type : Half-sine (3 times each direction per each a AC: ±1,500 V Duration impulse noise Altitude Classifi Power Digital/Analog Cation supply Communication in Supply Co	Peak acceleration: 147 m/s² (15G) Duration: 11ms Pulse wave type: Half-sine (3 times each direction per each axis) Square wave

Notes

1) IEC (International Electrotechnical Commission)

: An international civil community that promotes international cooperation for standardization of electric/ electro technology, publishes international standard and operates suitability assessment system related to the above.

2) Pollution Degree

: An index to indicate the pollution degree of used environment that determines the insulation performance of the device. For example, pollution degree 2 means the state to occur the pollution of non-electric conductivity generally, but the state to occur temporary electric conduction according to the formation of dew.

Chapter 4 CPU Specifications

4.1 Performance Specifications

The following table shows the general specifications of the XGB module type CPU.

14.	ems	S	e)	Remark	
110	51115	XBM-DR16S	XBM-DN16S	XBM-DN32S	Nemark
Program control method		Cyclic execution of s Process-driven inter			
I/O control	method	Batch processing by Directed by program	simultaneous scan (For instruction	Refresh method),	
Program la	nguage	Ladder Diagram, Ins	struction List		
Number of		28			
instructions	Application	677			
Processing (Basic instr		0.16 <i>⊭</i> s/Step			
Program ca	apacity	10 ksteps			
Max. I/O po	pints	240 point (Main + E	xpansion 7 stages)	256 point	-
	Р	P0000 ~ P127F (2,0	48 point)		
	М	M0000 ~ M255F (4,	096 point)		
	K	K00000 ~ K2559F (
	L	L00000 ~ L1279F (2			
	F	F000 ~ F255F (4,09			
Data area	Т	100ms, 10ms, 1ms (Adjustable by parar			
	С	C000 ~ C255			
	S	S00.00 ~ S127.99			
	D	D0000 ~ D5119 (51			
	U	U00.00 ~ U07.31 (A	Word		
	Z	Z000~Z127 (128 Wo	Word		
	N	N0000~N3935 (393			
Total progra	am	128			
Initial task		1 (_INT)			
Cyclic task		Max. 8			
I/O task		Max. 8			
Internal device task		Max. 8			
Operation mode		RUN, STOP, DEBU	-		
Self-diagnosis function		Detects errors of sca			
Program port		RS-232C (Loader)			
Back-up me	ethod	Latch area setting in	n basic parameter		
Internal consu	umption current	400 mA	250 mA	280 mA	
Weight		140 g	100 g	110 g	

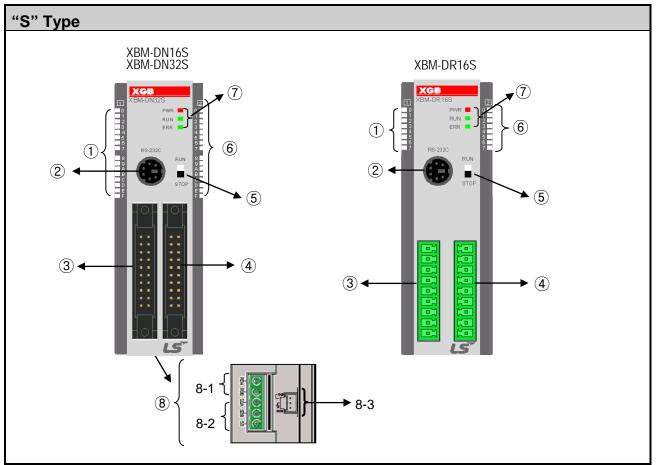
The following table shows the general specifications of the XGB compact type CPU (XBC-DR32/64H, XBC-

DN32/DN64).

N32/DN64).				(f) = +1; (41 lll +			
14	om 0	Specifications ("H" type) XBC-DN32H XBC-DR32H XBC-DN64H XBC-DR64H XBC					Domork
Itt	ems	(/DC)	(/DC)	(/DC)	XBC-DR64H (/DC)	XBC- DR32HL	Remark
Program co	ontrol method	Cyclic execu Process-driv		program, Time-o	driven interrup	t,	
I/O control	method	Batch processing by simultaneous scan (Refresh method), Directed by program instruction					
Program la	nguage	Ladder Diag	ram, Instructio	n List			
Number of	Basic	28					
instructions	Application	687					
Processing (Basic instr		0.083 µs/Ste	ep				
Program ca	apacity	15 Kstep				30kstep	-
Max. I/O po		stages)		384 point (Main stages)	+ Expansion 10	352 point	
	Р	P0000 ~ P1	023F (16,384	point)			
	M	M0000 ~ M1	1023F (16,384	point)			
	K	K0000 ~ K4	095F (65,536	point)			
	L		047F (32,768 p				
	F		023F (16,384 <mark>բ</mark>				
	Т	100ms, 10ms, 1ms: T0000 ~ T1023 (1,024 point) (Adjustable by parameter setting)					
Data area	С	C0000 ~ C1	023 (1.024)				
	S	S00.00 ~ S1					
	D		0239 (10,240	word)			
	U		•	data refresh are	ea: 352 word)		
	Z	Z000~Z127			,		
	N	N0000~N5119 (5,120 Word)					Word
	R	P0000 P10	220 (10 240 \	(ord)			-
Total progr		128	239 (10,240 W	voiu)			
Initial task	aiii	1 (_INT)					┤
Cyclic task							_
I/O task		Max. 8					-
Internal device task		Max. 8 Max. 8					_
Operation mode		RUN, STOP	DEBLIC				I
Self-diagnosis function		,	<u> </u>	memory, I/O an	d nower supply	<u> </u>	┤
Program port							┤
Back-up m		RS-232C 1 channel, USB 1 channel (USB 1.1 supported) Latch area setting in basic parameter				┤ 	
	umption current	260 mA	660 mA	330 mA	1,040 mA	660 mA	
Weight	amption ourient	500 g	600 g	800 g	900 g	600 g	
vveignt		500 g	000 g	000 g	500 g	500 g	

	Items		Specific	cations	Damada
	ite	ms	"S" type	"H" type	Remark
	PID control function		Controlled by instructions, Autroutput, Adjustable operation scafunction, SV-Ramp function Dedicated protocol support		
	Cne	t I/F function	MODBUS protocol support User defined protocol support	RS-232C 1 port RS-485 1 port	
		Capacity	1 phase: 20 kHz 4 channel 2 phase: 10 kHz 2 channel	1 phase: 100 kHz 4 channel, 20kHz 4 channel 2 phase: 50 kHz 2 channel, 10kHz 2 channel	
	High-speed counter mode Additional function		4 different counter modes acco addition/subtraction method • 1 phase pulse input: addit • 1 phase pulse input: addit phase • 2 phase pulse input: addit • 2 phase pulse input: addit phase differences	ion/subtraction counter ion/subtraction counter by B ion/subtraction counter	-
			Internal/External preset function Latch counter function Comparison output function Revolution number per unit time function		
Built-in function	nction	Basic function	No. of control axis: 2 axes Control method: position/speed control Control unit: pulse Positioning data: 30 data/axis (operation step No. 1~30) Operation mode: End/Keep/ Continuous Operation method: Single, Repeated operation	No. of control axis: 2 axes Control method: position/speed control Control unit: pulse Positioning data: 80 data/axis (operation step No. 1~80) Operation mode: End/Keep/Continuous Operation method: Single, Repeated operation	
	Positioning function function		Positioning method: Absolut Address range: -2,147,483,6 Speed: Max. 100Kpps(settin Acceleration / Deceleration m	TR output type support	
	Return to Origin		Origin detection when appro Origin detection when appro Origin detection by approximate		
	JOG operation Additional function		Setting range: 1~100,000 (High / Low speed) Inching operation, Speed synchronizing operation Position synchronizing operation, linear interpolation operation etc.		
	Pulse catch		50 µs 8 point (P0000 ~ P0007)	10 \(\mu \s 4 \text{ point} \) (P0000 \(\sim \text{ P0003}) 50 \(\mu \s 4 \text{ point} \) (P0004 \(\sim \text{ P0007})	
		rnal interrupt	8 point: 50 µs (P0000 ~ P0007)	10 \(\mu \s 4 \text{ point} \) (P0000 \(\sim \text{ P0003} \) 50 \(\mu \s 4 \text{ point} \) (P0004 \(\sim \text{ P0007} \)	
	I	nput filter	Select among 1,3,5,10,20,7	0,100 ms (Adjustable)	

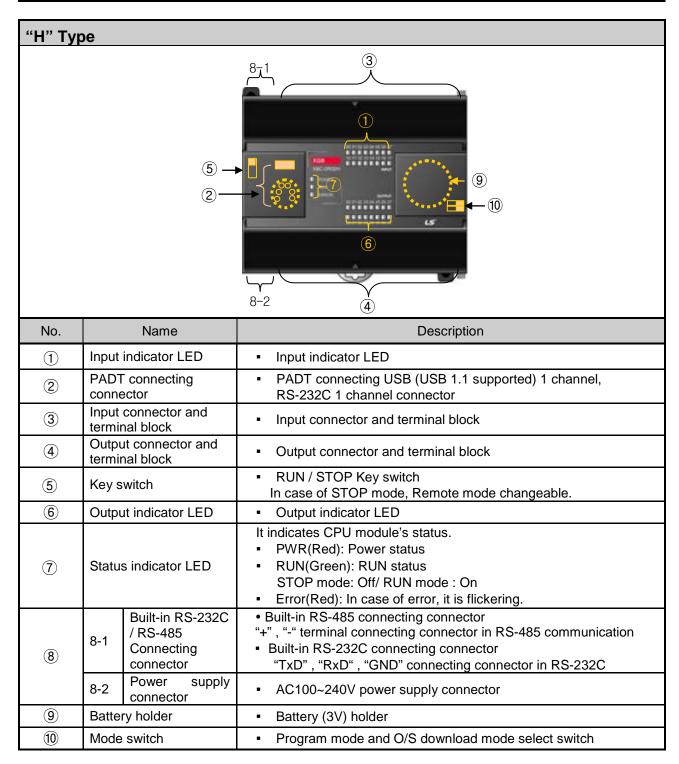
4.2 Names of Part and Function



No.	Name	Description			
1)	Input indicator LED	Input indicator LED			
2	PADT connecting connector	PADT connecting connector			
3	Input connector and terminal block	Input connector and terminal block			
4	Output connector and terminal block	Output connector and terminal block			
(5)	Key switch	 RUN / STOP Key switch In case of STOP mode, Remote mode changeable. 			
6	Output indicator LED	Output indicator LED			
7	Status indicator LED	It indicates CPU module's status. PWR(Red): Power status RUN(Green): RUN status STOP mode: Off/ RUN mode: On Error(Red): In case of error, it is flickering.			

Chapter 4. CPU Specifications

No.	Name		Description	
	8-1	Built-in RS-485 connecting connector	Built-in RS-485 connecting connector "+", "-" terminal connecting connector in RS-485 communication	
8	8-2	Built-inRS-232C connecting connector	Built-in RS-232C connecting connector "TxD", "RxD", "GND" terminal connecting connector in RS-232C communication	
	8-3	Power supply connector	Power supply connector (24V)	



4.3 Power Supply Specifications

It describes the power supply specification of main unit.

	Items	Specification ("S" type)	
	Rated voltage	DC24V	
	Input voltage range	DC20.4~28.8V (-15%, +20%)	
	Inrush current	70APeak or less	
Input	Input current	1A (Typ.550 ^{mA})	
	Efficiency	60% or more	
	Permitted momentary	Less than 10 ms	
	power failure	Less than 10 ms	
	Output voltage	DC5V (±2%)	
Output	Output current	1.5 A	
Power	supply status indication	LED On when power supply is normal	
(Cable specification	0.75 ~ 2 mm²	

				Specification ("H" type)			
	Items		XBC- DR32H(/HL), XBC-DN32H	XBC-DR64H, XBC-DN64H	XBC-DR32H/DC, XBC-DN32H/DC	XBC-DR64H/DC, XBC-DN64H/DC	
	Rated voltage (UL warranty voltage)		AC 100 ~ 240 V		DC 24V		
	Input vol	tage range	AC85~264V(-15	%, +10%)	DC19.2~28.8V(-2	20%, +20%)	
	Inrush	current	50APeak or less				
Input	Input current		AC 220V : 0.5A or less, AC 110V : 1A or less		0.7A or less	1A or less	
	Effic	ciency	65% or more				
	Permitted momentary power failure		Less than 10 ms				
	Rated	DC5V	2A	3A	2A	ЗА	
Output	output DC24V		0.4A	0.6A	-	-	
Output voltage ripple		DC5V (±2%)					
Power s	Power supply status indication		LED On when power supply is normal				
<u> </u>	able specific		0.75 ~ 2 mm ²				

^{*} Use the power supply which has 4 A or more fuse for protecting power supply.

Chapter 4. CPU Specifications

1) Consumption current (DC 5V)

Item	Model	Current consumption
	XBM-DR16S	400
	XBM-DN16S	250
	XBM-DN32S	280
	XBC-DR32H(/HL)	660
	XBC-DR64H	1,040
Main unit	XBC-DN32H	260
	XBC-DN64H	330
	XBC-DR32H/DC	660
	XBC-DR64H/DC	1,040
	XBC-DN32H/DC	260
	XBC-DN64H/DC	330
	XBE-DC32A	50
	XBE-DC16A	30
	XBE-DC08A	20
	XBE-RY16A	440
	XBE-RY08A	240
	XBE-TN32A	80
Expansion I/O module	XBE-TN16A	50
	XBE-TN08A	40
	XBE-TP32A	80
	XBE-TP16A	50
	XBE-TP08A	40
	XBE-DR16A	250
	XBE-DN32A	60
	XBF-AD04A	120
	XBF-DV04A	110
	XBF-DC04A	110
Expansion special module	XBF-RD04A	100
	XBF-RD01A	100
	XBF-TC04S	100
	XBL-C21A	110
Expansion communication	XBL-C41A	110
module	XBL-EMTA	190

4.4 Calculation Example of Consumption Current/Voltage

Calculate the consumption current and configure the system not to exceed the output current capacity of basic

(1) XGB PLC configuration example 1

Consumption of current/voltage is calculated as follows.

Туре	Model	Unit No.	Internal 5V consumption current (Unit: mA)	Remark
Main unit	XBM-DN16S	1	250	_
	XBE-DC32A	2	50	In case contact points are On. (Maximum consumption current)
	XBE-TN32A	2	80	(Maximum concumption current)
Expansion module	XBF-AD04A	1	120	
Integrate	XBF-DC04A	1	110	All channel is used. (Maximum consumption current)
	XBL-C21A	1	110	(Maximum concumption current)
Consumption current	830 mA		-	
Consumption voltage	4.25 W			0.85 * 5V = 4.25W

In case system is configured as above, since 5V consumption current is total 850mA and 5V output of XGB standard type main unit is maximum 1.5A, normal system configuration is available.

(2) XGB PLC configuration example 2

Туре	Model	Unit No.	Internal 5V consumption current (Unit: mA)	Remark	
Main unit	XBM-DR16S	1	400		
	XBE-DR16A	3	250	In case all contact points are On. (Maximum consumption current)	
Expansion	XBE-TN32A	2	80	(maximum concumption currently	
module	XBF-AD04A	1	120	All channel is used.	
	XBL-C21A 1 1		110	(Maximum consumption current)	
Consumption current	1,540 mA			-	
Consumption voltage	7.7W			1.54 * 5V = 7.7W	

If system is configured as above, total 5V current consumption is exceeded 1,540 mA and it exceeds the 5V output of XGB standard type main unit. Normal system configuration is not available. Although we assume the above example that all contact points are on, please use high-end type main unit which 5V output capacity is higher than standard type main unit.

Chapter 4. CPU Specifications

(3) XGB PLC configuration example 3

Туре	Model	Unit No.	Internal 5V consumption current (Unit: mA)	Remark
Main unit	XBC-DR32H	1	660	In case of all contact points are
	XBE-DR16A	3	250	On.
Expansion	XBE-TN32A	2	80	(Maximum consumption current)
module .	XBF-AD04A	1	120	All channel is used.
	XBL-C21A	1	110	(Maximum consumption current)
Consumption current	1,800 mA		•	-
Consumption voltage	9W		1.8 * 5V = 9W	

The above system is an example using XBC-DR32H about system example (2). Unlike (2) example, 5V output capacity of XBC-DR32H is maximum 2A, normal configuration is available.

Remark

Calculating of consumption current is based on maximum consumption current. In application system, the consumption current is consumed less than above calculation.

4.5 Battery

This contents is only applied to "H" type.

4.5.1 Battery specification

Item	Specification
Voltage/Current	DC 3V / 220 mA
Warranty period	3 years (ambient temp.)
Purpose	Program and data backup, RTC operation in case of power failure
Specification	Manganese Dioxide lithium battery
Dimension (mm)	φ 20 X 3.2 mm

4.5.2 Notice in using

- (1) Do not heat the battery or solder the polarity. (It may cause the reduction of life.)
- (2) Do not measure the voltage or short with tester. (It may cause the fire.)
- (3) Do not disassemble the battery.

4.5.3 Life of battery

Life of battery depends on the power failure time and ambient temperature etc..

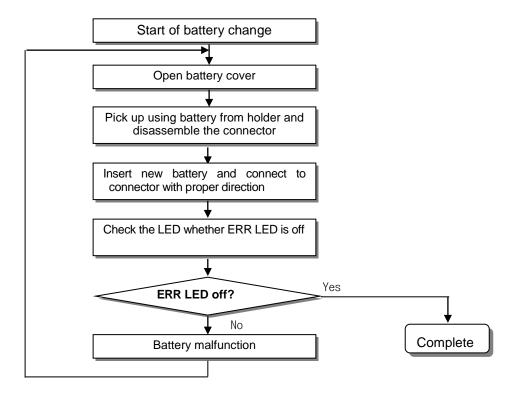
If battery is getting low, main unit cause the warning, 'battery voltage low warning'. The user can check it by error LED, flag and error message of XG5000.

Since battery works properly for long time, after battery voltage low warning, so the user can take the action after battery voltage low warning occurred.

4.5.4 How to change the battery

The user should change the battery used to save the program and backup the data in case of power failure periodically. Though the user eliminate the battery, it works for 30 minute by super capacitor. Change the battery as fast as possible.

Sequence changing battery is as follows.



4.6 Data Back-up Time

Super capacitor-based data backup is applied to XBM series.

Model	Backup time	Note
XBM-DR16S XBM-DN16S XBM-DN32S	10 days	Standard ambient temperature (25℃)

Remark

- (1) It takes about 30minutes to charge XBM super capacitor
- (2) In case of data backup failure within backup time, please contact LS ELECTRIC distributors.
- (3) The backup time depends on the ambient temperature. The higher the temperature is, the shorter the backup time will be.

5.1 Program Instruction

5.1.1 Program execution methods

1) Cyclic operation method (Scan)

This is a basic program proceeding method of PLC that performs the operation repeatedly for the prepared program from the beginning to the last step, which is called 'program scan'. The series of processing like this is called 'cyclic operation method'. The processing is divided per stage as below.

Stage	Processing description		
Start	-		
Initialization processing	 A stage to start the scan processing which is executed once when power is applied or Reset is executed, as below. Self-diagnosis execution Data clear Address allocation of I/O module and type register If initializing task is designated, Initializing program is executed. 		
Input image area refresh	Reads the state of input module and saves it in input image area before starting the operation of program.		
Program operation processing Program start Program last step	Performs the operation in order from the program start to last step.		
Output image area refresh	Performs the operation in order from the program start to last step.		
END	 A processing stage to return to the first step after CPU module completes 1 scan processing and the processing performed is as below. Update the current value of timer and counter etc. User event, data trace service Self-diagnosis High speed link, P2P e-Service Check the state of key switch for mode setting 		

2) Interrupt operation (Cycle time, Internal device)

This is the method that stops the program operation in proceeding temporarily and carries out the operation processing which corresponds to interrupt program immediately in case that there occurs the status to process emergently during PLC program execution.

The signal to inform this kind of urgent status to CPU module is called 'interrupt signal'. There is a Cycle time signal that operates program every appointed time and external interrupt signal that operates program by external contact (I/O; P000~P007). Besides, there is an internal device start program that starts according to the state change of device assigned inside.

3) Constant Scan (Fixed Period)

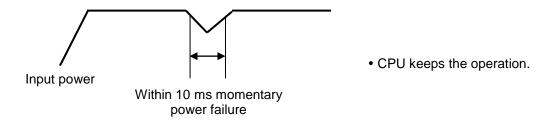
This is the operation method that performs the scan program every appointed time. This stands by for a while after performing all the scan program, and starts again the program scan when it reaches to the appointed time. The difference from constant program is the update of input/output and the thing to perform with synchronization. At constant operation, the scan time indicates the net program processing time where the standby time is deducted. In case that scan time is bigger than 'constant', [F0005C] '_CONSTANT_ER' flag shall be 'ON'.

5.1.2 Operation processing during momentary power failure

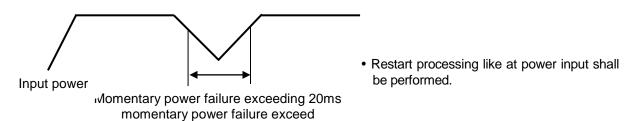
CPU module detects the momentary power failure when input power voltage supplied to power module is lower than the standard. If CPU module detects the momentary power failure, it carries out the operation processing as follows.

If momentary power failure within 10 ms is occurred, main unit (CPU) keeps the operation. But, if momentary power failure above 10 ms, the operation is stop and the output is Off. Restart processing like at power input shall be performed.

1) Momentary power failure within 10 ms



2) Momentary power failure exceeding 10 ms



Remark

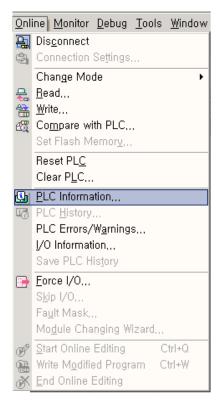
1) Momentary power failure?

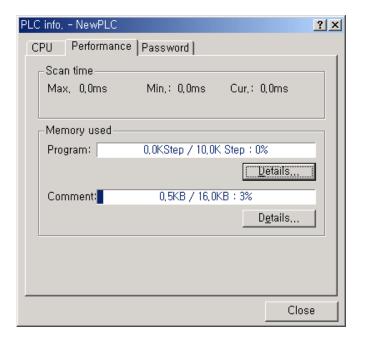
This means the state that the voltage of supply power at power condition designated by PLC is lowered as it exceeds the allowable variable range and the short time (some ms ~ some dozens ms) interruption is called 'momentary power failure').

5.1.3 Scan time

The processing time from program step 0 to the next step 0 is called 'Scan Time'.

- 1) Scan time calculation expression
 - Scan time is the sum of the processing time of scan program and interrupt program prepared by the user and PLC internal time, and is distinguished by the following formula.
 - (1) Scan time = Scan program processing time + Interrupt program processing time + PLC internal processing time
 - Scan program processing time = processing time of user program not saved as interrupt program
 - Interrupt program processing time = Sum of interrupt program proceeding time processed during 1 scan
 - PLC internal processing time = Self-diagnosis time + I/O refresh time + Internal data processing time + Communication service processing time
 - (2) Scan time depends on whether to execute interrupt program and communication processing.
 - 2) Scan time monitor
 - (1) Scan time can be monitored <code>"Online"</code> <code>"PLC Information"</code> <code>"Performance"</code> .





- (2) Scan time is save in special relay (F) area as follows.
 - F0050: max. value of scan time (unit: 0.1 ms)
 - F0051: min. value of scan time (unit: 0.1 ms)
 - F0052: current value of scan time (unit: 0.1 ms)

5.1.4 Scan Watchdog timer

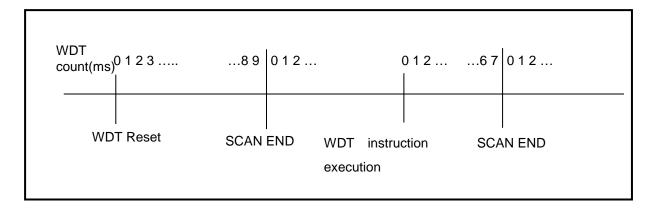
WDT (Watchdog Timer) is the function to detect the program congestion by the error of hardware and software of PLC CPU module.

- 1) WDT is the timer used to detect the operation delay by user program error. The detection time of WDT is set in Basic parameter of XG5000.
- 2) If WDT detects the excess of detection setting time while watching the elapsed time of scan during operation, it stops the operation of PLC immediately and keeps or clears the output according to parameter setting
- 3) If the excess of Scan Watchdog Time is expected in the program processing of specific part while performing the user program (FOR ~ NEXT instruction, CALL instruction), clear the timer by using 'WDT' instruction.

'WDT' instruction initializes the elapsed time of Scan Watchdog Timer and starts the time measurement from 0 again.

(For further information of WDT instruction, please refer to Instruction.)

4) To clear the error state of watchdog, we can use the following method: power re-supply, manipulation of manual reset switch, mode conversion to STOP mode.



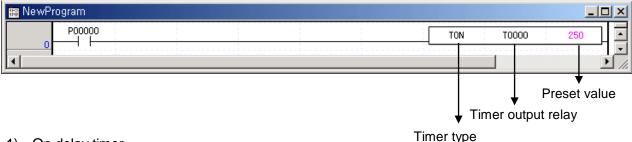
Remark

1) The setting range of Watchdog Timer is 10 ~ 1000ms (Unit: 1ms).

5.1.5 Timer processing

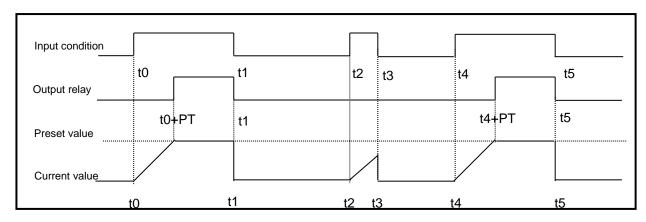
The XGB series use up count timer. There are 5 timer instructions such as on-delay (TON), off-delay (TOFF), integral (TMR), monostable (TMON), and re-triggerable (TRTG) timer.

The measuring range of 100msec timer is $0.1 \sim 6553.5$ seconds, 10msec timer is $0.01 \sim 655.35$ seconds, and that of 1msec timer is $0.001 \sim 65.53$ seconds. Please refer to the 'XG5000 User manual' for details.



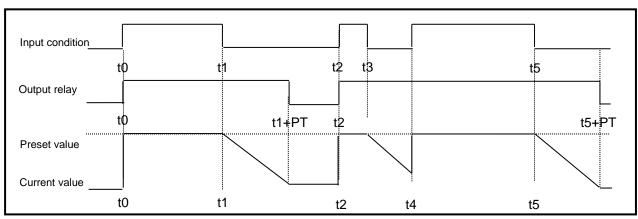
1) On delay timer

The current value of timer starts to increase from 0 when the input condition of TON instruction turns on. When the current value reaches the preset value (Current value=Preset value), the timer output relay (Txxxx) turns on. When the timer input condition is turned off, the current value becomes 0 and the timer output relay is turned off.



Off delay timer

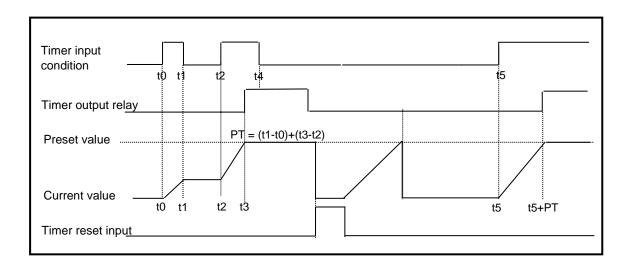
The current value of timer set as preset value and the timer output relay is turned on when the input condition of TOFF instruction turns on. When the input condition is turned off, the current value starts to decrease. The timer output relay is turned off when the current value reaches 0.



3) Integral timer

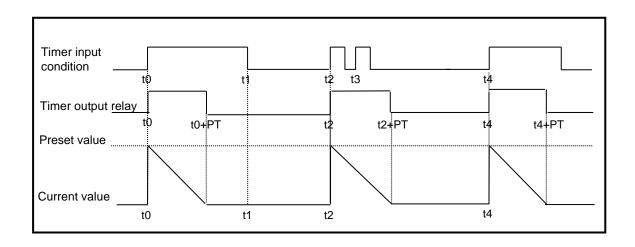
In general, its operation is same as on-delay timer. Only the difference is the current value will not be clear when the input condition of TMR instruction is turned off. It keeps the elapsed value and restart to increase when the input condition is turned on again. When the current value reaches preset value, the timer output relay is turned on.

The current value can be cleared by the RST instruction only.



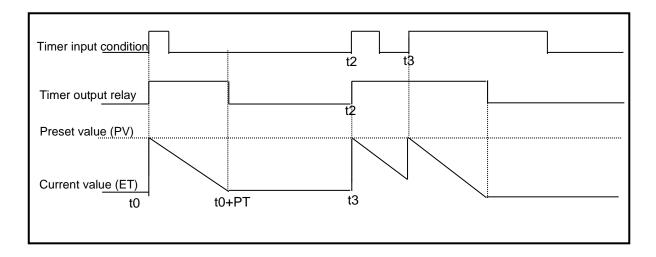
4) Monostable timer

In general, its operation is same as off-delay timer. However, the change of input condition is ignored while the timer is operating (decreasing). When current value reaches preset value the timer output relay is turned off and current value is cleared.



5) Retriggerable timer

The operation of retriggerable timer is same as that of monostable timer. Only difference is that the retriggerable timer is not ignore the input condition of TRTG instruction while the timer is operating (decreasing). The current value of retriggerable timer will be set as preset value whenever the input condition of TRTG instruction is turned on.



Remark

The Maximum timing error of timers of XGB series is '1 scan time + the time from 0 step to timer instruction'

5.1.6 Counter processing

The counter counts the rising edges of pulses driving its input signal and counts once only when the input signal is switched from off to on. XGB series have 4 counter instructions such as CTU, CTD, CTUD, and CTR. The followings shows brief information for counter operation. Refer to the 'XGB Instruction Manual' for details.

- Up counter increases the current value.
- Down counter decreases the current value.
- Up/Down counter compares the input value from both counters input.
- Ring counter increase the current value and the current value is cleared as 0 when the current value reaches the preset value.
- 1) Renewal of counter's current value and contact On/Off

(1) Up counter

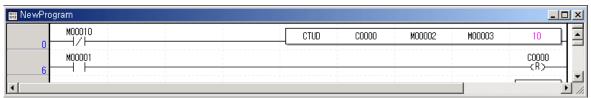


- Up counter increases the current value at the rising edges of input.
- The counter output contact (Cxxx) is turned On when the current value reaches the preset value. When the reset input is turned On, the counter output contact (Cxxx) is turned Off.

(2) Down counter

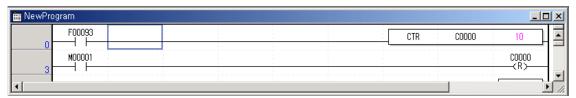


- Down counter decreases the current value at the rising edges of input.
- The counter output contact (Cxxx) is turned On when the current value reaches the preset value. When the reset input is turned On, the counter output contact (Cxxx) is turned Off.
- (3) Up/Down counter



- The current value is increased with the rising edge of up-count input signal, and decreased with the rising edge of down-count input signal. The counter output contact (Cxxx) is turned On when the current value is same as or more than current value. The counter output contact (Cxxx) is turned Off when the current value is same as or less than current value.
- When the reset input is turned On, the current value is cleared as 0.

(4) Ring counter



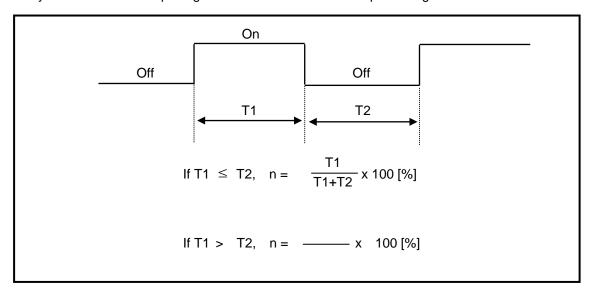
- The current value is increased with the rising edge of the counter input signal, and the counter output contact (Cxxx) is turned on when the current value reaches the preset value. Then the current value and counter output contact (Cxxx) is cleared as 0 when the next rising edge of the counter input signal is applied.
- When the reset input is turned On, the counter output contact is cleared as 0.

2) Maximum counting speed

The maximum counting speed of determined by the length of scan time. Counting is possible only when the on/off switching time of the counter input signal is longer than scan time.

Maximum counting speed
$$C_{\text{max}} = \frac{n}{100} \times (\frac{1}{t_s})$$
 $n : \text{duty (\%)}$ $t_s : \text{scan time [s]}$

• Duty is the ratio of the input signal's on time to off time as a percentage.



Remark

1) Use of High Speed Counter

In order to counter pulse that is faster than maximum counting speed of normal counter, use built-in High Speed counter function.

5.2 Program Execution

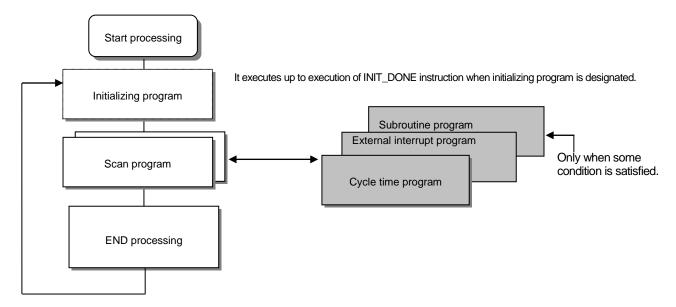
5.2.1 Configuration of program

All functional elements need to execute a certain control process are called as a 'program'. Program is stored in the built-in RAM mounted on a CPU module or flash memory of a external memory module. The following table shows the classification of the program.

Program type	Description
Initializing program	It will be executed till the specific Flag 'INIT_DONE' is On. And while the initialization task is executed, several of initializing program is programmed. (If INIT_DONE instruction is executed, scan program is executed.)
Scan program	The scan program is executed regularly in every scan.
Cycle time interrupt program	 The program is performed according to the fixed time interval in case that the required processing time condition is as below. In case that the faster processing than 1 scan average processing time is required In case that the longer time interval than 1 scan average processing time is required In case that program is processed with the appointed time interval
External interrupt program	The external interrupt program is performed process on external interrupt signal.
Subroutine program	Only when some condition is satisfied.(in case that input condition of CALL instruction is On)

5.2.2 Program execution methods

Here describes the program proceeding method that is executed when the power is applied or key switch is 'RUN'. The program performs the operation processing according to the configuration as below.



1) Scan program

- (1) Function
 - This program performs the operation repeatedly from 0 step to last step in order prepared by the program to process the signal that is repeatedly regularly every scan.
 - In case that the execution condition of interrupt by task interrupt or interrupt module while executing program is established, stop the current program in execution and perform the related interrupt program.

2) Interrupt program

- (1) Function
 - This program stops the operation of scan program and then processes the related function in prior to process the internal/external signal occurred periodically/non-periodically.

(2) Type

- Task program is divided as below.
 - ▶ Cycle time task program: available to use up to 8.
 - ▶ Internal device task program: available to use up to 8.
 - ▶ I/O (External contact task program): available to use up to 8. (P000 ~ P007)
- Cycle time task program
 - ▶ Performs the program according to the fixed time internal.
- Internal device task program
 - Performs the corresponding program when the start condition of internal device occurs.
 - ▶ The start condition detection of device shall be performed after processing of scan program.
- I/O (External contact task program)
 - ▶ Performs the program according to the input external signal (P000~P007).

Remark

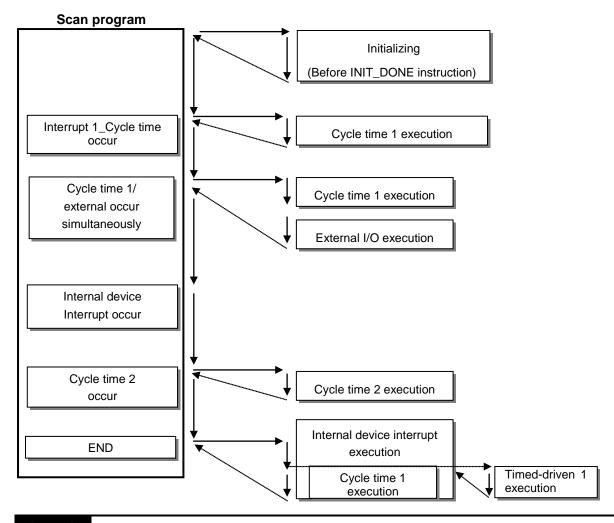
- (1) Write the interrupt program as shortly as possible. In case same interrupt occurs repeatedly before completion of interrupt, program is not executed and O/S watch dog error may occur.
- (2) Though interrupt which has lower priority occurs many times during execution of interrupt which has higher priority, interrupt which has lower priority occurs only one time.

5.2.3 Interrupt

For your understanding of Interrupt function, here describes program setting method of XG5000 which is an XGB programming S/W. Example of interrupt setting is as shown bellows.

Interrupt setting

Interrupt source	Interrupt name	priority	Task No.	Program
Initializing	Interrupt 0_	-	-	1
Cycle time 1	Interrupt 1_cycle time	2	0	Cycle time 1
External	Interrupt 2_external	2	8	External
Internal device	Interrupt 3_internal	3	14	Internal
Cycle time 2	Interrupt 4_cycle time	3	1	Cycle time 2

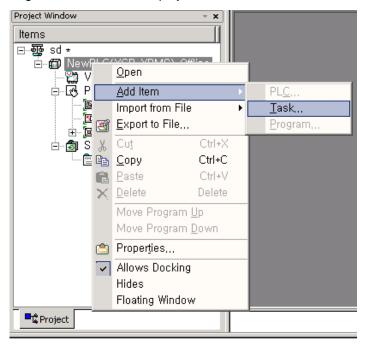


Remark

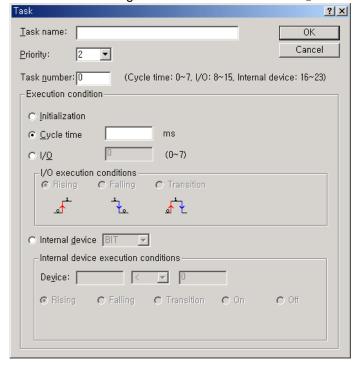
- In case that several tasks to be executed are waiting, execute from the highest Task Program in priority. When the same priority tasks are waiting, execute from the order occurred.
- While interrupt executing, if the highest interrupt is occurred, the highest interrupt is executed earliest of all.
- When power On, All interrupts are in the state 'Disable'
- Internal device interrupt is executed after END instruction.

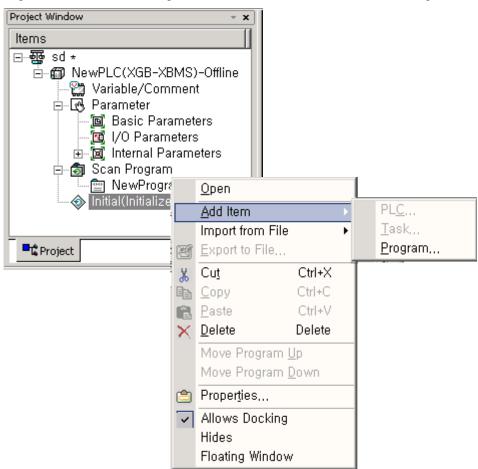
1) How to prepare interrupt program

Generate the task in the project window of XG5000 as below and add the program to be performed by each task. For further information, please refer to XG5000 user's manual. (It can be additional when XG5000 is not connected with PLC.)



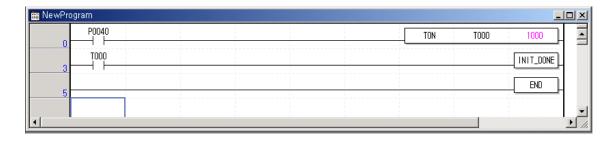
• The screen of Task setting is shown. Click 『Initialization』 in Execution condition and make a Task name.





• Click right button of mouse at registered task and select <code>"Add Item" - "Program"</code> .

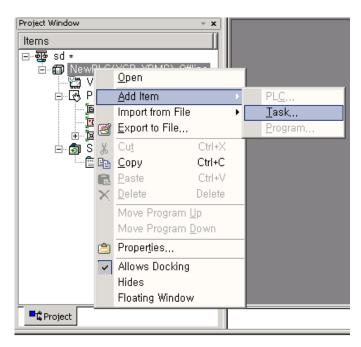
• Make initializing program. In initializing program, INIT_DONE instruction must be made. If not, Scan program is not executed.



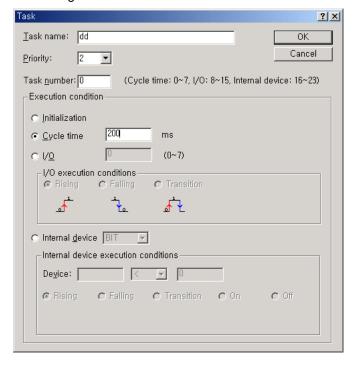
2) How to prepare Cycle interrupt program

Generate the task in the project window of XG5000 as below and add the program to be performed by each task. For further information, please refer to XG5000 user's manual. (It can be additional when XG5000 is not connected with PLC)

• Click right button of mouse at registered task and select <code>"Add Item"</code> - <code>"Program"</code> .

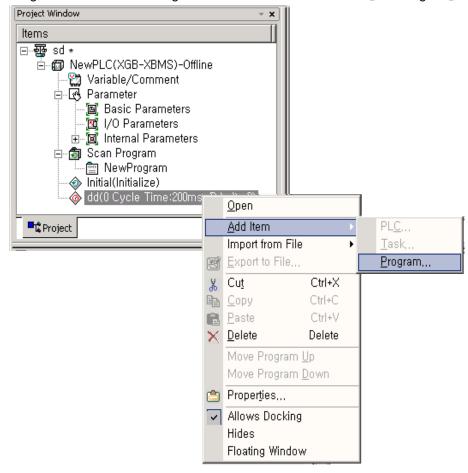


• It shows setting screen of Task.

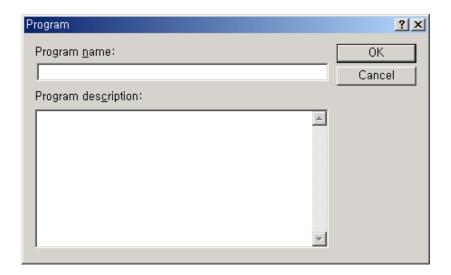


Classification		Description	Remark
Task name	,	Make Task name.	Character, number available
Priority		Set the priority of task. (2~7)	"2" is the highest priority number.
Task number		Set the Task number. • Cycle time task (0 ~ 7): 8 • External I/O task (8 ~ 15): 8 • Internal device task (16 ~ 23): 8	-
	Initialization	Set the initial program when running the project.	Till the execution of INIT_DONE instruction
Execution condition	Cycle time	Set the cyclic interrupt.	0~4294967295 ms available
	I/O	Set the external I/O.	P000 ~ P007 available
	Internal device	Set the internal device to interrupt execution. • Bit: Among Rising, Falling, Transition, On, Off • Word: Among >,>=,<,<=	-

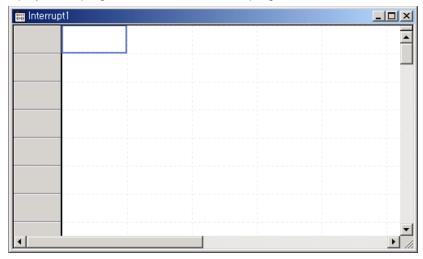
• Click right button of mouse at registered task and select <code>"Add Item"</code> - <code>"Program"</code> .



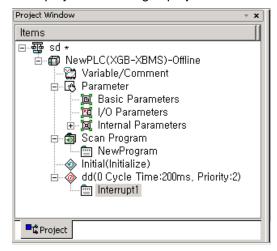
• Register the Program name and Program description.



• It is displayed the program window to write task program.



• It is displayed the setting in project window.



3) Task type

Task type and function is as follows.

Type Spec.	Cycle time task (Interval task)	I/O task (Interrupt task)	Internal device task (Single task)	
Max. Task number	8	8	8	
Start condition	Cyclic (setting up to max. 4,294,967.295 sec. by 1ms unit)	Rising or falling edge of main unit's contact P000 ~P007	Internal device execution condition	
Detection and execution	Cyclic execution per setting time	Immediate execution at the edge of main unit's contact	Retrieve the condition and execute after completing Scan Program	
Detection delay time	Max. 1 ms delay	Max. 0.05 ms delay	Delay as much as max. scan time	
Execution priority	2~7 level setting (2 level is highest in priority)	2~7 level setting (2 level is highest in priority)	2~7 level setting (2 level is highest in priority)	
Task no.	Within 0~7 range without user duplication With 8		Within 16~23 range without user duplication	

4) Processing methods of task program

Here describes common processing method and notices for Task program.

(1) Feature of task program

- Task Program is executed only when execution condition occurs without every scan repeat processing. When preparing Task Program, please consider this point.
- For example, if a timer and counter were used in cyclic task program of 10 second cycle, this timer occurs the tolerance of max. 10 seconds and the counter and the timer and as the counter checks the input status of counter per 10 seconds, the input changed within 10 seconds is not counted up.

(2) Execution priority

- In case that several tasks to be executed are waiting, execute from the highest Task Program in priority. When the same priority tasks are waiting, execute from the order occurred.
- In case Cycle time task and external I/O task is occurred concurrently, execute from the highest task program. (In sequence of XG5000 setting)
- The task program priority should be set considering the program features, importance and the emergency when the execution requested.

(3) Processing delay time

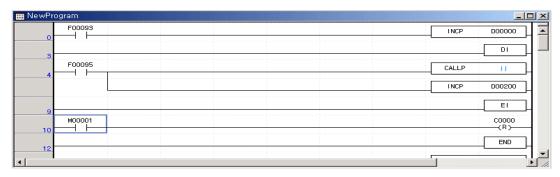
There are some causes for Task Program processing delay as below. Please consider this when task setting or program preparation.

- Task detection delay (Refer to detailed description of each task.)
- Program proceeding delay caused by Priority Task Program proceeding

(4) Relationship of initialize, Scan Program and Task Program

- ser identification task does not start while performing Initialization Task Program.
- As Scan Program is set as lowest priority, if task occurs, stop Scan Program and process Task Program in advance. Accordingly, if task occurs frequently during 1 scan or concentrates intermittently, scan time may extend abnormally. Cares should be taken in case of task condition setting.

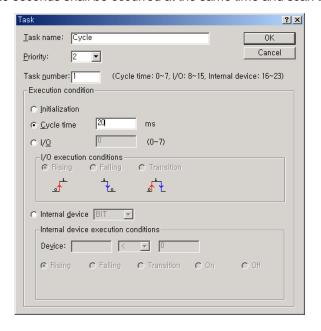
- (5) Protection of Program in execution from Task Program
- In case that the continuity of program execution is interrupted by high priority Task Program during program execution, it is available to prohibit the execution of Task Program partially for the part in problem. In this case, it is available to perform the program protection by 'DI (Task Program Start Disabled) and 'EI (Task Program Start Enabled)' application instruction.
- Insert 'DI' application instruction in the start position of the part requiring the protection and insert 'EI' application instruction in the position to release. Initialization Task is not influenced by 'DI', 'EI' application instruction.
- If interrupt is occurred while 'CALLP' instruction executing, interrupt program is executed after 'CALLP' instruction execution.



5) Cyclic task program processing method

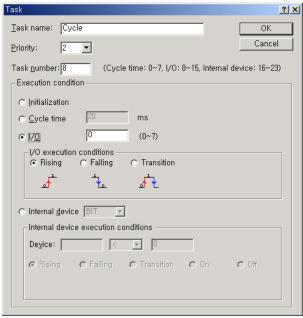
Here describes the processing method in case that task (start condition) of Task program is set as Cycle time.

- (1) Items to be set in Task
 - Set the execution cycle and priority which are the start condition of Task program to execution. Check the task no. to manage the task.
- (2) Cyclic task processing
 - Performance the corresponding cyclic task program per setting time interval (execution cycle).
- (3) Notice in using cyclic task program
- When cyclic task program is in execution currently or waiting for execution, if the demand to execute the same task program occurs, the new occurred task shall be disregarded.
- Timer that makes a demand to execute cyclic task program only while operation mode is Run mode, shall be added. The shutdown time shall be all disregarded.
- When setting the execution cycle of cyclic task program, consider the possibility that the demand to execute several cyclic task program at the same time occurs.
 - If 4 cyclic task programs that the cycle is 2sec, 4sec, 10sec and 20sec are used, 4 demands of execution per 20 seconds shall be occurred at the same time and scan time may extend instantaneously.



6) I/O task program processing

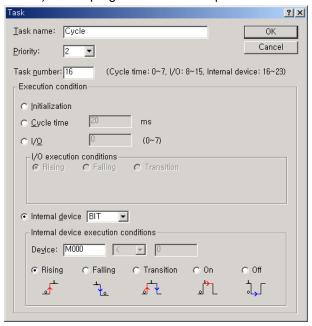
It described the I/O task program processing. (P000 ~ P007)



- (1) Items to be set in Task
- Set the execution condition and priority to the task being executed. Check the task no. to manage the task.
- (2) I/O task processing
- If interrupt signal from external signal (I/O) is occurred on main unit (P000 ~ P007), task program is executed by external (I/O) signal.
- (3) Precaution in using I/O task program
 - If task program which is executed by interrupt signal is on execution or standby status, new task program which is requested by identical I/O is ignored.
 - Only operation mode is Run mode, execution request of task program is recognized. Namely, execution request of task program is ignored when operation mode is Stop mode.

7) Internal device task program processing

Here describes the processing method of international device task program which extended the task (start condition) of task program from contact point to device as execution range.



- (1) Items to be set in Task
 - Set the execution condition and priority to the task being executed. Check the task no. for task management.
- (2) Internal device task processing
 - After completing the scan program execution in CPU module, if the condition that becomes the start condition of internal device task program is met, according to the priority, it shall be executed.
- (3) Precautions in using internal device task program
 - Accordingly, even if the execution condition of internal device task program occurs in Scan Program
 or Task Program (Cycle time, I/O), it shall not be executed immediately but executed at the time of
 completion of Scan Program.
 - If the demand to execute Internal Device Task Program occurs, the execution condition shall be examined at the time of completion of Scan Program. Accordingly, if the execution condition of Internal Device Task occurs by Scan Program or Task Program (Cycle time) during '1 scan' and disappears, the task shall not be executed as it is not possible to detect the execution at the time of examination of execution condition.

8) Verification of task program

(1) Is the task setting proper?

If task occurs frequently more than needed or several tasks occur in one scan at the same time, scan time may lengthen or be irregular. In case not possible to change the task setting, verify max. scan time.

(2) Is the priority of task arranged well?

The low priority task program shall be delayed by the high priority task program, which results in disabling the processing within the correct time and even task collision may occur as next task occurs in the state that the execution of previous task is delayed. Consider the emergency of task and execution time etc when setting the priority.

(3) Is the Task Program written in shortest?

If the execution time of Task Program is longer, scan time may lengthen or be irregular. Even it may cause the collision of task program. Write the execution time as short as possible. (Especially, when writing the cyclic task program, write the execution time so that the task program can be executed within 10% cycle of the shortest task among several tasks.)

(4) Is program protection for the high priority task needed during program execution?

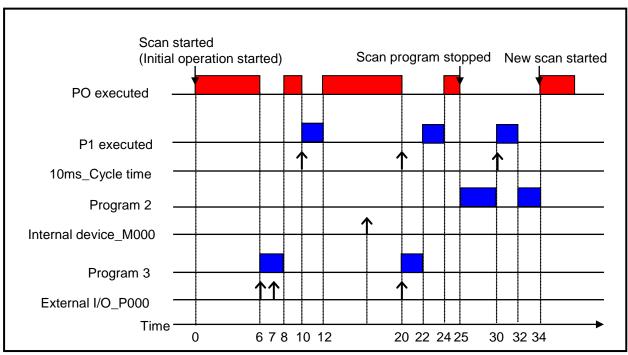
If other task is inserted during task program execution, complete the task in execution and operate the standby tasks in the order of high priority. In case that it is not allowed to insert other task in Scan Program, prevent the insert partially by using 'DI' and 'EI' application instruction. The problem may occur while processing the global variables used commonly with other program or special or communication module.

9) Program configuration and processing example

If task and program are registered as below.

in tack and program are registered as below				
Interrupt type	Interrupt name	Priority	Task No.	Program
Cycle time	10 ms_cycle time	3	0	Program 1
Internal device	Internal device_M00	5	16	Program 2
I/O	I/O_P00	2	8	Program 3

- Scan program name: "Scan Program"
- Execution time respective program: Scan program = 17 ms, Program 1 = 2 ms, Program 2= 7 ms, Program 3 = 2 ms



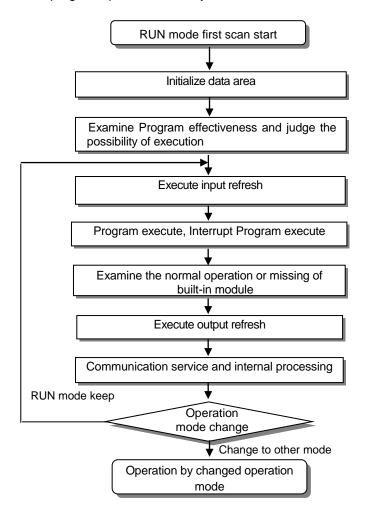
Process per	Process per time		
Time (ms)	Process		
0	Scan started and scan program started to execute.		
0~6	Scan program is executed.		
6~8	Scan program is stop because execution external I/O (P000) is requested. And program 3 is executed. Request of execution at 7[ms] is ignored because program 3 has been executing.		
8~10	Program 3 is finished and Scan program is continued.		
10~12	Scan program is stop by request of '10 ms_Cycle time' interrupt signal and execute program 1.		
12~20	Program 1 is finished and Scan program is continued.		
20	Request of 'Cycle time' interrupt signal and 'External I/O (P000)' signal is occurred concurrently but priority of 'External I/O' signal is higher than 'Cycle time' interrupt signal so program 3 is executed and program 1 is standby.		
20~22	Program 3 is finished and Scan program is continued.		
22~24	After program 3 is completed, program 1 (the program of '10ms_Cycle time' is executed.		
24~25	P1 execution completed and the stopped scan program execution finished		
25	At the finished point of scan program, check the request of Internal device 'M000' execution and execute program 2.		
25~30	Program P2 is executed.		
30~32	When '10 ms_Cycle time' interrupt signal is occurred, the priority of that is higher than Internal device 'M000' though program 2 is stopped and program 1 is executed.		
32~34	P1 executed completed and the stopped P2 execution finished		
34	New scan starts (Start scan program execution)		

5.3 Operation Mode

For operation mode of CPU module, there are 3 types such as RUN mode, STOP mode and DEBUG mode.. Here describes the operation processing of each operation mode.

5.3.1 RUN mode

This is the mode to executed program operation normally.



1) Processing at mode change

At the beginning, execute initialization of data area and examine the effectiveness of program and judge the possibility of execution.

2) Operation processing contents

Execute I/O refresh and program operation.

- (1) Detects the start condition of Interrupt Program and executes Interrupt Program.
- (2) Examines the normal operation or missing of built-in module.
- (3) Communication service and other internal processing.

5.3.2 STOP mode

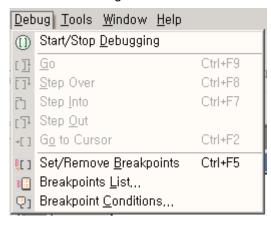
This is the mode in stop state without Program operation. It is available to transmit the program through XG5000 only in Remote STOP mode.

- 1) Processing at Mode Change
 - Clear the output image area and execute output refresh.
- 2) Operation Processing Contents
 - (1) Executes I/O refresh.
 - (2) Examines the normal operation or missing of built-in module.
 - (3) Communication service or other internal processing.

5.3.3 DEBUG mode

This is the mode to detect Program error or trace the operation process and the conversion to this mode is available only in STOP mode. This is the mode to check the program execution state and the contents of each data and verify the program.

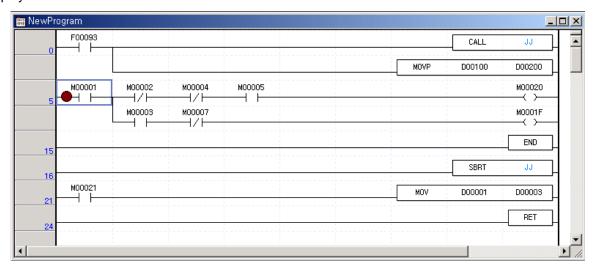
- 1) Processing at mode change
 - (1) Initializes the data area at the beginning of mode change.
 - (2) Clears the output image area and execute input refresh.
- 2) Operation processing contents
 - (1) Executes I/O refresh.
 - (2) Debug operation according to setting state.
 - (3) After finishing Debug operation by the end of Program, execute output refresh.
 - (4) Examine the normal operation or missing of built-in module.
 - (5) Executes communication service or other service.
- 3) Debug operation
 - ☐ It describes debug mode.



Item	Description	Remark
Start/Stop Debugging	Change the debug ↔ stop mode	
Go	It starts debug operation.	
Step Over	It operates by 1 step.	
Step Into	It starts the subroutine program.	Other operation is
Step Out	It finished the subroutine program.	identical to Step Over.
Go to Cursor	It operates to current cursor position.	
Set/Remove Breakpoints	Set/Removes current cursor position to break points.	
Breakpoints List	It displays list of breakpoints.	
Breakpoint Conditions	It specifies device value and number of scan.	

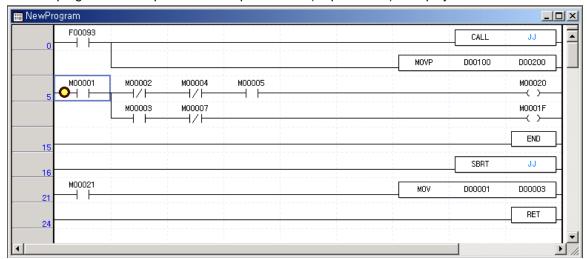
(1) Set/Remove Breakpoints

• Sets breakpoint at current cursor position. After breakpoint setting, (breakpoint setting indicator) is displayed.



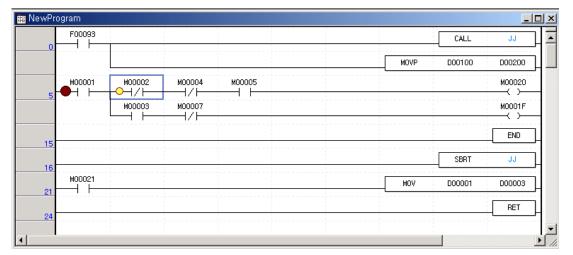
(2) Go

■ Run the program to breakpoint. At break-pointer -O- (stop indicator) is displayed.



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- (3) Step Over
 - Run the program to next step. At break point, Step over indicator -○ is displayed.

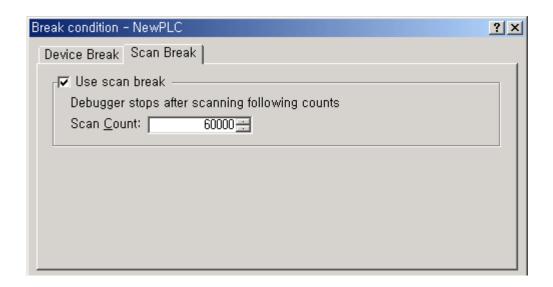


- (4) Breakpoint List
 - It displays current Breakpoint List. It supports Select All, Reset All, Goto, Remove, Remove All.



- (5) Break condition
 - It sets Device Break and Scan Break.





Remark

• Refer to XG5000 Users Manual 'Chapter 12 Debugging' for detailed information.

5.3.4 Change operation mode

1) Operation Mode Change Method

The method to change operation mode are as follows.

- (1) By mode key of CPU module
- (2) By connecting the programming tool (XG5000) to communication port of CPU
- (3) By changing the operation mode of other CPU module connected to network by XG5000 connected to communication port of CPU.
- (4) By using XG5000, HMI, computer link module connected to network
- (5) By 'STOP' instruction during program execution

2) Type of operation mode

The operation mode setting is as follows.

Operation mode switch	XG5000 command	Operation mode
RUN	Х	Run
STOP	RUN	Remote Run
	STOP	Remote Stop
	Debug	Debug Run
	Mode change	Previous operation mode
RUN -> STOP	-	Stop

- (1) Remote mode conversion is available only in the state of 'Remote Enabled: On', 'Mode switch: Stop'.
- (2) In case of changing the Remote 'RUN' mode to 'STOP' by switch, operate the switch as follows. (STOP) \rightarrow RUN \rightarrow STOP.

. Warning

In case of changing Remote RUN mode to RUN mode by switch, PLC operation continues the operation without interruption.

It is available to modify during RUN in RUN mode by switch but the mode change operation by XG5000 is limited. This should be set only in case that remote mode change is not allowed.

5.4 Memory

There are two types of memory in CPU module that the user can use. One is Program Memory that saves the user program written by the user to build the system, and the other is Data Memory that provides the device area to save the data during operation.

5.4.1 Data memory

1) Bit device area

Various Bit Device are provided per function. The indication method is indicated by device type for first digit, word position by decimal for middle digit and bit position by hexadecimal for the last digit.

Area per device				
"S" type	"H" type	Device features	Description	
P0000 ~ P127f	P0000~ P1023f	I/O device "P"	Image area to save the state of I/O device. After reading the input module state, saves it in the corresponding P area and sends P area Data saving the operation result to output module.	
M0000 ~ M255f	M0000~ M1023f	Internal device "M"	Internal Memory provided to save Bit Data in Program	
L0000 ~ L1279f	L0000~ L2047f	Communication device "L"	Device to indicate high speed link/P2P service state information of communication module.	
K00000 ~ K2559f	K00000~ K4095f	Preservation device "K"	Device area to preserve the data during power shutdown, which is used without setting power shutdown preservation parameter separately. (Pay attention to write in special area (K2600 ~ 2559F)).	
F0000 ~ F255f	F0000~ F1023f	Special device "F"	System flag area that manages the flag necessary for system operation in PLC.	
T0000 ~ T255	T0000~ T1023	Timer device "T"	Area to save the state of contact/current value/set value of timer device	
C0000 ~ C255	C0000~ C1023	Counter device "C"	Area to save the state of contact/current value/set value of counter device	
S00.00 ~ S127.99	S00.00~ S127.99	Step controller "S" 128 x 100 step	Relay for step control	

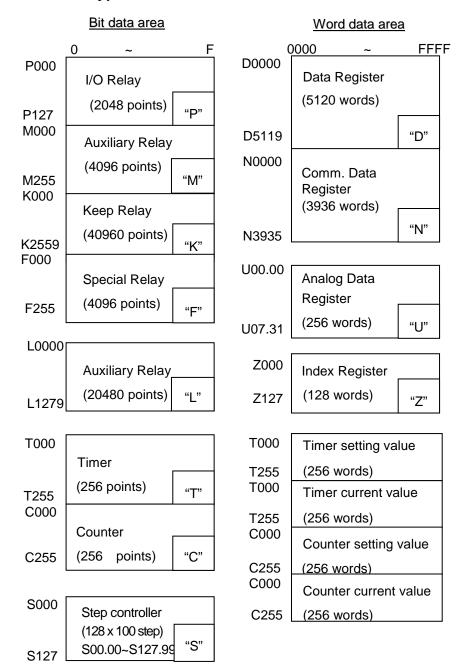
Chapter 5. Program Configuration and Operation Method

2) Word device area

Area per device		Device features	Description	
"S" type	"H" type	Device realares	Besonption	
D00000 ~ D5119	D0000~ D10239	Data register "D"	Area to preserve the internal data. Bit expression possible. (D0000.0)	
U00.00 ~ U07.31	U00.00~ U0A.31	Analog data register "U"	Register used to read data from special module installed in the slot. Bit expression possible	
N0000 ~ N3935	N0000~ N5119	Communication data register "N"	P2P Service Save area of communication module. Bit expression impossible	
Z000 ~ Z127	Z000~ Z127	Index register "Z"	Dedicated device to use Index function Bit expression impossible	
T0000 ~ T255	T0000~ T1023	Timer current value register "T"	Area to indicate the current value of timer	
C0000 ~ C255	C0000~ C1023	Counter current value register "C"	Area to indicate the current value of counter	
-	R0000~ R10239	File register "R"	Register for saving the file	

5.5 Configuration Diagram of Data Memory

5.5.1 "S" type



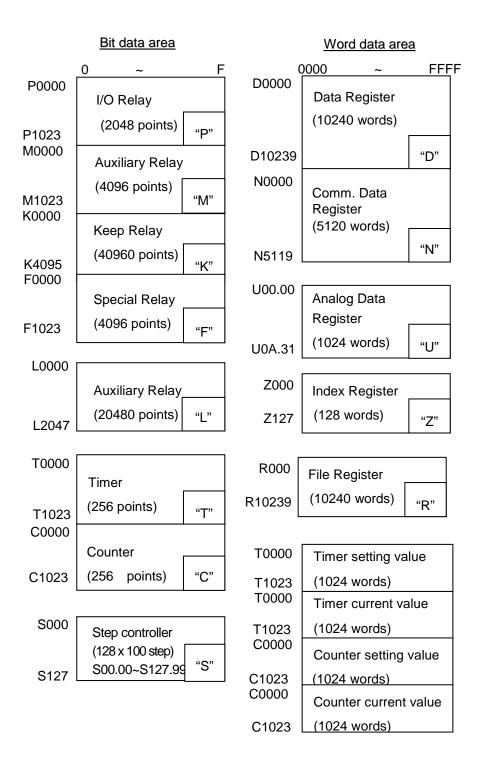
User Program area

Parameter area

User Program area

(10 K step)

5.5.2 "H" type



User Program area

Parameter area
User Program area (15 K step)

5.5.3 Data latch area setting

When PLC stops and restarts the data required for operation or the data occurred during operation, if you want to keep and use those data, data latch can be used and it is available to use a certain area of some data device as latch area by parameter setting.

The below shows the features for latch device.

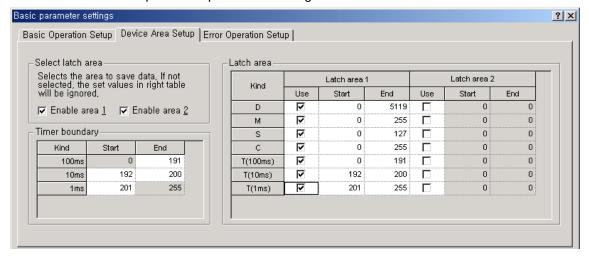
Device	1st latch	2 nd latch	Features
Р	Х	Х	Image area to save the state of I/O device
М	0	0	Internal device area
K	Х	Х	Device keeping the device state during power shutdown
F	Х	Х	System flag area
Т	0	0	Timer related area (Bit/words both)
С	0	0	Counter related area (Bit/words both)
S	0	0	Relay for step control
D	0	0	General words data save area
U	Х	Х	Analog Data Register (latch disabled)
L	Х	Х	High speed link/P2P Service state device of communication module (latch enabled)
N	X	Х	P2P Service address area of communication module (latch enabled)
Z	X	Χ	Index dedicated Register (latch disabled)
R	Х	Х	File register (latch enabled)

Remark

• K, L, N, R devices are basically latched.

1) Latch area setting

Click Device Area Setup of Basic parameter settings.



Chapter 5. Program Configuration and Operation Method

2) Data latch area operation

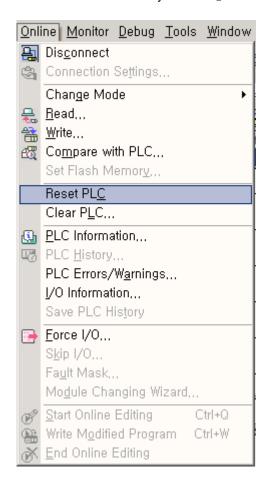
The method to delete the latched data is as below.

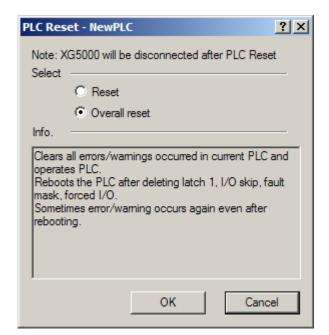
- latch 1, latch 2 clear operation by XG5000
- write by Program (initialization program recommended)
- write '0' FILL from XG5000 monitor mode.

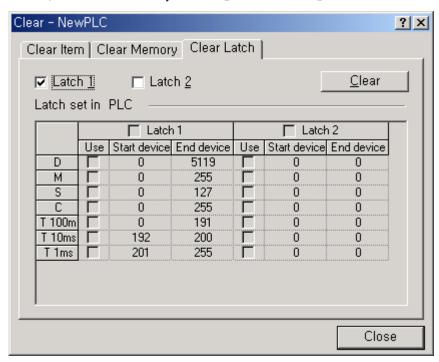
For keep or reset (clear) operation of latch area data according to PLC operation, please refer to the below table.

No.	Classification	Detailed operation	Latch 1	Latch 2
1	Power change	Off/On	Keep	Keep
2	Reset by XG5000	Overall reset	Reset	Keep
3	Program write (online)	-	Keep	Keep
	. Detailed a	SRAM broken by battery error	Reset	Reset
4	Data broken	Data broken by other reason	Reset	Reset
_	5 XG5000 online	Clear Latch 1	Reset	Keep
5		Clear Latch 2	Reset	Reset

■ Latch 1 area is cleared by 『Online』 - 『Reset PLC』 - "Overall reset".





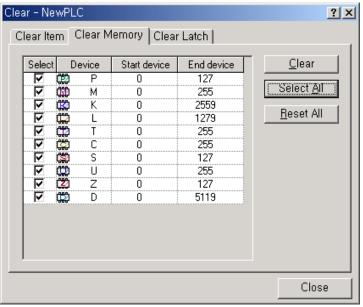


■ Latch 1, 2 area is cleared by 『Online』 - 『Clear PLC』 .

3) Data initialization

In case of Memory Delete state, the memory of all device shall be cleared as '0'. In case of giving the data value at the beginning according to system, please use the initialization task.

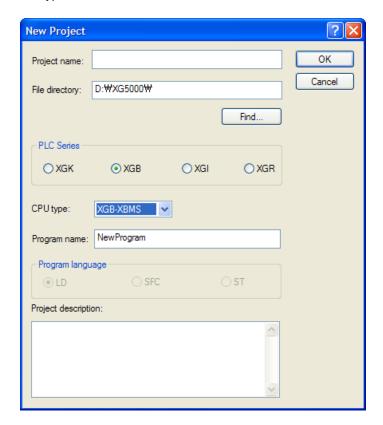
Device area is cleared by click 'Clear' in "Online" - "Clear PLC" - "Clear Memory".





Chapter 6 CPU Functions

6.1 Type SettingIt describes setting of XGB PLC type.



PLC Series	CPU type	Description	Reference
	XGB-DR16C3	Dedicated product	Module type
XGB	XGB-XBMS	"S" type: XBM-DN16/32S, XBM-DR16S	Module type
	XGB-XBCH	"H" type: XBC-DR32/64H, XBC-DN32/64H	Compact type

Remark

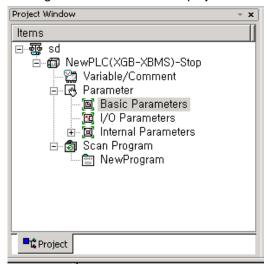
• In case type is different, connection is not available.

6.2 Parameter Setting

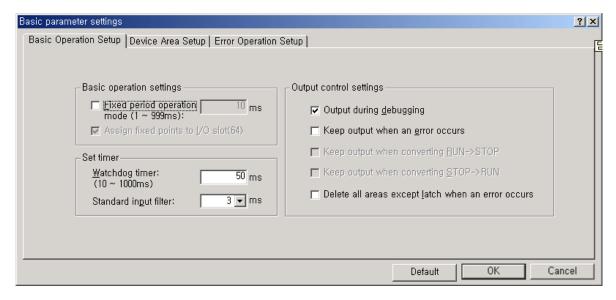
This paragraph describes how to set parameters.

6.2.1 Basic parameter setting

Clicking Basic Parameter in the project window shows the following window.



There are three main options; "Basic Operation Setup", "Device Area Setup" and "Error Operation Setup".

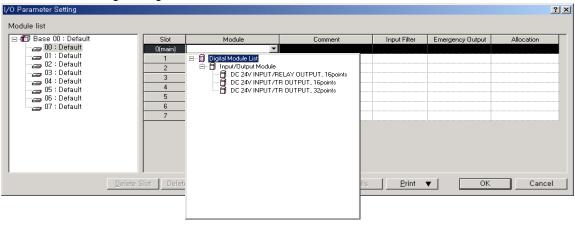


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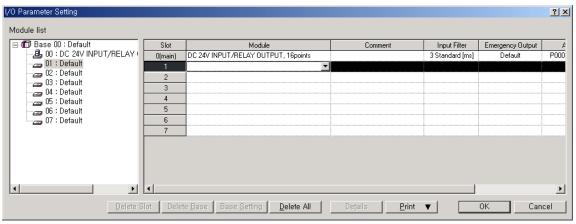
Category	Item	Description	Note
	Fixed period operation	Set the time of fixed period operation.	1~999 ms
	Watchdog timer	Set the time of scan watchdog.	10~1000 ms
	Standard input filter	Set the time of standard input filter.	1,3,5,10,20,70,100 ms
Basic operations	Output during debugging	Set whether to allow output actually during debugging operation.	Allowance/Prohibition
	Keep output when an error occurs	Set whether to preserve output holding function set in I/O parameter in case of error.	Allowance/Prohibition
	Delete all areas except latch when an error occurs	Set whether to clear each device that is not designated as a latch area in case of error	Allowance/Prohibition
Device area	Select latch area	Set the latch area of each device.	-
Error operation	Operation resumes in case of operation error	Set whether to pause or resume operation in case of operation error.	Pause/Resume

6.2.2 I/O parameter setting

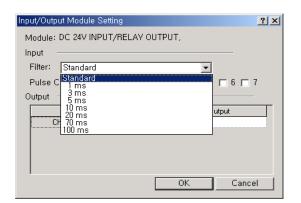
This setting is to set and reserve each I/O information. Clicking <code>[I/O Parameter]</code> in the project window shows the following setting window.

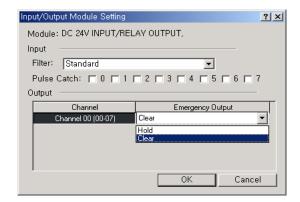


Clicking <code>"Module_"</code> in <code>"Slot Position_"</code> indicates a list of modules, in which you may set I/O corresponding to the actual system. Then, the following window is displayed.



Clicking "Details" in "Slot Position" shows the following window to set filter and emergency output.





Remark

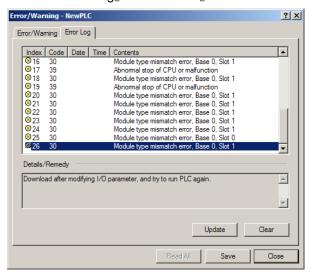
If settings are different with I/O module actually accessed, "Inconsistent module type error" occurs, displaying error.

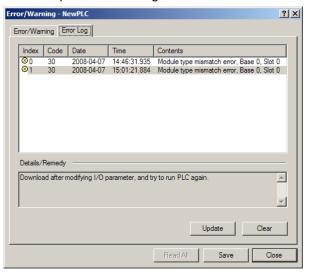
Without settings, CPU reads each I/O module information and operates.

6.3 Self-diagnosis Function

6.3.1 Saving of error log

CPU module logs errors occurred so that the causes will be identified and fixed easily. Clicking "Error/Warning" of "Online" shows the current error and previous error log.





["S" type] ["H" type]

Item	Description	Remarks
Error/Warning	Display the current error/warning.	-
Error Log	Display a log of error/warning occurred.	Saving up to 100

Remark

- 1) Saved data are not deleted until selecting a menu of XG5000 and clicking "Delete".
- 2) "H" type displays Data and Time.

6.3.2 Troubleshooting

(1) Trouble types

Trouble occurs due to PLC itself, system configuration error or abnormal operation result detected. Trouble is divided into trouble mode stopping operation for the safety and warning mode generating alert to user with a mode in trouble.

The causes troubling PLC system are as follows.

- PLC hardware trouble
- System configuration error
- Operation error while operating user program
- Error detected owing to external device in trouble

(2) Operation mode if trouble occurs

PLC system logs any trouble occurred in flag and determines whether to stop or resume operation depending on trouble mode.

A) PLC hardware trouble

In case an error occurs so that PLC such as CPU module and power module may not work normally, the system is halted, but any warning may not interfere with the operation.

B) Operation error while operating user program

Representing an error occurred during operation of user program, in case of numeric operation error, it displays the error in error flag but the system resumes operating. However, if the operation time exceeds by the operation monitoring time limit and I/O module does not control it normally, the system is halted.

C) Error detected owing to external device in trouble

Representing the detection of external device to be controlled by users program of PLC, if an error is detected, the system is halted, but any warning may not interfere with the operation.

Remark

- 1) If any trouble occurs, the unique trouble number is saved in a special relay F****.
- 2) For details of flag, refer to the appendix 1 Flag List.

6.4 Remote Functions

CPU module may change operation by communication as well as by key switches mounted on the module. To operate it remotely, it is necessary to set 'RUN/STOP' switch to 'STOP'.

- (1) Remote operations are as follows.
 - Operable by accessing to XG5000 through RS-232C port mounted on CPU module.
 - Can operate other PLC connected to PLC network with CPU module connected to XG5000.

(2) Remote RUN/STOP

- Remote RUN/STOP is the externally controlled RUN/STOP function.
- It is convenient when CPU module is located at a position hard to control or when CPU module within control panel is to control RUN/STOP function remotely.

(3) Remote DEBUG

- •It manages debugging remotely when remote mode is STOP. Namely, DEBUG operation is to execute program operation depending on designated operation conditions.
- •Remote DEBUG is a convenient function when confirming program operation status or data during system debugging.

(4) Remote Reset

- •Remote reset is to reset CPU module remotely if an error occurs at a place hard to directly control CPU module.
- •Like operation by switches, it supports 'Reset' and 'Overall Reset'.

Remark

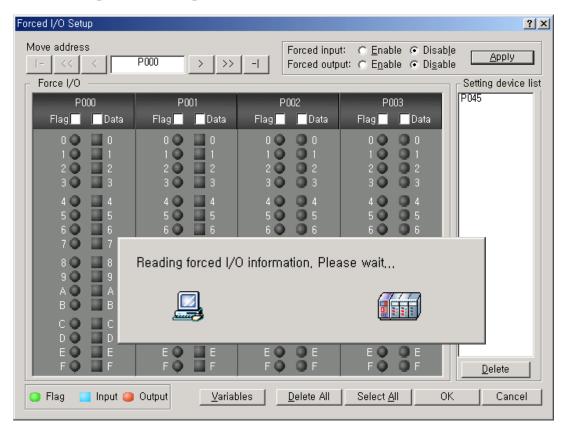
1) For details regarding remote functions, refer to 'Online' of XG5000 Users Manual.

6.5 Forced Input/Output On and Off Function

Force I/O function is used to force to turn I/O areas on or off, regardless of program results.

6.5.1 Force I/O setup

Click ${}^{\mathbb{F}}$ Online ${}_{\mathbb{F}}$ - ${}^{\mathbb{F}}$ Force I/O ${}_{\mathbb{F}}$.



Item		Description	
11		Move to the beginning and end of I/O area (P000↔P127)	
Move address		Move to ±8 of I/O area displayed at the very left.	
	< >	Move to ±1 of I/O area.	
Application		Set whether to allow or not Force I/O	
Single	Flag	Set whether to allow or not Force I/O by bits.	
Sirigle	Data	Set Force I/O data on or off by bits.	
Select All		Set to allow Force I/O with all I/O area on	
Delete All		Delete to allow Force I/O with all I/O area off.	
Setting device		Display I/O area set as a bit.	

6.5.2 Processing time and processing method of Force Input/Output On and Off

(1) Forced Input

Regarding input, at the time of input refresh it replaces the data of contact set as Force On/Off among data read from input module with the data as Force and updates input image area. Therefore, user program executes operations with actual input data while Force input area is operated with data set as Force.

(2) Forced Output

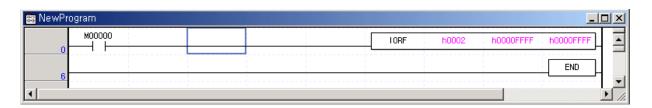
Regarding output, at the time of output refresh upon the execution user program operation, it replaces the data of contact set as Force On/Off among data of output image area containing operation results with data set as Force and outputs the data in output module. Unlike (Force) input, the output image area is not changed by Force On/Off setting.

- (3) Cautions when using Force I/O function
 - It operates from the time when I/O is individually set as 'Allow' after setting Force data.
 - It is possible to set Force input although I/O module is not actually mounted.
 - Despite of the power changed Off -> On, operation mode changes or any operation by pressing reset key, the data of which On/Off is set before is kept in CPU module.
 - Even in STOP mode, Force I/O data is not removed.
 - To set new data from the beginning, it is necessary to deselect all settings of I/O by using 'Delete All' option.

6.6 Direct Input/Output Operation

Refreshing I/O operates after completion of scan program. If data of I/O is changed while program is scanned, it does not refreshed at the changed moment. Refreshed I/O data is applied after 'END' instruction on program.

This function may be useful when directly reading the status of input contact during program operation by refreshing I/O by means of 'IORF' instruction or outputting operation results to output contact.



'IORF' command is operated when M00000 is ON. First operand designates slot number. Second operand designates the upper 32 bit data as mask data. Third operand designates the lower 32 bit data as mask data. The bit to refresh set as 1 (hFF) and others set as 0 (h00) (not refreshed).

Remark

For details regarding IORF instruction, refer to XGB Instructions List.

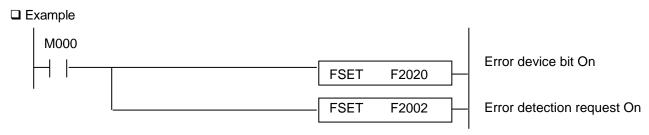
6.7 Diagnosis of External Device

This flag is provided for a user to diagnose any fault of external device and, in turn, execute halt or warning of the system. Use of this flag displays faults of external device without any complicated program prepared and monitors fault location without any specific device (XG5000 and etc) or source program.

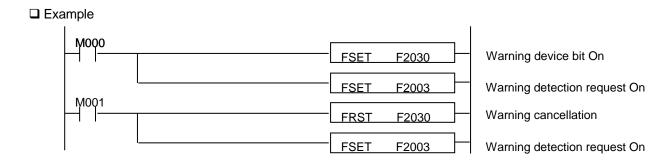
- (1) Detection and classification of faults in external device
 - •The trouble (fault) of external device may be detected by user program and largely divided, depending on the type, into error and warning; the former requires halt of PLC operation and the latter simply displays the status while PLC keeps working.
 - •'Error' uses 'F202 (_ANC_ERR)' and 'Warning' uses 'F203 (_ANC_WB) flag'.
 - •As the detection request flag, 'Error' uses 'F2002 (_CHK_ANC_ERR) flag' while 'Warning' uses 'F2003 (CHK ANC WB) flag'.

(2) Troubleshooting external device

- When detecting any trouble of external device in user program, it writes a value except '0' by classifying the type, which is defined by a user in 'F202 (_ANC_ERR)' while the detection request flag checks it at the time when the program ends with 'F2002 (_CHK_ANC_ERR) On, and PLC turns off all output, making it as the same error status as detected by PLC itself.
- If any trouble occurs, a user may identify the cause by using XG5000 and alternatively by monitoring 'F202 (_ANC_ERR) flag'.



- •If any trouble occurs, CPU is in error status and operation halts. At this moment, F2020 and F2002 flags are off (error LED switches on and off every second.)
- (3) Processing warning of external device
 - •When detecting any warning of external device in user program, it turns on a flag in the warning position of system flag 'F203 (_ANC_WB) and if turning on the detection request flag, 'F2003 (_CHK_ANC_WB)', it displays warning at the time when scan program ends. If a warning occurs, the detection request flag, 'F2003 (_CHK_ANC_WB)' is automatically off (F203 is not deleted).
 - •If a warning occurs, the LED switches on and off every other second.
 - •If turning off a bit in question of F203 and turning on F2003 bit after processing warning, warning is cancelled and the LED turns off.



6.8 Allocation of Input/Output Number

Allocation of I/O number is to allocate an address to every I/O of each module to read data from input module and output data to output module when it executes operations. XGB series adopts 64 points occupation to every module.

(1) Allocation of I/O number

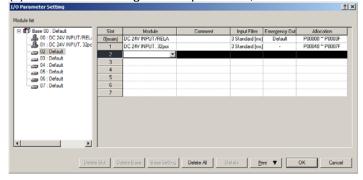
64 points are allocated to every module (incl. special, communication).

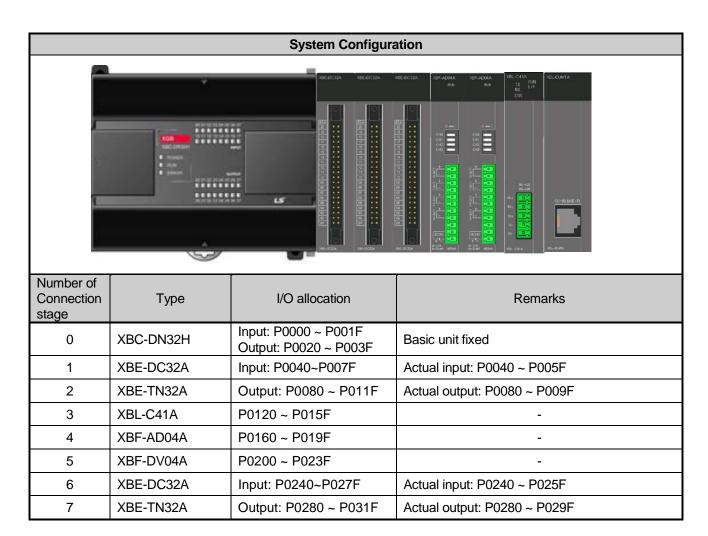


Number of Connection stage	Туре	I/O allocation	Remarks
0	XBM-DN32S	Input: P0000 ~ P001F Output: P0020 ~ P003F	Basic unit fixed
1	XBE-DC32A	Input: P0040~P007F	Actual input: P0040 ~ P004F
2	XBE-TN32A	Output: P0080 ~ P011F	Actual output: P0080 ~ P009F
3	XBL-C41A	P0120 ~ P015F	-
4	XBF-AD04A	P0160 ~ P019F	-
5	XBE-DV04A	P0200~P027F	-
6	XBE-DC32A	Input: P0240~P027F	Actual input: P0240 ~ P024F
7	XBE-TN32A	Output: P0280 ~ P031F	Actual output: P0280 ~ P028F

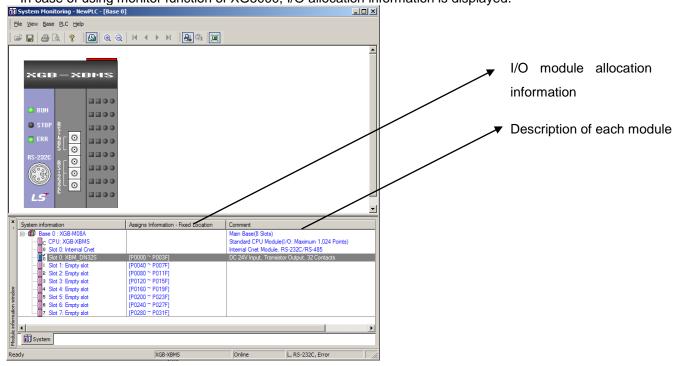
Empty I/O point is available for internal relay.

(2) In case of allocating IO of IO parameter, allocation information is displayed.





In case of using monitor function of XG5000, I/O allocation information is displayed.

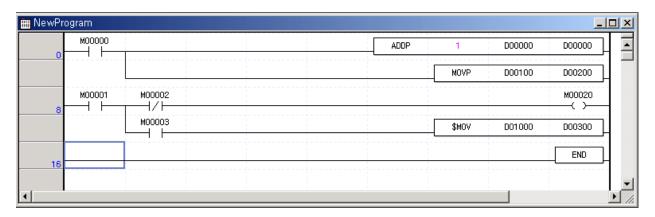


6.9 Online Editing

It is possible to modify program and communication parameter during operation of PLC without control operation stopped. The following describes basic modification. For details of modifying program, refer to XG5000 Users Manual.

Items to be modified during operation are as follows.

- Program
- Communication parameter
- (1) It displays programs that are currently running.



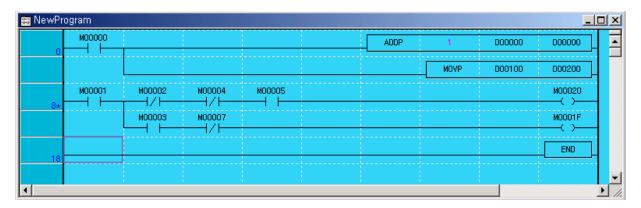
(2) Click "Online" - "Start Online Editing".



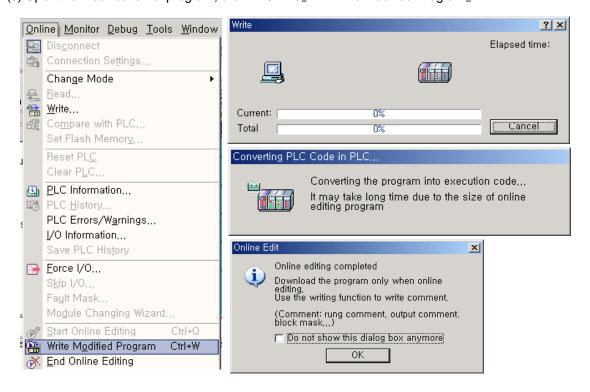
(3) It turns to program modification mode during run when the program background is changed.



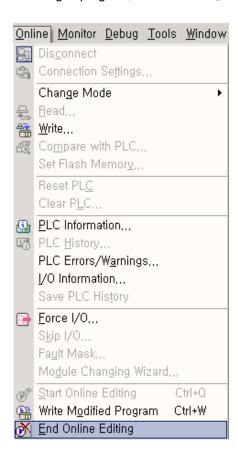
(4) Modifying a program.



(5) Upon the modification of program, click <code>"Online"</code> - <code>"Write Modified Program"</code> .

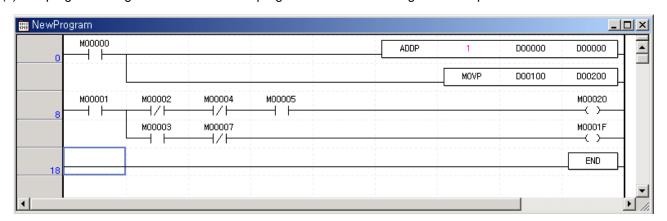


(6) Upon the writing of program, click <code>"Online"</code> - <code>"End Online Editing"</code> .





(7) The program background returns and the program modification during run is completed.



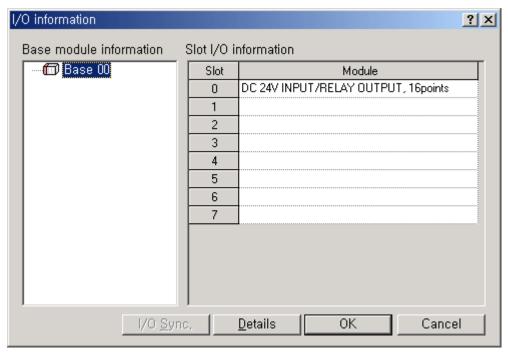
Remark

 \blacksquare For parameter modification during run, change each parameter on XG-PD and click $\verb|"Online||$ - $\verb|"Write Modified Program || .$

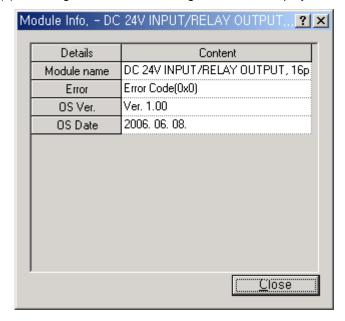
6.10 Reading Input/Output Information

It monitors information of individual modules consisted of XGB series system.

(1) Click <code>"Online_" - "I/O Info_"</code> . Then, information of each module connected to the system is monitored.



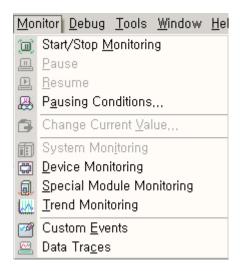
(2) If clicking Details after selecting a module, it displays detail information of a selected module.



6.11 Monitoring

It monitors system information of XGB series system.

(1) Clicking 「Monitor」 displays the following sub-menus.



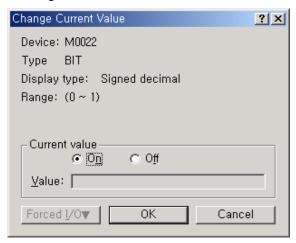
(2) Items and descriptions

Item	Description	Remarks		
Start/Stop Monitoring	Designate the start and stop of monitor.	Click for reverse turn.		
Pause	Pause monitoring.	-		
Resume	Resume paused monitor.	-		
Pausing Conditions	Pause monitoring if a preset value of device corresponds to condition.	Monitor resumes; clicking for resume.		
Change Current Value	Change the present value of currently selected device.	-		
System Monitoring	Monitor general system information.	-		
Device Monitoring	Monitor by device (type).	-		
Trend Monitoring	Monitor trend of device set in the system.			
Custom Events	Custom Events Monitor the value of device set when an event set by a user occurs.			
Data Traces	Trace the value of device.	XG5000 Users Manual.		

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(a) Change current value

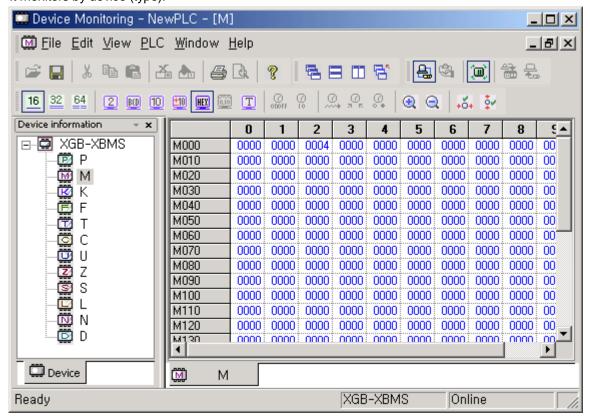
•It changes the current value of each device selected in the current program window.





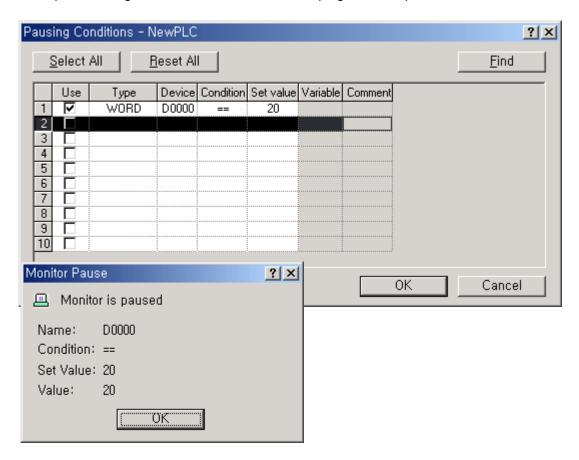
(b) Device monitoring

It monitors by device (type).



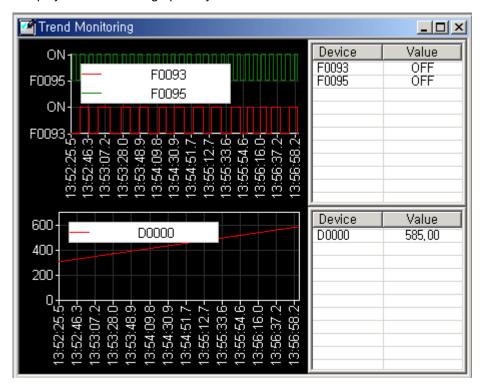
(c) Pausing conditions

•It stops monitoring in case a device value set in the program corresponds.



(d) Trend monitoring

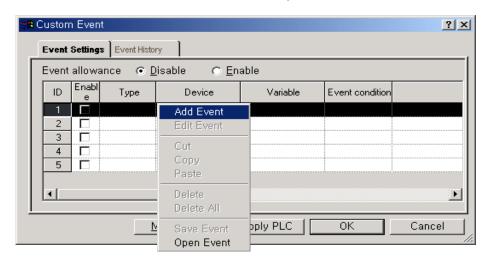
It displays device values graphically.



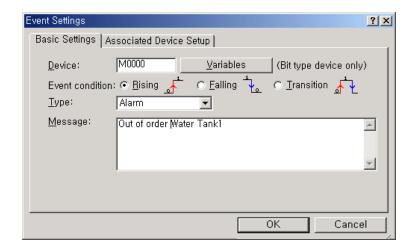
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(e) Custom events

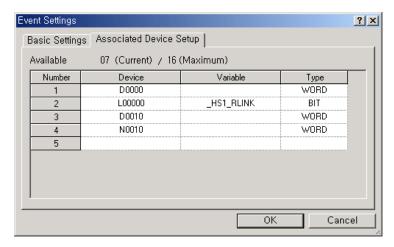
•It monitors detail information when an event set by a user occurs. Additional user event may be registered.



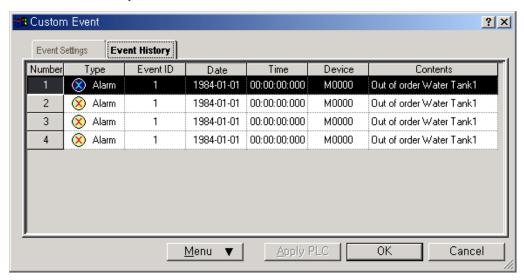
•It sets basic setting and relative device.
If rising edge of M0000 device occurs, it records the message of an alarm, "Out of order Water Tank 1" and the device values of D0000,L0000,D0100,N1000 are recorded.



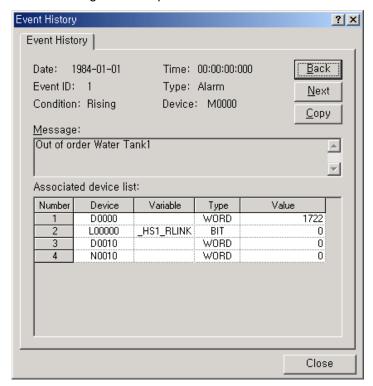
• Set the relative device(s).



Monitor event history of custom event.



• Double-clicking a number produced monitors the relative values of device and the detail message as follows.



Remark

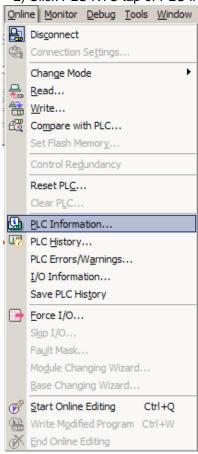
•For details of monitor, refer to XG5000 Users Manual.

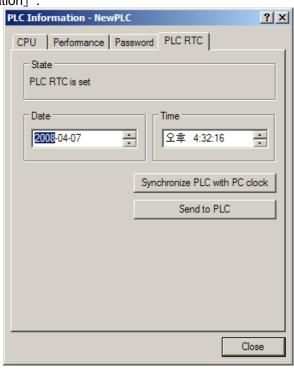
6.12 RTC function

"H" type (XBC-DxxxH) supports the RTC (clock) function and user can use this function for time management of system or error log. RTC function is executed steadily when power is off or instantaneous power cut status. Current time of RTC is renewed every scan by system operation status information flag.

6.12.1 How to use

- (1) Reading/setting clock data
 - (a) Reading or setting from XG5000
 - 1) Click 『Online』의 『PLC Information』.
 - 2) Click PLC RTC tap of PLC Information』.





- 3) In case the user wants to send the clock of PC to PLC, press 'Synchronize PLC with PC clock'.
- 4) In case the user wants to send the clock the user wants, change the setting value of Time box and press 'Send to PLC'.
- (b) Reading by special relay

The user can monitor as follows by special relay.

Special relay area	Data	Contents	
F053	H0709	07year 9month	
F054	H1214	12date 14hour	
F055	H2040	20minute 40second	
F056	H2003	20XXyear, Wednesday	

(c) Modification of clock data by program



07year 9month

12date 14hour

20minute 40second

20XXyear, Wednesday

area	Content
K0000	Year, month
K0001	Date, hour
K0002	Minute, second
K0003	Centaury, day

Write clock data to temporary device (P, M, K, L, Z, U, D, R) and turn on/off input contact point M0000. (If date and day data is not matched, Write is not available.)

Monitor and check the above special area (F053~F056)

(d) How to express the day

Number	0	1	2	3	4	5	6
Day	Sunday	Monday	Tuesday	Wednesday	Thursday	Friday	Saturday

(2) Deviation of clock data ±2.2s / 1 d

Remark

- 1) Initially, RTC may not have any clock data.
- 2) When using the CPU module, first make sure to set the accurate clock data.
- 3) If any data out of the clock data range is written into RTC, it does not work properly. i.e.) 14M 32D 25H
- 4) RTC may stop or have an error due to abnormal battery and other causes. The error is released if a new clock data is written.

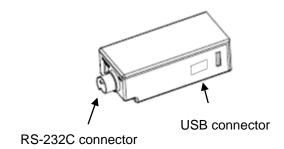
6.13 External Memory Module

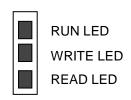
You can save the user program safely and download the program into the system when program is damaged without special manipulation by using external memory module.

6.13.1 Memory module specification

Item	XBO-M2MB	Ref.
Memory capacity	2MByte	
Memory type	Flash Memory	
Specification	USB supported, Program Read/Write	
Indicator	LED	1. RUN 2. WRITE
Operating mode setup	Mode setup by rotary switch	3. READ
Operating power supply	RS-232C communication connecter, USB connector	5V
Purpose	For moving	

6.13.2 Memory module structure







- 1: READ mode
- 3: WRITE mode
- 5: PADT I/F mode

Note

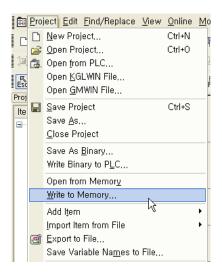
- -. Memory module can be used for XGB (not supported for XGK/I/R)
- -.Memory module is not supported at the version below (XBMS: V2.5 or less, XBCH: V1.8 or less, XECH: V1.2 or less)

6.13.3 How to use memory module

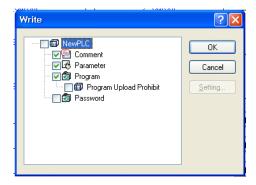
- (1) Save program, parameter, communication parameter at external memory module
 - (a) Set the switch of memory module as 1
 - (b) Install memory module at the RS-232C port of main unit
 - After installation, program and parameter (including communication) is saved into memory module and READ LED is on
 - If Saving program and parameter is complete, READ LED is off
 - (c) Separate memory module from main unit
- (2) Save user program of external memory module at main unit
 - (a) Set the operating mode of main unit as STOP
 - In RUN mode, you can't save program
 - (b) Set the switch of memory module as 3
 - (c) Install the memory module
 - Install it at the RS-232C port of the main unit.
 - PLC program and parameter (including communication) is written and WRITE LED is on
 - If saving program and parameter is complete, WRITE LED is off.
 - (d) If you change operation mode of PLC into RUN, PLC operates with program and parameter saved in memory module.

With the above handling, you can run PLC with program saved in memory module

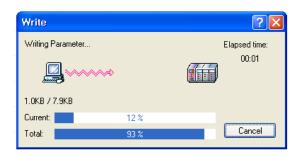
- (3) Save program of XG5000at the memory module
 - (a) Set the mode switch of XBO-M2MB as "5" and connect XBO-M2MB to USB port of PC
 - (b) Select Project → Write to Memory on XG5000 menu.



(c) 'Write' window is created as follows.

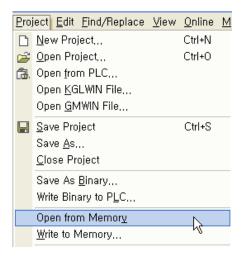


(d) "Writing completed" window appears.

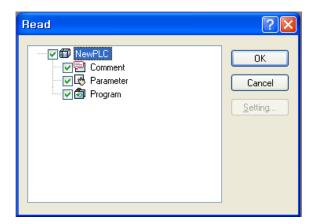




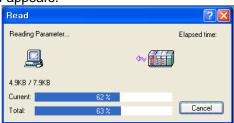
- (e) With above method, through PADT, you can save program, parameter, communication parameter at XBO-M2MB
- (4) Open from memory module
 - (a) Set the mode switch of XBO-M2MB as "5" and connect XBO-M2MB to USB port of PC
 - (b) Select "Project → Open from Memory" on XG5000 menu

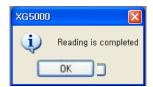


(c) "Read" window is created as follows.

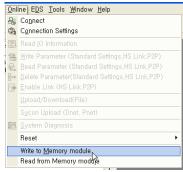


(d) "Reading is completed" window appears.





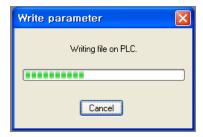
- (e) With above method, through PADT, you can save program, parameter, communication parameter from XBO-M2MB
- (5) Write to Memory module
 - (a) Set the mode switch of XBO-M2MB as "5" and connect XBO-M2MB to USB port
 - (b) Click "Online → Write to Memory module" on XG-PD menu



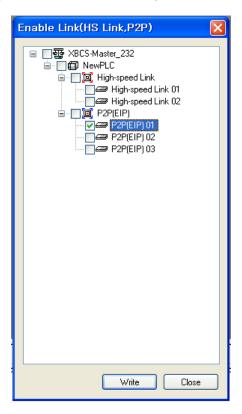
(c) If you click "OK" button, it saves each parameter at the memory module.



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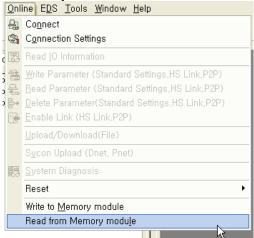
(d) If "Enable Link" window appears, check the item and press "Write"



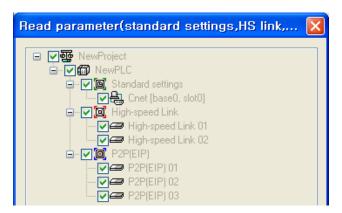
(e) "Enable, Disable" window appears

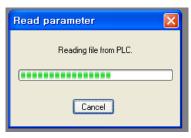


- (6) Read from Memory module
 - (a) Set the mode switch of XBO-M2MB as "5" and connect XBO-M2MB to USB port of PC
 - (b) Select "Online → Read from Memory module" on XG-PD menu.



(c) If you click "OK" button", it read each parameter form the memory module.



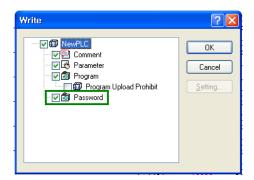


Note

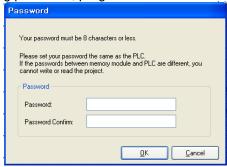
- -. "Open from memory module" and "Write to Memory module" menus of PADT are activated when PLC is Offline. They are deactivated when PLC is Online.
- -. When connecting with PADT, connection type should be 'USB'

6.13.4 How to use when password is set

- (1) When connecting PADT with memory module
 - (a) When setting password at program and writing program to memory module, it is saved according to rotary switch operating mode without functions cancelling the password
 - 1) When writing program, check whether to use password at 'Write' window.



2) If you press 'OK' after setting password, program is saved at memory module with that password.



- (b) When reading password-set program to PADT, screen appears, which is same as when password is set in PLC.
 - 1) "Password" window is created.



- 2) If you input password same as that in memory module, it reads program.
- 3) When password is incorrect, error message appears as follows.



(2) Write to PLC by memory module

- (a) When password of program in memory module is not set
 - 1) When no password is set in PLC
 - Saves program of the memory module in PLC
 - 2) When password is set in PLC
 - Writing is not executed
- (b) When password of program in memory module is set
 - 1) When no password is set in PLC
 - Writing to PLC is executed
 - But, password of the memory module is not written to PLC.
 - 2) When password is set in PLC
 - When PLC password is same as that of the memory module, writing is executed.
 - When PLC password is not same as that of the memory module, writing is not executed.
 (WRITE LED flickers)

(3) Reading program in PLC to memory module

- (a) When password of program in PLC is not set
 - 1) When no password is set in the memory module
 - Reads program from PLC
 - 2) When password is set in the memory module
 - After reading, it clears password of the memory module
- (b) When password of program in PLC is set
 - 1) When no password is set in the memory module
 - Writing is not executed
 - 2) When password is set in the memory module
 - When PLC password is same as that of the memory module, writing is executed.
 - When PLC password is not same as that of the memory module, writing is not executed.

(4) When LED flickers

	Condition	LED
1	PLC type is not XGB	RUN LED flickers
2	Operating mode changes while being connected to PADT or PLC	RUN LED flickers
3	Connected to PADT while mode switch is "1"	READ LED flickers
4	PLC program upload is prohibited	READ LED flickers
5	You execute reading when password is set in PLC	READ LED flickers
	(when password is not same as that of memory module)	
6	Connected to PADT while mode switch is "3"	WRITE LED flickers
7	You execute writing the memory module when PLC mode is RUN	WRITE LED flickers
8	Connected to the different type of PLC with the type set in the memory	WRITE LED flickers
	module	
9	You executes writing when PLC password is not same as that of memory	WRITE LED flickers
	module	

Note

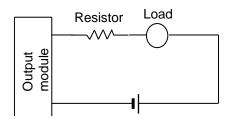
- -. Memory module can cancel PLC password and read/write but can't set, delete and change the password.
- -. Do not run PLC while external memory module is connected to.
- -. Do not remove memory module while READ/WRITE LED is on.

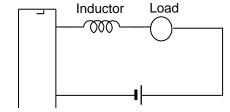
Chapter 7 Input/Output Specifications

7.1 Introduction

Here describes the notices when selecting digital I/O module used for XGB series.

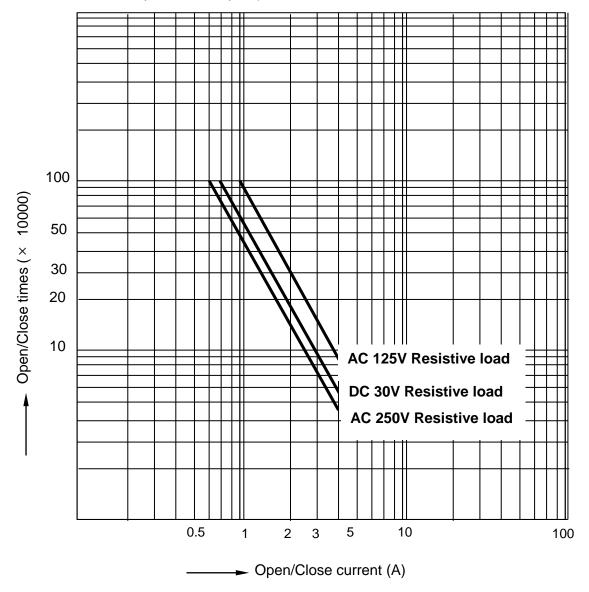
- 1) For the type of digital input, there are two types such as current sink input and current source input.
- 2) The number of max. Simultaneous input contact point is different according to module type. It depends on the input voltage, ambient temperature. Use input module after checking the specification.
- 3) When response to high speed input is necessary, use interrupt input contact point. Up to 8 interrupt points are supported.
- 4) In case that open/close frequency is high or it is used for conductive load open/close, use Transistor output module or triac output module as the durability of Relay Output Module shall be reduced.
- 5) For output module to run the conductive (L) load, max. open/close frequency should be used by 1second On, 1 second Off.
- 6) For output module, in case that counter timer using DC/DC Converter as a load was used, Inrush current may flow in a certain cycle when it is ON or during operation. In this case, if average current is selected, it may cause the failure. Accordingly, if the previous load was used, it is recommended to connect resistor or inductor to the load in serial in order to reduce the impact of Inrush current or use the large module having a max. load current value.





7) Relay life of Relay output module is shown as below.

Max. life of Relay used in Relay output module is shown as below.



Chapter 7. Input/Output Specifications

8) A clamped terminal with sleeve can not be used for the XGB terminal strip. The clamped terminals suitable for terminal strip are as follows (JOR 1.25-3:Daedong Electricity in Korea).



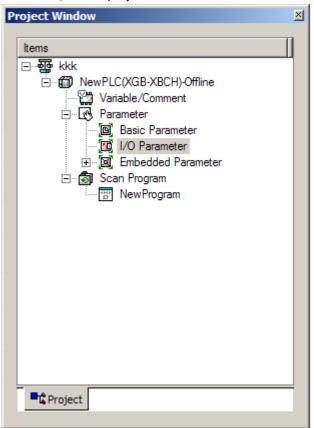
- 9) The cable size connected to a terminal strip should be 0.3~0.75 m² stranded cable and 2.8 mm thick. The cable may have different current allowance depending on the insulation thickness.
- 10) The coupling torque available for fixation screw and terminal strip screw should follow the table below.

Coupling position	Coupling torque range
IO module terminal strip screw (M3 screw)	42 ~ 58 N⋅cm
IO module terminal strip fixation screw	66 ~ 89 N⋅cm
(M3 screw)	

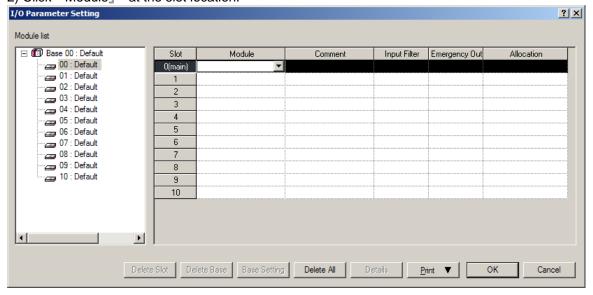
- 11) Relay life graph is not written based on real use. (This is not a guaranteed value). So consider margin. Relay life is specified under following condition.
- (a) Rated voltage, load: 3 million times: 100 million times
- (b) 200V AC 1.5A, 240V AC 1A (COS¢ =0.7): 1 million times
- (c) 200V AC 0.4A, 240V AC 0.3A (COS¢ =0.7): 3 million times
- (d) 200V AC 1A, 240V AC 0.5A (COS¢ =0.35): 1 million times
- (e) 200V AC 0.3A, 240V AC 0.15A (COS¢ =0.35): 3 million times
 - (f) 24V DC 1A, 100V DC 0.1A (L/R=7ms): 1million times
 - (g) 24V DC 0.3A, 100V DC 0.03A (L/R=7ms): 3million times
- 12) Noise can be inserted into input module. To prevent this noise, the user can set filter for input delay in parameter. Consider the environment and set the input filter time.

Input filter time (ms)	Noise signal pulse size (ms)	Reference
1	0.3	
3	1.8	Initial value
5	3	
10	6	
20	12	
70	45	
100	60	

- (a) Setting input filter
- 1) Click I/O Parameter』 in the project window of XG5000

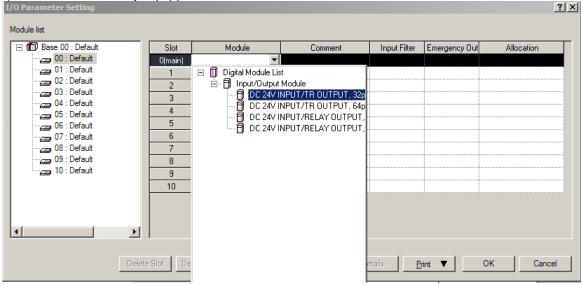


2) Click "Module at the slot location.

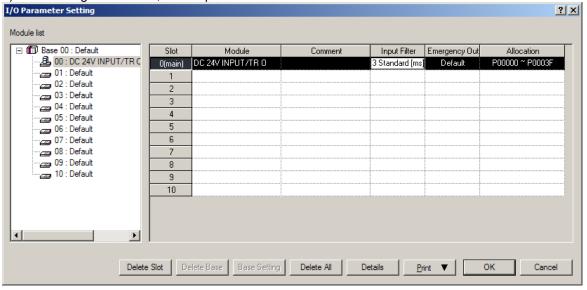


Chapter 7. Input/Output Specifications

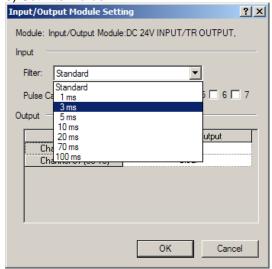
3) Set I/O module really equipped.



4) After setting I/O module, click Input Filter.

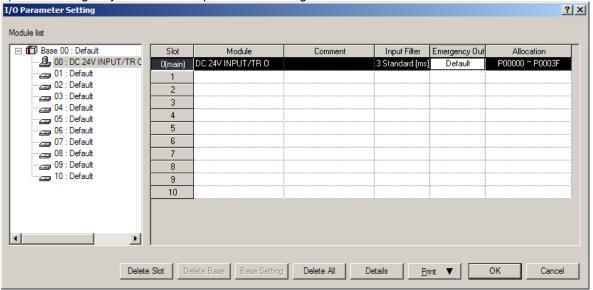


5) Set filter value.

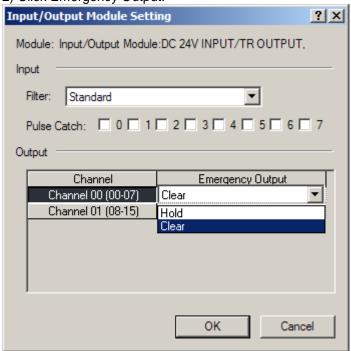


(b) Setting output status in case of error

1) Click Emergency Out in the I/O parameter setting window.



2) Click Emergency Output.



If it is selected as Clear, the output will be Off and if Hold is selected, the output will be kept.

7.2 Basic Digital Input Unit Specifications 7.2.1 XBM-DR16S input unit (Source/Sink type)

	Model	Basic unit				
Specification	on	XBM-DR16S				
Input point		8 point				
Insulation m	nethod	Photo coupler insulation				
Rated input	voltage	DC24V				
Rated input	current	About 4 mA (00~03: About 7	mA)			
Operation v	oltage range	DC20.4~28.8V (ripple rate <	5%)			
On Voltage/	Current	DC19V or higher/ 3 mA or hig	her			
Off Voltage/	'Current	DC6V or lower/ 1 mA or lower	•			
Input resista	ance	About 5.6 kΩ (P00~P03: abo	ut 3.3 kն	3)		
Response	$Off \to On$	1/3/5/10/20/70/100 ms (set by	, I/O po	omotor)	Default: 2 ms	
time	$On \to Off$	1/3/3/10/20/10/100 IIIS (Set b)	y I/O pai	ameter)	Delault. 3 IIIS	
Insulation p	ressure	AC560Vrms / 3Cycle (altitude	e 2000m	1)		
Insulation re	esistance	ance 10 ^{MΩ} or more by Megohmmeter				
Common M	ethod	8 point / COM				
Proper cable	e size	Twisted pair 0.3~0.75 m² (external diameter 2.8 mm or less)				
Current con	sumption (mA)	180 ^{mA} (When Input On LED On)				
Operation in		Input On, LED On				
External cor method	nnection	9 pin terminal block connecto	or			
Weight		140g				
	Circuit co	nfiguration	No.	Contact	Type	
			TB1	00		
			TB2	01	TB1	
		\$ \$	TB3	02	TB2	
- TE	81 R	Photo counter	TB4	03	TB3	
	Ŕ	¥ * 【	TB5	04	TB5	
0 TB	— v	Internal Circuit	TB6	05	тве 🖳	
	DM		TB7	06	TB7	
DC24V	Terminal block no.		TB8	07	TB8	
	reminal block Ho.		TB9	СОМ	103	

7.2.2 XBM-DN16S input unit (Source/Sink type)

Mod	del			Basic un	nit			
Specification	XBM-DN16S							
Input point		8 point						
Insulation method		Photo coupler insulati	on					
Rated input voltage		DC24V						
Rated input current		About 4 mA (Contact p	oint 0~	3: Abou	t 7 mA)			
Operation voltage rang	е	DC20.4~28.8V (ripple	rate <	5%)				
On Voltage/Current		DC19V or higher / 3	¹ ^A or hi	gher				
Off Voltage/Current		DC6V or less / 1 mA o	r less					
Input resistance		About 5.6 kΩ (P00~P0)3: Abo	ut 3.3 ks	2)			
Response Off \rightarrow C)n	1/3/5/10/20/70/100 ms	(cot by	√I/O par	amoto	r) Dofau	It· 2 mg	
time On → C	ff	1/3/3/10/20/10/100 113	(set b)	y I/O pai	amete	i) Delau	II. 3 III3	
Insulation pressure		AC560Vrms / 3Cycle	(altitude	e 2000m	1)			
Insulation resistance		10 MΩ or more by Meg	Megohmmeter					
Common method		8 point / COM						
Proper cable size		0.3 mm²						
Current consumption		180 mA (when all poin	180 ^{mA} (when all point On)					
Operation indicator		Input On, LED On						
External connection me	ethod	20 pin connector						
Weight		100g						
Circuit	config	uration	No.	Contact	No.	Contact	Type	
			B10	00	A10	NC		
			B09	01	A09	NC		
	Pł	noto coupler 😝 💢	B08	02	A08	NC	B10 A10 B09 A09	
0 B10 R			B07	03	A07	NC	B08 A08 B07 A07	
	<u></u>	B06	04	A06	NC	B06 A06 B05 A05		
0 B03 0 S	• •	Internal circuit	B05	05	A05	NC	B04 – A 04 B03 – A 03	
COM			B04	06	A04	NC	B02 - A02 B01 - A01	
DC24V Connector No.				07	A03	NC		
Somission no.			B02	СОМ	A02	NC		
			B01	СОМ	A01	NC		

7.2.3 XBM-DN32S input unit (Source/Sink type)

	Model	Basic unit						
Specification	on		XB	M-DN32	:S			
Input point		16 point						
Insulation me	ethod	Photo coupler insulation						
Rated input v	oltage/	DC24V						
Rated input of	current	About 4 mA (Contact poi	nt 0~3:	About 7	mA)			
Operation vo	ltage range	DC20.4~28.8V (ripple ra	ite < 5%	%)				
On Voltage/C	Current	DC19V or higher / 3 mA	or high	ner				
Off Voltage/C	Current	DC6V or less / 1 mA or le	ess					
Input resistar	nce	About 5.6 kΩ (P00~P03:	About	3.3 kΩ)				
Response	$Off \rightarrow On$	1/3/5/10/20/70/100 ms (s	oot by I	/O paran	notor) [Dofault: 1	2 me	
time	$On \rightarrow Off$	1/3/3/10/20/70/100 110 (3	Set Dy I	O paran	ietei) i	Delault.	3 1110	
Insulation pre	essure	AC560Vrms / 3Cycle (al	titude 2	2000m)				
Insulation res	sistance	10 ^{MΩ} or more by Megol	ohmmeter					
Common me	thod	16 point / COM						
Proper cable	size	0.3 mm²						
Current cons	umption	200 mA (when all point C	On)					
Operation inc	dicator	Input On, LED On						
External con method	nection	20 pin connector						
Weight		110g						
	Circuit con	figuration	No.	Contact	No.	Contact	Туре	
			B10	00	A10	08		
		₩ ↔	B09	01	A09	09		
0 B10	- R	Photo counier	B08	02	A08	0A	B10 A10 B09 A09	
	R	★ ★ 【!	B07	03	A07	0B	B08 A08 B07 A07	
FA03	\frac{1}{5}	Internal circuit	B06	04	A06	0C	B06 A06 B05 A05	
■ B02 COM		Circuit	B05	05	A05	0D	B04 – – A04 B03 – – A03	
DC24V			B04	06	A04	0E	B02 A02 B01 A01	
<u>'</u>	Connector no.		B03	07	A03	0F		
			B02	COM	A02	СОМ		
			B01	COM	A01	СОМ		

7.2.4 XBC-DR32H / XBC-DN32H input unit (Source/Sink type)

			Basi	ic unit						
Specification	on	XBC-DR32H(/D0	C)		XBC-DN32H(/DC)					
Input point		16 point								
Insulation me	thod	Photo coupler insulation	า							
Rated input v	oltage	DC24V								
Rated input c	urrent	About 4 mA (Contact po	int 0~3:	Abou	it 7 mA)					
Operation vol	tage range	DC20.4~28.8V (ripple ra	ate < 5%	6)						
On Voltage/C	urrent	DC19V or higher / 3 mA	or high	er						
Off Voltage/C	urrent	DC6V or less / 1 mA or I	ess							
Input resistan	ice	About 5.6 kΩ (P00~P03	: About	3.3 kg	3)					
Response	$Off \to On$	4 0 F 4 0 00 70 4 00 mg	'4 l I	/0	D	facility O mo				
time	$On \to Off$	1/3/5/10/20/70/100 ms (set by i	O pa	rameter) De	Tault: 3 IIIS				
Insulation pre	essure	AC560Vrms / 3Cycle (a	Ititude 2	2000m	٦)					
Insulation res	istance	10 MΩ or more by Mego	hmmete	er						
Common met	thod	16 point / COM								
Proper cable	size	0.3 mm²								
Current consi	umption	200 mA (when all point of	On)							
Operation ind	licator	Input On, LED On	t On, LED On							
External conr method	nection	24 points connecting co	nnector	(M3	X 6 screw)					
Weight		600g		5	500g					
	Circuit conf	iguration	No.	Conta	act No.	Contact		Ту	ре	
_			TB2	485+	TB1	RX	-			1
0		Photocoupler Photocoupler	TB4	485-	TB3	TX	TB2	485+	RX	TB1
S B10	R		TB6	00	TB5	SG	TB4	485-	TX	TB3 TB5
F A03	[5]	Internal			ТВ7	01	TB6	P00	SG P01	TB7
B02 COM		circuit	TB8	02	TB9	03	TB8	P02	P03	TB9
DC24V	Terminal block no).	TB10	04	TB11	05	TB12	P04 P06	P05	TB11
			TB12	06	TB13	07	TB14	P08	P07	TB13
			TB14	08	TB15	09	TB16	POA	P09	TB15
				0A			TB18	POC	POB POD	TB19
		TB18	0C	TB17	0B	TB20	POE COM	POF	TB21	
			TB20	0E	TB19	0D	TB24	24V	24G	TB23
			TB22	CON		0F			•	J
			TB24	24V	TB23	24G				

7.2.5 XBC-DR64H / XBC-DN64H input unit (Source/Sink Type)

Model	Basic unit								
Specification	XBC-DR64H(/D0	C) XBC-DN64H(/DC)							
Input point 32 point									
Insulation method	Photo coupler insulation								
Rated input voltage	DC24V	<u>-</u>							
Rated input current	About 4 mA (Contact po	out 4 mA (Contact point 0~3: About 7 mA)							
Operation voltage range	DC20.4~28.8V (ripple r	ate < 5%	6)	ĺ					
On Voltage/Current	DC19V or higher / 3 mA	or high	ner						
Off Voltage/Current	DC6V or less / 1 mA or l	ess							
Input resistance	About 5.6 kΩ (P00~P03	: About	3.3 kΩ)						
Response Off → On			-		\ D - (- 1)	0 ===			
time On → Off	1/3/5/10/20/70/100 ms	(set by	CPU par	ameter) Default:	3 ms			
Insulation pressure	AC560Vrms / 3Cycle (a	Ititude 2	2000m)						
Insulation resistance	10 ^{MΩ} or more by Mego	hmmete	er						
Common method	16 point / COM								
Proper cable size	0.3 mm²								
Current consumption	200 mA (when all point of	On)							
Operation indicator	Input On, LED On	-							
External connection	42 point connecting cor	nector	(M3 X 6 s	crew)					
method		inector	<u> </u>						
Weight	900g	T	8000			1			
Circuit conf	figuration	No.	contact	No.	contact		typ	е	
		TB2	485+	TB1	RX		\oplus		TB1
				TB3	TX	TB2	485+	RX	
	\ \ \ \ \ \	TB4	485-	TB5	SG	TB4	485-	TX	TB3
TB6 R Pho	oto coupler	TB6	00			TB6		SG	TB5
	₹ ₹7:	TB8	02	TB7	01		P00	P01	ТВ7
OF TB21	Internal	TD40	0.4	TB9	03	TB8	P02	P03	TB9
TB22	circuit	TB10	04	TB11	05	TB10	P04		TB11
сомо		TB12	06	TB13	07	TB12	P06	P05	TB13
DC24V		TB14	08	TB15	09	TB14	P08	P07	
10 TP24 Ph	oto coupler	TB16	0A			TB16	POA	P09	TB15
10 TB24 R		TB18	0C	TB17	0B	TB18		POB	TB17
	 ▼ 			TB19	0D		POC	POD	TB19
1F 0 TB39	<u></u>	TB20	0E	TB21	0F	TB20	POE	POF	TB21
TB40 COM1		TB22	COM0	TB23	NC	TB22	СОМ0	NC	TB23
COM1		TB24	10			TB24	P10	NC	TDOE
Terminal block n	0.	TB26	12	TB25	11	TB26	P12	P11	TB25
Tominal block in	. .	TB28	14	TB27	13	TB28	P14	P13	TB27
		TB30	16	TB29	15	TB30	P16	P15	TB29
				TB31	17	TB32	P18	P17	TB31
		TB32	18	TB33	19	TB34		P19	TB33
		TB34	1A	TB35	1B	TB36	P1A	P1B	TB35
		TB36	1C	TB37	1D	TB38	P1C	P1D	TB37
		TB38	1E	TB39	1F	TB40	P1E	P1F	TB39
		TB40	COM1	TB41	24G	TB42	СОМ	24G	TB41
		TB42	24V	ודטי	2-10	.5.2	24V	①	

7.3 Basic Digital Output Unit Specification

7.3.1 XBM-DR16S relay output unit

	Model	Basic unit						
Specificatio	n	XBM-DR16S						
Output poin	t	8 point						
Insulation m	nethod	Relay insula	ation					
Rated load	voltage / current	DC24V 2A(Resistive load) / A0	C220V 2A((COSΨ = 1), 5A/COM		
Min. load vo	oltage/current	DC5V / 1 m/	1					
Max. load v	oltage/current	AC250V, D	C125V					
Off leakage	current	0.1 mA (AC2	220V, 60 Hz)					
Max. On/Of	f frequency	3,600 times	/hr					
Surge abso	rber	None						
	Mechanical	20 millions	times or more					
		Rated load	voltage / current 10	00,000 tim	es or more			
Service life	Electrical	AC200V / 1	.5A, AC240V / 1A ($COS\Psi = 0$	0.7) 100,00	00 times or more		
	Liectrical	AC200V / 1	A, AC240V / 0.5A ($COS\Psi = 0$).35) 100,00	00 times or more		
		DC24V / 1A	, DC100V / 0.1A (L	_/R = 7 ms	3) 100,000	times or more		
Response	$Off \rightarrow On$	10 ms or les	SS					
time	$On \rightarrow Off$	12 ms or less						
Common m	ethod	8 point / CC	DM					
Proper cabl	e size	Twisted pai	r0.3~0.75 mm² (Exte	rnal diame	eter 2.8 mm	or less)		
Current con	sumption	360 ^{mA} (wh	en all point On)					
Operation in	ndicator	Output On,	LED On					
External co	nnection method	9 point term	ninal block connecto	or				
Weight		140g						
	Circuit co	onfiguration		No.	Contact	Туре		
			,	TB1	20			
	OC5V			TB2	21	TB1		
				TB3	22	TB2		
	ternal RY	<u> </u>	TB	TB4	23	TB3		
	rcuit		TB8	TB5	24	TB5		
			TB9	TB6	25	TB7		
			Torreinal black no	TB7	26	TB8		
			Terminal block no.	TB8	27			
				TB9	СОМ			

7.3.2 XBM-DN16S transistor output unit (Sink type)

	Model		ı	Basic unit		
Specification			XI			
Output point		8 point				
Insulation meth	nod	-	coupler insulation			
Rated load vol		DC 12	•			
Load voltage ra			2 ~ 26.4V			
			Il output: 0.2A/ 1point,			
Max. load volta	age		for positioning (P20, P	21): 0.1A/ ⁻	1 point, 2A/1	ICOM
Off leakage cu	rrent	0.1 mA	or less			
Max. inrush cu	rrent	4A / 10	ms or less			
Max. voltage d	rop (On)	DC 0.4	V or less			
Surge absorbe	r	Zener [Diode			
Response	$Off \rightarrow On$	1 ms or	less			
time	$On \rightarrow Off$	1 ms or	less (Rated load, resi	stive load)		
Common meth	od	8 point	/ COM	· · · · · · · · · · · · · · · · · · ·		
Proper cable s	ize	0.3 mm²				
Current consur		180 mA	(when all point On)			
External	Voltage		$24V \pm 10\%$ (ripple volta	age 4 Vp-p	or less)	
power supply	Current		r less (DC24V connec		,	
Operation indic	cator		On, LED On	<u> </u>		
External conne			connector			
Weight		100g				
3	Circuit coi		1	No.	Contact	Туре
			<u> </u>	B10	20	.) [-
				B09	21	
				B08	22	
→ DC5	V			B07	23	
			B10	B06	24	
		ı <u>⊢</u> 1.		B05	25	B10 FLF A10
		┦╬┱╃		B04	26	B09 A09
Internal		7		B03	27	B08 A08 B07 A07
circuit			B03	B02	DC12 /24V	B06 A06
	-	-		B01 A10	NC	B05 A05 B04 A04
			B01.B02	A09	NC NC	B03 A03
			1001.002	A08	NC	B02 - A02 B01 - A01
			A01,A02	A07	NC	
1			DC12/24V	A06	NC	
			Connector no.	A05	NC	
			33100101 1101	A04	NC	
				A03	NC	
				A02	СОМ	
				A01	COIVI	

7.3.3 XBM-DN32S transistor output unit (Sink type)

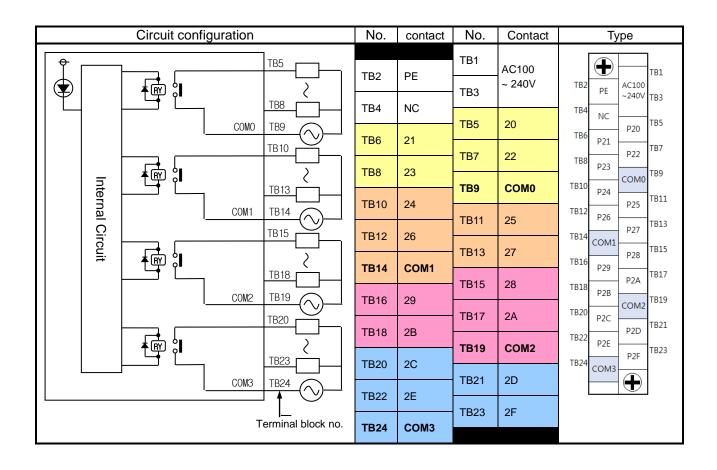
	Model			Basic unit			
Specification			XE	BM-DN32S			
Output point		16 point					
Insulation meth	nod	Photo co	oupler insulation				
Rated load vol	tage	DC 12/	24V				
Load voltage ra	ange	DC 10.2	2 ~ 26.4V				
Max. load volta	age		output: 0.2A/ 1point, or positioning (P20, P	21): 0.1A/	1 point, 2A/1	ICOM	
Off leakage cu	rrent	0.1 mA c	or less				
Max. inrush cu	rrent	4A / 10	ms or less				
Max. voltage d	rop (On)	DC 0.4\	or less				
Surge absorbe	r	Zener D	iode				
Response	$Off \rightarrow On$	1 ms or	less				
time	$On \rightarrow Off$	1 ms or	less (Rated load, resis	stive load)			
Common meth	od	16 point	/ COM				
Proper cable s	ize	0.3 mm²					
Current consur	mption	200 mA	200 mA (when all point On)				
External	Voltage	DC12/2	$4V \pm 10\%$ (ripple volta	age 4 Vp-p	or less)		
power supply	Current	10 mA or	less (DC24V connect	tion)			
Operation indic	cator	Output 0	On, LED On				
External conne	ection method	20 pin c	onnector				
Weight		110g					
	Circuit co	nfiguration		No.	Contact	Type	
				B10	20		
			_	B09 B08	21 22		
♥ DC5	V			B07	23		
			B10	B06	24		
				B05	25		
		┤┋╅		B04	26	B10 - A10	
Internal	 	5		B03	27	B09 A09 B08 A08	
circuit	147	<i></i>	100	B02	DC12	B07 A07	
		<u>`</u>	A03	B01	/24V	B06 A06 B05 A05	
			PO1 PO2	A10	28	B04 A04	
			B01.B02	A09 A08	29 2A	B03 A03 B02 A02	
			A01,A02	A07	2B	B01 A01	
			DC12/24V	A06	2C		
			Connector no.	A05	2D		
				A04	2E		
				A03	2F		
				A02	СОМ		
				A01			

Chapter 7. Input/Output Specifications

7.3.4 XBC-DR32H output unit

Model		Basic unit				
Specification	n	XBC-DR32H(/DC)				
Output poi	int	16 point				
Insulation n	nethod	Relay insulation				
Rated load voltage/cur	rent	DC24V 2A (Resistive load) / AC220V 2A (COSΦ = 1), 5A/COM				
Min. load voltage/cur	rent	DC5V / 1 mA				
Max. load v	oltage	AC250V, DC125V				
Off leakage	current	0.1 mA (AC220V, 60 Hz)				
Max. on/off	frequency	3,600 times / hour				
Surge killer		None				
	Mechanical	20 million or above				
		Rated load voltage / current one hundred thousand or above				
Life	Electrical	AC200V / 1.5A, AC240V / 1A (COS Φ = 0.7) one hundred thousand or above				
	Electrical	AC200V / 1A, AC240V / 0.5A (COS Φ = 0.35) one hundred thousand or above				
		DC24V / 1A, DC100V / 0.1A (L / R = 7ms) one hundred thousand or above				
Response	$Off \rightarrow On$	10 ms or less				
time	$On \rightarrow Off$	12 ms or less				
Common m	ethod	4 point / COM				
Proper cable size		Strand wire 0.3~0.75 m² (External diameter 2.8 mm or less)				
Internal consumption current		360 ^{mA} (When all output are on)				
Operation is	ndicator	Output On, LED On				
External conn	ection method	24 point terminal block connector (M3 X 6 screw)				
Weight		600g				

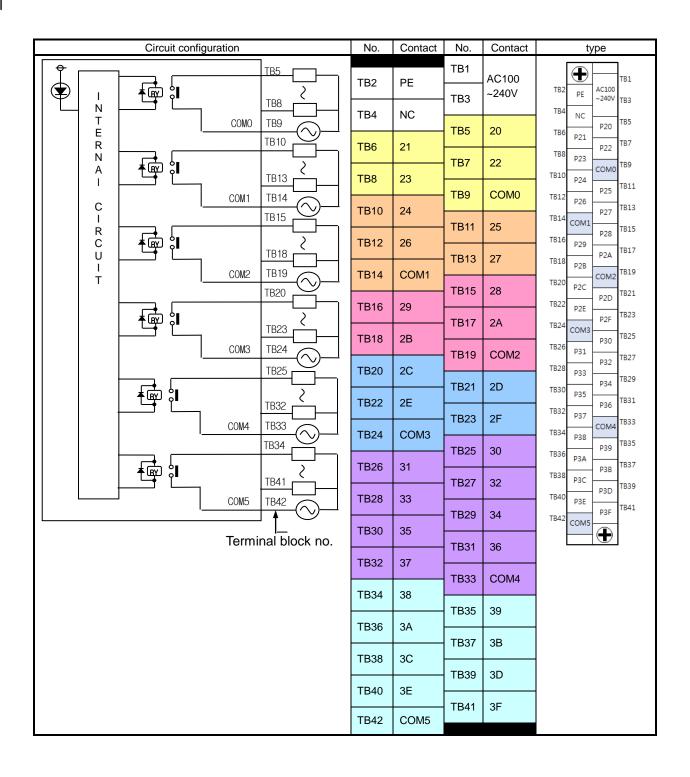
Chapter 7 Input/Output Specifications



Chapter 7. Input/Output Specifications

7.3.5 XBC-DR64H output unit

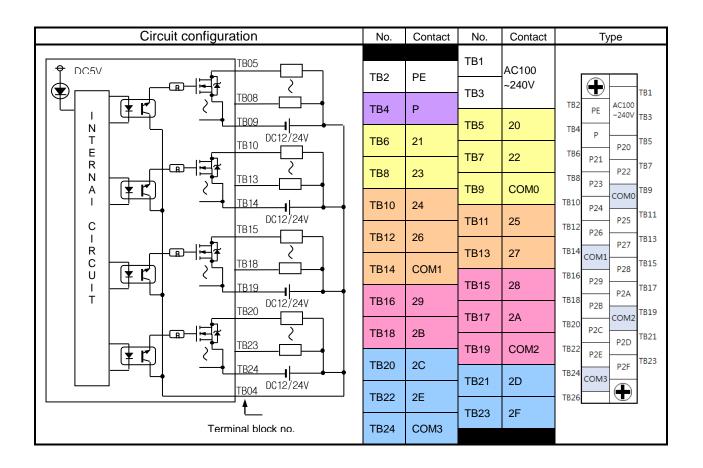
Model		Basic unit			
Specifica	ation	XBC-DR64H(/DC)			
Output poi	nt	32 point			
Insulation m	ethod	Relay insulation			
Rated load voltage/curr	ent	DC24V 2A (resistive load) / AC220V 2A (COS Φ = 1), 5A/COM			
Min. load voltage/curr	ent	DC5V / 1 mA			
Max. load vo	oltage	AC250V, DC125V			
Off leakage	current	0.1 mA (AC220V, 60 Hz)			
Max. on/off	frequency	3,600 times / hour			
Surge killer		None			
	Mechanical	20 million or above			
	Electrical	Rated load voltage / current one hundred thousand or above			
Life		AC200V / 1.5A, AC240V / 1A (COS Φ = 0.7) one hundred thousand or above			
		AC200V / 1A, AC240V / 0.5A (COS Φ = 0.35) one hundred thousand or above			
		DC24V / 1A, DC100V / 0.1A (L / R = 7 ms) one hundred thousand or above			
Response	$Off \rightarrow On$	10 ms or less			
time	$On \rightarrow Off$	12 ms or less			
Common m	ethod	4 point / COM (COM0~COM3), 8 point / COM (COM4~COM5)			
Proper cable size		Strand wire 0.3~0.75 m² (External diameter 2.8 mm or less)			
Internal consumption current		720 mA (When all output are on)			
Operation indicator		Output On, LED On			
External cor	nnection method	42 point terminal block connector (M3 X 6 screw)			
Weight		900g			



7 3 6 XBC-DN32H output unit (Sink type)

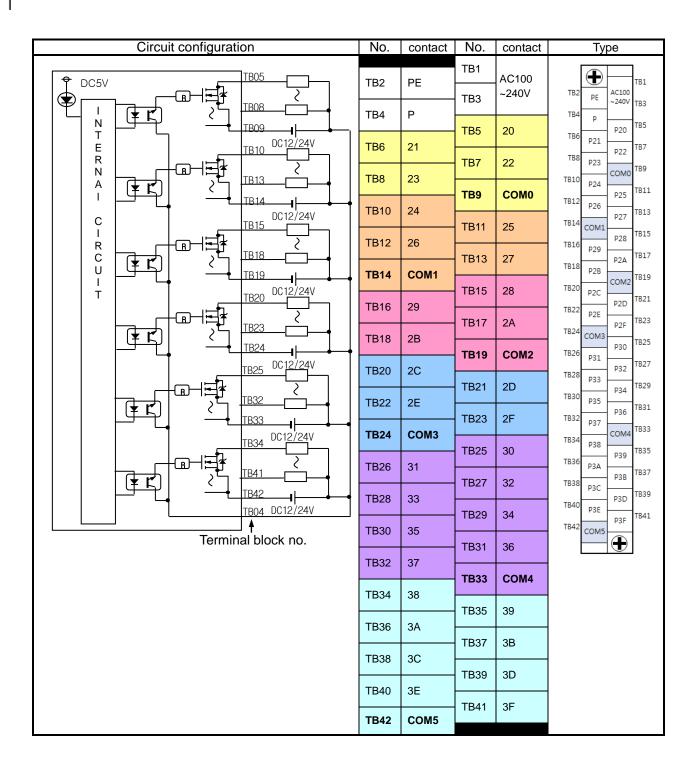
Specification	Model	Basic unit				
Opecinication		XBC-DN32H(/DC)				
Output point		16 point				
Insulation metho	d	Photo coupler insulation				
Rated load voltage/current		DC 12 / 24V				
Min. load voltage/current		DC 10.2 ~ 26.4V				
Max. load voltag	е	General output: 0.5A/ 1point, 2A/1COM Output for positioning (P20, P21, P22, P23): 0.1A/ 1 point, 0.4A/1COM				
Off leakage curre	ent	0.1 mA or less				
Max. on/off frequ	iency	4A / 10 ms or less				
Surge killer		DC 0.4V or less				
Output point		Zener diode				
Doon once time	$Off \rightarrow On$	1 ms or less				
Response time	$On \rightarrow Off$	1 ms or less (Rated load, resistive load)				
Common method	d	4 point / COM				
Proper cable siz	е	Strand wire 0.3~0.75 m² (external diameter 2.8 mm or less)				
Internal consum current	otion	400 mA (When all output are on)				
External power	Voltage	DC12/24V ± 10% (ripple voltage 4 Vp-p or less)				
supply	Current	25 mA or less (When connecting DC24V)				
Operation indica	tor	Output On, LED On				
External connec	tion method	24 point terminal block connector (M3 X 6 screw)				
Weight		500g				

Chapter 7 Input/Output Specifications



7 3 7 XBC-DN64H output unit (Sink type)

7.3.7 ADC		put unit (Sink type)			
	Model	Basic unit			
Specification		XBC-DN64H(/DC)			
Output point		32 point			
Insulation metho	od	Photo coupler insulation			
Rated load voltage		DC 12 / 24V			
Load voltage r	ange	DC 10.2 ~ 26.4V			
Max. load curr	ent	General output: 0.5A/ 1point, 2A/1COM Output for positioning (P20, P21, P22, P23): 0.1A/ 1 point, 0.4A/1COM			
Off leakage cur	rent	0.1 mA or less			
Max. inrush cu	ırrent	4A / 10 ms or less			
On max. voltag	ge drop	DC 0.4V or less			
Surge killer	-	Zener diode			
Response	Off → On	1 ms or less			
time	On → Off	1 ms or less (Rated load, Resistive load)			
Common meth	nod	4 point / COM (COM0~COM3), 8 point / COM (COM4~COM5)			
Proper cable siz	e	Strand wire 0.3~0.75 mm² (external diameter 2.8 mm or less)			
Internal consumption current		500 mA (When all output are on)			
External power	Voltage	DC12/24V ± 10% (Ripple voltage 4 Vp-p or less)			
supply	Current	25 mA or less (when connecting DC24V)			
Operation indicator		Output On, LED On			
External connec	tion method	42 point terminal block connector (M3 X 6 screw)			
Weight		800g			



7.4 Digital Input Module Specification 7.4.1 8 point DC24V input module (Source/Sink type)

	Model	DC input module				
Specification		XBE-DC08A				
Input point		8 point				
Insulation me	ethod	Photo coupler insulation				
Rated input v	/oltage	DC24V				
Rated input of	current	About 4 mA				
Operation vo	Itage range	DC20.4~28.8V (ripple rate	< 5%)			
On Voltage/0	Current	DC19V or higher / 3 mA or	higher			
Off Voltage/0	Current	DC6V or less / 1 mA or less				
Input resistar	nce	About 5.6 kΩ				
Response time	$\begin{array}{c} Off \to On \\ On \to Off \end{array}$	1/3/5/10/20/70/100 ms(set b	y CPU pa	arameter) D	Default: 3 ms	
Insulation pre	essure	AC560Vrms / 3Cycle (altitu	de 2000n	า)		
Insulation res	sistance	10 MΩ or more by Megohm	meter			
Common me	thod	8 point / COM				
Proper cable	size	Stranded pair 0.3~0.75 m² (External diameter 2.8 mm or less)				
Current cons	umption	30 mA (when all point On)				
Operation inc		Input On, LED On				
External con method	nection	10 point terminal block connector				
Weight		52 g				
	Circuit co	nfiguration	No.	Contact	Туре	
			TB2	0		
		Φ Φ	TB2	1	TB1	
0	R +	Photo coupler	TB3	2	TB2	
	 R	1 -11 ★ ★ 【!	TB4	3	TB3	
7 TB8		Internal circuit	TB5	4	TB5	
TB9 COM		Chount	TB6	5	тв6	
DC24V			TB7	6	TB7	
	Terminal block no.		TB8	7	TB8	
			TB9	СОМ	TB10	
			TB10	СОМ		

7.4.2 16 point DC24V input module (Sink/Source type)

	Model	DC input module			
Specification		XBE-DC16A			XBE-DC16B
Input point		16 point			
Insulation met	hod	Photo coupler insula	tion		
Rated input vo	oltage	DC24V		DC	C12/24V
Rated input cu	ırrent	About 4 mA		Ab	out 4/8 mA
Operation volt	age range	DC20.4~28.8V (ripple rate < 5%)			
On Voltage/Cเ	urrent	DC19V or higher / 3 n	A or hig	her D	C9V or higher / 3 ^{mA} or higher
Off Voltage/Cu	urrent	DC6V or less / 1 mA	or less	DC	C5V or less / 1 mA or less
Input resistand	ce	About 5.6 kΩ		Ab	out 2.7 kΩ
Response time	$\begin{array}{c} \text{Off} \rightarrow \text{On} \\ \text{On} \rightarrow \text{Off} \end{array}$	1/3/5/10/20/70/100 m	s (set b	y CPU p	parameter) Default: 3 ms
Insulation pres	ssure	AC560Vrms / 3Cycle	e (altitud	e 2000n	n)
Insulation resi	stance	10 ^{MΩ} or more by Me	egohmm	eter	
Common meth	nod	16 point / COM			
Proper cable s	size	Stranded cable 0.3~	0.75 ㎜	(Externa	al diameter 2.8 mm or less)
Current consu	mption	40 ^{mA} (when all point On)			
Operation indi	cator	Input On, LED On			
External conn	ection method	8 pin terminal block	connect	or + 10 p	oin terminal block connector
Weight		53 g			
	Circuit configu	ıration	No.	Contac	t Type
			TB1	0	TB1
			TB2	1	TB2
			TB3	2	TB3
			TB4	3	TB4
			TB5	4	TB5
			TB6	5	TB6
l		A A	TB7	6	TB7
	R + +	Photo coupler	TB8	7	TB8
		-] [TB1	8	TB1
7	学	Internal	TB2	9	TB2
TB9 S Internal circuit			TB3	Α	TB3
COM			TB4	В	TB4
DC24V Connector No.			TB5	C	TB5
			TB6	D -	TB6
			TB7 TB8	E	TB8
				F	TB9
				COM	TB10
			TB10	COM	

7.4.3 32 point DC24V input module (Source/Sink type)

Model	DC input module					
Specification			XBE-DC	32A		
Input point						
Insulation method	Photo coupler insu	lation				
Rated input voltage	DC24V					
Rated input current	About 4 mA					
Operation voltage range	DC20.4~28.8V (rip	ple rate	< 5%)			
Input Derating	Refer to Derating d		•			
On Voltage/Current	DC 19V or higher /		r hiaher			
Off Voltage/Current	DC 6V or less / 1 m					
Input resistance	About 5.6 kΩ	di les	8			
T	About 3.0 No.					
Response time $Off \rightarrow On$ On $\rightarrow Off$	1/3/5/10/20/70/100	ns (set l	by CPU p	aramet	er) Defau	ult:3 ms
Insulation pressure	AC 560Vrms / 3 Cy	∕cle (alti	tude 200	0m)		
Insulation resistance	10 MΩ or more by N	/legohm	meter			
Common method	32 point / COM					
Proper cable size	0.3 mm²					
Current consumption	50 ^{mA} (when all point On)					
Operation indicator	Input On, LED On					
External connection method	40 pin connector					
Weight	60g					
Circuit configu	ration	No.	Contact	No.	Contact	Туре
		B20	00	A20	10	
0	♥ DC5V ♥	B19	01	A19	11	
B20 R Pho	o counier LED	B18	02	A18	12	B20 1 1 1 A20
		B17	03	A17	13	B19 A19
1F A05	Internal circuit	B16 B15	04 05	A16	14	B18 A18 B17 A17
B02 COM		B14	06	A15 A14	15 16	B16 A16
DC24V Connector no.		B13	07	A13	17	B15 A15
		B12	08	A12	18	B14 A14 B13 A13
Input Derating diagram		B11	09	A11	19	B12
100	T	B10	0A	A10	1A	B10 A10
90	1 1 1 1 1 2 2 2 2 2 1 1	B09	0B	A09	1B	B09 A09 B08 A08
80	DC28.8V	B08	0C	A08	1C	B07
% 70 de co		B07	0D	A07	1D	B06 A06 B05 A05
% 70 60 50		B06	0E	A06	1E	B04 A04
40		B05	0F	A05	1F	B02 A02
0 10 20 30	40 50 55 °C	B04	NC	A04	NC	B01 A01
Ambient tempera	ature (°C)	B03	NC	A03	NC	ш
		B02	COM	A02	COM	
		B01	COM	A01	COM	

7.5 Digital Output Module Specification

7.5.1 8 point relay output module

	Model	Relay output module					
Specification	on	XBE-RY08A					
Output point		8 point	8 point				
Insulation m	ethod	Relay insulation					
Rated load v	oltage / Current	DC24V 2A (Resistive load) /	AC220V 2A	(COSΨ =	1), 5A/COM		
Min. load vo	ltage/Current	DC5V / 1 mA					
Max. load vo	oltage/Current	AC250V, DC125V					
Off leakage	current	0.1 mA (AC220V, 60 Hz)					
Max. On/Off	frequency	3,600 times/hr					
Surge absor	ber	None					
	Mechanical	20 millions times or more					
		Rated load voltage / current	100,000 time	es or more			
Service life	Electrical	AC200V / 1.5A, AC240V / 1A	$A (COS\Psi = 0)$	0.7) 100,00	0 times or more		
	Licetrical	AC200V / 1A, AC240V / 0.5A	$A (COS\Psi = 0)$	0.35) 100,00	00 times or more		
		DC24V / 1A, DC100V / 0.1A	(L/R = 7 ms)	3) 100,000	times or more		
Response	$Off \rightarrow On$	10 ms or less					
time	$On \rightarrow Off$	12 ms or less					
Common me	ethod	8 point / COM					
Proper cable	size	Stranded cable 0.3~0.75 mm² (External diameter 2.8 mm or less)					
Current cons	sumption	230 mA (when all point On)					
Operation in	dicator	Output On, LED On					
External con	nection method	9 pin terminal block connector					
Weight		80g					
	Circuit co	onfiguration	No.	Contact	Туре		
			TB1	0			
•	DC5V		TB2	1			
			TB3	2	TB1		
Internal circuit		TB1	TB4	3	TB2 TB3		
		_ <	TB5	4	TB4		
		TB8	TB6	5	TB6		
		TB9	TB7	6	TB7 TB8		
		Terminal block no.	TB8	7	TB9		
			TB9	СОМ			

7.5.2 8 point relay output module(Relay insulation)

	Model	Relay output module					
Specification	on	XBE-RY08B					
Output point		8 point					
Insulation m		Relay insulatio	n				
Rated load v	oltage / Current	DC24V 2A (Re	sistive load) / A	C220V 2A	(COSΨ =	1), 5A/COM	
Min. load vo	Itage/Current	DC5V / 1 mA	,		,	,	
Max. load vo	oltage/Current	AC250V, DC12	25V				
Off leakage	current	0.1 mA (AC220	V, 60 Hz)				
Max. On/Off	frequency	3,600 times/hr					
Surge absor	ber	None					
	Mechanical	20 millions time	es or more				
		Rated load volt	tage / current 10	00,000 tim	es or more)	
Service life	Clastical	AC200V / 1.5A	, AC240V / 1A (COSΨ =	0.7) 100,00	00 times or more	
	Electrical	AC200V / 1A, A	AC240V / 0.5A (COSΨ =	0.35) 100,0	00 times or more	
		DC24V / 1A, D	C100V / 0.1A (L	_/R=7 m	s) 100,000	times or more	
Response	$Off \rightarrow On$	10 ms or less					
time	$On \rightarrow Off$	12 ms or less					
Common me	ethod	8 point / COM					
Proper cable	e size	Stranded cable	Stranded cable 0.3~0.75 m² (External diameter 2.8 mm or less)				
Current cons	sumption	230 mA (when all point On)					
Operation in	dicator	Output On, LED On					
External con	nection method	9 pin terminal block connector					
Weight		81g					
	Circuit o	onfiguration		No.	Contact	Туре	
				TB1	0	TB1	
				TB2	COMO	TB1	
				TB3	1	TB3	
				TB4	COM1	TB4	
	♥ DC5V			TB5	2	TB5	
				TB6	COM2	TB6	
	Y			TB7	3	TB7	
			TB1	TB8	COM3	TB8	
	★ ₩) 		TB9	NC	109	
			TB2 _\	TB1	4	TB1 📜	
		5	5	TB2	COM4	TB2	
	Internal	<		TB3	5	TB3	
	circuit		TB7	TB4	COM5	TB4	
			_	TB5	6	TB6	
			TB8 (\(\sigma\)	TB6	COM6	TB7	
			†	TB7	7	TB8	
			Terminal block n 0	TB8	COM7	TB9	
			reminar block fit	TB9	NC		

7.5.316 point relay output module

	Model	Relay output module				
Specificatio	n	XBE-RY16A				
Output poin		16 point				
Insulation n	nethod	Relay insulation				
Rated load	voltage/ current	DC24V 2A (Resistive load	I) / AC220V	2A (COSΨ	= 1), 5A/COM	
Min. load vo	oltage/current	DC5V / 1 mA			•	
Max. load v	oltage/current	AC250V, DC125V				
Off leakage	current	0.1 mA (AC220V, 60 Hz)				
Max. On/Of	f frequency	3,600 times/hr				
Surge abso	rber	None				
	Mechanical	20 millions times or more				
		Rated load voltage / curre	nt 100,000 t	imes or mo	re	
Service life	Floatsiaal	AC200V / 1.5A, AC240V /	1A (COSΨ	= 0.7) 100,0	000 times or more	
III C	Electrical	AC200V / 1A, AC240V / 0	.5A (COSΨ	= 0.35) 100	,000 times or more	
		DC24V / 1A, DC100V / 0.	1A (L / R = 7	7 ms) 100,00	0 times or more	
Response	$Off \rightarrow On$	10 ms or less				
time	$On \rightarrow Off$	12 ms or less				
Common m	ethod	8 point / COM				
Proper cabl	e size	Stranded cable 0.3~0.75 m² (External diameter 2.8 mm or less)				
Current con	sumption	420 mA (when all point On)				
Operation in	ndicator	Output On, LED On				
External co	nnection method	9 pin terminal block connector x 2 ea				
Weight		130g				
	Circuit cor	figuration	No.	Contact	Туре	
			TB1	0	TB1	
			TB2	1	TB2	
l l ç	DC5V		TB3	2	TB3	
)		TB4	3	TB4	
		TB1	TB5	4	TB6	
			TB6 TB7	5 6	TB7	
Inter			TB8	7	TB8	
		TB8	TB9	COM	- TB9 🔛	
			TB1	8 8	TB1	
		TB9	TB2	9	TB2	
			TB3	A	TB3	
	Terminal block no.			В	TB4	
			TB4 TB5	С	TB5	
			TB6	D	TB6	
			TB7	E	TB7	
			TB8	F	TB9	
			TB9	COM		

7.5.4 8 point transistor output module (Sink type)

	Model	Transistor output module			
Specification				A	
Output point 8 point					
Insulation me	thod	Photo coupler insulation			
Rated load vo	oltage	DC 12 / 24V			
Load voltage	range	DC 10.2 ~ 26.4V			
Max. load vol	tage	0.5A / 1 point			
Off leakage of	current	0.1 mA or less			
Max. inrush o	current	4A / 10 ms or less			
Max. voltage	drop (On)	DC 0.4V or less			
Surge absorb	er	Zener Diode			
Response	$Off \rightarrow On$	1 ms or less			
time	$On \to Off$	1 ms or less (Rated load, resi	stive load)	
Common me	thod	8 point / COM			
Proper cable	size	Stranded cable 0.3~0.75 m² (External	diameter 2	.8 mm or less)
Current cons	umption	40 mA (when all point On)			
External power	Voltage	DC12/24V ± 10% (ripple voltage 4 Vp-p or less)			
supply	Current	10 mA or less (DC24V connec	tion)		
Operation inc		Output On, LED On			
External conr method	nection	10 pin terminal block connector			
Weight		52g			
	Circuit co	nfiguration	No.	Contact	Туре
			TB01	0	
→ DC5V			TB02	1	TB01
		TB01	TB03	2	TB02
			TB04	3	TB03
Internal circuit		<u>کا ا</u> (ا	TB05	4	TB04
		TB08	TB06	5	TB06
		TB09	TB07	6	TB07
		TB10	TB08	7	ТВ09
		DC12/24V Terminal block no.	TB09	DC12 /24V	TB10
		Terrinal Mock III.	TB10	СОМ	

7.5.5 16 point transistor output module (Sink type)

	Model		Transist	or output module				
Specification			Х	BE-TN16A				
Output point		16 point	16 point					
Insulation meth	nod	Photo coupler insulation						
Rated load vol	tage	DC 12 /						
Load voltage ra		DC 10.2	2 ~ 26.4V					
Max. load volta	age	0.5A / 1	point, 2A / 1COM					
Off leakage cu	rrent	0.1 mA c	or less					
Max. inrush cu	rrent	4A / 10	ms or less					
Max. voltage d	rop (On)	DC 0.4\	or less					
Surge absorbe	r	Zener D	iode					
Response	$Off \rightarrow On$	1 ms or	less					
time	$On \rightarrow Off$	1 ms or	less (Rated load, resi	stive load)				
Common meth	od	16 point	/ COM					
Proper cable s	ize	Stranded cable 0.3~0.75 mm² (External diameter 2.8 mm or less)						
Current consur	mption	60 ^{mA} (when all point On)						
External	Voltage	DC12/24V ± 10% (ripple voltage 4 Vp-p or less)						
power supply	Current	10 mA or less (DC24V connection)						
Operation indic	cator	Output On, LED On						
External conne	ection method	8 pin terminal block connector + 10 pin terminal block connector						
Weight		54 g						
	Circuit cor	nfiguration		No.	Contact	Туре		
				TB01	0	TB01		
			_	TB02	1	TB02		
♥ DC5	V			TB03 TB04	3	TB03		
	V		 TB01	TB05	4	TB04 TB05		
			1501	TB06	5	TB06		
		⊣ ;=5}}		TB07	6	TB07		
Internal		' ` \		TB08	7	TB08		
circuit	(2		TB01	8	TB01		
			TB08	TB02	9	TB02		
				TB03	Α	TB03		
			TB09	TB04	В	TB04		
TB10			TB05	С	TB05			
DC12/24V			TB06	D	TB06			
			」	TB07 TB08	E F	TB07		
			Terminal block no.		DC12	TB08		
				TB09	/24V	TB09		
				TB10	COM			

7.5.6 32 point transistor output module (Sink type)

	Model	Transistor output module							
Specification			XE	BE-TN32	2A				
Output point 32 point									
Insulation method		Photo coupler insulation							
Rated load voltag	Rated load voltage								
Load voltage rang	je	DC 10.2 ~ 26.4V							
Max. load voltage		0.2A / 1 point, 2A / 1CC	DM						
Off leakage curre		0.1 mA or less							
Max. inrush curre	nt	0.7A / 10 ms or less							
Max. voltage drop	(On)	DC 0.4V or less							
Surge absorber		Zener Diode							
	$Off \rightarrow On$	1 ms or less							
Response time On \rightarrow Off		1 ms or less (Rated load	d, resis	tive loa	d)				
Common method		32 point / COM							
Proper cable size		0.3 mm²							
Current consumpt	ion	120 mA (when all point	On)						
External power	Voltage	DC12/24V ± 10% (ripple voltage 4 Vp-p or less)							
supply	Current	20 mA or less (DC24V c				<u>, , , , , , , , , , , , , , , , , , , </u>			
Operation indicate	or	Output On, LED On							
External connection	on method	40 pin connector							
Weight		60g							
	Circuit configur	ation	No.	Conta ct	No.	Conta ct	Ту	/ре	
			B20	00	A20	10			
			B19	01	A19	11	_	_	
↔ DC5V			B18	02	A18	12	B20	Ħ╢▗	\20
		B20	B17	03	A17	13	B19 	н	119
🖤			B16	04	A16	14	B18 B17	!!	\18 \17
			B15	05	A15	15	B16		116
Internal		. /	B14	06	A14	16	B15	!!	115
circuit	<u> </u>		B13	07	A13	17	B14 B13	11	\14 \13
	! <	A05	B12	08	A12	18	B12	11	112
			B11	09	A11	19	B11		A11 A10
		B01.B02	B10	0A	A10	1A	во9	• • A	۹09
	-	A01,A02 _I	B09	0B	A09	1B	B08 B07		\08 \07
		701,702	B08	0C	A08	1C	В06	a A	۸06
		DC12/24V	B07	0D	A07	1D	B05 B04	11	\05 \04
		Connector no.	B06	0E	A06	1E	B03	A	103
			B05	0F	A05	1F	B02 B01		\02 \01
			B04	NC	A04	NC	Щ	⋣ ∄ົ	
			B03	NC	A03	NC			
			B02	DC12/ 24V	A02	СОМ			
			B01	24 V	A01				

7.5.7 8 point transistor output module (Source type)

	Model	Transis	stor output	module				
Specification	1		XBE-TP08	A				
Output point		8 point						
Insulation me	ethod	Photo coupler insulation						
Rated load vo	oltage	DC 12 / 24V						
Load voltage	range	DC 10.2 ~ 26.4V						
Max. load vol	tage	0.5A / 1 point						
Off leakage c	urrent	0.1 mA or less						
Max. inrush o	current	4A / 10 ms or less						
Max. voltage	drop (On)	DC 0.4V or less						
Surge absorb	er	Zener Diode						
Response	$Off \to On$	1 ms or less						
time	$On \rightarrow Off$	1 ms or less (Rated load, res	sistive load)				
Common me	thod	8 point / COM						
Proper cable	size	Stranded cable 0.3~0.75 mm² (external diameter 2.8 mm or less)						
Current cons	umption	40 mA (when all outputs are	on)					
External	Voltage	DC12/24V \pm 10% (ripple volt	age 4 Vp- _l	o or less)				
power	Current	10 mA or less (when connect	ing DC24\	/)				
Operation inc		LED on when output on						
External method	connection	10 pin terminal block connec	tor					
Weight		30g						
	Circuit co	onfiguration	No.	Contact	Туре			
			TB01	0				
DC5\	I	TB09	TB02	1	TRO1			
			TB03	2	TB01 TB02			
Internal circuit		TB10	TB04	3	TB03			
	 	TB08	TB05	4	TB04			
	_		TB06	5	TB06			
	L_R		TB07	6	TB07			
		TB01	TB08	7	TB09			
		Terminal block no.	TB09	СОМ	TB10			
		DIOUR HO.	TB10	0V				

7.5.816 point transistor output module (Source type)

	Model	Transista	r autaut ma	adula.				
			r output mo E-TP16A	Daule				
Specification			6E-11916A					
Output point 16 point								
Insulation meth		Photo coupler insulation						
Rated load vol	tage	DC 12 / 24V						
Load voltage r	ange	DC 10.2 ~ 26.4V						
Max. load volta	age	0.5A / 1 point, 2A / 1COM						
Off leakage cu	rrent	0.1 mA or less						
Max. inrush cu	irrent	4A / 10 ms or less						
Max. voltage d	lrop (On)	DC 0.4V or less						
Surge absorbe	er	Zener Diode						
Response	$Off \rightarrow On$	1 ms or less						
time	$On \rightarrow Off$	1 ms or less (Rated load, resist	tive load)					
Common meth	nod	16 point / COM						
Proper cable s	ize	Stranded cable 0.3~0.75 mm² (e	xternal dia	meter 2.8 m	m or less)			
Current consul	mption	60 mA (When all outputs are on)						
External	DC12/24V ± 10% (ripple voltage	ge 4 Vp-p o	r less)					
power	Current	10 mA or less (connecting DC2	4V)					
Operation indic	cator	LED On when output On						
External conne	ection method	8 pin terminal block connector + 10 pin terminal block connector						
Weight		40g						
	Circuit co	onfiguration	No.	Contact	Туре			
			TB01	0	TB01			
			TB02	1	TB02			
→ DC5\	V	TD00	TB03	2	TB03			
LED 🕏		TB09	TB04	3	TB04			
	_	TB10 DC12/24V	TB05	4	TB05			
Internal		1010	TB06	5	TB06			
circuit		TB08	TB07	6	TB07			
			TB08	7	TB08			
			TB01	8				
			TB02	9	TB01			
	<u></u>	TD01	TB03	A	TB02			
		TB01 L	TB04	В	1500			
Terminal				С	1004			
block no.			TB05 TB06	D	1000			
					1200			
			TB07	E F	IBU/			
			TB08		1000			
			TB09	COM	1009			
			TB10	0V	TB10			

7.5.9 32 point transistor output module (Source type)

	Model	Т	ransisto	or outpu	ıt modu	le			
Specification		XBE-TP32A							
Output point									
Insulation method	d	Photo coupler insulation							
Rated load voltage	je	DC 12 / 24V							
Load voltage rang	ge	DC 10.2 ~ 26.4V							
Max. load voltage)	0.2A / 1 point, 2A / 1C	ОМ						
Off leakage curre	nt	0.1 mA or less							
Max. inrush curre	ent	4A / 10 ms or less							
Max. voltage drop	o (On)	DC 0.4V or less							
Surge absorber		Zener Diode							
Off → On		1 ms or less							
Response time	$On \to Off$	1 ms or less (Rated loa	ad, resi	stive loa	ad)				
Common method	Common method								
Proper cable size		0.3 ㎜²							
Current consump	tion	120 mA (When all outputs are on)							
Voltage DC12/24V ± 10%			le volta	ige 4 Vp	o-p or le	ess)			
External power	Current	20 mA or less (connect	ing DC	24V)					
Operation indicator		LED On when output (On						
External connecti	on method	40 pin connector							
Weight		60g							
	Circuit configura	ation	No.	Contact	No.	Contact	Type		
			B20	00	A20	10			
			B19	01	A19	11			
⊕ DC5V			B18	02	A18	12	B20 A20		
		B02,B01	B17 B16	03 04	A17 A16	13 14	B19 A19		
LED (¥)		DC12/24V	B15	05	A15	15	B18 A18 A17		
Internal	¬	A02,A01	B14	06	A14	16	B16 A16		
circuit	\[\frac{1}{2} \]	A05	B13	07	A13	17	B15 A15 B14 A14		
	<u>* [</u>	, NSS	B12	08	A12	18	B13		
	_		B11	09	A11	19	B12 A12 B11 A11		
			B10	0A	A10	1A	B10 . A10		
			B09	0B	A09	1B	B09 A09		
		B20	B08	0C	A08	1C	B07 A07		
	_	<u> </u>	B07	0D	A07	1D	B06 A06 B05 A05		
		Connector	B06	0E	A06	1E	B04 • A04		
		No.	B05	0F	A05	1F	B03 A03 B02 A02		
			B04	NC	A04	NC	B01 A01		
			B03	NC	A03	NC	<u> "</u> = -"		
			B02		A02				
			B01	COM	A01	0V			

7.6 Digital I/O Mixed module Input Specification 7.6.1 8 point DC24V input (Source/Sink type)

	Model]	OC input r	module				
Specification	on	XBE-DR16A						
Input point		8 point	8 point					
Insulation me	ethod	Photo coupler insulation						
Rated input v	oltage	DC24V						
Rated input of	current	About 4 mA						
Operation vo	Itage range	DC20.4~28.8V (within rippl	e rate 5%)				
On Voltage/C	Current	DC19V or higher / 3 mA or h	nigher					
Off Voltage/C	Current	DC6V or less / 1 mA or less						
Input resistar	nce	About 5.6 kΩ						
Response	$Off \to On$	1/2/E/10/20/70/100 mc/oot h	v CDU na	romotor) [Nofaulti 2 ms			
time	$On \to Off$	1/3/5/10/20/70/100 ms (set b	у СРО ра	iranneter) L	Perault. 3 IIIS			
Insulation pre	essure	AC560Vrms / 3Cycle (altitu	de 2000m	า)				
Insulation res	sistance	10 ^{MΩ} or more by Megohmmeter						
Common me	thod	8 point / COM						
Proper cable	size	Stranded cable 0.3~0.75 m² (External diameter 2.8 mm or less)						
Current cons	umption	280 ^{mA} (When all inputs and outputs are on)						
Operation inc	dicator	LED on when input on						
External method	connection	9 pin terminal block connec	tor					
Weight		81g						
	Circuit co	nfiguration	No.	Contact	Туре			
			TB1	0				
Г		⊕ DC5V Q	TB2	1	TB1			
	- R	Photo coupler	TB3	2	TB2			
[5	R :	LED¥	TB4	3	TB3			
7 TB8	\s\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	Internal	TB5	4	TB5			
TB9 COM		circuit	TB6	5	тв6			
			TB7	6	TB7			
	-Terminal block no.		TB8	7	TB8			
			TB9	СОМ				

7.6.2 16 point DC24V input (Source/Sink type)

Specification	del		D	C input n			
Specification				XBE-DN	32A		
Input point		16 point					
Insulation meth	nod	Photo coupler insu	lation				
Rated input vol	tage	DC24V					
Rated input cui	rrent	About 4 mA					
Operation volta	age range	DC20.4~28.8V (r	ipple rat	te < 5%)			
Input Derating		Refer to Derating of					
On Voltage/Cu		DC 19V or higher /					
Off Voltage/Cu	rrent	DC 6V or less / 1 m	A or les	S			
Input resistanc	e	About 5.6 kΩ					
Response time $Off \rightarrow On$ $1/3/5/10/20/70/100$				by CPU	parame	eter) Defa	ult:3 ms
Insulation pres	sure	AC 560Vrms / 3 Cy	ycle (a	Ititude 20	00m)		
Insulation resis	tance	10 MΩ or more by M	Ледоhm	meter			
Common meth	od	16 point / COM					
Proper cable si	ize	0.3 mm²					
Current consur	nption	60 mA (When all in	nputs ar	nd outputs	are on	1)	
Operation indic	ator	Input On, LED On					
External conne	ction method	40 pin connector					
Weight		60g					
	Circuit configur	ation	No.	Contact	No.	Contact	Туре
			B20	00	A20	20	
		• •	B19	01	A19	21	
- B20 - I	Photo	o counter	B18	02	A18	22	I.≓H.
>	♀ (字 ★		B17	03	A17	23	B20 A A
0 B05	5	Internal circuit	B16	04	A16	24	B18 A B17 A
□ B02 COM			B15	05	A15	25	B16 A
DC24V Te	rminal block no.		B14	06	A14	26	B15 A
Input Derati	ing diagram		B13	07	A13	27	B13 A
100		\Box	B12	08	A12	28	B12
90	 	\Box	B11	09	A11	29	B10 A B09 A
€ 80	 	 	B10	0A	A10	2A	B08
70 H			B09	0B	A09	2B	B07 A
00 on rate		2000 01/	B08	0C	80A	2C	B05 A B04 A
40 📙			B07	0D	A07	2D	B03 A
0	10 20 30 Ambient	40 50 55 emperature	B06	0E	A06	2E	B02 F A
	AHDICHL	comporature	B05	0F	A05	2F	<u>"</u>
			D = 1			_	

B04

B03

B02

B01

NC

NC

IN_COM

IN_COM

A04

A03

A02

A01

Ρ

Р

OUT_CO M OUT_CO M

7.7 Digital I/O Mixed module Output Specification 7.7.1 8 point relay output

	Model		Relay ou	utput modu	ıle		
Specificatio	n		XBE	-DR16A			
Output point 8 point							
Insulation method Relay insulation							
Rated load voltage / Cu	urrent	DC24V 2A(Re	esistive load) / AC2	20V 2A(C	OSΨ = 1),	5A/COM	
Min. load vo	oltage/Current	DC5V / 1 mA					
Max. load v	oltage	AC250V, DC1	25V				
Off leakage	current	0.1 mA (AC220	0V, 60 ^{Hz})				
Max. On/Of	f frequency	3,600 times/h	r				
Surge abso	rber	None					
	Mechanical	20 millions tim	nes or more				
		Rated load vo	Itage / current 100,	000 times	or more		
Service life	Electrical	AC200V / 1.5	A, AC240V / 1A (C	OSΨ = 0.7	') 100,000 t	times or more	
	Liectrical	AC200V / 1A,	AC240V / 0.5A (C	OSΨ = 0.3	35) 100,000) times or more	
		DC24V / 1A, [DC100V / 0.1A (L /	R = 7 ms	100,000 tin	nes or more	
Response	$Off \rightarrow On$	10 ms or less					
time	$On \rightarrow Off$	12 ms or less					
Common m	ethod	8 point / COM					
Proper cabl	e size	Stranded cabl	e 0.3~0.75 mm² (ext	ernal diam	eter 2.8 mm	or less)	
Current con	sumption	280 ^{mA} (Wher	all inputs and outp	outs are or	ገ)		
Operation in		LED on when output on					
External method	connection	9 pin terminal block connector					
Weight		81g					
	Circui	t configuration		No.	Contact	Туре	
			_	TB1	0		
	O DC5V			TB2	1		
LED (TD1	TB3	2	TB1	
	nternal circuit		TB1 L	TB4	3	твз 🖳	
		Ϊ	TB8	TB5	4	TB4	
			TB9	TB6	5	TB6	
			Terminal	TB7	6	тва 📆	
			block no.	TB8	7	TB9	
				TB9	СОМ		

7.7.2 16 point transistor output (Sink type)

Mod	el	Tr	ansisto	r output	modu	le			
Specification		XBE-DN32A							
Output point		16 point							
Insulation method		Photo coupler insulation							
Rated load voltage	Э	DC 12 / 24V							
Load voltage rang	e	DC 10.2 ~ 26.4V							
Max. load voltage		0.2A / 1 point, 2A / 1COM							
Off leakage currer	nt	0.1 mA or less							
Max. inrush currer		0.7A / 10 ms or less							
Max. voltage drop		DC 0.4V or less							
Surge absorber	(-1-)	TVS Diode							
Cargo aboorbor	$Off \rightarrow On$	1 ms or less							
Response time	$On \rightarrow Off$	1 ms or less (Rated lo	ad rac	istiva lo	ad)				
Common method	011 -> 011	16 point / COM	au, res	istive io	au)				
Proper cable size		0.3 mm²							
-	ion			toto.o	ro on)				
Current consumpt		60 mA (When all inputs				1 \			
External power	Voltage	DC12/24V ± 10% (rip)			p-p or	iess)			
supply	Current	20 mA or less (DC24V	conne	ction)					
Operation indicate		Output On, LED On							
External connection	on method	40 pin connector							
Weight		60g			1				
	Circuit configura	ation	No.	Conta ct	No.	Contac t	T	ype	
			B20	00	A20	20			
			B19	01	A19	21			
⊕ DC5V			B18	02	A18	22	F	Ħ.	
		A20	B17	03	A17	23	B20 B19	• •	A20 A19
		1120	B16	04	A16	24	B18	<u>ال</u> ا	A18
	_ 1-1		B15	05	A15	25	B17 B16	0 D	A17
			B14	06	A14	26	B15	11	A16 A15
Internal circuit	, 'T		B13 B12	07 08	A13 A12	27 28	B14	11	A14
circuit			B11	09	A11	29	B13 B12		A13 A12
		A05	B10	0A	A10	2A	B11	11	A11
			B09	0B	A09	2B	B10	• • <i>•</i>	A10
		A03,A04	B08	0C	A08	2C	B09 B08	• •	A09 A08
		A01,A02	B07	0D	A07	2D	B07	= = <i>-</i>	A07
		A DO12/24/	B06	0E	A06	2E	B06 B05		A06 A05
		DC12/24V Terminal block no.	B05	0F	A05	2F	B04	[] [A05 A04
			B04	NC	A04	Р	B03 B02		A03
			B03	NC	A03	Р	B02 B01		A02 A01
			B02	IN_COM	A02	OUT_CO M	μ	╽	'
			B01	IN_COM	A01	OUT_CO	_	—	

7.8 IO Wiring by Using Smart Link Board 7.8.1 Smart link board

Easy wiring is available by connecting the IO connector with smart link board.

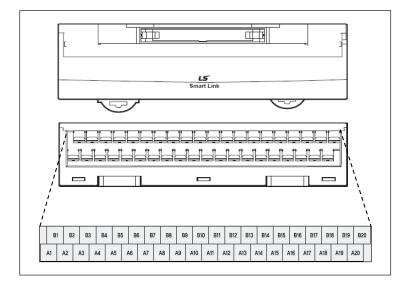
The available smart link and IO cable are as follows.

X	ЗB	Smart	link		Conn	ection cable
Item	Model	Model	No. of Pin	Model	Length	Contents
Main unit	XBM- DN32S XBM- DN16S	SLP- T40P	40	SLT-CT101- XBM	1m	For main unit connection (20Pin + 20Pin)
	XBE- DC32A	SLP- T40P	40	SLT-CT101- XBE	1m	For expansion module
Expansion		SLP- T40P	40	SLT-CT101- XBE	1m	connection (40Pin)
module	XBE- TN32A	SLP- RY4A	40	SLP-CT101- XBE	1m	For expansion module connection (40Pin) Exclusive for relay built-in SLP type

It describes wring of XGB, SLP-T40P and SLT-CT101-XBM. For wring of other smart link boards or XGB extension module, refer to XGB user manual for hardware.

1) SLT-T40P terminal array

Terminal array of SLP-T40P is as follows.

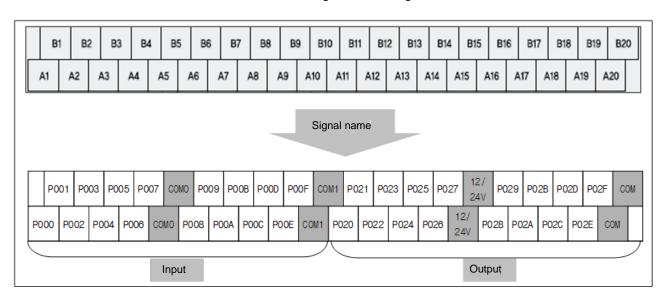


Item	Specification
Rated voltage	AC/DC 125[V]
Rated current	Max. 1[A]
Withstanding voltage	600V 1min
Insulation resistor	100 № (DC500V)
Cable specification	1.25[mm] or below
Terminal/screw	M3 X 8L
Torque	6.2 kgf.cm or above
Terminal material	PBT, UL94V-0
Weight	186g

2) Wiring of SLT-T40P and XGB extension module Wiring of XGB main unit through SLP-T40P and SLT-CT101-XBM is as follows.



At this time, relationship of XGB IO signal and Smart link board terminal number is as follows. The following figure describes signal allocation when SLT-CT101-XBM is used as connection cable. When the user makes the cable, make sure that wring is done as figure below.



Chapter 8 Built-in High-speed Counter Function

XGB series have built-in function of High-speed counter in basic unit. This chapter describes specifications and usage of High-speed counter's function.

8.1 High-speed Counter Specifications

☐ It describes specifications, setting and usage of function, programming and wiring with external device of built-in basic unit.

8.1.1 Performance specifications

1	1\	Performance	enecification
(1)	Performance	specification

01		Desc	cription		
Class	sification	"S" type	"H" type		
Count input	Signal	A-phase, B-phase			
signal	Input type	Voltage input (Open collector)			
_	Signal level	24V	400 lungs		
Max. coefficie	•		100 kpps		
Number of	1 phase		8 (10kpps 4 channels/20kpps 4 channels)		
channels	2 phase		(50kpps 2 channels/ 10kpps 2 channels)		
		In case of 4 multiplication: 8kpps	(50kpps 2 channels/ 8kpps 2 channels)		
Coefficient ra	nge	Signed 32 Bit (-2,147,483,648 ~ 2,	147,483,647)		
Count mode		Linear count (if 32-bit range exceeded,	Carry/Borrow occurs)		
(Program sett	tina)	Counter max. and min. value is indicated			
(i rogram sett	urig)	Ring count (repeated count within setting range)			
Input mode		1-phase input			
•	tina)	2-phase input			
(Program sett	urig)	CW/CCW input			
Signal type	1	Voltage			
	1 phase input	Increasing/decreasing operation setting by B-phase input			
Up/Down		Increasing/decreasing operation setting by program			
setting	2 phase input	Automatic setting by difference in phase			
3	CW/CCW	A-phase input: increasing operation			
		B-phase input: decreasing operation			
Multiplication	1 phase input	1 multiplication			
function	2 phase input	4 multiplication			
	CW/CCW	1 multiplication			
Control input	Signal Javal	Preset instruction input			
Control Input	Signal level	DC 24V input type			
	Signal type	Voltage 1 point/channel (for each channel)	2 point/channel (for each channel)		
	Output nainte	, ,			
External	Output points	:output contact point of basic unit	:output contact point of basic unit		
output		available	available		
-	Туре	Select single-compared (>, >=, =, <, <) or section compared output			
	71-	(included or excluded) (program setting)			

Classification "S" type		Description		
		"S" type	"H" type	
	Output type	Relay, Open-collector output (Sink)		
Count Enable To be set through program (count available only in enable status)		available only in enable status)		
Preset function		To be set through terminal (contact) or program		
Auxiliary mode		Count Latch		

(2) Counter/Preset input specification

Classification	Spcification
Input voltage	24V DC (20.4V ~ 28.8V)
Input current	4 mA
On guranteed voltage (min.)	20.4V
Off guranteed voltage (max.)	6V

8.1.2 Designation of parts(1) Designation of parts

Name	"S"ty	pe	"H" type
	XBM-DN16/32S	XBM-DN16/32S XBM-DR16S XBC-DN32/64H	
Structure	P00 P01 P02 P03 P04 P05 P06 P07 COM	P00 P01 P02 P03 P04 P05 P06 P07 COM	

(a) "S" type

Terminal	Names		Usage		
No.	1-phase	2-phase	1-phase	2-phase	
P000	Ch0 counter input	Ch0 A-phase input	Counter input terminal	A-phase input	
P001	Ch1 counter input	Ch0 B-phase input	Counter input terminal	B-phase input	
P002	Ch2 counter input	Ch2 A-phase input	Counter input terminal	A-phase input	
P003	Ch3 counter input	Ch2 B-phase input	Counter input terminal	B-phase input	
P004	Ch0 preset 24V	Ch0 preset 24V	Preset input terminal	Preset input terminal	
P005	Ch1 preset 24V	-	Preset input terminal	No use	
P006	Ch2 preset 24V	Ch2 preset 24V	Preset input terminal	Preset input terminal	
P007	Ch3 preset 24V	-	Preset input terminal	No use	
COM0	Input common	Input common	Common terminal	Common terminal	

(b) "H" type

Terminal	Nar	nes	Usage		
No.	1-phase	2-phase	1-phase	2-phase	
P000	Ch0 counter input	Ch0 A-phase input	Counter input terminal	A-phase input	
P001	Ch1 counter input	Ch0 B-phase input	Counter input terminal	B-phase input	
P002	Ch2 counter input	Ch2 A-phase input	Counter input terminal	A-phase input	
P003	Ch3 counter input	Ch2 B-phase input	Counter input terminal	B-phase input	
P004	Ch4 counter input	Ch4 A-phase input	Counter input terminal	A-phase input	
P005	Ch5 counter input	Ch4 B-phase input	Counter input terminal	B-phase input	
P006	Ch6 counter input	Ch6 A-phase input	Counter input terminal	A-phase input	
P007	Ch7 counter input	Ch6 B-phase input	Counter input terminal	B-phase input	
P008	Ch0 preset 24V	Ch0 preset 24V	Preset input terminal	Preset input terminal	
P009	Ch1 preset 24V	-	Preset input terminal	No use	
P00A	Ch2 preset 24V	Ch2 preset 24V	Preset input terminal	Preset input terminal	
P00B	Ch4 preset 24V	-	Preset input terminal	No use	
P00C	Ch5 preset 24V	Ch4 preset 24V	Preset input terminal	Preset input terminal	
P00D	Ch6 preset 24V	-	Preset input terminal	No use	
P00E	Ch7 preset 24V	Ch6 preset 24V	Preset input terminal	Preset input terminal	
P00F	Ch8 preset 24V	-	Preset input terminal	No use	
COM0	Input common	Input common	Input common	Input common	

(2) Interface with external devices

The internal circuit of High-speed counter is as shown below.

(a) "S" type

(a) "S" type		T'1	Si	gnal	ion	On/Off
I/O	Internal circuit	Terminal No.	1-phase	2-phase	Operation	guaranteed voltage
	3.3 kΩ	P00	Ch 0	Ch 0	On	20.4~28.8V
	3.3 K22	1 00	Pulse input	A-phase input	Off	6V or less
		P01	Ch 1	Ch 0	On	20.4~28.8V
		FUI	Pulse input	B-phase input	Off	6V or less
		P02	Ch 2	Ch 2	On	20.4~28.8V
	3.3 kΩ	P02	Pulse input	A-phase input	Off	6V or less
		P03	Ch 3	Ch 2	On	20.4~28.8V
	→ → → → 3.3 kΩ	1 03	Pulse input	B-phase input	Off	6V or less
Input		P04	Ch 0	Ch 0	On	20.4~28.8V
	5.6 kΩ	F 04	Preset input	Preset input	Off	6V or less
		P05	Ch 1		On	20.4~28.8V
	5.6 kΩ 5.6 kΩ	F 03	Preset input	-	Off	6V or less
	· · · · · · · · · · · · · · · · · · ·	P06	Ch 2	Ch 2	On	20.4~28.8V
	5.6 kΩ	. 50	Preset input	Preset input	Off	6V or less
		P07	Ch 2	-	On	20.4~28.8V
	5.6 kΩ	_	Preset input		Off	6V or less
		COM0	COM (inp	ut common)		

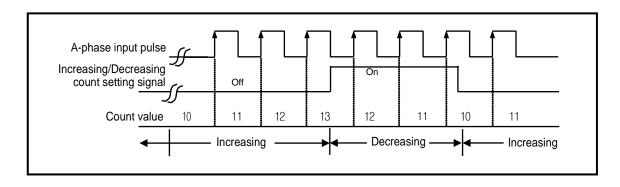
			Si	ignal	C	On/Off
I/O	Internal circuit	Terminal No.	1-phase	2-phase	Operation	guaranteed voltage
		D0000	Ch 0	Ch 0	On	20.4~28.8V
	2.7 kΩ	P0000	Pulse input	A-phase input	Off	6V or less
		P0001	Ch 1	Ch 0	On	20.4~28.8V
	2.7 kΩ	P0001	Pulse input	B-phase input	Off	6V or less
		P0002	Ch 2	Ch 2	On	20.4~28.8V
	2.7 kΩ	P0002	Pulse input	A-phase input	Off	6V or less
		P0003	Ch 3	Ch 2	On	20.4~28.8V
	2.7 kΩ	P0003	Pulse input	B-phase input	Off	6V or less
		P0004	Ch 4	Ch 4	On	20.4~28.8V
	2.7 kΩ	P0004	Pulse input	A-phase input	Off	6V or less
	- ^^^	- P0005	Ch 5	Ch 4	On	20.4~28.8V
		- 20005	Pulse input	B-phase input	Off	6V or less
		D0004	Ch 6	Ch 6	On	20.4~28.8V
	2.7 kΩ	P0006	Pulse input	A-phase input	Off	6V or less
		D0007	Ch 7	Ch 6	On	20.4~28.8V
	2.7 kΩ	P0007	Pulse input	B-phase input	Off	6V or less
Input		D0000	Ch 0	Ch 0	On	20.4~28.8V
	5.6 kΩ	P0008	Preset input	Preset input	Off	6V or less
		D0000	Ch 1		On	20.4~28.8V
	5.6 kΩ	P0009	Preset input	-	Off	6V or less
	- ^^^	D000A	Ch 2	Ch 2	On	20.4~28.8V
	5.6 kΩ	- P000A	Preset input	Preset input	Off	6V or less
		- P000B	Ch 3		On	20.4~28.8V
	5.6 kΩ	PUUUD	Preset input	•	Off	6V or less
		P000C	Ch 4	Ch 4	On	20.4~28.8V
	5.6 kΩ	FUUUL	Preset input	Preset input	Off	6V or less
	- ^^^	- P000D	Ch 5		On	20.4~28.8V
	5.6 kΩ	- F000D	Preset input	<u> </u>	Off	6V or less
	T T	P000E	Ch 6	Ch 6	On	20.4~28.8V
	5.6 kΩ	PUUUE	Preset input	Preset input	Off	6V or less
		P000F	Ch 7		On	20.4~28.8V
	5.6 kΩ	FUUUF	Preset input	<u> </u>	Off	6V or less
		COM0	COM (inp	out common)		

8.1.3 "S" type Functions

- (1) Counter mode
 - A) High Speed counter module can count High Speed pulses which can not be processed by CPU module's counter instructions (CTU, CTD, CTUD, etc.), up to binary value of 32 bits (-2,147,483,648 ~ 2,147,483,647).
 - B) Available input is 1-phase input, 2-phase input and CW/ CCW input.
 - C) Count increasing/decreasing methods are as follows;
 - (1) For 1-phase input: (1) Increasing/decreasing count operation by program setting
 - (2) Increasing/decreasing count operation by B-phase input signal
 - (2) For 2-phase input: setting by difference in phase between A-phase and B-phase
 - (3) For CW/CCW input: Increasing operation if B-phase is LOW with A-phase input, and Decreasing operation if A-phase is LOW with B-phase input.
 - D) Auxiliary modes are as follows;
 - 1 Count Latch
 - 2 Periodic Pulse Count
 - E) Pulse input mode
 - (1) Increasing/decreasing count operation by program setting
 - a) 1-phase 1-input 1-multiplication operation mode
 A-phase input pulse counts at rising and increasing/decreasing will be decided by the applicable program.

Increasing/Decreasing classification	A-phase input pulse rising	A-phase input pulse falling
Increasing/decreasing count setting signal Off	Increasing count	-
Increasing/decreasing count setting signal On	Decreasing count	=

• Operation example

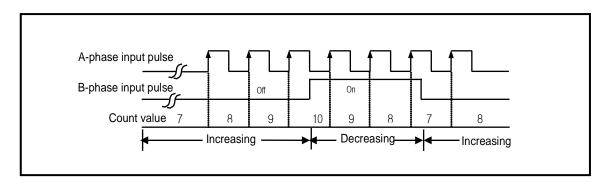


- (2) Increasing/decreasing count operation by B-phase input signal
 - a) 1-phase 2-input 1-multiplication operation mode

A-phase input pulse counts at rising and increasing/decreasing will be decided by B-phase.

Increasing/Decreasing classification	A-phase input pulse rising	A-phase input pulse falling
B-phase input pulse Off	Increasing count	-
B-phase input pulse On	Decreasing count	-

• Operation example

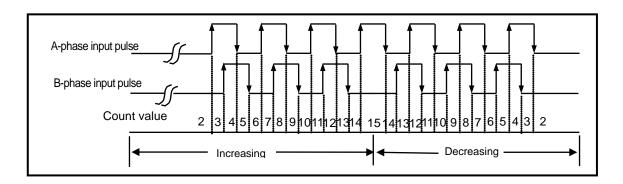


2) 2-phase count mode

a) 2-phase 4-multiplication operation mode

A-phase input pulse and B-phase input pulse count at rising/falling respectively. If A-phase input is antecedent to B-phase input, increasing operation starts, and if B-phase input is antecedent to A-phase input, decreasing operation starts.

Operation example



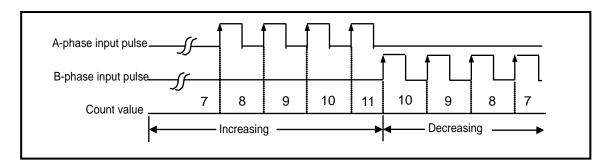
3) CW(Clockwise)/CCW(Counter Clockwise) operation mode

A-phase input pulse counts at rising, or B-phase input pulse counts at rising.

Increasing operation executed when B-phase input pulse is Low with A-phase input pulse at rising, and Decreasing operation executed when A-phase input pulse is Low with B-phase input pulse at rising.

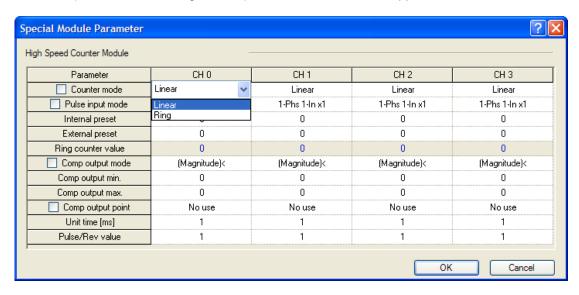
Increasing/Decreasing classification	A-phase input pulse High	A-phase input pulse Low
B-phase input pulse High	-	decreasing count
B-phase input pulse Low	Increasing count	-

Operation example



(2) Counter type

2 types of count (Linear counter, Ring counter) can be selected for the applicable use based on functions.



Counter mode is saved at the following special K area.

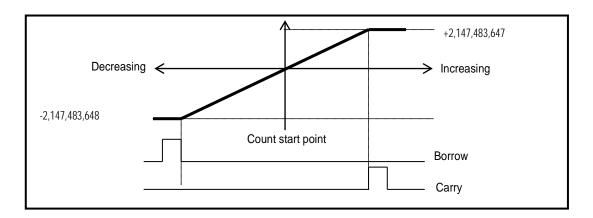
Mode		Reference*1)			
iviode	Ch.0	Ch.1	Ch.2	Ch.3	Reference "
Counter mode	K300	K330	K360	K390	0 : linear 1 : ring

^{*1)} If counter mode is set as value other than 0, 1, error code '20' will occur.

2 types of count can be selected for the applicable use based on functions.

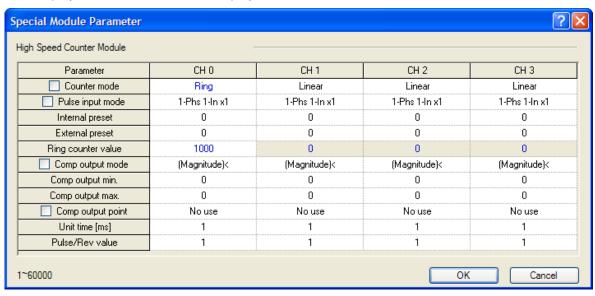
A) Linear counter

- Linear Count range: -2,147,483,648 ~ 2,147,483,647
- If count value reaches the maximum value while increased, Carry will occur, and if count value reaches the minimum value while decreased, Borrow will occur.
- If Carry occurs, count stops and increasing is not available but decreasing is available.
- If Borrow occurs, count stops and decreasing is not available but increasing is available.



B) Ring count

- Ring Count range: user-defined minimum value ~ user-defined maximum value
- Count display: If Ring Counted, user-defined minimum value of Ring Count is counted and displayed, but the value is not displayed.

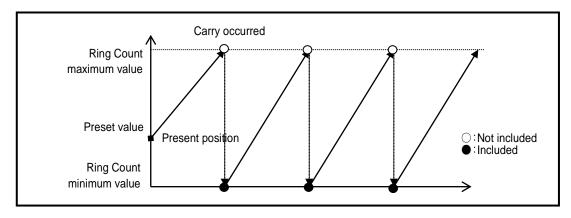


• Ring counter value is saved at the following special K area.

turno	Aı	Reference			
type	Ch.0	Ch.1	Ch.2	Ch.3	Reference
Ring counter value	K310	K340	K270	K400	

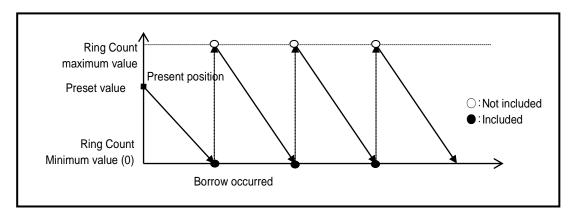
1) During increasing count

■ Even if count value exceeds user-defined maximum value during increasing count, Carry only occurs and count does not stop differently to Linear Count.

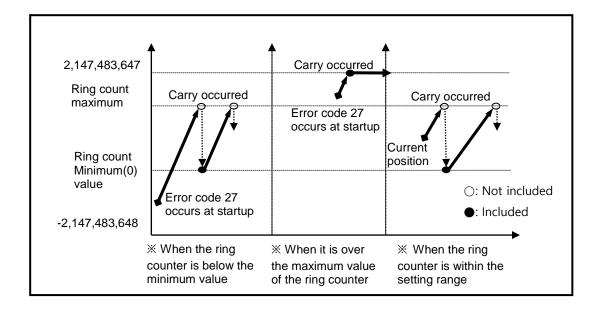


2) During decreasing count

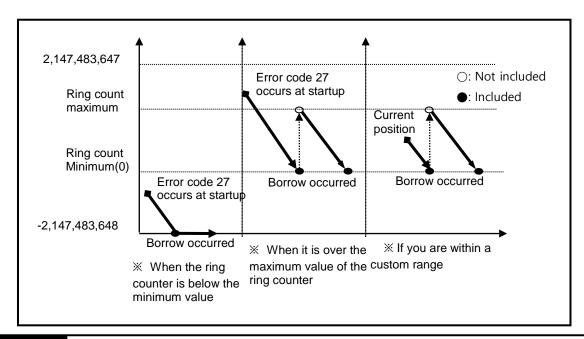
■ Even if count value exceeds user-defined minimum value during decreasing count, Borrow only occurs and count does not stop differently to Linear Count.



- 3) Operation when setting Ring Count based on present count value (during increasing count)
 - When setting the ring count, the current count value is below the minimum value of the ring counter.
 - Opens an error (Code No. 27), operates as a linear counter, and operates as a ring count when the current count value falls within the range of the ring count (error codes are not cleared).
 - When setting the ring count, the current count value is above the maximum value of the ring counter.
 - Displays an error (Code No. 27), operates as a linear counter, and stops counting when the current count value reaches the maximum count value (error code is not cleared).
 - When setting the ring count, the current count value is within the user setting range
 - It starts to increase from the current count value, increases to the maximum value set by the user, then becomes the minimum value set by the user and continues to count after carrying a carry.
 - As shown in the figure below, the maximum value is not displayed and the count continues after displaying the minimum value.



- 4) Operation when setting Ring Count based on present count value (during decreasing count)
 - When setting the ring count, the current count value is below the minimum value of the ring counter.
 - When an error (Code No. 27) is displayed, it operates as a linear counter, and if the current count value falls within the range of the ring count, it operates as a ring count. (The error code is not cleared)
 - When setting the ring count, the current count value is above the maximum value of the link counter.
 - An error (Code No. 27) is displayed, and it operates as a linear counter, but stops counting when the current count value reaches the count minimum value. (The error code is not cleared)
 - When setting the ring count, the current count value is within the user setting range
 - It starts to decrease from the current count value, decreases to the minimum value set by the user, and becomes the maximum value set by the user, and then continues counting after Borrow occurs.

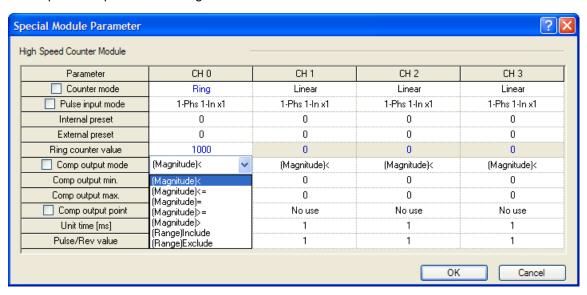


Remark

(1) When using a ring count, be sure to place the count value within the range using a preset or the like.

(3) Compared output

- (a) High Speed counter module has a compared output function used to compare present count value with compared value in size to output as compared.
- (b) Available compared outputs are 2 for 1 channel, which can be used separately.
- (c) Compared output conditions are 7 associated with >, =, < .
- (d) Parameter setting
- Compared output mode setting



■ Upper setting value is saved in special K area.

Compared output condition	Memory address (word)	Value*2)
Present Value < Compared Value		Set to "0"
Present Value ≤ Compared Value		Set to "1"
Present Value = Compared Value	Channel 0 : K302	Set to "2"
Present Value ≥ Compared Value	Channel 1 : K330 Channel 2 : K358	Set to "3"
Present Value > Compared Value	Channel 3 : K386	Set to "4"
Compared value 1 ≤ Count value ≤ Compared value 2		Set to "5"
Count value ≤ Compared value 1, Count value ≥ Compared value 2		Set to "6"

^{*2)} If compared output value not set to 0~6 using counter, error code '23' will be occurred.

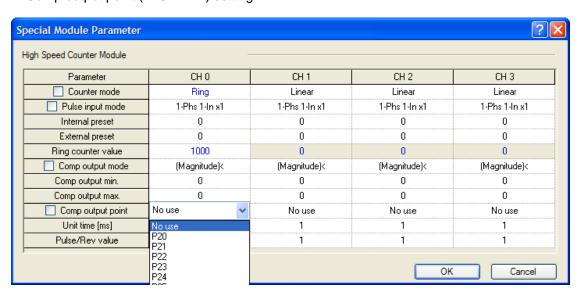
■ In order to make actual comparison enabled after compared output condition set, the compared enable signal is to be On.

Classification	Area per channel				Operation	
Classification	Ch. 0	Ch. 1	Ch. 2	Ch. 3	Operation	
Count enable signal	K2600	K2700	K2800	K2900	0: N/A, 1: enable	
Compared enable signal	K2604	K2704	K2804	K2904	0: forbidden, 1: enable	

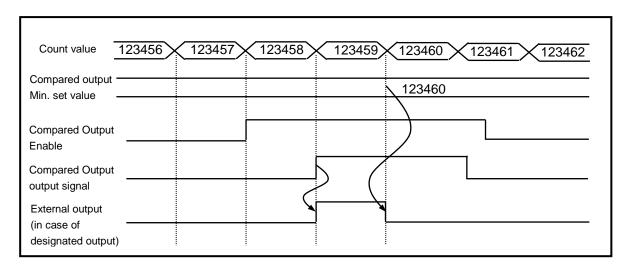
• In order to make external output, the compared equivalent output signal (P20~P27) must be set. If Compared output contact is Off, Compared coincidence output signal (internal device) is only output.

Classification	Area per channel				Operation	
Classification	Ch. 0	Ch. 1	Ch. 2	Ch. 3	Operation	
Compared equivalent output signal	K2612	K2712	K2812	K2912	O: Compared output not equivalent 1: Compared output equivalent	

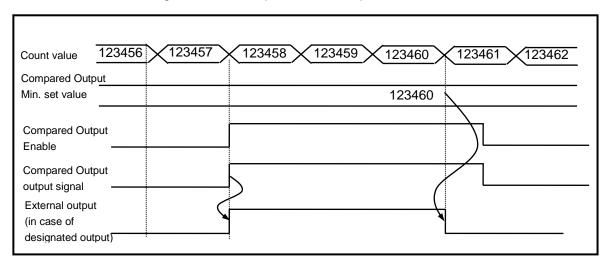
• Comp output point (P20 ~ P27) setting



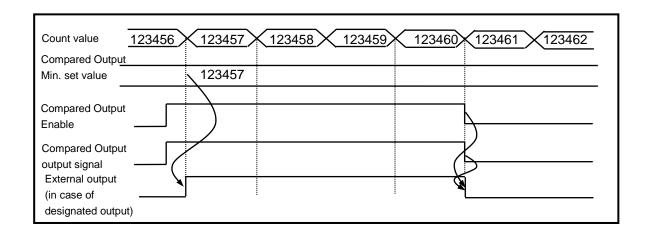
- (e) Detailed description for compared output
 - A) Mode 0 (Present value < Compared value)
 - If counted present value is less than compared value, output is sent out, and if present value increases to be equal to or greater than compared value, output is not sent out.



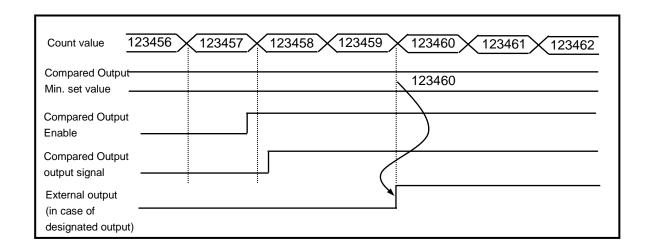
- B) Mode1 (Count value ≤ Compared value)
- If present count value is less than or equal to compared value, output is sent out, and if count value increases to be greater than compared value, output is not sent out.



- C) Mode 2 (Count value = Compared value)
- If present count value is equal to compared value, output is sent out. In order to turn the output Off, Compared output Enable and Compared output signal is to be On.

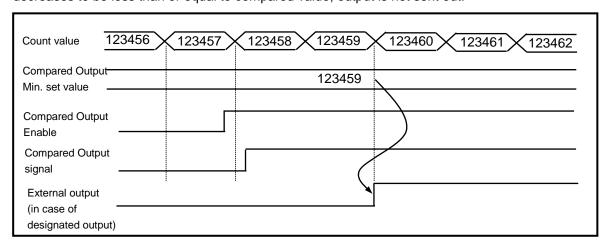


- D) Mode 3 (Count value ≥ Compared value)
- If present count value is greater than or equal to compared value, output is sent out, and if count value decreases to be less than compared value, output is not sent out.



E) Mode 4 (Count value > Compared value)

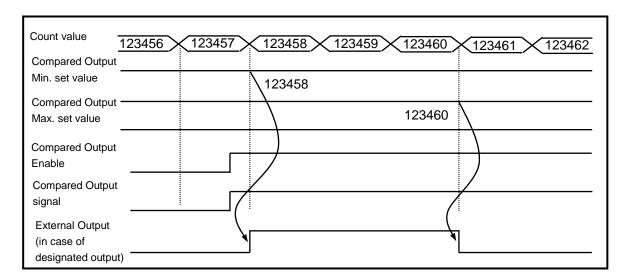
■ If present count value is greater than compared value, output is sent out, and if count value decreases to be less than or equal to compared value, output is not sent out.



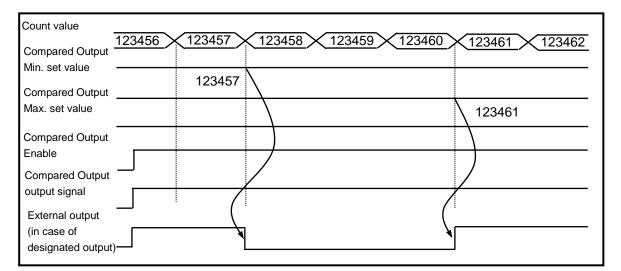
F) Mode 5

(Compared output Min. set value ≤ Count value ≤ Compared output Max. set value)

■ If present count value is greater than or equal to compared output Min. value and less than or equal to compared output Max. set value, output is sent out, and if count value increases/decreases to exceed compared value's range, output is not sent out.



- G) Mode 6 (Count value ≤ Compared output Min. value, Count value ≥ Compared output Max. value)
 - If present count value is less than or equal to compared output Min. value and greater than or equal to compared output Max. value, output is sent out, and if count value increases/decreases to exceed compared value's range, output is not sent out.



(4) Carry signal

- A) Carry signal occurs
- (1) When count range maximum value of 2,147,483,647 is reached during Linear Count.
- (2) When user-defined maximum value of Ring Count changed to the minimum value during Ring Count.
- B) Count when Carry Signal occurs
- (1) Count stops if Carry occurs during Linear Count.
- (2) Count does not stop even if Carry occurs during Ring Count.
- C) Carry reset
 - (1) The Carry generated can be cancelled by Carry/Borrow reset signal On.

Classification	Device area per channel					
	Channel 0	Channel 1	Channel 2	Channel 3		
Carry signal	K2610	K2710	K2810	K2910		

(5) Borrow signal

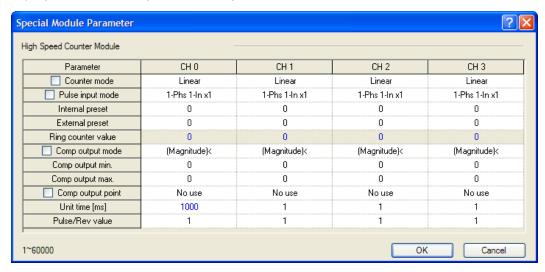
- A) Borrow signal occurs
 - (1) When count range minimum value of -2,147,483,648 is reached during Linear Count.
 - (2) When user-defined minimum value of Ring Count changed to the maximum value during Ring Count.
- B) Count when Borrow signal occurs
- (1) Count stops if Borrow occurs during Linear Count.
- (2) Count does not stop even if Borrow occurs during Ring Count.
- C) Borrow reset
- (1) The Borrow generated can be cancelled by Carry/Borrow reset signal On..

Classification	Device area per channel					
	Channel 0	Channel 1	Channel 2	Channel 3		
Borrow signal	K2611	K2711	K2811	K2911		

(6) Revolution/Unit time

While auxiliary mode enable signal is On, it counts the number of input pulses for a specified time.

- A) Setting
 - (1) Unit time setting
 - 1) Input unit time and pulse number per 1 revolution



Setting value is saved at the following special K are and user can designate it directly.

Classification	Device area per channel				
Classification	Channel 0	Channel 1	Channel 2	Channel 3	
Unit time (1~60000ms)*3)	K322	K352	K382	K412	

^{*3)} If revolution per unit time is enabled and unit time value is other than 1~60000ms, error code '34' occurs.

2) Input pulse number per 1 revolution

Classification	Device area per channel					
Classification	Channel 0	Channel 1	Channel 2	Channel 3		
Pulse number /revolution (1~60000)*4)	K323	K353	K383	K413		

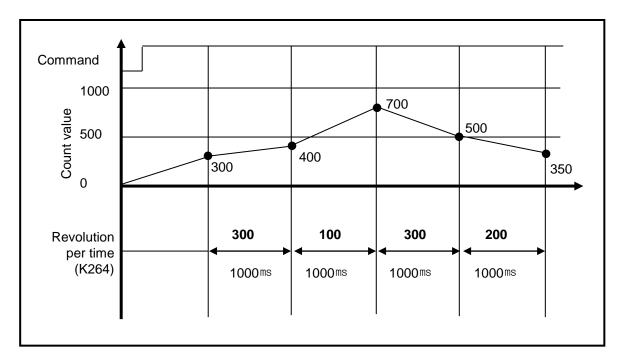
^{*4)} If revolution per unit time is enabled and pulse number/revolution is other than 1~60000, error code '35' occurs.

3) If Count function of revolution per unit time is used, enable signal set by On.

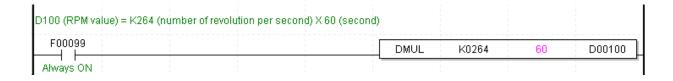
Classification	Device area per channel					
Classification	Channel 0	Channel 1	Channel 2	Channel 3		
Revolution/unit time command	K2605	K2705	K2805	K2905		

B) Count function of Revolution per Unit time is used to count the number of pulses for a specified time while Enable signal is On.

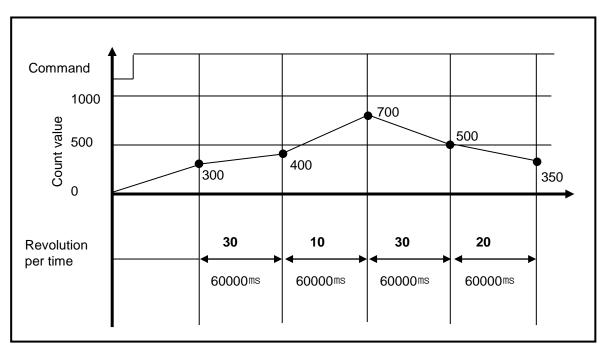
- C) With the displayed number of pulses updated for a specified time and the number of pulses per revolution input, Revolution/Unit time can be counted.
- D) Number of Revolution per 1 second is indicated after number of pulse per 1 revolution is set and time is set to 1 second (1000ms). In order to indicate by Revolutions per minute (RPM), the operation is executed in program.
- E) The example that number of pulse per 1 revolution set to '1' and time is set to 1000 ms is as shown below. (Ch0)



F) In order to indicate revolution per minute (RPM), the program is as shown below. In case of DMUL operation, RPM value is saved 64 bit in D100~D103. If operated RPM value is used, it can use to Word or Dword type according to system (case of RPM value is small number).



G) The example that number of pulse per 1 revolution set to '10' and time is set to 60,000 ms is as shown below.



(7) Count latch

- (a) When Count latch signal is On, present count value is latched.
- (b) Setting

If present counter value is to latch, Count Latch function is set 'Use'.

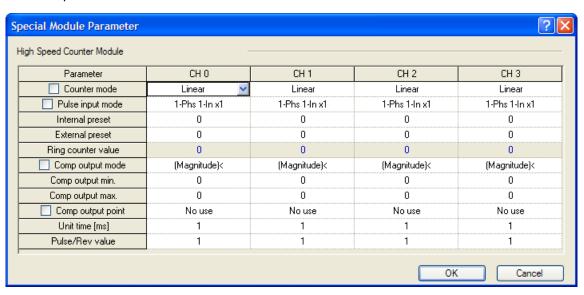
Classification	Device area per channel				
Classification	Channel 0	Channel 1	Channel 2	Channel 3	
Count latch command	K2606	K2706	K2806	K2906	

- Count latch function is operated when Count latch signal is On. Namely, counter value is not cleared when power supply Off =>On and mode change, it is counted from previous value.
- In latch counter function, internal or external preset function has to use for clearing present value.

(8) Preset function

It changes the current value into preset value.

There are two types of preset function, internal preset and external preset. External preset is fixed as input contact point.



• Preset setting value is saved at the following special K area.

Tyroo	Area per each channel (Double word)					
Туре	Ch.0	Ch.1	Ch.2	Ch.3	Ref.	
Internal preset	K304	K334	K364	K394	-	
External preset	K306	K336	K366	K396	-	

• Preset command is specified through the following special K area, external preset is used by executing the designated input contact point after allowance bit is on.

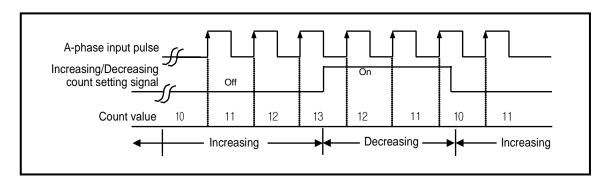
Turo	Area per each channel (Bit)						
Туре	Ch.0	Ch.1	Ch.2	Ch.3	Ref.		
Internal preset command	K2601	K2701	K2801	K2901	-		
External preset allowance	K2602	K2702	K2802	K2902	-		
External preset command	P008	P009	P00A	P00B	-		

8.1.4 "H" type Functions

- (1) Counter mode
 - A) High Speed counter module can count High Speed pulses which can not be processed by CPU module's counter instructions (CTU, CTD, CTUD, etc.), up to binary value of 32 bits (-2,147,483,648 ~ 2,147,483,647).
 - B) Available input is 1-phase input, 2-phase input and CW/ CCW input.
 - C) Count increasing/decreasing methods are as follows;
 - (1) For 1-phase input: (1) Increasing/decreasing count operation by program setting
 - (2) Increasing/decreasing count operation by B-phase input signal
 - (2) For 2-phase input: setting by difference in phase between A-phase and B-phase
 - (3) For CW/CCW input: Increasing operation if B-phase is LOW with A-phase input, and Decreasing operation if A-phase is LOW with B-phase input.
 - D) Auxiliary modes are as follows;
 - 1 Count Latch
 - 2 Count function about the number of revolution per unit time
 - E) Pulse input mode
 - 1) 1 phase count mode
 - A) Increasing/decreasing count operation by program setting
 - a) 1-phase 1-input 1-multiplication operation mode
 A-phase input pulse counts at rising and increasing/decreasing will be decided by the applicable program.

Increasing/Decreasing classification	A-phase input pulse rising	A-phase input pulse falling	
Increasing/decreasing count setting signal Off	Increasing count	-	
Increasing/decreasing count setting signal On	Decreasing count	-	

• Operation example

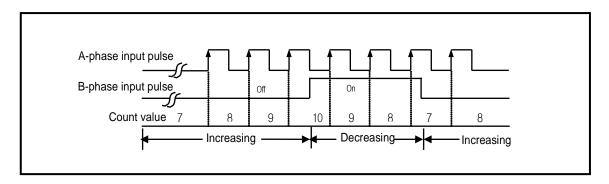


- B) Increasing/decreasing count operation by B-phase input signal
 - b) 1-phase 2-input 1-multiplication operation mode

A-phase input pulse counts at rising and increasing/decreasing will be decided by B-phase.

Increasing/Decreasing classification	A-phase input pulse rising	A-phase input pulse falling		
B-phase input pulse Off	Increasing count	-		
B-phase input pulse On	Decreasing count	-		

• Operation example

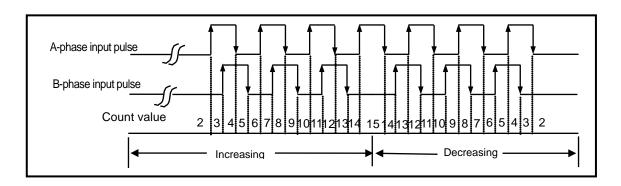


2) 2-phase count mode

a) 2-phase 4-multiplication operation mode

A-phase input pulse and B-phase input pulse count at rising/falling respectively. If A-phase input is antecedent to B-phase input, increasing operation starts, and if B-phase input is antecedent to A-phase input, decreasing operation starts.

Operation example



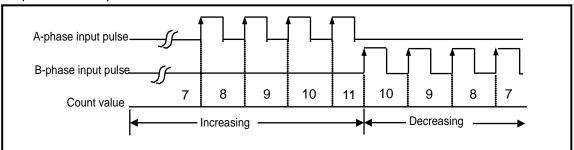
3) CW(Clockwise)/CCW(Counter Clockwise) operation mode

A-phase input pulse counts at rising, or B-phase input pulse counts at rising.

Increasing operation executed when B-phase input pulse is Low with A-phase input pulse at rising, and Decreasing operation executed when A-phase input pulse is Low with B-phase input pulse at rising.

Increasing/Decreasing classification	A-phase input pulse High	A-phase input pulse Low
B-phase input pulse High	-	decreasing count
B-phase input pulse Low	Increasing count	-

Operation example



(2) Counter type

2 types of count (Linear counter, Ring counter) can be selected for the applicable use based on functions.

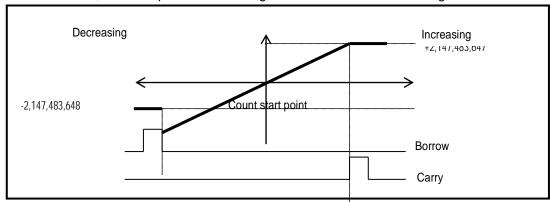
Parameter	CH 4	CH 5	CH 6	CH 7
Counter mode	Linear 🗸	Linear	Linear	Linear
Pulse input mode	Linear	1-Phs 1-In x1	1-Phs 1-In x1	1-Phs 1-In x1
Internal preset	Internal preset Ring 0		0	0
External preset	0	0	0	0
Ring Counter Min. Value	ing Counter Min. Value 0 0		0	0
Ring Counter Max. Value	ox. Value 0 0		0	0
Comp0 output mode	iomp0 output mode (Magnitude)< (Magnitude)< (Ma		(Magnitude)<	(Magnitude)<
Comp1 output mode	mp1 output mode (Magnitude)< (Magnitude)< (Magnitude)		(Magnitude)<	(Magnitude)<
Comparator Output0 Min.Value	stor Output 0 Min. Value 0 0		0	0
Comparator Output0 Max.Value	oarator Output0 Max.Value 0 0		0	0
Comparator Output1 Min.Value	0	0	0	0
Comparator Output1 Max.Value	0	0	0	0
Comp0 output point	No use	No use	No use	No use
Comp1 output point	No use	No use	No use	No use
Unit time [ms]	Unit time [ms] 1 1		1	1
Pulse/Rev value	1	1 1		1

Counter mode is saved at the following special K area.

Mode	Area per each channel (word)						Ref.		
iviode	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Kei.
Counter mode	K300	K330	K360	K390	K2220	K2250	K2280	K2310	0 : linear 1 : ring

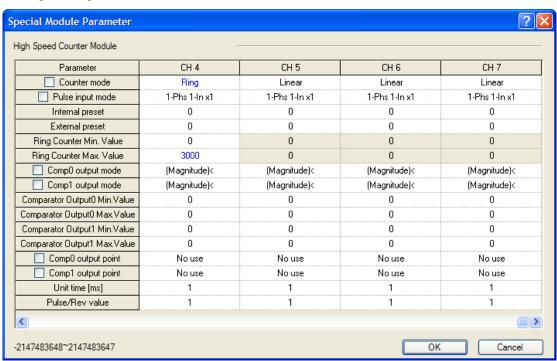
A) Linear counter

- Linear Count range: -2,147,483,648 ~ 2,147,483,647
- If count value reaches the maximum value while increased, Carry will occur, and if count value reaches the minimum value while decreased, Borrow will occur.
- If Carry occurs, count stops and increasing is not available but decreasing is available.
- If Borrow occurs, count stops and decreasing is not available but increasing is available.



B) Ring count

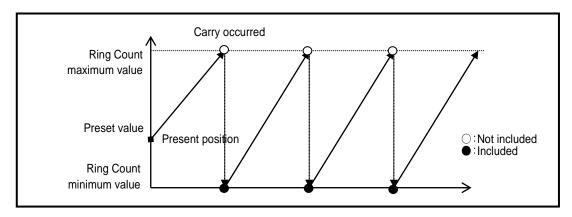
Set Ring Counter Min. Value and Max. value. Preset value and compared set value should be in range of ring counter min. value and max. value.



· Ring counter max. and min value is saved at the following special K area.

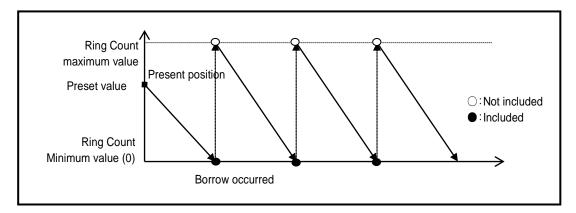
typo	Area per each channel (Double word)									
type	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Ref.	
Ring counter min. value	K308	K338	K368	K398	K2228	K2258	K2288	K2318	-	
Ring counter max. value	K310	K340	K270	K400	K2230	K2260	K2290	K2320	-	

- Range of Ring counter: user defined min. value ~ user defined max. value
- Counter display: in case of using ring counter, user defined max. value is not displayed.
 - a. During increasing count
 - Even if count value exceeds user-defined maximum value during increasing count, Carry only occurs and count does not stop differently to Linear Count.

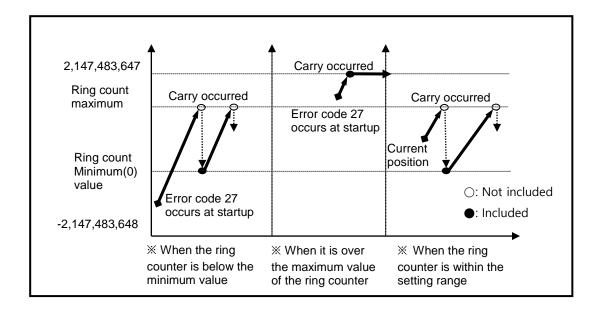


b. During decreasing count

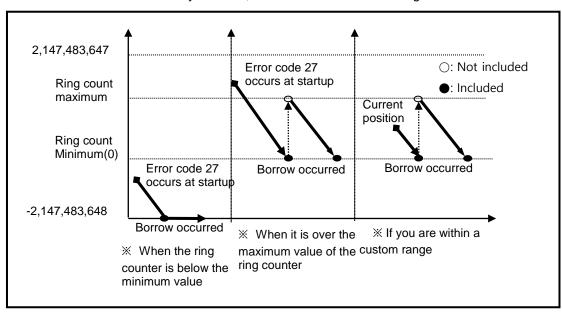
■ Even if count value exceeds user-defined minimum value during decreasing count, Borrow only occurs and count does not stop differently to Linear Count.



- c. Operation when setting Ring Count based on present count value (during increasing count)
- When setting the ring count, the current count value is below the minimum value of the ring counter.
- Opens an error (Code No. 27), operates as a linear counter, and operates as a ring count when the current count value falls within the range of the ring count (error codes are not cleared).
- When setting the ring count, the current count value is above the maximum value of the ring counter.
- Displays an error (Code No. 27), operates as a linear counter, and stops counting when the current count value reaches the maximum count value (error code is not cleared).
- When setting the ring count, the current count value is within the user setting range
- It starts to increase from the current count value, increases to the maximum value set by the user, then becomes the minimum value set by the user and continues to count after carrying a carry.
- As shown in the figure below, the maximum value is not displayed and the count continues after displaying the minimum value.



- d. Operation when setting Ring Count based on present count value (during decreasing count)
 - When setting the ring count, the current count value is below the minimum value of the ring counter.
 - When an error (Code No. 27) is displayed, it operates as a linear counter, and if the current count value falls within the range of the ring count, it operates as a ring count. (The error code is not cleared)
 - When setting the ring count, the current count value is above the maximum value of the link counter.
 - An error (Code No. 27) is displayed, and it operates as a linear counter, but stops counting when the current count value reaches the count minimum value. (The error code is not cleared)
 - When setting the ring count, the current count value is within the user setting range
 - It starts to decrease from the current count value, decreases to the minimum value set by the user, and becomes the maximum value set by the user, and then continues counting after Borrow occurs.

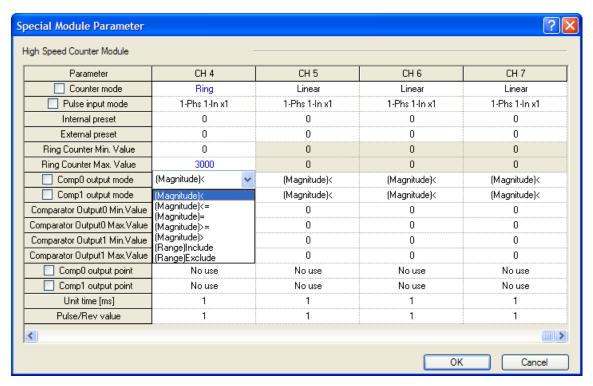


Remark

(1) When using a ring count, be sure to place the count value within the range using a preset or the like.

Compared output

- (a) High Speed counter module has a compared output function used to compare present count value with compared value in size to output as compared.
- (b) Available compared outputs are 2 for 1 channel, which can be used separately.
- (c) Compared output conditions are 7 associated with >, =, < .
- (d) Parameter setting
- Comp. output mode setting



■ Upper setting value is saved in special K area.

Compared output condition	Memory address	(word)	Value* ²⁾	
Compared output condition	Comp output 0	Comp output 1	value -	
Present Value < Compared Value			Set to "0"	
Present Value ≤ Compared Value	Ch.0 K302	Ch.0 K303	Set to "1"	
Present Value = Compared Value	Ch.1 K332 Ch.2 K362	Ch.1 K333 Ch.2 K363	Set to "2"	
Present Value ≥ Compared Value	Ch.3 K392 Ch.4 K2222	Ch.3 K393 Ch.4 K2223	Set to "3"	
Present Value > Compared Value	Ch.5 K2252	Ch.5 K2253	Set to "4"	
Compared value 1 ≤ Count value ≤ Compared value 2	Ch.6 K2282 Ch.7 K2312	Ch.6 K2283 Ch.7 K2313	Set to "5"	
Count value ≤ Compared value 1, Count value ≥ Compared value 2		5	Set to "6"	

^{*2)} If compared output mode set value is other than 0~6 at using counter, error code '23' occurs.

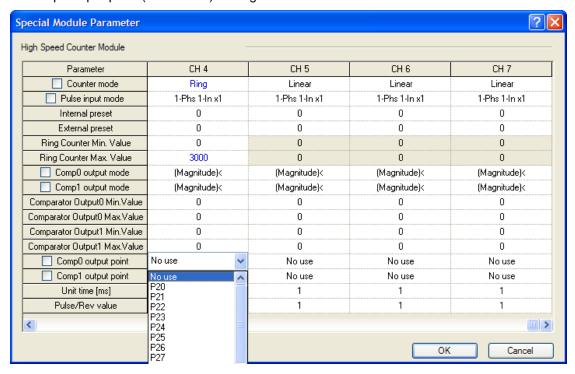
■ In order to output the compared output signal, compared output enable flag set to '1' after compared output condition set.

Classification				Area per	channel				Operation
Classification	Ch. 0	Ch. 1	Ch. 2	Ch. 3	Ch. 4	Ch. 5	Ch. 6	Ch. 7	Operation
Count enable signal	K2600	K2700	K2800	K2900	K21800	K21900	K22000	K22100	0:disable, 1: enable
Compared 0 enable signal	K2604	K2704	K2804	K2904	K21804	K21904	K22004	K22104	0: disable, 1: enable
Compared 1 enable signal	K2607	K2707	K2807	K2907	K21807	K21907	K22007	K22107	0: disable, 1: enable

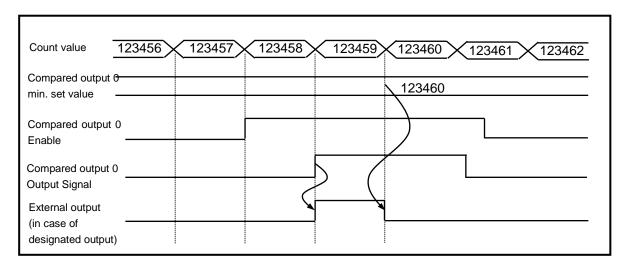
• In order to make external output, the compared coincidence output signal (P20~P2F) must be set.
If Compared output contact is 'Off' at Special Module Parameter Setting of XG5000, Compared coincidence output signal (internal device) is only output.

Classification			Operation					
Classification	Ch. 0	Ch. 1	Ch. 2	Ch.4	Ch.5	Ch. 6	Ch.7	Operation
Compared coincidence	K2612	K2712	K2812	K2912	K21812	K22012	K22112	0: Compared output Off
output signal 0	N2012	N2712	N2012	N2912	K21012	K22012	N22112	1: Compared output On
Compared coincidence	K2613	K2713	K2813	K2913	K21813	K22013	K22113	0: Compared output Off
output signal 1	K2013	K2713	N2013	K2913	K21013	K22013	K22113	1: Compared output On

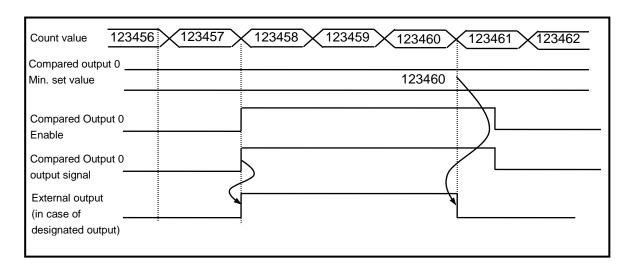
• Comp. output point (P20 ~ P2F) setting



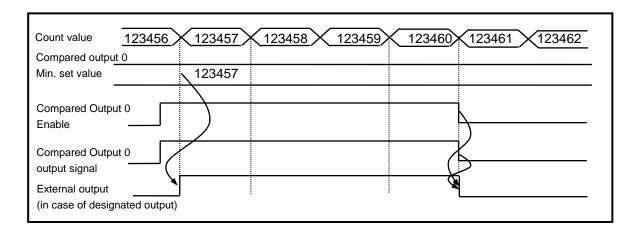
- (e) Detail of comparator output
- It describes detail of comparator output (based on comparator output 0)
- 1) Mode 0 (Present value < Compared value)
 - If counted present value is less than the minimum value of compared output 0, output is sent out, and if present value increases to be equal to or greater than the minimum value of compared output 0, output is not sent out.



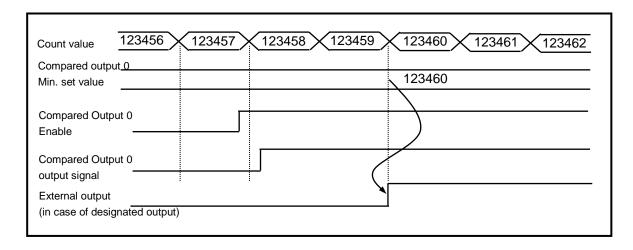
- 2) Mode1 (Count value ≤ Compared value)
 - If present count value is less than or equal to the minimum set value of compared output 0, output is sent out, and if count value increases to be greater than the minimum set value of compared output 0, output is not sent out.



- 3) Mode 2 (Count value = Compared value)
 - If present count value is equal to the minimum set value of compared output 0, output is sent out. In order to turn the output Off, Compared output Enable signal 0 or Compared Coincidence Output Enable signal 0 is to be Off.

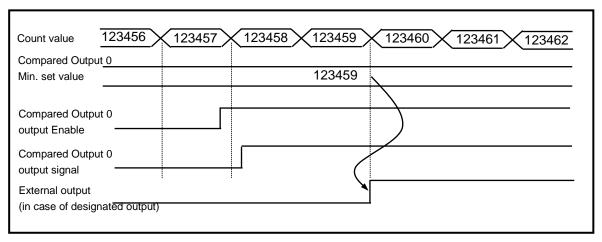


- D) Mode 3 (Count value ≥ Compared value)
- If present count value is greater than or equal to the minimum set value of compared output 0, output is sent out, and if count value decreases to be less than the minimum set value of compared output 0, output is not sent out.



E) Mode 4 (Count value > Compared Output value)

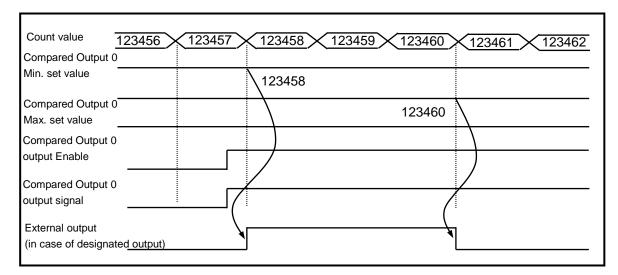
■ If present count value is greater than the minimum set value of compared output 0, output is sent out, and if count value decreases to be less than or equal to the minimum set value of compared output 0, output is not sent out.



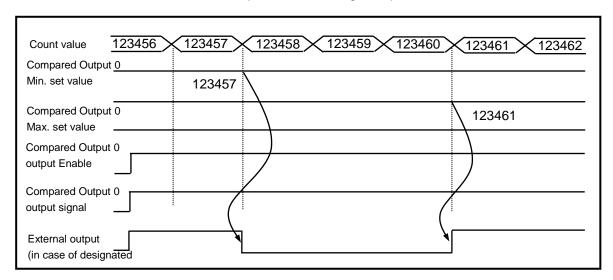
F) Mode 5

(Section comparison: Min. set value of Compared Output 0 ≤ Count value ≤ Max. set value of Compared Output 0)

■ If present count value is greater than or equal to the minimum set value of compared output 0 and less than or equal to the maximum set value of compared output 0, output is sent out, and if count value increases/decreases to exceed compared value's range, output is not sent out.



- G) Mode 6 (Count value ≤ Min. set value of Compared Output 0 or Count value ≥ Max. set value of Compared Output 0)
 - If present count value is less than or equal to the minimum set value of compared 0 and greater than or equal to the maximum set value of compared 0, output is sent out, and if count value increases/decreases to exceed compared value's range, output is not sent out.



Chapter 8 Built-in High-speed Counter Function

(3) 4 Carry signal

- A) Carry signal occurs
- (1) When count range maximum value of 2,147,483,647 is reached during Linear Count.
- (2) When user-defined maximum value of Ring Count changed to the minimum value during Ring Count.
- B) Count when Carry Signal occurs
- (1) Count stops if Carry occurs during Linear Count.
- (2) Count does not stop even if Carry occurs during Ring Count.
- C) Carry reset
 - (1) The Carry generated can be cancelled by Carry/Borrow reset signal On.

Classification	Device area per channel									
Classification	Ch.0	Ch.0 Ch.1 Ch.2 Ch.3 Ch.4 Ch.5 Ch.6 Ch.						Ch.7		
Carry signal	K2610	K2710	K2810	K2910	K21810	K21910	K22010	K22110		

(4) Borrow signal

- A) Borrow signal occurs
 - (1) When count range minimum value of -2,147,483,648 is reached during Linear Count.
 - (2) When user-defined minimum value of Ring Count changed to the maximum value during Ring Count.
- B) Count when Borrow signal occurs
- (1) Count stops if Borrow occurs during Linear Count.
- (2) Count does not stop even if Borrow occurs during Ring Count.
- C) Borrow reset
- (1) The Borrow generated can be cancelled by Carry/Borrow reset signal On.

Classification	Device area per channel									
Classification	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7		
Borrow signal	K2611	K2711	K2811	K2911	K21811	K21911	K22011	K22111		

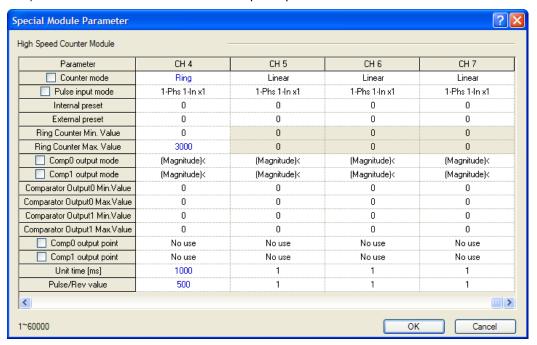
(5) Revolution/Unit time

While the Flag about the number of revolution per unit time is On, it counts the number of input pulses for a specified time.

A) Setting

(1) Unit time setting

1) Set the unit time and the number of pulse per 1 revolution.



Setting value is saved at the following special K area and user can designate directly.

Closs	Class Device per each channel (Word)								
Class	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	range
Unit time	K322	K352	K382	K412	K2242	K2272	K2302	K2332	1~60000ms
Pulse/Rev value	K323	K353	K383	K413	K2243	K2273	K2303	K2333	1~60000

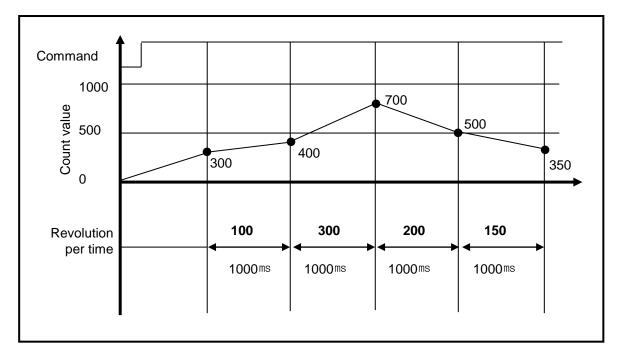
2) In case of using Rev/unit time function, enable the following special K area

Close	Device per each channel (Word)								Operation
Class	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Operation
Rev/unit time command	K2605	K2705	K2805	K2905	K21805	K21905	K22005	K22105	0: disable 1: enable

3) Rev/unit time value is saved at the following special K area.

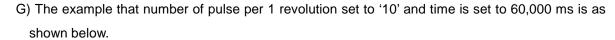
Class		Device per each channel (Word)								
Class	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Ref.	
Rev/unit time	K264	K274	K284	K294	K2184	K2194	K2204	K2214	-	

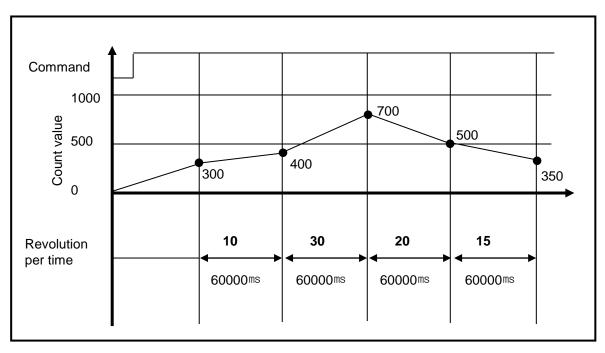
- B) Count function of Revolution/Unit time is used to count the number of pulses for a specified time while auxiliary mode enable signal is On.
- C) With the displayed number of pulses updated for a specified time and the number of pulses per revolution input, Revolution/Unit time can be counted.
- D) Number of Revolution per 1 second is indicated after number of pulse per 1 revolution is set and time is set to 1 second (1000ms). In order to indicate by Revolutions per minute (RPM), the operation is executed in program.
- E) The example that number of pulse per 1 revolution set to '1' and time is set to 1000 ms is as shown below. (Ch0)



F) In order to indicate revolution per minute (RPM), the program is as shown below. In case of DMUL operation, RPM value is saved 64 bit in D100~D103. If operated RPM value is used, it can use to Word or Dword type according to system (case of RPM value is small number).

D100 (RPM value) = K264	(number of revolution pe	er second) X 60 (second	i)			
F00099			DMUL	K0264	60	D00100
Always ON			-			





(6) Count latch

- When Count latch signal is On, present count value is latched.
- Setting

If present counter value is to latch, Count Latch function is set 'Use'.

Class Device area per channel									Operation
Glass	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	o por autori
Count latch	K2606	K2706	K2806	K2906	K21806	K21006	K22006		0: disable
command	N2000	1\2100	112000	112300	K21806	K21906	K22006	K22106	1: enable

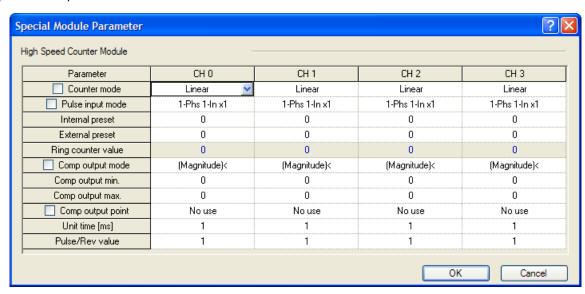
- Count latch function is operated when Count latch signal is On. Namely, counter value is not cleared when power supply Off =>On and mode change, it is counted from previous value.
- In latch counter function, internal or external preset function has to use for clearing present value.

Chapter 8 Built-in High-speed Counter Function

(7) Preset function

It changes the current value into preset value.

There are two types of preset function, internal preset and external preset. External preset is fixed as input contact point.



• Preset setting value is saved at the following special K area.

Turo	Type Area per each channel (Double word)										
туре	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Ref.		
Internal preset value	K304	K334	K364	K394	K2224	K2254	K2284	K2314	_		
External preset value	K306	K336	K366	K396	K2226	K2256	K2286	K2316	_		

• Preset command is specified through the following special K area, external preset is used by executing the designated input contact point after allowance bit is on.

Tuno			Area	per each	channel	(Bit)			Ref.
Type	Ch.0	Ch.1	Ch.2	Ch.3	Ch.4	Ch.5	Ch.6	Ch.7	Kei.
Internal preset command	K2601	K2701	K2801	K2901	K21801	K21901	K22001	K22101	ı
External preset allowance	K2602	K2702	K2802	K2902	K21802	K21902	K22002	K22102	ı
External preset command	P008	P009	POOA	P00B	P00C	POOD	P00E	P00F	-

8.2 Installation and Wiring

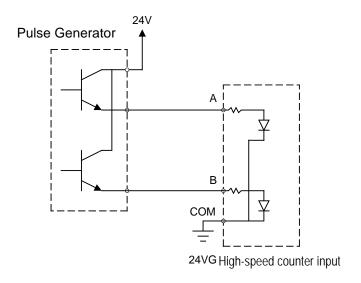
8.2.1 Precaution for wiring

Pay attention to the counteractions against wiring noise especially for High-speed pulse input.

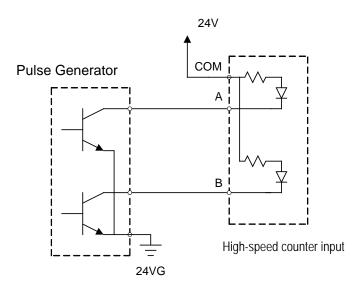
- 1) Surely use twisted pair shielded cable, grounded with 3 class applied.
- 2) Keep away from power cable or I/O line which may cause noise.
- 3) Stabilized power should be used for filter.
 - ► Connect A-phase only for 1-phase input.
 - ► Connect A-phase and B-phase for 2-phase input.

8.2.2 Example of wiring

(1) In case of pulse generator (encoder) is voltage output type



(2) In case of pulse generator is open collector type



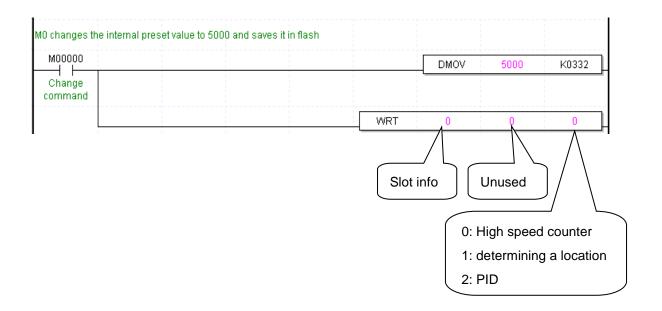
8.3 Internal Memory

8.3.1 Special area for High-speed counter

Parameter and operation command area of built-in high-speed counter use a special K device.

If values set in parameter are changed, it works with the changed values. At the moment, makes sure to use WRT command to save the changed value to flash. If not saved in flash, the changed values with the power off => on and mode changed may not be maintained.

- The following example shows that the internal preset values of CH1 set in parameter are changed by program and saved in flash.
 - Receiving an order command (M000), it moves (MOV) the new internal preset value (5000) to the CH1 present area (K332).
 - To save the changed settings into flash, it uses WRT command. At the moment, slot information is set to '0' in case of built-in function.



Remark

- (1) In case of saving in flash memory using WRT instruction, processing time of about 200~300ms is required.
- (2) Turning off the PLC power while writing to the flash memory or repetitively using the WRT command may damage the flash memory, so be careful when using it.

(1) "S" type

(a) Parameter setting

Parameter		Description	De	vice area	per chan	inel	Remark
Farameter	Value	Setting	Ch 0	Ch 1	Ch 2	Ch 3	Kemark
Counter	h0000	Linear count					
mode	h0001	Ring count	K300	K330	K360	K390	Word
	h0000	1 phase 1 input 1 multiplication					
Pulse input	h0001	1 phase 2 input 1 multiplication	1/204	14004	14004	K391	Word
mode	h0002	CW / CCW	K301	K331	K361		vvora
	h0003	2 phase 4 multiplication					
	h0000	(Magnitude) <					
	h0001	(Magnitude) ≤			K362	K392	
	h0002	(Magnitude) =	K302	K332			
Comp.	h0003	(Magnitude) ≥					Word
Output mode	h0004	(Magnitude) >					
	h0005	(Range) Include					
	h0006	(Range) Exclude					
Internal							
preset value	-2,147,4	83,648 ~ 2,147,483,647	K304	K334	K364	K394	DWord
setting							
External							
preset value	-2,147,4	83,648 ~ 2,147,483,647	K306	K336	K366	K396	DWord
setting							

Doromotor		Description	De	vice area	per chan	inel	Remark
Parameter	Value	Setting	Ch 0	Ch 1	Ch 2	Ch 3	Remark
Ring counter Max. value setting	-2,147,483	,648 ~ 2,147,483,647	K310	K340	K370	K400	DWord
Comp. Output Min. value setting	-2,147,483	,648 ~ 2,147,483,647	K312	K342	K372	K402	DWord
Comp. output Max. value setting	-2,147,483	,648 ~ 2,147,483,647	K314	K344	K374	K404	DWord
Comp. output point designation	HFFFF h0000 h0001 h0002 h0003 h0004 h0005 h0006	P0020 P0021 P0021 P0022 P0022 P0023 P0024 P0025 P0026		K350	K380	K410	Word
Unit time [ms]		1 ~ 60,000	K322	K352	K382	K412	DWord
Pulse/Rev.value		1 ~ 60,000	K323	K353	K383	K413	DWord

(b) Operation command

Dozomotor		Device are	ea per channel	
Parameter	Ch 0	Ch 1	Ch 2	Ch 3
Counter enabling	K2600	K2700	K2800	K2900
Internal preset	K2601	K2701	K2801	K2901
designation of counter	N2001	N2701	K2001	K2901
External preset enabling	K2602	K2702	K2802	K2902
of counter	N2002	N2102	N2002	N2902
Designation of	K2603	K2703	K2803	K2903
decremental counter	N2003	N2703	N2003	N2903
Comp. output enabling	K2604	K2704	K2804	K2904
Enabling of revolution	K2605	K2705	K2805	K2905
time per unit time	N2005	N2705	K2003	N2905
Designation of latch	K2606	K2706	K2806	K2906
counter	NZOOO	N2700	NZOOO	N2300
Carry signal (Bit)	K2610	K2710	K2810	K2910
Borrow signal	K2611	K2711	K2811	K2911
Comp. output signal	K2612	K2712	K2812	K2912

(c) Area of monitoring

Doromotor		Domork			
Parameter	Ch 0	Ch 1	Ch 2	Ch 3	Remark
Current counter value	K262	K272	K282	K292	DWord
Revolution time per unit time	K264	K274	K284	K294	DWord

(2) "H" type

(a) Parameter setting

		Description	De	vice area	per chan	nel	
Parameter	Value	Camira -	Ch 0	Ch 1	Ch 2	Ch 3	Remark
	Value	Setting	Ch 4	Ch 5	Ch 6	Ch 7	
Counter	h0000	Linear count	K300	K330	K360	K390	Word
mode	h0001	Ring count	K2220	K2250	K2280	K2310	vvora
	h0000	1 phase 1 input 1 multiplication	1/2024	1/004	1/004	1/204	Mand.
Pulse input	h0001	1 phase 2 input 1 multiplication	K301	K331	K361	K391	Word
mode setting	h0002	CW / CCW	1/0004	1/0054	1/0004	1/0044	M /I
Setting	h0003	2 phase 4 multiplication	K2221	K2251	K2281	K2311	Word
	h0000	(Magnitude) <					
	h0001	(Magnitude) ≤	14000	K332	1/000	14000	
Comp.	h0002	(Magnitude) =	- K302	NSSZ	K362	K392	
Output 0 mode	h0003	(Magnitude) ≥					Word
setting	h0004	(Magnitude) >					
Journa	h0005	(Range) Include	K2222	K2252	K2282	K2312	
	h0006	(Range) Exclude					
	h0000	(Magnitude) <					
Comp	h0001	(Magnitude) ≤	K303	K333	K363	K393	
Comp. Output 1	h0002	(Magnitude) =	1000	1333	1303	11333	
mode	h0003	(Magnitude) ≥					Word
setting	h0004	(Magnitude) >					
Cotting	h0005	(Range) Include	K2223	K2253	K2283	K2313	
	h0006	(Range) Exclude					
Internal			K304	K334	K364	K394	
preset value setting	-2,147,483	3,648 ~ 2,147,483,647	K2224	K2254	K2284	K2314	DWord
External			K306	K336	K366	K396	
<pre>preset value setting</pre>	-2,147,483	3,648 ~ 2,147,483,647	K2226	K2256	K2286	K2316	DWord

		Description	De	vice area	per chan	inel	
Parameter	Mal .	0.445.	Ch 0	Ch 1	Ch 2	Ch 3	Remark
	Value	Setting	Ch 4	Ch 5	Ch 6	Ch 7	
Ring counter			K308	K338	K368	K398	
min. value	-2,147,483	,648 ~ 2,147,483,645	Kaaaa	KOOEO	1/0000	1/0040	DWord
setting			K2228	K2258	K2288	K2318	
Ring counter			K310	K340	K370	K400	
max. value	-2,147,483	,646 2,147,483,647	K2230	K2260	K2290	K2320	DWord
setting			112230	112200	112230	112320	
Comp. output			K312	K342	K372	K402	
min. value	-2,147,483	,648 ~ 2,147,483,647	K2232	K2262	K2292	K2322	DWord
setting			NZZJZ	N2202	N2292	NZSZZ	
Comp. output			K314	K344	K374	K404	
max. value	-2,147,483	5,648 ~ 2,147,483,647	K2234	K2264	K2294	K2324	DWord
setting			102254	112204	112234	112324	
	HFFFF	No use					
	h0000	P0020					
	h0001	P0021			K380	K410	
	h0002	P0022					
	h0003	P0023	K320	K350			
	h0004	P0024					
	h0005	P0025					
Comp. output 0	h0006	P0026					
point	h0007	P0027					Word
designation	h0008	P0028					
	h0009	P0029					
	h000A	P002A					
	h000B	P002B	K0040	1/0070	1/0000	Kaaaa	
	h000C	P002C	K2240	K2270	K2300	K2330	
	h000D	P002D					
	h000E	P002E					
	h000F	P002F					

		Description	De	vice area	per chan	inel	
Parameter	Value	Catting	Ch 0	Ch 1	Ch 2	Ch 3	Remark
	value	Setting	Ch 4	Ch 5	Ch 6	Ch 7	
	HFFFF	No use					
	h0000	P0020					
	h0001	P0021					
	h0002	P0022					
	h0003	P0023	K321	K351	K381	K411	
	h0004	P0024					
	h0005	P0025					
Comp. output 1	h0006	P0026					
point	h0007	P0027					Word
designation	gnation h0008 P0028						
	h0009	P0029		140074			
	h000A	P002A			160004		
	h000B	P002B	1/00/44			1/0004	
	h000C	P002C	K2241	K2271	K2301	K2331	
	h000D	P002D					
	h000E	P002E					
	h000F	P002F					
Unit time [ms]	1 ~ 60,000 ms		K322	K352	K382	K412	Word
Unit time [ms]			K2242	K2272	K2302	K2332	vvoid
Pulse/Rev.value	1 ~ 60,000		K323	K353	K383	K413	Word
r uise/Nev.value		1 ~ 00,000	K2243	K2273	K2303	K2333	vvoiu

(b) Operation command

Danamatan			Dev	ice area	per char	nnel		
Parameter	Ch 0	Ch 1	Ch 2	Ch 3	Ch 4	Ch 5	Ch 6	Ch 7
Counter enabling	K2600	K2700	K2800	K2900	K21800	K21900	K22000	K22100
Internal preset designation of counter	K2601	K2701	K2801	K2901	K21801	K21901	K22001	K22101
External preset enabling of counter	K2602	K2702	K2802	K2902	K21802	K21902	K22002	K22102
Designation of decremental counter	K2603	K2703	K2803	K2903	K21803	K21903	K22003	K22103
Comp. output 0 enabling	K2604	K2704	K2804	K2904	K21804	K21904	K22004	K22104
Comp. output 1 enabling	K2607	K2707	K2807	K2907	K21807	K21907	K22007	K22107
Enabling of revolution time per unit time	K2605	K2705	K2805	K2905	K21805	K21905	K22005	K22105
Designation of latch counter	K2606	K2706	K2806	K2906	K21806	K21906	K22006	K22100
Carry signal (Bit)	K2610	K2710	K2810	K29100	K21810	K21910	K22010	K22110
Borrow signal	K2611	K2711	K2811	K29101	K21811	K21911	K22011	K22111
Comp. output 0 signal	K2612	K2712	K2812	K29102	K21812	K21912	K22012	K22112
Comp. output 1 signal	K2613	K2713	K2813	K29103	K21813	K21913	K22013	K22113

(c) Area of monitoring

D	Device area per channel								
Parameter	Ch 0	Ch 1	Ch 2	Ch 3	Ch 4	Ch 5	Ch 6	Ch 7	
Current counter value	K262	K272	K282	K292	K2182	K2192	K2202	K2212	
Revolution per unit time	K264	K274	K284	K294	K2184	K2194	K2204	K2214	

8.3.2 Error code

It describes errors of the built-in high-speed counter.

• Error occurred is saved in the following area.

Cotogory	Device area per channel								
Category	Ch0	Ch1	Ch2	Ch3	Ch4	Ch5	Ch6	Ch7	Remark
Error code	K266	K276	K286	K296	K2186	K2196	K2206	K2216	Word

Error codes and descriptions

Error code (Decimal)	Description	Remark
20	Counter type is set out of range	
21	Pulse input type is set out of range	
22	Requesting #1(3,5,7)channel Run during the 2-phase operation of #0(2,4,6) * During #0(2,4,6) channel 2-phase operation, using #1(3,5,7)channel is not possible.	
23	Compared output type setting is set out of range.	
25	Internal preset value is set out of counter range	
26	External present value is set out of counter range	
27	Ring counter setting is set out of range * Note ring counter setting should be 2 and more.	
28	Compared output min. value is set out of permissible max. input range	
29	Compared output max. value is set out of permissible max. input range	
30	Error of Compared output min. value>Compared output max. value	
31	Output point designation value of Compared output is set out of range	
34	Set value of Unit time is out of the range	
35	Pulse value per 1 revolution is set out of range	
36	Compared output min. value is set out of permissible max. input range (Compared output 1)	"H" type
37	Compared output max. value is set out of permissible max. input range (Compared output 1)	"H" type
38	Error of Compared output min. value>Compared output max. value (Compared output 1)	"H" type
39	Output point designation value of Compared output is set out of range (Compared output 1)	"H" type

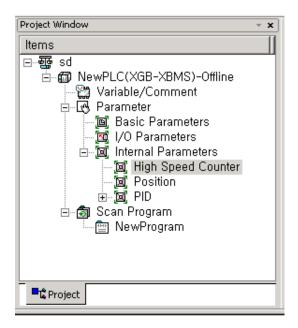
Remark

• If two and more errors occur, the module saves the latter error code and removes the former one.

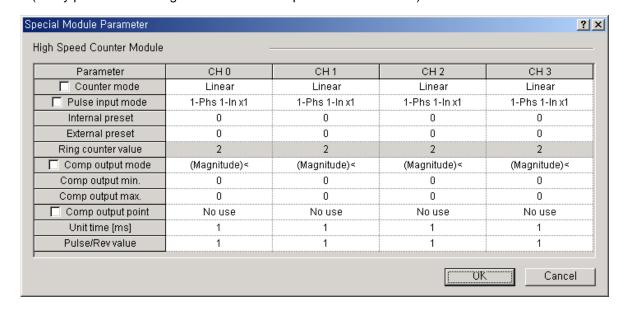
8.4 Examples: Using High-speed Counter

It describes examples of using high-speed counter.

- Setting high-speed counter parameter
 How to set types of parameters to operate a high-speed counter is described as follows.
 - A) Set 『Internal Parameters』 in the basic project window.



B) Selecting high-speed counter opens a window to set high-speed counter parameters as follows. For details regarding each parameter setting, refer to 8.1~8.3. (Every parameter settings are saved in the special K device area.)

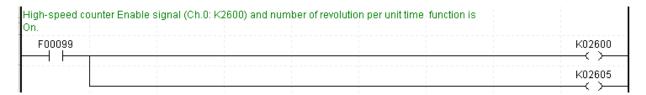


Chapter 8 Built-in High-speed Counter Function

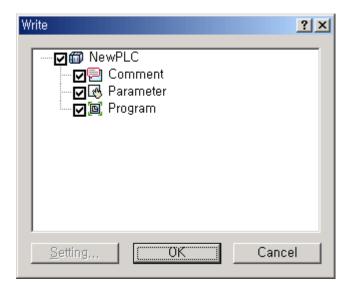
C) Turn 'ON' the high-speed counter Enable signal (CH0:K2600) in the program.



- D) To use additional functions of the high-speed counter, you needs to turn on the flag allowing an operation command.
 - * Refer to 2. Operation Command, <8.3.1 Special K Area for High-speed Counter> For instance, turn on 2605 bit if among additional functions, rotation number function is used.



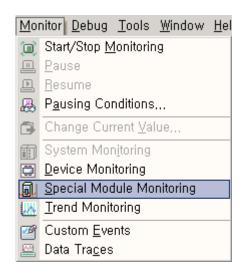
E) Upon the setting, download program and parameter to PLC.

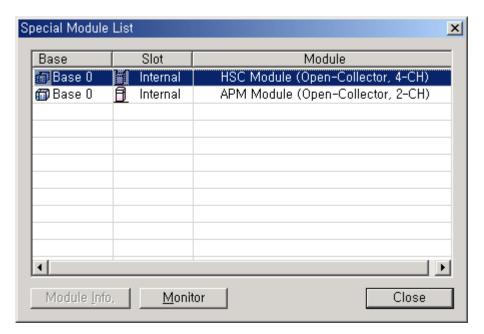


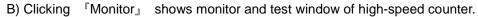
2) Monitoring and setting command

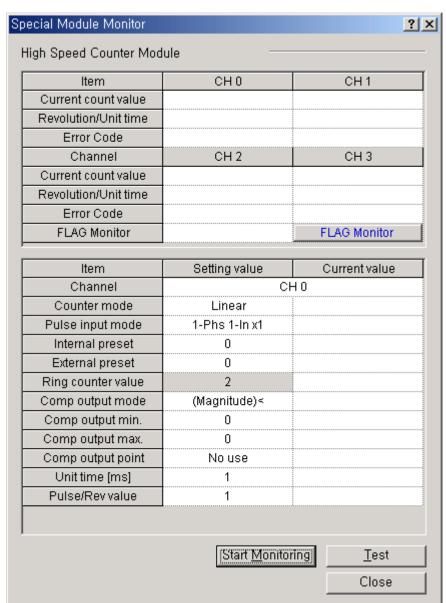
Monitoring and command setting of high-speed counter are described as follows.

A) If starting a monitor and clicking a Special Module Monitor, the following window is opened.



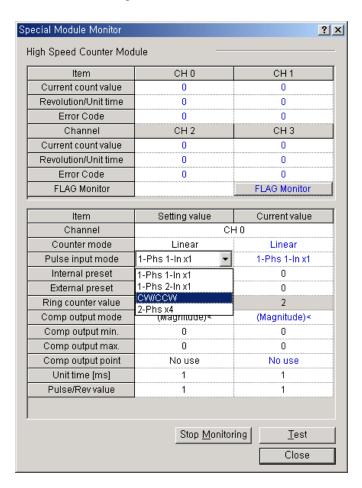




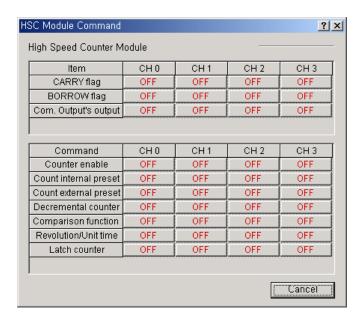


Item	Description
FLAG Monitor	Show flag monitoring and command window of high-speed counter
Start Monitoring	Start monitoring each item (special K device area monitor).
Test	Write each item setting to PLC. (Write the setting to special K device)
Close	Close monitor

C) Clicking "Start Monitoring_ shows the high-speed counter monitor display, in which you may set each parameter. At this moment, if any, changed values are not saved if power off=> on or mode is changed.



D) Clicking FLAG Monitor shows the monitor of each flag in high-speed counter, in which you may direct operation commands by flags (clicking commands reverse turn).



Chapter 9 Installation and Wiring

9.1 Safety Instruction

🔼 Danger

- ▶ Please design protection circuit at the external of PLC for entire system to operate safely because an abnormal output or an malfunction may cause accident when any error of external power or malfunction of PLC module.
 - (1) It should be installed at the external side of PLC to emergency stop circuit, protection circuit, interlock circuit of opposition action such as forward /reverse operation and interlock circuit for protecting machine damage such as upper/lower limit of positioning.
 - (2) If PLC detects the following error, all operation stops and all output is off.
 - (Available to hold output according to parameter setting)
 - (a) When over current protection equipment or over voltage protection operates
 - (b) When self diagnosis function error such as WDT error in PLC CPU occurs
- In case of error about IO control part that is not detected by PLC CPU, all output is off.
 Design Fail Safe circuit at the external of PLC for machine to operate safely. Refer to 9.1.1 Fail Safe circuit.
 - (1) Because of error of output device, Relay, TR, etc., output may not be normal. About output signal that may cause the heavy accident, design supervisory circuit to external.
- In case load current more than rating or over current by load short flows continuously, danger of heat, fire may occur so design safety circuit to external such as fuse.
- ▶ Design for external power supply to be done first after PLC power supply is done. If external power supply is done first, it may cause accident by misoutput, misoperation.
- ▶ In case communication error occurs, for operation status of each station, refer to each communication manual.
- ▶ In case of controlling the PLC while peripheral is connected to CPU module, configure the interlock circuit for system to operate safely. During operation, in case of executing program change, operation status change, familiarize the manual and check the safety status. Especially, in case of controlling long distance PLC, user may not response to error of PLC promptly because of communication error or etc.
 - Limit how to take action in case of data communication error between PLC CPU and external device adding installing interlock circuit at the PLC program.

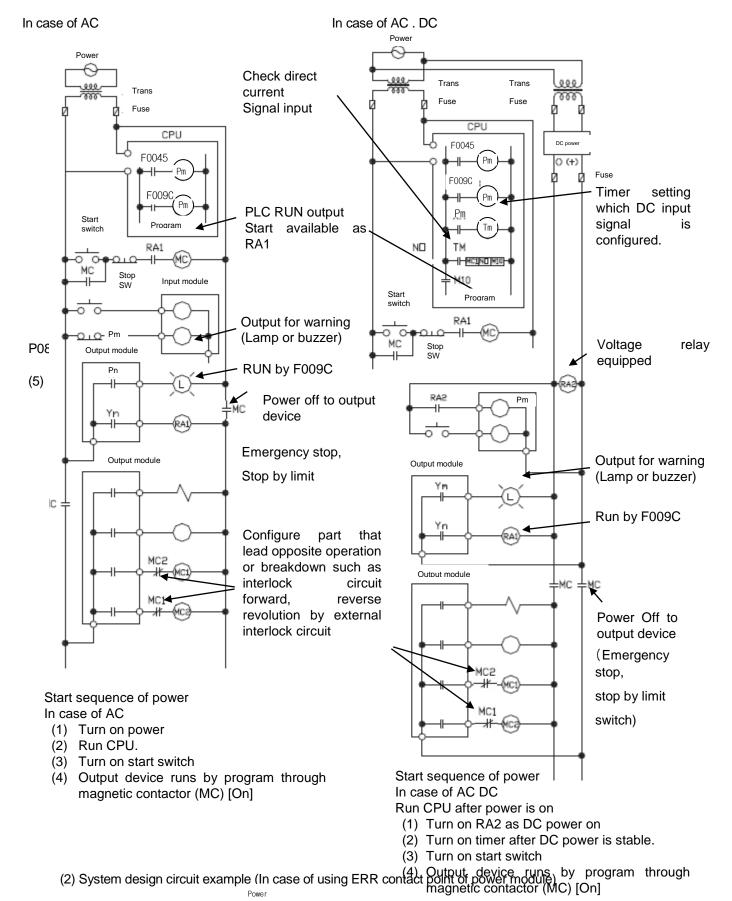
Or in case of external power error or PLC error, it may cause the malfunction.

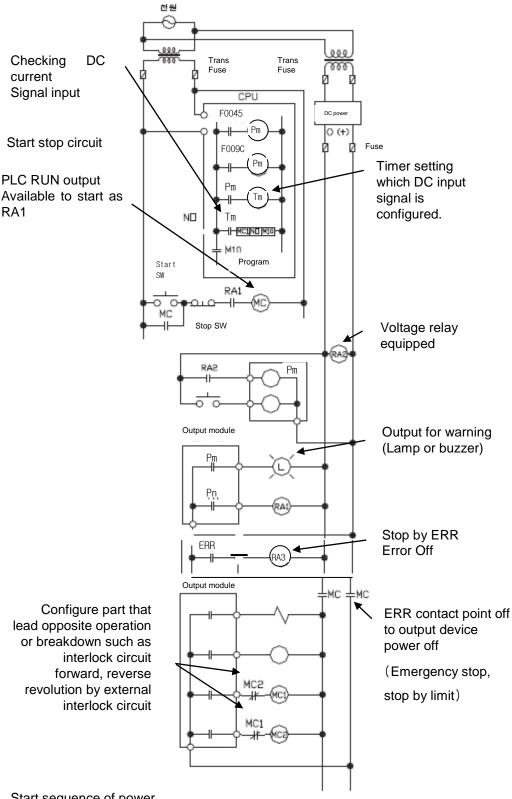
Danger

- ▶ Don't close the control line or communication cable to main circuit or power line. Distance should be more than 100mm. It may cause malfunction by noise.
- In case of controlling lamp load, heater, solenoid valve, etc. in case of Off -> On, large current (10 times of normal current) may flows, so consider changing the module to module that has margin at rated current.
- Process output may not work properly according to difference of delay of PLC main power and external power for process (especially DC in case of PLC power On-Off and of start time.
 For example, in case of turning on PLC main power after supplying external power for process, DC output module may malfunction when PLC is on, so configure the circuit to turn on the PLC main power first
- ▶ Not to lead above error to entire system, part causing breakdown of machine or accident should be configured at the external of PLC

9.1.1 Fail safe circuit

(1) example of system design (In case of not using ERR contact point of power module)





Start sequence of power In case of AC DC

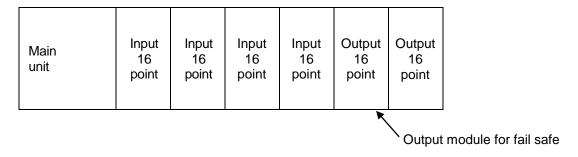
- (1) Run CPU after turning on power.
- (2) Turn on RA2 with DC power supplied
- (3) Turn on timer after DC power is stable
- (4) Turn on start switch Output device runs by program through magnetic contactor (MC) [On]

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(3) Fail safe countermeasure in case of PLC error

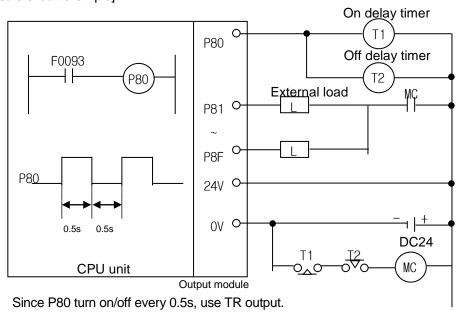
Error of PLC CPU and memory is detected by self diagnosis but in case error occurs in IO control part, etc., CPU can detect the error. At this case, though it is different according to status of error, all contact point is on or off, so safety may not be guaranteed. Though we do out best to our quality as producer, configure safety circuit preparing that error occurs in PLC and it lead to breakdown or accident.

System example



Equip output module for fail safe to last slot of system.

[Fail safe circuit example]



9.1.2 PLC heat calculation

- (1) Power consumption of each part
 - (a) Power consumption of module

The power conversion efficiency of power module is about 70% and the other 30% is gone with heat; 3/7 of the output power is the pure power consumption. Therefore, the calculation is as follows.

• $W_{pw} = 3/7 \{(I_{5} \lor X_{5}) + (I_{24} \lor X_{24})\} (W)$

15v: power consumption of each module DC5V circuit(internal current consumption)

l₂₄v: the average current consumption of DC24V used for output module

(current consumption of simultaneous On point)

If DC24V is externally supplied or a power module without DC24V is used, it is not applicable.

(b) Sum of DC5V circuit current consumption

The DC5V output circuit power of the power module is the sum of power consumption used by each module.

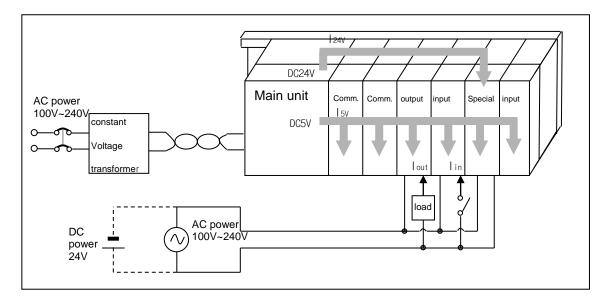
- $W_{5V} = I_{5V} X 5 (W)$
- (c) DC24V average power consumption(power consumption of simultaneous On point)

The DC24V output circuit's average power of the power module is the sum of power consumption used by each module.

- W24V = I24V X 24 (W)
- (d) Average power consumption by output voltage drop of the output module(power consumption of simultaneous On point)
 - Wout = lout X Vdrop X output point X simultaneous On rate (W)

lout: output current (actually used current) (A)

Vdrop: voltage drop of each output module (V)



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- (e) Input average power consumption of input module (power consumption of simultaneous On point)
 - W_{in} = l_{in} X E X input point X simultaneous On rate (W) l_{in}: input current (root mean square value in case of AC) (A) E: input voltage (actually used voltage) (V)
- (f) Power consumption of special module power assembly
 - Ws = I₅ \vee X 5 + I₂₄ \vee X 24 + I₁₀₀ \vee X 100 (W)

The sum of power consumption calculated by each block is the power consumption of the entire PLC system.

• $W = W_{PW} + W_{5V} + W_{24V} + W_{out} + W_{in} + W_{s} (W)$

Calculate the heats according to the entire power consumption(W) and review the temperature increase within the control panel.

The calculation of temperature rise within the control panel is displayed as follows.

 $T = W / UA [^{\circ}C]$

W: power consumption of the entire PLC system (the above calculated value)

A: surface area of control panel [m²]

U: if equalizing the temperature of the control panel by using a fan and others - - - 6

If the air inside the panel is not ventilated - - - - - 4

If installing the PLC in an air-tight control panel, it needs heat-protective(control) design considering the heat from the PLC as well as other devices. If ventilating by vent or fan, inflow of dust or gas may affect the performance of the PLC system.

9.2 Attachment/Detachment of Modules

9.2.1 Attachment/Detachment of modules

Caution in handling

Use PLC in the range of general specification specified by manual.

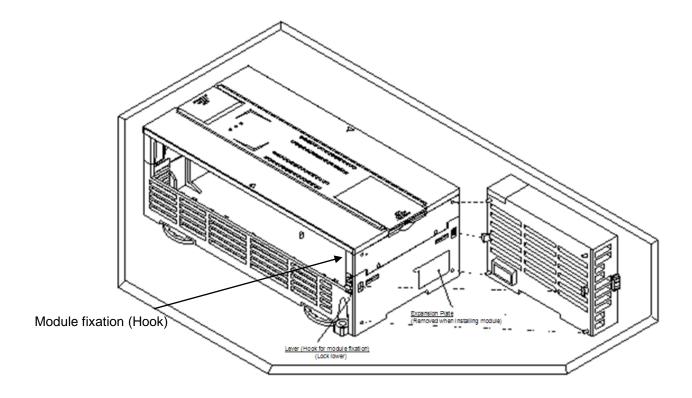
In case of using out of range, it may cause electric shock, fire, malfunction, damage of product.

Warning

- ▶ Module must be mounted to hook for fixation properly before its fixation. The module may be damaged from over-applied force. If module is not mounted properly, it may cause malfunction.
- ▶ Do not drop or impact the module case, terminal block connector.
- ▶ Do not separate the PCB from case.

(1) Equipment of module

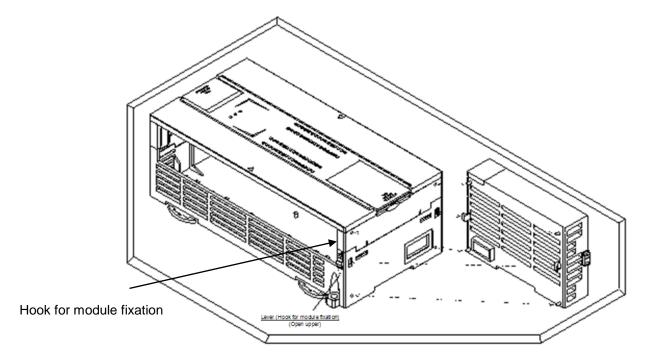
- Eliminate the extension cover at the upper of module.
- Push the module and connect it in agreement with hook for fixation of four edges and hook for connection at the bottom.
- After connection, get down the hook for fixation at the upper part and lower part and fix it completely.



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(2) Detachment of module

- Get up the hook for fixation of upper part and lower part and disconnect it.
- Detach the module with two hands. (Don't force over-applied force.)



Caution

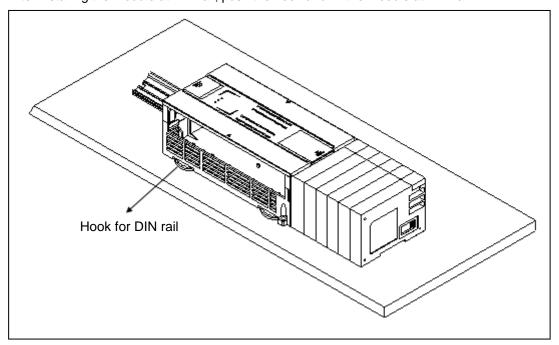
▶ When separating module, don't force over-applied power. If so, hook may be damaged.

(3) Installation of module

XGB PLC main unit and expansion unit are having the hook for DIN rail (rail width 35mm). So they can be installed at DIN rail.

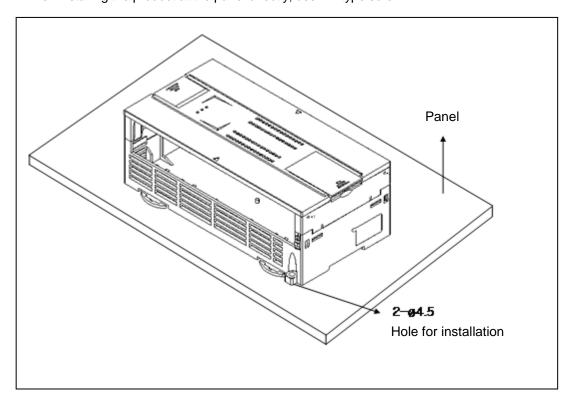
(a) In case of installing at DIN rail

- Pull out the hook for DIN rail in the bottom of module and install the module at DIN rail.
- After installing the module at DIN rail, push the hook and fix the module at DIN rail.



(b) In case of installing at the panel

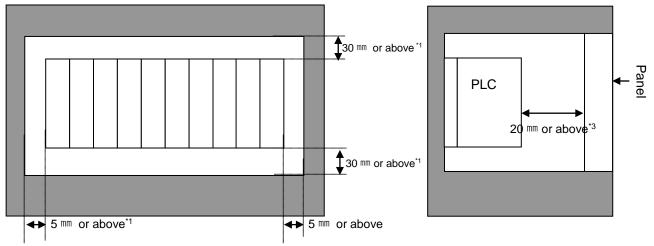
- You can install the XGB compact type main unit at the panel directly by using screw hole.
- When installing the product at the panel directly, use M4 type screw



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(4) Module equipment location

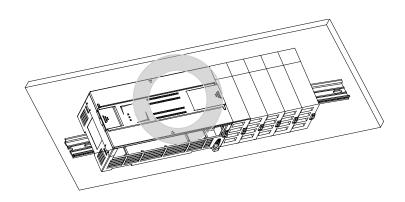
Keep the following distance between module and structure or part for well ventilation and easy detachment and attachment.



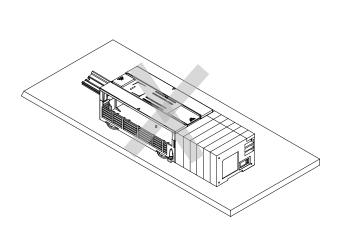
- *1 : In case height of wiring duct is less than 50 mm (except this 40mm or above)
- *2: In case of equipping cable without removing near module, 20mm or above
- *3: In case of connector type, 80mm or above

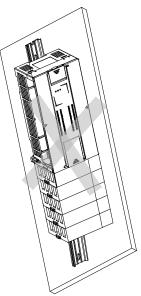
(5) Module equipment direction

(a) For easy ventilation, install like the following figure.



(b) Don't install like the following figure

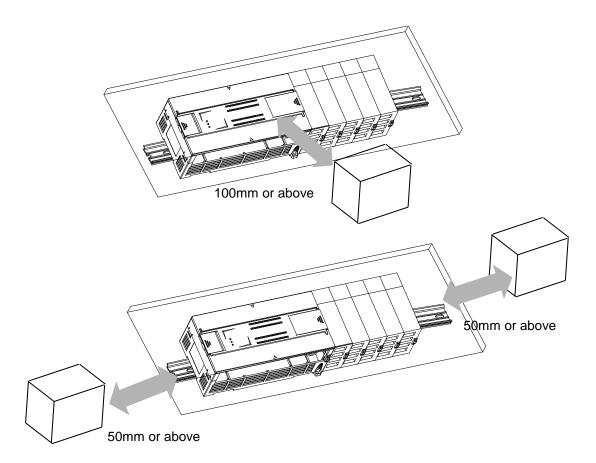




(6) Distance with other device

To avoid radiation noise or heat, keep the distance between PLC and device (connector and relay) as far as the following figure.

Device installed in front of PLC: 100 mm or above Device installed beside PLC: 50 mm or above



9.2.2 Caution in handling

Here describes caution from open to install

- Don't drop or impact product.
- Don't disassemble the PCB from case. It may cause the error.
- In case of wiring, make sure foreign substance not to enter upper part of module. If it enters, eliminate it.

(1) Caution in handling IO module

It describes caution in handling IO module.

(a) Recheck of IO module specification

For input module, be cautious about input voltage, for output module, if voltage that exceeds the max. open/close voltage is induced, it may cause the malfunction, breakdown or fire.

(b) Used wire

When selecting wire, consider ambient temp, allowed current and minimum size of wire is AWG22(0.3mm²) or above.

(c) Environment

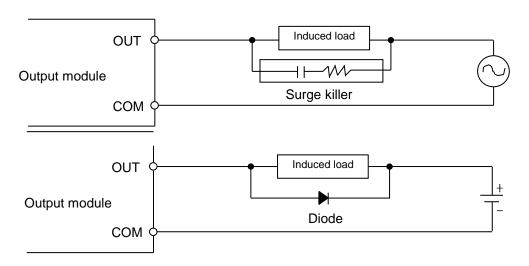
In case of wiring IO module, if device or material that induce high heat is too close or oil contacts wire too long time, it may cause short, malfunction or error.

(d) Polarity

Before supplying power of module which has terminal block, check the polarity.

(e) Wiring

- In case of wiring IO with high voltage line or power line, induced obstacle may cause error.
- Let no cable pass the IO operation indication part (LED). (You can't discriminate the IO indication.)
- In case induced load is connected with output module, connect the surge killer or diode load to load in parallel. Connect cathode of diode to + side of power.



(f) Terminal block

Check close adhesion status. Let no foreign material of wire enter into PLC when wring terminal block or processing screw hole. At this case, it may cause malfunction.

(g) Don't impact to IO module or don't disassemble the PCB from case.

9.3 Wire

In case using system, it describes caution about wiring.



Danger

- ▶ When wiring, cut off the external power.
- ▶ If all power is cut, it may cause electric shock or damage of product.
- ▶ In case of flowing electric or testing after wiring, equip terminal cover included in product. It not, it may cause electric shock.

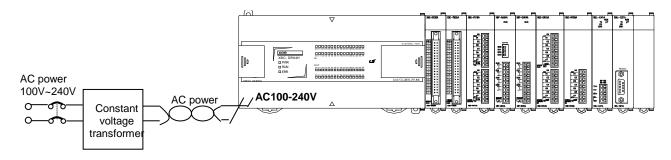
<u>/!\</u>

Caution

- ▶ Do D type ground (type 3 ground) or above dedicated for PLC for FG and LG terminal. It may cause electric shock or malfunction.
- ▶ When wiring module, check the rated voltage and terminal array and do properly. If rating is different, it may cause fire, malfunction.
- ▶ For external connecting connector, use designated device and solder. If connecting is not safe, it may cause short, fire, malfunction.
- ▶ For screwing, use designated torque range. If it is not fit, it may cause short, fire, malfunction.
- Let no foreign material enter such as garbage or disconnection part into module. It may cause fire, malfunction, error.

9.3.1 Power wiring

(1) In case voltage regulation is larger than specified, connect constant voltage transformer.

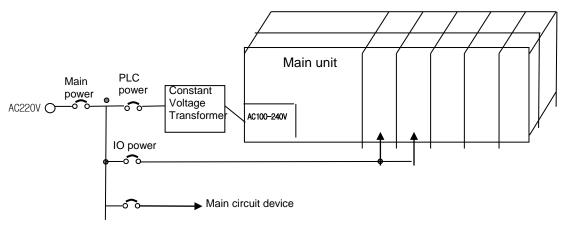


(2) Connect noise that include small noise between line and earth.

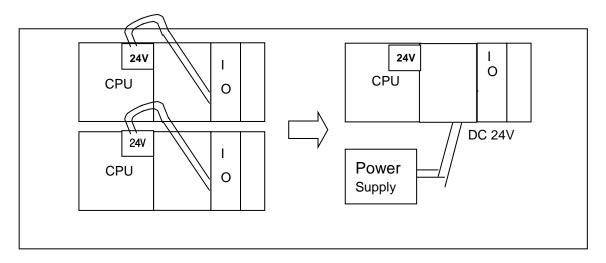
(When there are many noise, connect insulated transformer.)

Chapter 9. Installation and Wiring

(3) Isolate the PLC power, I/O devices and power devices as follows.

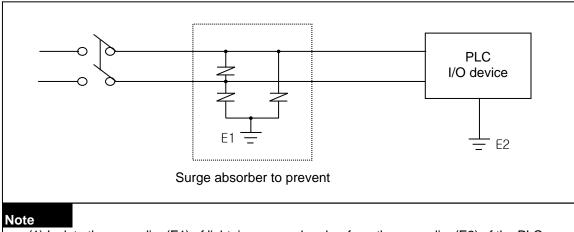


- (4) If using DC24V of the power module
 - (a) Do not connect DC24V of several power modules in parallel. It may cause the destruction of a module.
 - (b) If a power module can not meet the DC24V output capacity, supply DC24V externally as presented below.



- (5) AC110V/AC220V/DC24V cables should be compactly twisted and connected in the shortest distance.
- (6) AC110V/AC220V cable should be as thick as possible(2mm²) to reduce voltage drop.
- (7) AC110V/ DC24V cables should not be installed close to main circuit cable(high voltage/high current) and I/O signal cable. They should be 100mm away from such cables

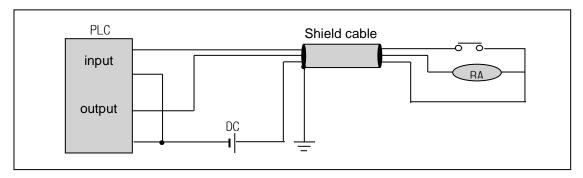
(8) To prevent surge from lightning, use the lightning surge absorber as presented below.



- (1) Isolate the grounding(E1) of lightning surge absorber from the grounding(E2) of the PLC.
- (2) Select a lightning surge absorber type so that the max. voltage may not the specified allowable voltage of the absorber.
- (9) When noise may be intruded inside it, use an insulated shielding transformer or noise filter.
- (10) Wiring of each input power should be twisted as short as possible and the wiring of shielding transformer or noise filter should not be arranged via a duct.

9.3.2 I/O Device wiring

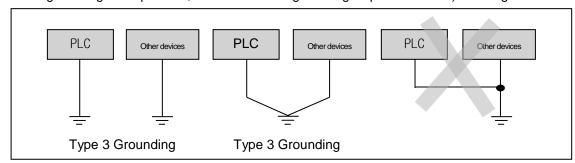
- (1) The size of I/O device cable is limited to 0.3~2 mm² but it is recommended to select a size(0.3 mm²) to use conveniently.
- (2) Please isolate input signal line from output signal line.
- (3) I/O signal lines should be wired 100mm and more away from high voltage/high current main circuit cable.
- (4) Batch shield cable should be used and the PLC side should be grounded unless the main circuit cable and power cable can not be isolated.



(5) When applying pipe-wiring, make sure to firmly ground the piping.

9.3.3 Grounding wiring

- (1) The PLC contains a proper noise measure, so it can be used without any separate grounding if there is a large noise. However, if grounding is required, please refer to the followings.
- (2) For grounding, please make sure to use the exclusive grounding. For grounding construction, apply type 3 grounding(grounding resistance lower than 100 Ω)
- (3) If the exclusive grounding is not possible, use the common grounding as presented in B) of the figure below.



- A) Exclusive grounding: best
- B) common grounding: good
- C) common grounding: defective
- (4) Use the grounding cable more than 2 mm². To shorten the length of the grounding cable, place the grounding point as close to the PLC as possible.
- (5) If any malfunction from grounding is detected, separate the FG of the base from the grounding.

9.3.4 Specifications of wiring cable

The specifications of cable used for wiring are as follows.

Types of external	Cable specification (mm²)			
connection	Lower limit	Upper limit		
Digital input	0.18 (AWG24)	1.5 (AWG16)		
Digital output	0.18 (AWG24)	2.0 (AWG14)		
Analogue I/O	0.18 (AWG24)	1.5 (AWG16)		
Communication	0.18 (AWG24)	1.5 (AWG16)		
Main power	1.5 (AWG16)	2.5 (AWG12)		
Protective grounding	1.5 (AWG16)	2.5 (AWG12)		

Chapter 10 Maintenance

Be sure to perform daily and periodic maintenance and inspection in order to maintain the PLC in the best conditions.

10.1 Maintenance and Inspection

The I/O module mainly consist of semiconductor devices and its service life is semi-permanent. However, periodic inspection is requested for ambient environment may cause damage to the devices. When inspecting one or two times per six months, check the following items.

Check Items		Judgment	Corrective Actions	
Change rate of	input voltage	Within change rate of input voltage (Less than –15% to +20%)	Hold it with the allowable range.	
Power supply	for input/output	Input/Output specification of each module	Hold it with the allowable range of each module.	
Ambient	Temperature	0 ~ + 55° C	Adjust the operating temperature and humidity with the	
environment	Humidity	5 ~ 95%RH	defined range.	
GIIVII GIIIII GIII	Vibration	No vibration	Use vibration resisting rubber or the vibration prevention method.	
Play of modules		No play allowed	Securely enrage the hook.	
Connecting conditions of terminal screws		No loose allowed	Retighten terminal screws.	
		Check the number of	Course the selection and immediately	
Spare parts		Spare parts and their Store conditions	Cover the shortage and improve the conditions.	

10.2 Daily Inspection

The following table shows the inspection and items which are to be checked daily.

Check Items		Check Points	Judgment	Corrective Actions
Connection of base	conditions of	Check the screws.	Screws should not be loose.	Retighten Screws.
Connection of Input/Output	conditions of module	Check the connecting screws Check module cover.	Screws should not be loose.	Retighten Screws.
Connecting	conditions of	Check for loose mounting screws.	Screws should not be loose.	Retighten Screws.
terminal blo	ck or extension	Check the distance between solderless terminals.	Proper clearance should be provided.	Correct.
Cable		Connecting of expansion cable.	Connector should not be loose.	Correct.
	PWR LED	Check that the LED is On.	On(Off indicates an error)	See chapter 5.
	Run LED Check that the LED is 0		On (flickering indicates an error)	See chapter 5.
LED	ERR LED	Check that the LED is Off during Run.	Off(On indicates an error)	See chapter 5.
indicator	Input LED	Check that the LED turns On and Off.	On when input is On, Off when input is off.	See chapter 5.
	Output LED	Check that the LED turns On and Off	On when output is On, Off when output is off	See chapter 5.

10.3 Periodic Inspection

Check the following items once or twice every six months, and perform the needed corrective actions.

Che	eck Items	Checking Methods	Judgment	Corrective Actions	
Analytensi	Ambient temperature	Measure with thermometer	0 ~ 55 °C	Adjust to general standard	
Ambient environment	Ambient Humidity	and hygrometer	5 ~ 95%RH	(Internal environmental	
	Ambient pollution level	measure corrosive gas	There should be no corrosive gases	standard of control section)	
PLC	Looseness, Ingress	The module should be move the unit	The module should be mounted securely.	Retighten screws	
Conditions	dust or foreign material	Visual check	No dust or foreign material		
	Loose terminal screws	Re-tighten screws	Screws should not be loose	Retighten	
Connecting conditions	Distance between terminals	Visual check	Proper clearance	Correct	
CONTUITIONS	Loose connectors	Visual check	Connectors should not be loose.	Retighten connector mounting screws	
Line v	voltage check	Measure voltage between input terminals	DC24V: DC20.4 ~ 28.8V	Change supply power	

Chapter 11 Troubleshooting

The following explains contents, diagnosis and corrective actions for various errors that can occur during system operation.

11.1 Basic Procedure of Troubleshooting

System reliability not only depends on reliable equipment but also on short downtimes in the event of fault. The short discovery and corrective action is needed for speedy operation of system. The following shows the basic instructions for troubleshooting.

1) Visual checks

Check the following points.

- Machine operating condition (in stop and operation status)
- Power On/Off
- Status of I/O devices
- Condition of wiring (I/O wires, extension and communications cables)
- Display states of various indicators (such as POWER LED, RUN LED, ERR LED and I/O LED)

After checking them, connect peripheral devices and check the operation status of the PLC and the program contents.

2) Trouble Check

Observe any change in the error conditions during the following.

- Switch to the STOP position, and then turn the power on and off.
- 3) Narrow down the possible causes of the trouble where the fault lies, i.e.:
 - Inside or outside of the PLC?
 - I/O module or another module?
 - PLC program?

11.2 Troubleshooting

This section explains the procedure for determining the cause of troubles as well as the errors and corrective actions.

Is the power LED turned Off?

Is the ERR LED flickering?

Flowchart used when the POWER LED is turned Off.

Flowchart used when the ERR LED is flickering.

Flowchart used when the RUN turned Off.

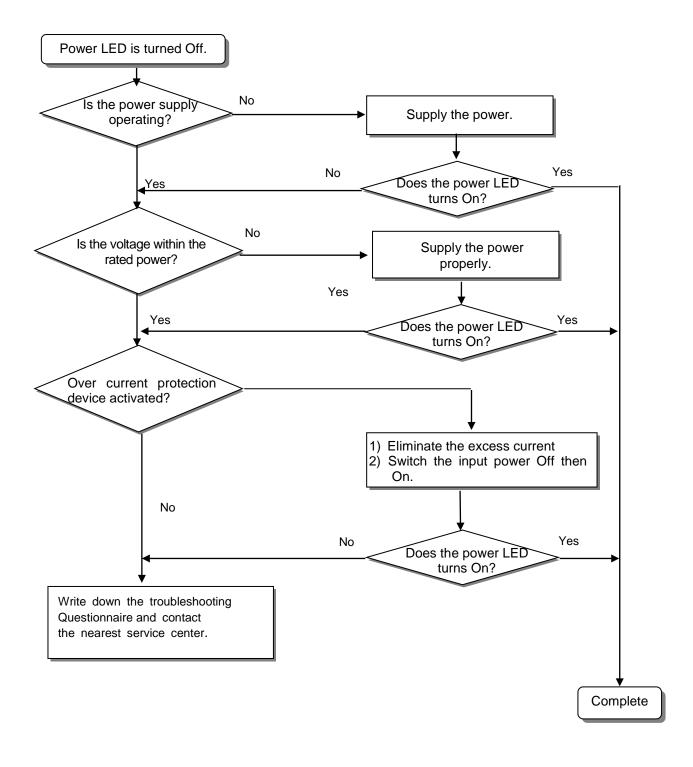
Flowchart used when the RUN turned Off.

Flowchart used when the output load of the output module doesn't turn on.

Flowchart used when a program can't be written to the PLC.

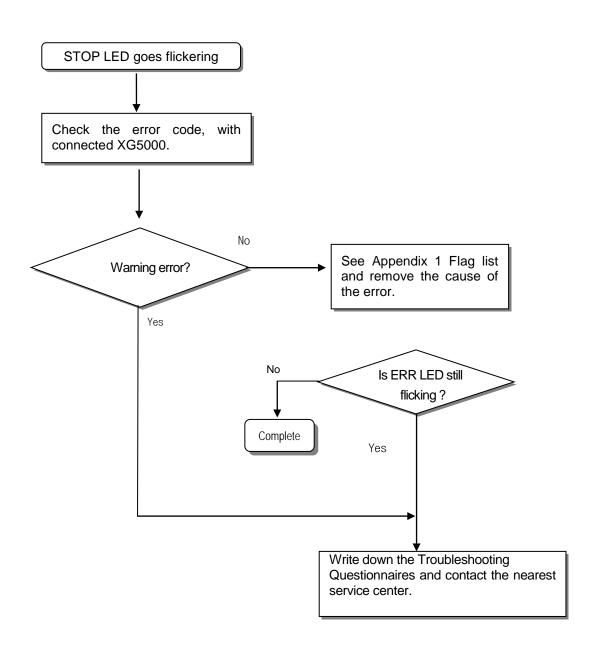
11.2.1 Troubleshooting flowchart used when the PWR (Power) LED turns Off.

The following flowchart explains corrective action procedure used when the power is supplied or the power LED turns Off during operation.



11.2.2 Troubleshooting flowchart used with when the ERR (Error) LED is flickering

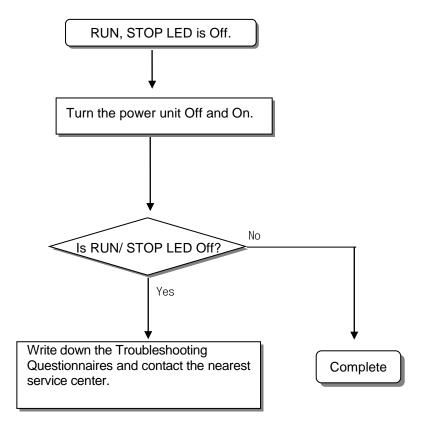
The following flowchart explains corrective action procedure use when the power is supplied starts or the ERR LED is flickering during operation.



Though warning error appears, PLC system doesn't stop but corrective action is needed promptly. If not, it may cause the system failure.

11.2.3 Troubleshooting flowchart used with when the RUN, STOP LED turns Off.

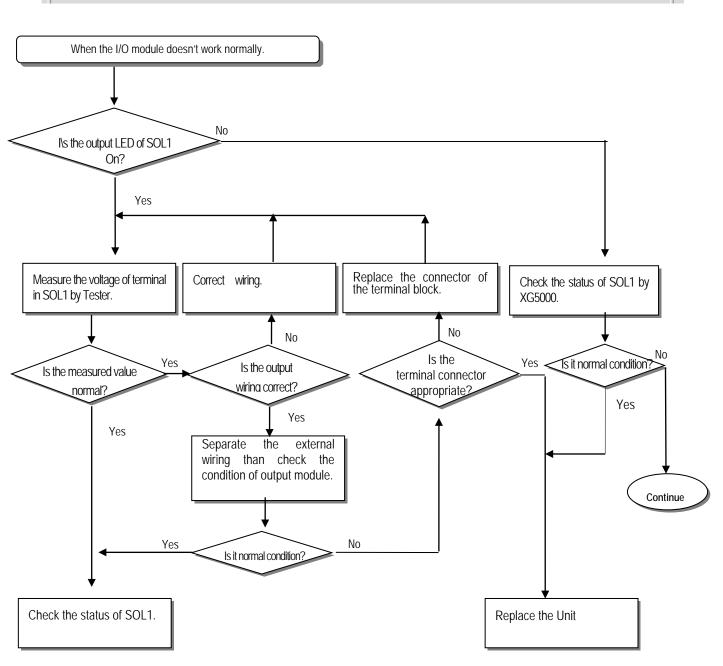
The following flowchart explains corrective action procedure to treat the lights-out of RUN LED when the power is supplied, operation starts or operation is in the process.

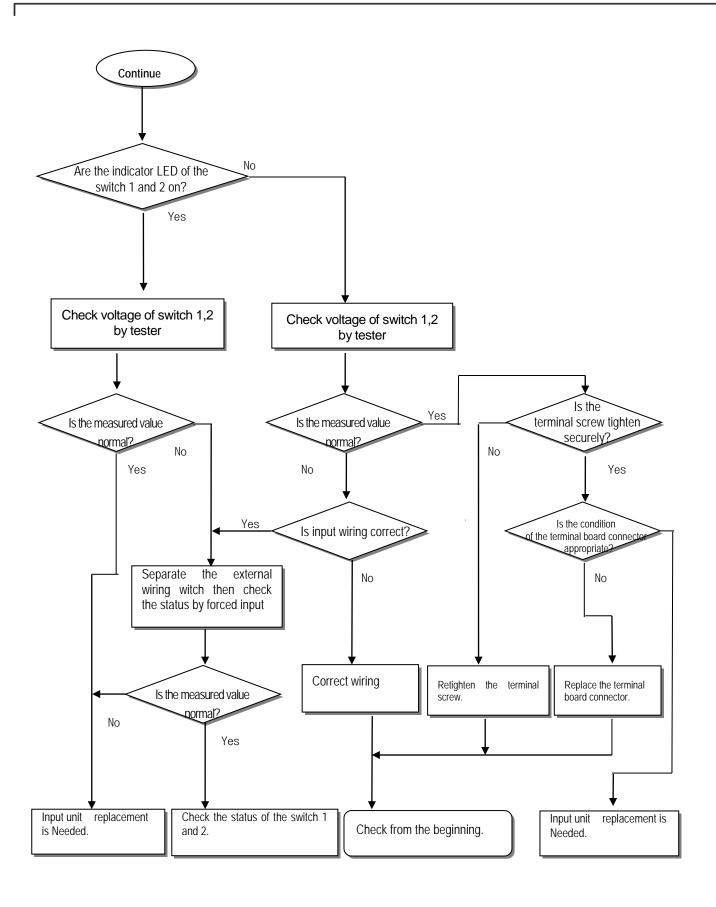


11.2.4 Troubleshooting flowchart used when the I/O part doesn't operate normally.

The following flowchart explains corrective action procedure used when the I/O module doesn't operate normally.







11.3 Troubleshooting Questionnaire

When problems have been met during operation of the XGC series, please write down this Questionnaires and contact the service center via telephone or facsimile.

• For errors relating to special or communication modules, use the questionnaire included in the User's manual of the unit.

)

Tellephone & FAX No Tell) Using equipment model:	FAX)		
3. Details of using equipment CPU model: () OS version No.:(XG5000 (for program compile) version No.: ()) \$	Serial No.(
4.General description of the device or system used as the contr	ol obje	ect:	
5. The kind of the base unit: - Operation by the mode setting switch (), - Operation by the XG5000 or communications (), - External memory module operation (),			
6. Is the ERR. LED of the CPU module turned On ? Yes(),	No()	
7. XG5000 error message:			
8. History of corrective actions for the error message in the artic	ele 7:		
9. Other tried corrective actions:			
 10. Characteristics of the error Repetitive(): Periodic(), Related to a particular sequence Sometimes(): General error interval: 	e(),	Related to environment()
11. Detailed Description of error contents:			
12. Configuration diagram for the applied system:			

11.4 Troubleshooting ExamplesPossible troubles with various circuits and their corrective actions are explained.

11.4.1 Input circuit troubles and corrective actions

The followings describe possible troubles with input circuits, as well as corrective actions.

Condition	Cause	Corrective Actions
Input signal doesn't turn off.	Leakage current of external device (Such as a drive by non-contact switch) AC input External device	Connect an appropriate register and capacity, which will make the voltage lower across the terminals of the input module. AC input
Input signal doesn't turn off. (Neon lamp may be still on)	Leakage current of external device (Drive by a limit switch with neon lamp) AC input External device	 CR values are determined by the leakage current value. Recommended value C: 0.1 ~ 0.47 μF R: 47 ~ 120 Ω (1/2W) Or make up another independent display circuit.
Input signal doesn't turn off.	Leakage current due to line capacity of wiring cable. AC input External device	Locate the power supply on the external device side as shown below. AC input External device
Input signal doesn't turn off.	Leakage current of external device (Drive by switch with LED indicator) DC input External device	Connect an appropriate register, which will make the voltage higher than the OFF voltage across the input module terminal and common terminal. OC input
Input signal doesn't turn off.	• Sneak current due to the use of two different power supplies. • E1 > E2, sneaked.	Use only one power supply. Connect a sneak current prevention diode. DC input

11.4.2 Output circuit and corrective actions

The following describes possible troubles with output circuits, as well as their corrective actions.

Condition	Course	
Condition When the output	Cause •Load is half-wave rectified inside (in some	
is off, excessive voltage is applied to the	cases, it is true of a solenoid) •When the polarity of the power supply is as shown in ①, C is charged. When the polarity is	across the load in parallel.
load.	as shown in ②, the voltage charged in C plus	
	the line voltage are applied across D. Max.	
	voltage is approx. 2√2. Load Load	Load
	*) If a resistor is used in this way, it does not	
	pose a problem to the output element. But it may make the performance of the diode (D), which is built in the load, drop to cause problems.	
The load doesn't	• Leakage current by surge absorbing circuit, which is connected to output element in parallel.	• Connect C and R across the load, which are of registers of tens KΩ. When the wiring distance
turn off.	which is connected to output clothers in parallel.	from the output module to the load is long, there
	Output	may be a leakage current due to the line
	Load	capacity.
	Leakage current -	Load Load
When the load is C-R type timer, time	Leakage current by surge absorbing circuit, which is connected to output element in parallel.	 Drive the relay using a contact and drive the C-R type timer using the since contact. Use other timer than the C-R contact some
constant fluctuates.	Output	timers have half-ware rectified internal circuits therefore, be cautious.
	Leakage current	
		Output
The load does not turn off.	Sneak current due to the use of two different power supplies.	Use only one power supply. Connect a sneak current prevention diode.
	Output Load TE1	Output Load E
	E1 <e2, (e2="" e1="" is="" off="" on),="" sneaks.="" sneaks.<="" td=""><td>If the load is the relay, etc, connect a counter-electromotive voltage absorbing code as shown by the dot line.</td></e2,>	If the load is the relay, etc, connect a counter-electromotive voltage absorbing code as shown by the dot line.

Output circuit troubles and corrective actions (continued).

Condition	Cause	Corrective actions
The load off response time is long.	Over current at off state [The large solenoid current fluidic load (L/R is large) such as is directly driven with the transistor output. Outpu Outpu Loa E	Insert a small L/R magnetic contact and
Output transistor is destroyed.	The off response time can be delayed by one or more second as some loads make the current flow across the diode at the off time of the transistor output. Surge current of the white lamp Output E1	To suppress the surge current make the dark current of 1/3 to 1/5 rated current flow. Output R R
	A surge current of 10 times or more when turned on.	Sink type transistor output Output R Source type transistor output

11.5 Error Code List

Error code	Error cause	Action (restart mode after taking an action)	Operation status	LED status	Diagnosis point
23	Program to execute is abnormal	Start after reloading the program	Warning	0.5 second Flicker	RUN mode
24	I/O parameter error	Start after reloading I/O parameter, Battery change if battery has a problem. Check the preservation status after I/O parameter reloading and if error occurs, change the unit.	Warning	0.5 second Flicker	Reset RUN mode switching
25	Basic parameter error	Start after reloading Basic parameter, Change battery if it has a problem. Check the preservation status after Basic parameter reloading and if error occurs, change the unit.	Warning	0.5 second Flicker	Reset RUN mode switching
30	Module set in parameter and the installed module does not match	modify the module or parameter and then restart.	Warning	0.5 second Flicker	RUN mode switching
31	Module falling during operation or additional setup	After checking the position of attachment/detachment of expansion module during Run mode	Warning	0.1 second Flicker	Every scan
33	Data of I/O module does not access normally during operation.	After checking the position of slot where the access error occurs by XG5000, change the module and restart (acc.to parameter.)	Heavy error	0.1 second Flicker	Scan end
34	Normal access of special/link module data during operation not available	After checking the position of slot that access error occurred by XG5000, change the module and restart (acc.to parameter).	Heavy error	0.1 second Flicker	Scan end
39	Abnormal stop of CPU or malfunction	Abnormal system end by noise or hard ware error. 1) If it occurs repeatedly when power reinput, request service center 2) Noise measures	Heavy error	0.1 second Flicker	Ordinary time
40	Scan time of program during operation exceeds the scan watchdog time designated by parameter.	After checking the scan watchdog time designated by parameter, modify the parameter or the program and then restart.	Warning	0.5 second Flicker	While running the program
41	Operation error occurs while running the user program.	Remove operation error \rightarrow reload the program and restart.	Warning	0.5 second Flicker	While running the program
44	Timer index user error	After reloading a timer index program modification, start	Warning	0.5 second Flicker	Scan end
50	Heavy error of external device	Refer to Heavy error detection flag and modifies the device and restart. (Acc. Parameter)	Heavy error	1 second Flicker	Scan end
60	E_STOP function executed	After removing error causes which starts E_STOP function in program, power reinput	Heavy error	1 second Flicker	While running the program

Error	Error cause	Action	Operation	LED	Diagnosis
code	Elloi cause	(restart mode after taking an action) status		status	point
500	Data memory backup not possible	If not error in battery, power reinput Remote mode is switched to STOP mode.	Warning	1 second Flicker	Reset
501	Abnormal clock data	Setting the time by XG5000 if there is no error	Warning	0.1 second Flicker	Ordinary time
502	Battery voltage falling	Battery change at power On status	Warning	0.1 second Flicker	Ordinary time

Appendix 1 Flag List

Appendix 1.1 Special Relay (F) List

Word	Bit	Variables	Function	Description
	-	_SYS_STATE	Mode and state	Indicates PLC mode and operation State.
	F0000	_RUN	Run	Run state.
	F0001	_STOP	Stop	Stop state.
	F0002	_ERROR	Error	Error state.
	F0003	_DEBUG	Debug	Debug state.
	F0004	_LOCAL_CON	Local control	Local control mode.
	F0006	_REMOTE_CON	Remote mode	Remote control mode.
	F0008	_RUN_EDIT_ST	Editing during RUN	Editing program download during RUN.
	F0009	_RUN_EDIT_CHK	Editing during RUN	Internal edit processing during RUN.
	F000A	_RUN_EDIT_DONE	Edit done during RUN	Edit is done during RUN.
	F000B	_RUN_EDIT_END	Edit end during RUN	Edit is ended during RUN.
	F000C	_CMOD_KEY	Operation mode	Operation mode changed by key.
	F000D	_CMOD_LPADT	Operation mode	Operation mode changed by local PADT.
F000~1	F000E	_CMOD_RPADT	Operation mode	Operation mode changed by Remote PADT.
	F000F	_CMOD_RLINK	Operation mode	Operation mode changed by Remote communication module.
	F0010	_FORCE_IN	Forced input	Forced input state.
	F0011	_FORCE_OUT	Forced output	Forced output state.
	F0014	_MON_On	Monitor	Monitor on execution.
	F0015	_USTOP_On	Stop	Stop by Stop function.
	F0016	_ESTOP_On	EStop	Stop by EStop function.
	F0017	_CONPILE_MODE	Compile	Compile on execution.
	F0018	_INIT_RUN	Initialize	Initialization task on execution.
	F001C	_PB1	Program Code 1	Program Code 1 selected.
	F001D	_PB2	Program Code 2	Program Code 2 selected.
	F001E	_CB1	Compile Code 1	Compile Code 1 selected.
	F001F	_CB2	Compile Code2	Compile Code 2 selected.
	-	_CNF_ER	System error	Reports heavy error state of system.
	F0021	_IO_TYER	Module Type error	Module Type does not match.
F000 0	F0022	_IO_DEER	Module detachment error	Module is detached.
F002~3	F0024	_IO_RWER	Module I/O error	Module I/O error.
	F0025	_IP_IFER	Module interface error	Special/communication module interface error.
	F0026	_ANNUM_ER	External device error	Detected heavy error in external Device.

Word	Bit	Variable	Function	Description
	F0028	_BPRM_ER	Basic parameter	Basic parameter error.
	F0029	_IOPRM_ER	IO parameter	I/O configuration parameter error.
	F002A	_SPPRM_ER	Special module parameter	Special module parameter is Abnormal.
F002~3	F002B	_CPPRM_ER	Communication module parameter	Communication module parameter is abnormal.
	F002C	_PGM_ER	Program error	Program error.
	F002D	_CODE_ER	Code error	Program Code error.
	F002E	_SWDT_ER	System watchdog	System watchdog operated.
	F0030	_WDT_ER	Scan watchdog	Scan watchdog operated.
	ı	_CNF_WAR	System warning	Reports light error state of system.
	F0041	_DBCK_ER	Backup error	Data backup error.
	F0043	_ABSD_ER	Operation shutdown error	Stop by abnormal operation.
	F0046	_ANNUM_WAR	External device error	Detected light error of external device.
F004	F0048	_HS_WAR1	High speed link 1	High speed link – parameter 1 error.
F004	F0049	_HS_WAR2	High speed link 2	High speed link – parameter 2 error.
	F0054	_P2P_WAR1	P2P parameter 1	P2P – parameter 1 error.
	F0055	_P2P_WAR2	P2P parameter 2	P2P – parameter 2 error.
	F0056	_P2P_WAR3	P2P parameter 3	P2P – parameter 3 error.
	F005C	_CONSTANT_ER	Constant error	Constant error.
	ı	_USER_F	User contact	Timer used by user.
	F0090	_T20MS	20ms	20ms cycle Clock.
	F0091	_T100MS	100ms	100ms cycle Clock.
	F0092	_T200MS	200ms	200ms cycle Clock.
	F0093	_T1S	1s Clock	1s cycle Clock.
	F0094	_T2S	2 s Clock	2s cycle Clock.
F009	F0095	_T10S	10 s Clock	10s cycle Clock.
F009	F0096	_T20S	20 s Clock	20s cycle Clock.
	F0097	_T60S	60 s Clock	60s cycle Clock.
	F0099	_On	Ordinary time On	Always On state Bit.
	F009A	_Off	Ordinary time Off	Always Off state Bit.
	F009B	_1On	1scan On	First scan On Bit.
	F009C	_1Off	1scan Off	First scan OFF bit.
	F009D	_STOG	Reversal	Reversal every scan.

Word	Bit	Variable	Function	Description
	-	_USER_CLK	User Clock	Clock available for user setting.
	F0100	_USR_CLK0	Setting scan repeat	On/Off as much as set scan Clock 0.
	F0101	_USR_CLK1	Setting scan repeat	On/Off as much as set scan Clock 1.
	F0102	_USR_CLK2	Setting scan repeat	On/Off as much as set scan Clock 2.
F010	F0103	_USR_CLK3	Setting scan repeat	On/Off as much as set scan Clock 3.
	F0104	_USR_CLK4	Setting scan repeat	On/Off as much as set scan Clock 4.
	F0105	_USR_CLK5	Setting scan repeat	On/Off as much as set scan Clock 5.
	F0106	_USR_CLK6	Setting scan repeat	On/Off as much as set scan Clock 6.
	F0107	_USR_CLK7	Setting scan repeat	On/Off as much as set scan Clock 7.
	-	_LOGIC_RESULT	Logic result	Indicates logic results.
	F0110	_LER	operation error	On during 1 scan in case of operation error.
F011	F0111	_ZERO	Zero flag	On when operation result is 0.
FULL	F0112	_CARRY	Carry flag	On when carry occurs during operation.
	F0113	_ALL_Off	All output OFF	On in case that all output is Off.
	F0115	_LER_LATCH	Operation error Latch	Keeps On during operation error.
	-	_CMP_RESULT	Comparison result	Indicates the comparison result.
	F0120	_LT	LT flag	On in case of "less than".
	F0121	_LTE	LTE flag	On in case of "equal or less than".
F012	F0122	_EQU	EQU flag	On in case of "equal".
	F0123	_GT	GT flag	On in case of "greater than".
	F0124	_GTE	GTE flag	On in case of "equal or greater than".
	F0125	_NEQ	NEQ flag	On in case of "not equal".
F014	-	_FALS_NUM	FALS no.	Indicates FALS no.
F015	-	_PUTGET_ERR0	PUT/GET error 0	Main base Put / Get error.
F023	-	_PUTGET_NDR0	PUT/GET end 0	Main base Put/Get end.
F044	-	_CPU_TYPE	CPU Type	Indicates information for CPU Type.
F045	-	_CPU_VER	CPU version	Indicates CPU version.
F046	-	_OS_VER	OS version	Indicates OS version.
F048	-	_OS_DATE	OS date	Indicates OS distribution date.
F050	-	_SCAN_MAX	Max. scan time	Indicates max. scan time.
F051	-	_SCAN_MIN	Min. scan time	Indicates min. scan time.
F052	-	_SCAN_CUR	Current scan time	Current scan time.
F0053			Month/year	Clock data (month/year)
F0054	-	_TIME_DAY	IME_DAY Hour/date Clock data (hour/date)	
F0055	-	_SEC_MIN	C_MIN Second/minute Clock data (Second/minute)	
F0056	-	_HUND_WK	Hundred year/week	Clock data (Hundred year/week)

Word	Bit	Variable	Function	Description
	-	_FPU_INFO	N/A	-
	F0570	_FPU_LFLAG_I	N/A	-
	F0571	_FPU_LFLAG_U	N/A	-
	F0572	_FPU_LFLAG_O	N/A	-
	F0573	_FPU_LFLAG_Z	N/A	-
F057	F0574	_FPU_LFLAG_V	N/A	-
F057	F057A	_FPU_FLAG_I	N/A	-
	F057B	_FPU_FLAG_U	N/A	-
	F057C	_FPU_FLAG_O	N/A	-
	F057D	_FPU_FLAG_Z	N/A	-
	F057E	_FPU_FLAG_V	N/A	-
	F057F	_FPU_FLAG_E	Irregular input	Reports in case of irregular input.
F058	-	_ERR_STEP	Error step	Saves error step.
F060	-	_REF_COUNT	Refresh	Increase when module Refresh.
F062	-	_REF_OK_CNT	Refresh OK	Increase when module Refresh is normal.
F064	-	_REF_NG_CNT	Refresh NG	Increase when module Refresh is Abnormal.
F066	-	_REF_LIM_CNT	Refresh Limit	Increase when module Refresh is abnormal (Time Out).
F068	-	_REF_ERR_CNT	Refresh Error	Increase when module Refresh is Abnormal.
F070	-	_MOD_RD_ERR_CNT	-	-
F072	-	_MOD_WR_ERR_CNT	-	-
F074	-	_CA_CNT	-	-
F076	-	_CA_LIM_CNT	-	-
F078	-	_CA_ERR_CNT	-	-
F080	-	_BUF_FULL_CNT	Buffer Full	Increase when CPU internal buffer is full.
F082	-	_PUT_CNT	Put count	Increase when Put count.
F084	-	_GET_CNT	Get count	Increase when Get count.
F086	-	_KEY	Current key	indicates the current state of local key.
F088	-	_KEY_PREV	Previous key	indicates the previous state of local key
F090	-	_IO_TYER_N	Mismatch slot	Module Type mismatched slot no.
F091	-	_IO_DEER_N	Detach slot	Module detached slot no.
F093	-	_IO_RWER_N	RW error slot	Module read/write error slot no.
F094	-	_IP_IFER_N	IF error slot	Module interface error slot no.
F096	-	_IO_TYER0	Module Type 0 error	Main base module Type error.

Word	Bit	Variable	Function	Description
F104	-	_IO_DEER0	Module Detach 0 error	Main base module Detach error.
F120	-	_IO_RWER0	Module RW 0 error	Main base module read/write error.
F128	-	_IO_IFER_0	Module IF 0 error	Main base module interface error.
F140	-	_AC_FAIL_CNT	Power shutdown times	Saves the times of power shutdown.
F142	-	_ERR_HIS_CNT	Error occur times	Saves the times of error occur.
F144	-	_MOD_HIS_CNT	Mode conversion times	Saves the times of mode conversion.
F146	-	_SYS_HIS_CNT	History occur times	Saves the times of system history.
F148	-	_LOG_ROTATE	Log Rotate	Saves log rotate information.
F150	-	_BASE_INFO0	Slot information 0	Main base slot information.
	ı	_USER_WRITE_F	Available contact point	Contact point available in program.
	F2000	_RTC_WR	RTC RW	Data write and read in RTC.
	F2001	_SCAN_WR	Scan WR	Initializing the value of scan.
F200	F2002	_CHK_ANC_ERR	Request detection of external serious error	Request detection of external error.
	F2003	_CHK_ANC_WAR	Request detection of external slight error (warning)	Request detection of external slight error (warning).
F204	-	_USER_STAUS_F	User contact point	User contact point.
F201	F2010	_INIT_DONE	Initialization completed	Initialization complete displayed.
F202	-	_ANC_ERR	Display information of external serious error	Display information of external serious error
F203	-	_ANC_WAR	Display information of external slight error (warning)	Display information of external slight error (warning)
F210	-	_MON_YEAR_DT	Month/year	Clock data (month/year)
F211	-	_TIME_DAY_DT	Hour/date	Clock data (hour/date)
F212	-	_SEC_MIN_DT	Second/minute	Clock data (Second/minute)
F213	-	_HUND_WK_DT	Hundred year/week	Clock data (Hundred year/week)

Appendix 1.2 Communication Relay (L) List

Here describes data link communication relay(L).

1. High-speed Link 1

Device	Keyword	Туре	Description
			High speed link parameter 1 normal operation of all station
L000	_HS1_RLINK	Bit	Indicates normal operation of all station according to parameter set in High speed link, and On under the condition as below. 1. In case that all station set in parameter is RUN mode and no error, 2. All data block set in parameter is communicated normally, and 3. The parameter set in each station itself is communicated normally. Once RUN_LINK is On, it keeps On unless stopped by LINK_DISABLE.
			Abnormal state after _HS1RLINK On
L001	_HS1_LTRBL Bit		In the state of _HSmRLINK flag On, if communication state of the station set in the parameter and data block is as follows, this flag shall be On. 1. In case that the station set in the parameter is not RUN mode, or 2. There is an error in the station set in the parameter, or 3. The communication state of data block set in the parameter is not good. LINK TROUBLE shall be On if the above 1, 2 & 3 conditions occur, and if the condition return to the normal state, it shall be OFF again.
		Bit Array	High speed link parameter 1, K block general state
L0020 ~ L005F	_HS1_STATE[k] (k = 00~63)		Indicates the general state of communication information for each data block of setting parameterHS1_STATE[k] = HS1MOD[k]&_HS1TRX[k]&(~_HS1_ERR[k])
L0060 ~	_HS1_MOD[k]	Bit	High speed link parameter 1, k block station RUN operation mode
L009F	(k = 00~63)	Array	Indicates operation mode of station set in K data block of parameter.
L0100 ~ L013F	_HS1_TRX[k] Bit (k = 00~63) Arra		Normal communication with High speed link parameter 1, k block station Indicates if communication state of Kdata of parameter is communicated smoothly according to the setting.
L0140 ~	_HS1_ERR[k]	Bit Array	High speed link parameter 1, K block station operation error mode
L017F	(k = 00~63)		Indicates if the error occurs in the communication state of k data block of parameter.
L0180 ~	UC1 SETDI OOKIIJ	Bit	High speed link parameter 1, K block setting
L021F	_HS1_SETBLOCK[k]	Array	Indicates whether or not to set k data block of parameter.

2. High-speed Link2

Device	Keyword	Туре	Description
			High-speed link parameter 2 normal operation of all station.
L0260 _HS2_RLINK		Bit	Indicates normal operation of all station according to parameter set in High-speed link and On under the condition as below. 1. In case that all station set in parameter is Run mode and no error 2. All data block set in parameter is communicated and 3. The parameter set in each station itself is communicated normally. Once RUN_LINK is On, it keeps On unless stopped by LINK_DISABLE.
			Abnormal state after _HS2RLINK On.
L0261	_HS2_LTRBL Bit		In the state of _HSmRLINK flag On, if communication state of the station set in the parameter and data block is as follows, this flag shall be On. 1. In case that the station set in the parameter is not RUN mode, or 2. There is an error in the station set in the parameter, or 3. The communication state of data block set in the parameter is not good. LINK TROUBLE shall be On if the above 1, 2 & 3 conditions occur, and if the condition return to the normal state, it shall be OFF again.
		Bit Array	High speed link parameter 1, k block general state.
L0280 ~ L031F	_HS2_STATE[k] (k = 00~63)		Indicates the general state of communication information for each data block of setting parameter. _HS2_STATE[k]=HS2MOD[k]&_HS2TRX[k]&(~_HS2_ERR[k])
L0320 ~	_HS2_MOD[k]	Bit	High speed link parameter 1, k block station RUN operation mode.
L035F	(k = 00~63)	Array	Indicates operation mode of station set in k data block of parameter.
L0360 ~ L039F	_HS2_TRX[k] Bit Array		Normal communication with High speed link parameter 1, K block station. Indicates if communication state of K data of parameter is communicated smoothly according to the setting.
L0400 ~	HGO EDDIN	Bit Array	High speed link parameter 1, K block station operation error mode.
L043F	_HS2_ERR[k] (k = 00~63)		Indicates if the error occurs in the communication state of k data block of parameter.
L0440 ~	_HS2_SETBLOCK[k]	Bit Array	High speed link parameter 1, K block setting.
L047F	_1132_3E1BLUUN[K]		Indicates whether or not to set k data block of parameter.

3. Common area

Communication flag list according to P2P service setting. P2P parameter: 1~3, P2P block: 0~31

Device	Keyword	Туре	Description
L5120	_P2P1_NDR00	Bit	Indicates P2P parameter 1, 0 Block service normal end.
L5121	_P2P1_ERR00	Bit	Indicates P2P parameter 1, 0 Block service abnormal end.
L513	_P2P1_STATUS00	Word	Indicates error code in case of P2P parameter 1, 0 Block service abnormal end.
L514	_P2P1_SVCCNT00	DWord	Indicates P2P parameter 1, 0 Block service normal count.
L516	_P2P1_ERRCNT00	DWord	Indicates P2P parameter 1, 0 Block service abnormal count.
L5180	_P2P1_NDR01	Bit	P2P parameter 1, 1 Block service normal end.
L5181	_P2P1_ERR01	Bit	P2P parameter 1, 1 Block service abnormal end.
L519	_P2P1_STATUS01	Word	Indicates error code in case of P2P parameter 1, 1 Block service abnormal end.
L520	_P2P1_SVCCNT01	DWord	Indicates P2P parameter 1, 1 Block service normal count.
L522	_P2P1_ERRCNT01	DWord	Indicates P2P parameter 1, 1 Block service abnormal count.
L524~L529	-	Word	P2P parameter 1,2 Block service total.
L530~L535	-	Word	P2P parameter 1,3 Block service total.
L536~L697	-	Word	P2P parameter 1,4~30 Block service total.
L698~L703	-	Word	P2P parameter 1,31 Block service total.

Appendix 1.3 Network Register (N) List

Here describes Network Register for communication (N). P2P parameter: 1~3, P2P block: 0~31

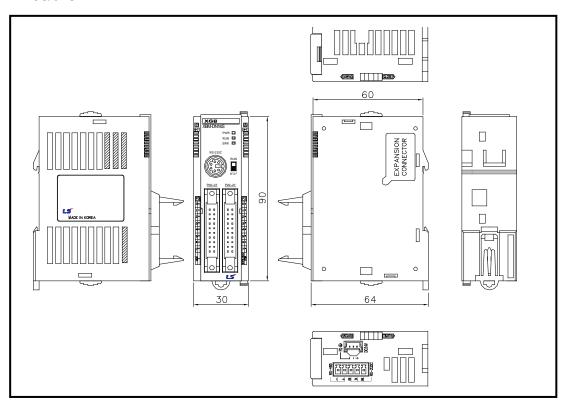
Device	Keyword	Туре	Description
N000	_P1B00SN	Word	Saves another station no. of P2P parameter 1, 00 block.
N0000~0004	_P1B00RD1	Word	Saves area device 1 to read P2P parameter 1, 01 block.
N005	_P1B00RS1	Word	Saves area size 1 to read P2P parameter 1, 01 block.
N0006~0009	_P1B00RD2	Word	Saves area device 2 to read P2P parameter 1, 01 block.
N010	_P1B00RS2	Word	Saves area size 2 to read P2P parameter 1, 01 block.
N0011~0014	_P1B00RD3	Word	Saves area device 3 to read P2P parameter 1, 01 block.
N015	_P1B00RS3	Word	Saves area size 3 to read P2P parameter 1, 01 block.
N0016~0019	_P1B00RD4	Word	Saves area device 4 to read P2P parameter 1, 01 block.
N020	_P1B00RS4	Word	Saves area size 4 to read P2P parameter 1, 01 block.
N0021~0024	_P1B00WD1	Word	Saves area device 1 to save P2P parameter 1, 01 block.
N025	_P1B00WS1	Word	Saves area size 1 to save P2P parameter 1, 01 block.
N0026~0029	_P1B00WD2	Word	Saves area device 2 to save P2P parameter 1, 01 block.
N030	_P1B00WS2	Word	Saves area size 2 to save P2P parameter 1, 01 block.
N0031~0034	_P1B00WD3	Word	Saves area device 3 to save P2P parameter 1, 01 block.
N035	_P1B00WS3	Word	Saves area size 3 to save P2P parameter 1, 01 block.
N0036~0039	_P1B00WD4	Word	Saves area device 4 to save P2P parameter 1, 01 block.
N040	_P1B00WS4	Word	Saves area size 4 to save P2P parameter 1, 01 block.
N0041~0081	-	Word	Saving area of P2P parameter 1, 01 block.
N0082~0122	-	Word	Saving area of P2P parameter 1, 02 block. P2P
N0123~1311	-	Word	Saving area of P2P parameter 1, 03~31 block.
N1312~2623	-	Word	Saving area of P2P parameter 2.
N2624~3935	-	Word	Saving area of P2P parameter 3.

Remark

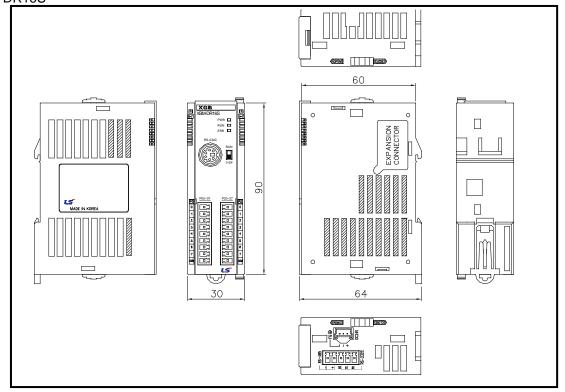
☐ In XGB series, Network register is available only monitoring. (Read Only)

Appendix 2 Dimension (Unit: mm)

- (1) standard type main unit ("S" type)
- -. XBM-DN16S/32S

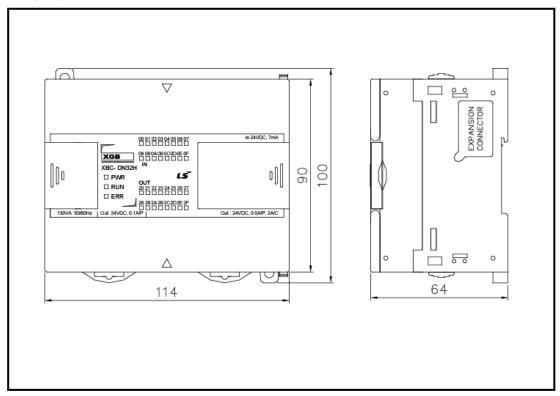


-. XBM-DR16S

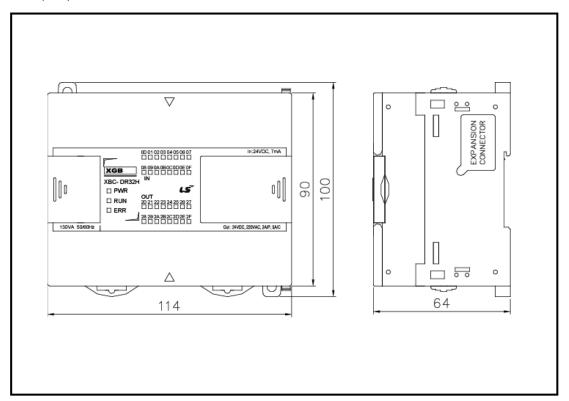


(2) Compact type main unit ("H" type)

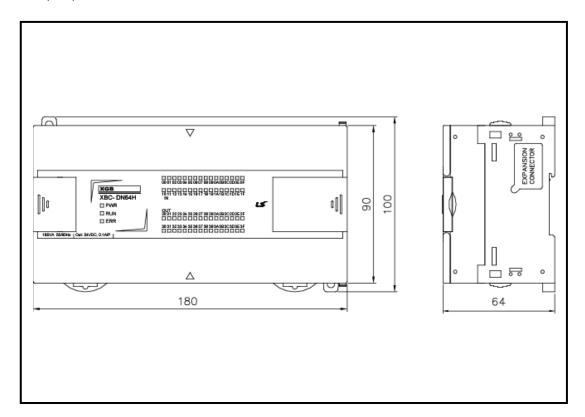
-. XBC-DN32H(/DC)



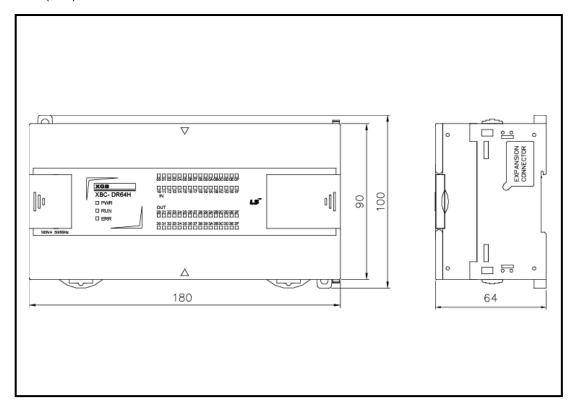
-. XBC-DR32H (/DC)



-. XBC-DN64H (/DC)

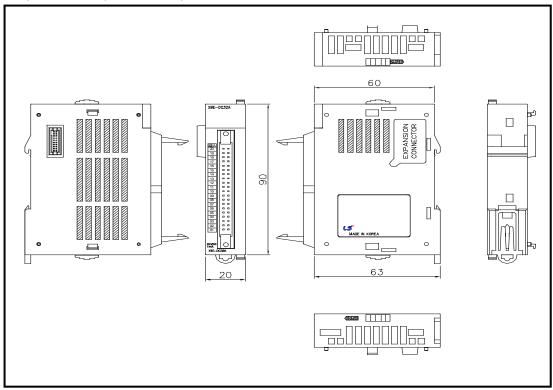


-. XBC-DR64H (/DC)

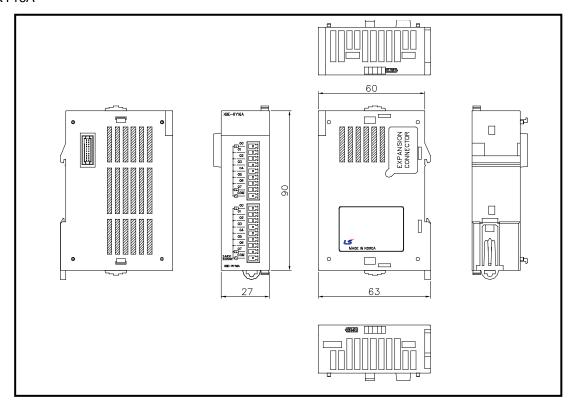


(3) Extension I/O module

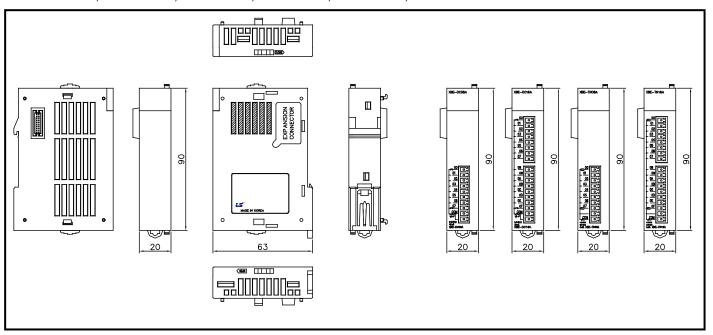
-. XBE-DC32A, XBE-TN32A, XBE-TP32A, XBE-DN32A



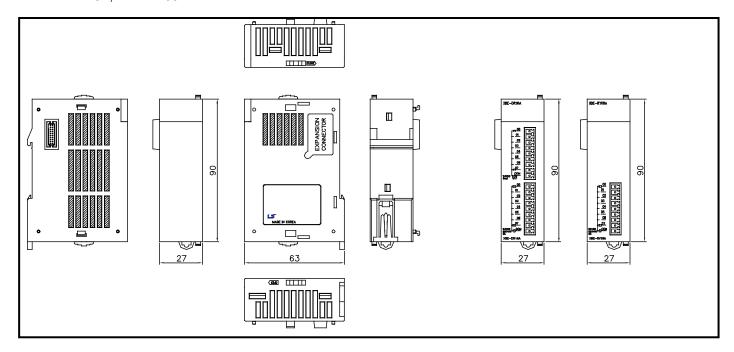
-. XBE-RY16A



-. XBE-DC08A, XBE-DC16A, XBE-TN08A, XBE-TP08A, XBE-TN16A, XBE-TP16A



-. XBE-DR16A, XBE-RY08A



Appendix 3 Compatibility with MASTER-K (Special Relay)

	MASTER-K		XGB		
Device	Function	Symbol	Device	Function	
F0000	RUN mode	_RUN	F0000	RUN Edit mode	
F0001	Program mode	_STOP	F0001	Program mode	
F0002	Pause mode	_ERROR	F0002	Error mode	
F0003	Debug mode	_DEBUG	F0003	Debug mode	
F0004	N/A	_LOCAL_CON	F0006	Remote mode	
F0005	N/A	_MODBUS_CON	F0006	Remote mode	
F0006	Remote mode	_REMOTE_CON	F0006	Remote mode	
F0007	User memory setup	-	F0007	N/A	
F0008	N/A	_RUN_EDIT_ST	F0008	Editing during RUN	
F0009	N/A	_RUN_EDIT_CHK	F0009	Editing during RUN	
F000A	User memory operation	_RUN_EDIT_DONE	F000A	Edit done during RUN	
F000B	N/A	_RUN_EDIT_END	F000B	Edit end during RUN	
F000C	N/A	_CMOD_KEY	F000C	Operation mode change by KEY	
F000D	N/A	_CMOD_LPADT	F000D	Operation mode change by PADT	
F000E	N/A	_CMOD_RPADT	F000E	Operation mode change by Remote PADT	
F000F	STOP command execution	_CMOD_RLINK	F000F	Operation mode change cause by remote communication module	
F0010	Ordinary time On	_FORCE_IN	F0010	Forced input	
F0011	Ordinary time Off	_FORCE_OUT	F0011	Forced output	
F0012	1 Scan On	_SKIP_ON	F0012	I/O Skip execution	
F0013	1 Scan Off	_EMASK_ON	F0013	Error mask execution	
F0014	Reversal every Scan	_MON_ON	F0014	Monitor execution	
		_USTOP_ON	F0015	Stop by Stop Function	
		_ESTOP_ON	F0016	Stop by ESTOP Function	
F0015 ~		_CONPILE_MODE	F0017	Compile	
F001C	N/A	_INIT_RUN	F0018	Initialize	
		-	F0019 ~ F001F	N/A	
		_PB1	F001C	Program Code 1	
F001D	N/A	_PB2	F001D	Program Code 2	
F001E	N/A	_CB1	F001E	Compile code 1	
F001F	N/A	_CB2	F001F	Compile code 2	

	MASTER-K			XGB
Device	Function	Symbol	Device	Function
F0020	1 Step RUN	_CPU_ER	F0020	CPU configuration error
F0021	Break Point RUN	_IO_TYER	F0021	Module type mismatch error
F0022	Scan RUN	_IO_DEER	F0022	Module detach error
F0023	Contact value match RUN	_FUSE_ER	F0023	Fuse cutoff error
F0024	Word value match RUN	_IO_RWER	F0024	I/O module read/write error
		_IP_IFER	F0025	Special/communication module interface error
		_ANNUM_ER	F0026	Heavy error detection of external equipment error
		-	F0027	N/A
		_BPRM_ER	F0028	Basic parameter error
		_IOPRM_ER	F0029	I/O configuration parameter error
F0025 ~ F002F	N/A	_SPPRM_ER	F002A	Special module parameter error
1 0021		_CPPRM_ER	F002B	Communication module parameter error
		_PGM_ER	F002C	Program error
		_CODE_ER	F002D	Program Code error
		_SWDT_ER	F002E	System watchdog error
		_BASE_POWER _ER	F002F	Base power error
F0030	Heavy error	_WDT_ER	F0030	Scan watchdog
F0031	Light error	-	F0031	-
F0032	WDT error	-	F0032	-
F0033	I/O combination error	-	F0033	-
F0034	Battery voltage error	-	F0034	-
F0035	Fuse error	-	F0035	-
F0036 ~ F0038	N/A	-	F0036 ~ F0038	-
F0039	Backup normal	-	F0039	-
F003A	Clock data error	-	F003A	-
F003B	Program change	-	F003B	-
F003C	Program change error	-	F003C	-
F003D ~ F003F	N/A	-	F003D ~ F003F	N/A

MAS	STER-K	XGB			
Device	Function	Symbol	Device	Function	
		_RTC_ER	F0040	RTC data error	
F0040~F005F N/A F0040 ~ F005F N/A F0060 ~ F006F Error Code save F0070 ~ F008F Fuse cutoff save F0090 20ms cycle Clock F0091 100ms cycle Clock F0092 200ms cycle Clock F0093 1s cycle Clock F0094 2s cycle Clock F0095 10s cycle Clock F0096 20s cycle Clock F0097 60s cycle Clock F0097 60s cycle Clock	_DBCK_ER	F0041	Data backup error		
		Symbol Device Function			
	N/A	_ABSD_ER	F0043	Abnormal operation stop	
F005F		_TASK_ER	F0044	Task collision	
		_BAT_ER	F0045	Battery error	
F0040~F005F F0060~F006F F0070~F008F F0090 F0091 F0092 F0093 F0094 F0095 F0096		_ANNUM_ER	F0046		
		_LOG_FULL	F0047	Log memory full warning	
		_HS_WAR1	F0048	High speed link parameter 1 error	
		_HS_WAR2	F0049	High speed link parameter 2 error	
		-	F004A ~ F0053	N/A	
F0040 F005F	NI/A	_P2P_WAR1	F0054	P2P parameter 1 error	
F0040 ~ F005F	N/A	_P2P_WAR2	F0055	P2P parameter 2 error	
		_P2P_WAR3	F0056	P2P parameter 3 error	
		-	F0057 ~ F005B	N/A	
		_Constant_ER	F005C	Constant error	
		-	F005D ~ F005F	N/A	
F0060 ~ F006F	Error Code save	-	F0060 ~ F006F	N/A	
F0070 ~ F008F	Fuse cutoff save	-	F0070 ~ F008F	N/A	
F0090	20ms cycle Clock	_T20MS	F0090	20ms cycle Clock	
F0091	100ms cycle Clock	_T100MS	F0091	100ms cycle Clock	
F0092	200ms cycle Clock	_T200MS	F0092	200ms cycle Clock	
F0093	1s cycle Clock	_T1S	F0093	1s cycle Clock	
F0094	2s cycle Clock	_T2S	F0094	2s cycle Clock	
F0095	10s cycle Clock	_T10S	F0095	10s cycle Clock	
F0096	20s cycle Clock	_T20S	F0096	20s cycle Clock	
F0097	60s cycle Clock	_T60S	F0097	60s cycle Clock	
		-	F0098	N/A	
		_ON	F0099	Ordinary time On	
5 000 5 000		_OFF	F009A	Ordinary time Off	
F0098 ~F009F	N/A	_10N	F009B	1 Scan On	
		_10FF	F009C	1 Scan Off	
		_STOG	F009D	Reversal every Scan	
		-	F009B ~ F009F	N/A	

MAS	STER-K	XGB			
Device	Function	Symbol	Device	Function	
F0100	User Clock 0	-	F0100	User Clock 0	
F0101	User Clock 1	-	F0101	User Clock 1	
F0102	User Clock 2	-	F0102	User Clock 2	
F0103	User Clock 3	-	F0103	User Clock 3	
F0104	User Clock 4	-	F0104	User Clock 4	
F0105	User Clock 5	-	F0105	User Clock 5	
F0106	User Clock 6	-	F0106	User Clock 6	
F0107	User Clock 7	-	F0107	User Clock 7	
F0108 ~ F010F		-	F0108 ~ F010F	N/A	
F0110	Operation error flag	_Ler	F0110	Operation error flag	
F0111	Zero flag	_Zero	F0111	Zero flag	
F0112	Carry flag	_Carry	F0112	Carry flag	
F0113	Full output Off	_AII_Off	F0113	Full output Off	
F0114	Common RAM R/W error	-	F0114	N/A	
F0115	Operation error flag (latch)	_Ler_Latch	F0115	Operation error flag(latch)	
F0116 ~ F011F		-	F0116 ~ F011F	N/A	
F0120	LT flag	_LT	F0120	LT flag	
F0121	LTE flag	_LTE	F0121	LTE flag	
F0122	EQU flag	_EQU	F0122	EQU flag	
F0123	GT flag	_GT	F0123	GT flag	
F0124	GTE flag	_GTE	F0124	GTE flag	
F0125	NEQ flag	_NEQ	F0125	NEQ flag	
F0126 ~ F012F	N/A	-	F0126 ~ F012F	N/A	
F0130~ F013F	AC Down Count	_AC_F_CNT	F0130~ F013F	AC Down Count	
F0140~ F014F	FALS no.	_FALS_NUM	F0140~ F014F	FALS no.	
		_PUTGET_ERR	F0150~ F030F	PUT/GET error flag	
F0150 F015E	PUT/GET error flag	CPU TYPE	F0440 ~ F044F	CPU TYPE	
F0150~ F015F	FUI/GET error liag	CPU VERSION	F0450 ~ F045F	CPU VERSION	
		OS version no.	F0460 ~ F047F	System OS version no.	
F0160~ F049F	N/A	OS date	F0480 ~ F049F	System OS DATE	

MA	MASTER-K XGB			
Device	Function	Symbol	Device	Function
F0500~ F050F	Max. Scan time	_SCAN_MAX	F0500~ F050F	Max. Scan time
F0510~ F051F	Min. Scan time	_SCAN_MIN	F0510~ F051F	Min. Scan time
F0520~ F052F	Current Scan time	_SCAN_CUR	F0520~ F052F	Current Scan time
F0530~ F053F	Clock data (year/month)	_YEAR_MON	F0530~ F053F	Clock data (year/month)
F0540~ F054F	Clock data (day/hr)	_DAY_TIME	F0540~ F054F	Clock data(day/hr)
F0550~ F055F	Clock data (min/sec)	_MIN_SEC	F0550~ F055F	Clock data(min/sec)
F0560~ F056F	Clock data (100year/weekday)	_HUND_WK	F0560~ F056F	Clock data(100year/weekday)
		_FPU_LFlag_I	F0570	-
		_FPU_LFlag_U	F0571	-
		_FPU_LFlag_O	F0572	-
		_FPU_LFlag_Z	F0573	-
		_FPU_LFlag_V	F0574	-
		-	F0575 ~ F0579	N/A
F0570~ F058F	N/A	_FPU_Flag_I	F057A	-
		_FPU_Flag_U	F057B	-
		_FPU_Flag_O	F057C	-
		_FPU_Flag_Z	F057D	-
		_FPU_Flag_V	F057E	-
		_FPU_Flag_E	F057F	-
		Error Step	F0580~ F058F	Error step save
F0590~ F059F	Error step save	-	F0590~ F059F	N/A
F0600~ F060F	FMM detailed error information	_REF_COUNT	F060~F061	Refresh Count
		_REF_OK_CNT	F062~F063	Refresh OK Count
		_REF_NG_CNT	F064~F065	Refresh NG Count
		_REF_LIM_CNT	F066~F067	Refresh Limit Count
		_REF_ERR_CNT	F068~F069	Refresh Error Count
F0040 F000F	N/A	_MOD_RD_ERR_CNT	F070~F071	MODULE Read Error Count
F0610~ F063F	N/A	_MOD_WR_ERR_CNT	F072~F073	MODULE Write Error Count
		_CA_CNT	F074~F075	Cmd Access Count
		_CA_LIM_CNT	F076~F077	Cmd Access Limit Count
		_CA_ERR_CNT	F078~F079	Cmd Access Error Count
		_BUF_FULL_CNT	F080~F081	Buffer Full Count

Appendix 4 Instruction List

Appendix 4.1 Classification of Instructions

Classification	Instructions	Details	Remarks
	Contact Point Instruction	LOAD, AND, OR related Instructions	
Basic	Unite Instruction	AND LOAD, OR LOAD, MPUSH, MLOAD, MPOP	
	Reverse Instruction	NOT	
	Master Control Instruction	MCS, MCSCLR	
	Output Instruction	OUT, SET, RST, 1 Scan Output Instruction, Output Reverse Instruction (FF)	
Instructions	Sequence/Last-input Preferred Instruction	Step Control Instruction (SET Sxx.xx, OUT Sxx.xx)	
	End Instruction	END	
	Non-Process Instruction	NOP	
	Timer Instruction	TON, TOFF, TMR, TMON, TRTG	
	Counter Instruction	CTD, CTU, CTUD, CTR	
	Data Transfer Instruction	Transfers specified Data, Group, String	4/8/64 Bits available
	Conversion Instruction	Converts BIN/BCD of specified Data & Group	4/8 Bits available
	Data Type Conversion Instruction	Converts Integer/Real Number	
	Output Terminal Compare Instruction	Saves compared results in special relay	Compare to Unsigned
	Input Terminal Compare Instruction	Saves compared results in BR. Compares Real Number, String & Group. Compares 3 Operands	Compare to Signed
	Increase/Decrease Instruction	Increases or decreases specified data 1 by 1	4/8 Bits available
	Rotate Instruction	Rotates specified data to the left and right, including Carry	4/8 Bits available
	Move Instruction	Moves specified data to the left and right, word by word, bit by bit	4/8 Bits available
	Exchange Instruction	Exchanges between devices, higher & lower byte, group data	
	BIN Operation Instruction	Addition, Subtraction, Multiplication & Division for Integer/ Real Number, Addition for String, Addition & Subtraction for Group	
Analtantan	BCD Operation Instruction	Addition, Subtraction, Multiplication, Division.	
Application Instructions	Logic Operation Instruction	Logic Multiplication, Logic Addition, Exclusive OR, Exclusive NOR, Group Operation	
	System Instruction	Error Display, WDT Initialize, Output Control, Operation Stop, etc.	
	Data Process Instruction	Encode, Decode, Data Disconnect/Connect, Search, Align, Max., Min., Total, Average, etc.	
	Data Table Process Instruction	Data Input/Output of Data Table	
	String Process Instruction	String related Convert, Comment Read, String Extract, ASCII Convert, HEX Convert, String Search, etc.	
	Special Function Instruction	Trigonometric Function, Exponential/Log Function, Angle/Radian Convert, etc.	
	Data Control Instruction	Max/Min Limit Control, Dead-zone Control, Zone Control	
	Time related Instruction	Date Time Data Read/Write, Time Data Adjust & Convert	
	Diverge Instruction	JMP, CALL	
	Loop Instruction	FOR/NEXT/BREAK	
	Flag related Instruction	Carry Flag Set/Reset, Error Flag Clear	
	Special/Communication related Instruction	Data Read/Write by BUSCON Direct Access	
	Interrupt related Instruction	Interrupt Enable/Disable	
	Signal Reverse Instruction	Reverse Integer/Real Signals, Absolute Value Operation	

Appendix 4.2 Basic Instructions

1) Contact point instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Зупьы	Description	XGK	XGB
	LOAD	$\vdash\vdash\vdash$	A Contact Point Operation Start	0	0
	LOAD NOT		B Contact Point Operation Start	0	0
	AND	— I	A Contact Point Series- Connected	0	0
	AND NOT		B Contact Point Series- Connected	0	0
	OR	<u></u>	A Contact Point Parallel- Connected	0	0
Contact	OR NOT		B Contact Point Parallel- Connected	0	0
Contact Point	LOADP	P	Positive Convert Detected Contact Point	0	0
	LOADN	N	Negative Convert Detected Contact Point	0	0
	ANDP	— P —	Positive Convert Detected Contact Point Series-Connected	0	0
	ANDN	— N —	Negative Convert Detected Contact Point Series-Connected	0	0
	ORP	└─ │ P ├ ──	Positive Convert Detected Contact Point Parallel-	0	0
	ORN	□ N I □	Negative Convert Detected Contact Point Parallel-	0	0

2) Union instruction

Classification	Designations	Symbol	Description	Support	
Classification	Designations	Symbol	Description	XGK	XGB
AND LOAD A,B Block Series-Connected OR LOAD A,B Block Parallel-Connected Operation Result Push up to present	AND LOAD	A B	A,B Block Series-Connected	0	0
	0	0			
Unite	MPUSH	Operation Result Push up to	0	0	
	MLOAD	MLOAD	Operation Result Load Previous to Diverge Point	0	0
	MPOP	MPOP	Operation Result Pop Previous to Diverge Point	0	0

3) Reverse instruction

Classification	Designations	Symbol	Description	Support	
				XGK	XGB
Reverse	NOT		Previous Operation results Reverse	0	0

4) Master Control instruction

Classification	Designations Symbol		Description	Support	
Ciassification	Designations	Зушьы	Description	XGK	XGB
Master	MCS	- MCS n	Master Control Setting (n:0~7)	0	0
Control	MCSCLR	MCSCLR n	Master Control Cancel (n:0~7)	0	0

5) Output instruction

Classification	Designations	Symbol	Description	Sup	oport
Classification	Designations	Symbol	Description	XGK	XGB
	OUT	—()—	Operation Results Output	0	0
	OUT NOT	—(/)—	Operation Results Reverse Output	0	0
	OUTP	——(P)—	1 Scan Output if Input Condition rises	0	0
Output	OUTN	Operation Results Output Operation Results Reverse Output 1 Scan Output if Input	0	0	
	SET		0	0	
	RST	——(R)—		0	0
	FF	—FF D		0	0

6) Sequence/Last-input preferred instruction

Classification	Designations	Cumbal	Description	Support	
Classification	Designations	Symbol	Description	XGK	XGB
Step	SET S	(S)	Sequence Control	0	0
Control	OUT S	(Last-input Preferred	0	0

7) End instruction

Classification	sification Designations	Cymhol	Description	Support	
Classification		Designations Symbol		XGK	XGB
End	END	— END	Program End	0	0

8) Non-process instruction

Classification	Designations	Cumbal	Description	Sup	oport
Classification	Designations	Symbol	Description	XGK	XGB
Non-Process	NOP	Ladder not displayed	Non-Process Instruction, used in Nimonic	0	0

9) Timer instruction

Classification	Designations	Symbol	Description	Sup	port
Ciassification	Designations	Cymbol	Description	XGK	XGB
	TON	—TON T t	Input t →	0	0
	TOFF	—TOFF T t	Inputt	0	0
Timer	TMR	— TMR T t	Input	0	0
	TMON	TMON T t	Input t →	0	0
	TRTG	-TRTG T t	Input	0	0

10) Counter instruction

Counter in	istruction			Cur	nort
Classification	Designations	Symbol	Description	XGK	port XGB
	CTD	—CTD C c	Reset Count Pulse Setting Present Output	· ·	0
	СТИ	—[СТИ ССЬ	Reset Count Pulse Setting Present Output	0	0
Counter	CTUD	— CTUD CUDC	Reset Increased Pulse Decreased Pulse Present Output	0	0
	CTR	—CTR C c ⊢	Reset Count Pulse Setting Present Output	0	0

Appendix 4.3 Application Instruction

1) Data transfer instruction

Data transfe			Dogorintian	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
16 bits	MOV	MOV SD	(0)	0	0
Transfer	MOVP	MOVP S D	(S) (D)	0	0
32 bits	DMOV	— DMOV SD	(2.12)	0	0
Transfer	DMOVP	— DMOVP SD	(S+1,S) → (D+1,D)	0	
Short Real Number	RMOV	-RMOV SD	(S+1,S) → (D+1,D)	0	0
Transfer	RMOVP	- RMOVP S D	(3+1,3)		
Long	LMOV	- LMOV SD	(S+3,S+2,S+1,S)	_	
Real Number Transfer	LMOVP	LMOVP SD-	→ (D+3,D+2,D+1,D)	0	0
4 bits	MOV4	MOV4 Sb Db	(Sb): Bit Position b15 b0 4bit trans	0	0
Transfer	MOV4P	MOV4P Sb Db	(Db): Bit Position	0	0
8 bits	MOV8	MOV8 Sb Db	(Sb): Bit Position	0	0
Transfer	MOV8P	MOV8P Sb Db	8bit trans (Db): Bit Position	O	O
	CMOV	— CMOV SD	1's complement	0	0
1's complement	CMOVP	-CMOVP S D	(S) ———(D)	O	O
Transfer	DCMOV	— DCMOV SD	1's complement	0	0
	DCMOVP	DCMOVP S D	(S+1,S) → (D+1,D))	
16 bits	GMOV	GMOV S D N	(S) (D) ↑N	0	0
Group Transfer	GMOVP	GMOVP S D N			
Multiple	FMOV	-FMOV S D N	(S) (D)	0	0
Transfer	FMOVP	-FMOVP S D N	→	Ŭ	
Specified Bits	BMOV	-BMOV S D N	(S) b0	0	0
Transfer	BMOVP	BMOVP S D N	(D) * Z: Control Word		
Specified Bits	GBMOV	- GBMOV S D Z N	(S) b15 b0 IN (S+N)	0	0
Group Transfer	GBMOVP	— GBMOVP S D Z N	(D+N) * Z: Control Word	0	0

1) Data Transfer Instruction (continued)

Classification	Designations Symbol	Description	Support		
Classification	Designations	Symbol	Description	XGK	XGB
String	\$MOV		String started from (S)	0	0
Transfer	\$MOVP		String started from (D)	0	0

2) BCD/BIN conversion instruction

Classification	Designations	Symbol	Description	-	port
Jiassilleation	Designations	бушьбі	·	XGK	XGB
	BCD	BCD S D	(S) — To BCD (D)	0	0
BCD	BCDP	BCDP S D	BIN(0~9999)	O	0
Conversion	DBCD	DBCD SD-	(S+1,S)	0	0
	DBCDP	— DBCDP S D	BIN(0~9999999)	0	0
	BCD4	BCD4 Sb Db	(Sb):Bit, BIN(0~9)	0	0
4/8 Bits BCD	BCD4P	BCD4P Sb Db	To 4bit BCD (Db): Bit	-	-
Conversion	BCD8	BCD8 Sb Db	(Sb):Bit, BIN(0~99) b15	0	0
	BCD8P	BCD8P Sb Db	To 8bit BCD (Db):Bit))
	BIN	-BIN S D	(S) To BIN (D)	0	0
BIN	BINP	-BINP S D	1 BCD(0∼9999)	0	O
Conversion	DBIN	DBIN S D	(S+1,S) To BIN (D+1,D)		
	DBINP	— DBINP S D	BCD(0~9999999)	0	0
	BIN4	BIN4 Sb Db	(Sb):Bit, BCD(0~9)	0	0
4/8 Bits BIN	BIN4P	BIN4P Sb Db	To 4bit BIN (Db):Bit		0
Conversion	BIN8	BIN8 Sb Db	(Sb):Bit, BCD(0~99)	0	0
	BIN8P	BIN8P Sb Db	To bit BIN (Db):Bit	Ü	O
	GBCD	GBCD S D N	☐ Data (S) to N converted to BCD,	0	0
Group BCD,BIN	GBCDP	GBCDP S D N	and (D) to N saved		0
Conversion	GBIN	GBIN S D N	□ Data (S) to N converted to BIN,	_	
	GBINP	GBINP S D N	and (D) to N saved	0	0

3) Data type conversion instruction

Classification	Designations	Symbol	Description	Sup	port		
Classification	Designations	Designations	Designations	Symbol	Description	XGK	XGB
	I2R	- I2R S D	(S) To Real (D+1,D)	0	0		
16 Bits Integer/Real	I2RP	— I2RP S D	Int(-32768~32767)				
Conversion	I2L	—[12L S D	$(S) \xrightarrow{\text{To Long}} (D+3,D+2,D+1,D)$	0	0		
	I2LP	— I2LP S D	Int(-32768~32767)				
	D2R	— D2R S D	(S+1,S) To Real $(D+1,D)$	0	0		
32 Bits Integer/Real	D2RP	D2RP S D	Dint(-2147483648~2147483647))	0		
Conversion	D2L	— D2L S D	(S+1,S) To Long (D+3,D+2,D+1,D)	0	0		
	D2LP	— D2LP S D	Dint(-2147483648~2147483647)		0		
	R2I	— R2I S D	(S+1,S)	0	0		
Short Real/Integer	R2IP	R2IP S D	Whole Sing Real Range		0		
Conversion	R2D	-R2D S D	(S+1,S)	0	0		
	R2DP	R2DP S D	Whole Sing Real Range))		
	L2I	— L2I S D	$(S+3,S+2,S+1,S) \xrightarrow{\text{To INT}} (D)$	0	0		
Long Real/Integer	L2IP	L2IP S D	Whole Double Real Range	0	0		
Conversion	L2D	— L2D S D	$(S+3,S+2,S+1,S) \xrightarrow{\text{To DINT}} (D+1,D)$	0			
	L2DP	L2DP S D	Whole Double Real Range	0	0		

Remark

1) Integer value and Real value will be saved respectively in quite different format. For such reason, Real Number Data should be converted as applicable before used for Integer Operation.

4) Comparison instruction

Classification	Designations	Symbol	Description	Sup	port
Ciassilication	Designations	Зушрог	Description	XGK	XGB
Unsigned	CMP		CMP(S1,S2) and applicable Flag SET	0	0
Compare	СМРР		(S1, S2 is Word)	0	O
with Special Relay	DCMP	DCMP S1 S2	CMP(S1,S2) and applicable Flag SET	0	
used	DCMPP	DCMPP S1 S2	(S1, S2 is Double Word)	0	0
	CMP4		CMP(S1,S2) and applicable Flag SET	0	0
4/8 Bits	CMP4P	CMP4P S1 S2	(S1, S2 is Nibble)	0	0
Compare	CMP8		CMP(S1,S2) and applicable Flag SET	0	0
	CMP8P		(S1, S2 is Byte)	0	0
	TCMP	TCMP S1 S2 D	CMP(S1,S2))		
Table	TCMPP	TCMPP S1 S2 D	CMP(S1+15,S2+15) Result:(D) ~ (D+15), 1 if identical	0	0
Compare	DTCMP	— DTCMP S1 S2 D	CMP((S1+1,S1),(S2+1,S2)) CMP((S1+31,S1+30),(S2+31,S2+30)) Result:(D) ~ (D+15)		
	DTCMPP	OTCMPP S1 S2 D		0	0
	GEQ	— GEQ S1 S2 D N			
	GEQP				
	GGT	— GGT S1 S2 D N			
	GGTP				
	GLT				
Group Compare	GLTP		Compares S1 data to S2 data word by word, and saves its result in Device (D) bit by bit from the lower	0	
(16 Bits)	GGE		bit $(N \le 16)$	0	0
	GGEP		(N \(\) (0)		
	GLE				
	GLEP				
	GNE				
	GNEP				

Remark

1) CMP(P), DCMP(P), CMP4(P), CMP8(P), TCMP(P) & DTCMP(P) Instructions all process the results of Unsigned Compare. All the other Compare Instructions will perform Signed Compare.

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	GDEQ S1S2DN	0	0		
	GDEQP	GDEQP S1 S2 D N		0	0
	GDGT			0	0
	GDGTP	GDGTP S1 S2 D N		0	0
	GDLT		Compares S1 data to S2 data 2 by 2 words, and saves its result in Device (D) bit by bit from the lower bit $ (N\leq16) $	0	0
Group Compare	GDLTP			0	0
(32 Bits)	GDGE			0	0
	GDGEP	GDGEP S1 S2 D N		0	0
	GDLE			0	0
	GDLEP	GDLEP S1 S2 D N		0	0
	GDNE			0	0
	GDNEP	GDNEP S1 S2 D N		0	0

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	LOAD=	= S1 S2			
	LOAD>	> S1 S2 —	Compares (S1) to (S2), and saves its result in Bit Result(BR) (Signed		
16 Bits Data	LOAD<	< S1 S2 —		0	0
Compare (LOAD)	LOAD>=	>= S1 S2	Operation)	O	0
	LOAD<=	<= S1 S2			
	LOAD<>				
	AND=	⊢⊢= S1 S2 —			
	AND>		Performs AND operation of (S1) &		
16 Bits Data	AND<	S1 S2	(S2) Compare Result and Bit Result (BR), and then saves its result in BR (Signed Operation)	0	0
Compare (AND)	AND>=			Ü	Ö
	AND<=	⊢			
	AND<>	H ← S1 S2 —			
16 Bits	OR=	= S1 S2	Performs OR operation of (S1) & (S2) Compare Result and Bit Result (BR), and then saves its result in BR (Signed Operation)		
Data Compare	OR<=	<= S1 S2		0	0
(OR)	OR<>	<> S1 S2			
	LOADD=	D= S1 S2			
	LOADD>	D> S1 S2			
32 Bits Data	LOADD<	D< S1 S2	Compares (S1) to (S2), and saves its result in Bit Result(BR) (Signed		
Compare (LOAD)	LOADD>=	D>= S1 S2	Operation)		
(==,,,)	LOADD<=	D<= S1 S2			
	LOADD<>	D<> S1 S2			

Remark

Comparison instruction for input process the result of Signed comparison instruction generally. To process Unsigned comparison, Use comparison instruction for input.

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	ANDD=				
32 Bits	ANDD<		Performs AND operation of (S1) &		
Data Compare	ANDD>=		(S2) Compare Result and Bit Result (BR), and then saves its result in	0	0
(AND)	ANDD<=		BR (Signed Operation)		
	ANDD<>				
	ORD=	D= S1 S2			
	ORD>	D> S1 S2			
32bt Data	ORD<	D< \$1 \$2	Performs OR operation of (S1) & (S2) Compare Result and Bit Result (BR), and then saves its result in BR (Signed Operation)	0	
Compare (OR)	ORD>=	D>= S1 S2		0	0
	ORD<=	D<= S1 S2			
	ORD<>	D<> S1 S2			
	LOADR=	R= S1 S2			
	LOADR>				
Short Real Number	LOADR<	R< S1 S2	Performs OR operation of (S1) & (S2) Compare Result and Bit Result		
Compare (LOAD)	LOADR>=	R>= S1 S2	(BR), and then saves its result in BR (Signed Operation)	0	0
	LOADR<=	R<= S1 S2			
	LOADR<>	R<> S1 S2			
	ANDR=	⊢⊢R= S1 S2 —			
	ANDR>				
Short Real Number	ANDR<	H R< S1 S2 H S2 H	Compares (S1+1,S) to (S2+1,S2) and saves its result in Bit Result	0	0
Compare (AND)	ANDR>=		(BR) (Signed Operation)		
	ANDR<=	H⊢R<= S1 S2			
	ANDR<>	H-R<> S1 S2-			

Classification	Designations	Symbol	Description		port
				XGK	XGB
	ORR=	R= S1 S2			
	ORR>	R> S1 S2			
Real Number	ORR<	R< \$1 \$2	Compares (S1+1,S1) to (S2+1,S2) and saves its result in Bit Result		
Compare (OR)	ORR>=	R>= S1 S2	(BR) (Signed Operation)	0	0
	ORR<=	R<= S1 S2			
	ORR<>	R<> S1 S2			
	LOADL=	L= S1 S2	Compares (S1+3,S1+2,S1+1,S) to (S2+3,S2+2, S2+1,S2) and saves its		
	LOADL>	L> S1 S2			
Long Real Number	LOADL<	L< \$1 \$2		0	0
Compare (LOAD)	LOADL>=	L>= S1 S2	result in Bit Result(BR) (Signed Operation)	0	0
	LOADL<=	L<= S1 S2			
	LOADL<>	L<> S1 S2			
	ANDL=				
	ANDL>				
Long Real Number	ANDL<		Performs AND operation of (S1+1,S1) & (S2+1,S2) Compare Result and Bit Result(BR), and then saves	0	0
Compare (AND)	ANDL>=		its result in BR (Signed Operation)	0	0
	ANDL<=				
	ANDL<>				

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	ORL=	L= S1 S2			
	ORL>	L> S1 S2			
Double Real Number	ORL<	L< \$1 \$2	Performs OR operation of (S1 +1,S1) & (S2+1,S2) Compare Result and Bit Result(BR), and	0	0
Compare (OR)	ORL>=	L>= S1 S2	then saves its result in BR (Signed Operation)	O	O
	ORL<=	L<= \$1 \$2			
	ORL<>	L<> \$1 \$2			
	LOAD\$=	\$= S1 S2	Compares (S1) to (S2) Starting String and saves its result in Bit Result(BR)		
	LOAD\$>	\$> S1 S2			
String Compare	LOAD\$<	\$< \$1 \$2		0	0
(LOAD)	LOAD\$>=	\$>= S1 S2		Ü	Ö
	LOAD\$<=	\$<= S1 S2			
	LOAD\$<>	\$<> S1 S2			
	AND\$=				
	AND\$>	\$> S1 S2			
String Compare	AND\$<		Performs AND operation of (S 1) & (S2) Starting String Compare	0	0
(AND)	AND\$>=		Result and Bit Result(BR), and then saves its result in BR		
	AND\$<=				
	AND\$<>				

Classification	Designations	Symbol	Description	Sup	
Ciadomoation	Doorgilations	Cymbol	Description	XGK	XGB
	OR\$=	\$= S1 S2			
	OR\$>	\$> S1 S2			
String	OR\$<	\$< \S1\S2	Performs OR operation of (S1) & (S2) Starting String Compare		
Compare (OR)	OR\$>=	\$>= S1 S2	Result and Bit Result(BR), and then saves its result in BR	0	0
	OR\$<=	\$<= S1 S2			
	OR\$<>	\$ \$1 \$2			
	LOADG=	G= S1 S2 N			
	LOADG>	G> S1 S2 N	Compares (C1) (C1.11)		
16 Bits	LOADG<	G< S1 S2 N	Compares (S1), (S1+1),, (S1+N) to (S2), (S2+1),, (S2+N) 1 to 1 and then solved		
Data Group Compare (LOAD)	LOADG>=	G>= S1 S2 N	(S2+N) 1 to 1, and then saves 1 in Bit Result(BR) if each value compared meets given condition	0	0
	LOADG<=	G<= S1 S2 N			
	LOADG<>	G<> S1 S2 N			
	ANDG=				
	ANDG>	HHG> S1 S1 N	Performs AND operation of		
16 Bits Data	ANDG<		(S1), (S1+1), ···, (S1+N) & (S2), (S2+1), ···, (S2+N) 1 to		
Group Compare (AND)	ANDG>=		1 Compare Result and Bit Result (BR), and then saves its	0	0
	ANDG<=		result in BR		
	ANDG<>				
	ORG=	G= S1 S2 N			
	ORG>	G> S1 S2 N			
16 Bits Data	ORG<	G< S1 S2 N	Performs OR operation of (S1), (S1+1),, (S1+N) & (S2), (S2+1),, (S2+N) 1 to 1		
Group Compare (OR)	ORG>=	G>= S1 S2 N	Compare Result and Bit Result (BR), and then saves its result in BR	0	0
	ORG<=	G<= S1 S2 N			
	ORG<>	G<> S1 S2 N			

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Зупівої	Description	XGX	XGB
	LOADDG=	DG= S1 S2 N — DG> S1 S2 N —			
32 Bits Data	LOADDG<	DG< S1 S2 N	Compares (S1), (S1+1),, (S1+N) to (S2), (S2+1),,		
Group Compare	LOADDG>=	DG>= S1 S2 N	(S2+N) 1 to 1, and then saves 1 in Bit Result(BR) if each value compared meets given	0	0
(LOAD)	LOADDG<=	DG<= S1 S2 N	condition		
	LOADDG<>	DG<> \$1 \$2 N			
	ANDDG=	H-DG= S1 S1 N			
	ANDDG>	HHDG> S1 S1 N	Performs AND operation of (S1), (S1+1),, (S1+N) & (S2), (S2+1),, (S2+N) 1 to 1 Compare Result and Bit Result(BR), and then saves its result in BR		
32 Bits Data Group	ANDDG<	H⊢DG< S1 S1 N		0	0
Compare (AND)	ANDDG>=				0
(/ ((12)	ANDDG<=				
	ANDDG<>				
	ORDG=	DG= S1 S2 N			
	ORDG>	DG> S1 S2 N			
32 Bits Data	ORDG<	DG< S1 S2 N	Performs OR operation of (S1), (S1+1),, (S1+N) & (S2), (S2+1),, (S2+N) 1 to		
Group Compare (OR)	ORDG>=	DG>= S1 S2 N	1 Compare Result and Bit Result(BR), and then saves its result in BR	0	0
	ORDG<=	DG<= S1 S2 N			
	ORDG<>	DG<> S1 S2 N			

Classification	Designations	Symbol	Description	Sup	
Jassinoation	_		Безоприон	XGK	XGB
	LOAD3=	3= S1 S2 S3			
	LOAD3>	3> S1 S2 S3 —			
Three 16-Bit	LOAD3<	3< S1 S2 S3 —	Saves 1 in Bit Result(BR) if each value of (S1), (S2), (S3) meets	0	0
Data Compare (LOAD)	LOAD3>=	3>= S1 S2 S3	given condition	O	O
	LOAD3<=	3<= \$1 \$2 \$3			
	LOAD3<>	3<> S1 S2 S3			
	AND3=				
	AND3>				
Three 16-Bit	AND3<	 	Performs AND operation of (S1), (S2), (S3) Compare Result by		
Data Compare (AND)	AND3>=		given condition and Bit Result (BR), and then saves its result in BR	0	0
	AND3<=		- DK		
	AND3<>				
	OR3=	3= S1 S2 S3			
	OR3>	3> S1 S2 S3			
Three 32-Bit	OR3<	<3 S1 S2 S3	Performs OR operation of (S1), (S2), (S3) Compare Result by		
Data Compare (OR)	OR3>=	>=3 S1 S2 S3	given condition and Bit Result (BR), and then saves its result in BR	0	0
	OR3<=	3<= S1 S2 S3			
	OR3<>	3<> \$1 \$2 \$3			
	LOADD3=	D3= S1 S2 S3			
	LOADD3>	D3> S1 S2 S3			
Three 16-Bit	LOADD3<	D3< S1 S2 S3	Saves 1 in Bit Result(BR) if each		
Data Compare (LOAD)	LOADD3>=	D3>= S1 S2 S3	value of (S1+1,S1), (S2+ 1,S2), (S3+1,S3) meets given condition	0	0
	LOADD3<=	D3<= S1 S2 S3			
	LOADD3<>	D3<> S1 S2 S3			

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	ANDD3=	⊢ D3= S1 S2 S3			
	ANDD3>	⊢⊢D3> S1 S2 S3 —			
Three 32-Bit	ANDD3<	⊢⊢D3< S1 S2 S3—	Performs AND operation of (S1+1,S1), (S2+1,S2), (S3+1,S3) Compare		_
Data Compare (AND)	ANDD3>=		Result by given condition and Bit Result (BR), and then saves its result in BR	0	0
	ANDD3<=				
	ANDD<>				
	ORD3=	D3= S1 S2 S3	Performs OR operation of (S1+1, S1), (S2+1,S2), (S3+1,S3) Compare		
	ORD3>	D3> S1 S2 S3			
Three 32-Bit	ORD3<	D3< S1 S2 S3		0	0
Data Compare (OR)	ORD3>=	D3>= S1 S2 S3	Result by given condition and Bit Result (BR), and then saves its result in BR	0	O
	ORD3<=	D3<= S1 S2 S3			
	ORD3<>	D3<> S1 S2 S3			

5) Increase/Decrease instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Зушьы	Description	XGK	XGB
	INC	- INC D	(D)+1 → (D)	2	
	INCP	INCP D	(0)	2	4-94
	DINC	— DINC D	(D+1,D)+1 → (D+1,D)	2	4-94
BIN Data Increase /	DINCP	— DINCP D	(0.1,0)	2	
Decrease (Signed)	DEC	— DEC D	(D)-1 (D)	2	
(Oigrica)	DECP	— DECP D		2	4-96
	DDEC	— DDEC D	(D+1,D)−1 → (D+1,D)	2	4-90
	DDECP	— DDECP D	, , , ,	2	
	INC4	[INC4 Db	(D:x bit ~ D:x bit+4) + 1	2	
	INC4P	INC4P Db	——→ (D:x bit ~ D:x bit+4)	3	4.05
	INC8	INC8 Db	(D:x bit ~ D:x bit+8) + 1	2	4-95
4/8 Bits Data Increase /	INC8P	INC8P Db	→ (D:x bit ~ D:x bit+8)	3	
Decrease (Signed)	DEC4	DEC4 Db	(D:x bit ~ D:x bit+4) - 1	2	
(Oigrica)	DEC4P	DEC4P Db	$\longrightarrow (D:x bit \sim D:x bit+4)$	3	4-97
	DEC8	DEC8 Db	(D:x bit ~ D:x bit+8) - 1	2	4-97
	DEC8P	DEC8P Db	→ (D:x bit ~ D:x bit+8)	3	
	INCU	INCU D	(D)+1 → (D)		
	INCUP	INCUP D		2	4.00
	DINCU	— DINCU D	(D+1,D)+1 → (D+1,D)		4-98
BIN Data Increase	DINCUP	— DINCUP D		2	
/ Decrease (Unsigned)	DECU	— DECU D	(D)−1 → (D)	_	
(Onsigned)	DECUP	DECUP D		2	4.00
	DDECU	— DDECU D	(D+1,D)−1 → (D+1,D)		4-99
	DDECUP	— DDECUP D		2	

6) Rotation instruction

Ola asiti asti as	Danimatiana	0		Description	Sup	port
Classification	Designations	Symbol		Description	XGK	XGB
	ROL	— ROL	D n	b <u>15</u> b0		
D-1-1- 1- 1-ft	ROLP	— ROLP	D n	CY D		
Rotate to Left	DROL	— DROL	D n	b31 b15 b0	0	0
	DROLP	— DROLP	D n			
	ROL4	-ROL4	Db n	b+3 b		
4/8 Bits	ROL4P	ROL4P	Db n			
Rotate to Left	ROL8	ROL8	Db n	b+7 b	0	0
	ROL8P	— ROL8P	Db n			
	ROR	— ROR	D n	b15 b0		
Datata ta Diaht	RORP	— RORP	D n	D		
Rotate to Right	DROR	— DROR	D n	b31 b15 b0	0	0
	DRORP	— DRORP	D n	D+1 D CY		
	ROR4	— ROR4	Db n	b+3 b CY b+7 b CY		
4/8 Bits	ROR4P	ROR4P	Db n		_	_
Rotate to Right	ROR8	ROR8	Db n		0	0
	ROR8P	ROR8P	Db n			
	RCL	— RCL	D n	b15 b0		
Rotate to Left	RCLP	—RCLP	D n	CY D		
(including Carry)	DRCL	— DRCL	D n	b31 b15 b0	0	0
	DRCLP	— DRCLP	D n	CY		
	RCL4	-RCL4	Db n	CY		
4/8 Bits Rotate to Left	RCL4P	— RCL4P	Db n		0	0
(including Carry)	RCL8	RCL8	Db n	b+7 b b d d d d d d d d d d d d d d d d d		O
,,	RCL8P	- RCL8P	Db n			
	RCR	— RCR	D n	b15 b0		
Rotate to Right	RCRP	— RCRP	D n	D		
(including Carry)	DRCR	— DRCR	D n	b31 b15 b0 CY	0	0
	DRCRP	— DRCRP	D n	D+1 D CY		
	RCR4	—RCR4	Db n	b+3 b CY		
4/8 Bits Rotate to Right	RCR4P	— RCR4P	Db n			_
(including Carry)	RCR8	— RCR8	Db n	b+7	0	0
	RCR8P	— RCR8P	Db n			

7) Move instruction

Classification	Designations	Correland	December	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Dita Maya	BSFT	BSFT St Ed	St Ed b15 b0	_	
Bits Move	BSFTP	BSFTP St Ed	† 0	0	0
	BSFL	BSFL D n	b15 b0 (D)		
Move to Higher	BSFLP	BSFLP D n	↑ 0	0	0
Bit	DBSFL	— DBSFL D n	(D+1, D)	0	O
	DBSFLP	— DBSFLP D n	CY 0		
	BSFL4	BSFL4 Db n	b+3 b		
Move to Higher Bit within 4/8	BSFL4P	BSFL4P Db n	CY	0	0
Bits range	BSFL8	BSFL8 Db n	b+7 b	0	0
	BSFL8P	BSFL8P Db n	CY		
	BSFR	BSFR D n	(D) D0	- 0	
Move to Lower	BSFRP	BSFRP D n	O CY		0
Bit	DBSFR	DBSFR D n	(D+1, D) b0		O
	DBSFRP	DBSFRP D n	T CY		
	BSFR4	BSFR4 Db n	b+3 b		
Move to Lower Bit within 4/8	BSFR4P	BSFR4P Db n	0 CY	0	0
Bits range	BSFR8	BSFR8 Db n	b+7 b	O	0
	BSFR8P	BSFR8P Db n	O CY		
Word Move	WSFT		h0000 — St (Start Word)	0	0
vvoid iviove	WSFTP		:	0	O
	WSFL	WSFL D1 D2 N	h0000		
Word Data Move to	WSFLP	WSFLP D1 D2 N	: \ \z\ _{D2}	0	0
Left/Right	WSFR	WSFR D1 D2 N	□ □ □ □		0
	WSFRP		h0000		
Bit Move	SR	SR Db I D N	Moves N bits starting from Db bit along Input direction (I) and Move direction (D)	0	0

8) Exchange instruction

Classification	Designations	Symbol	Description	Supp	port
Classification	Designations	Зупівої	Description	XGK	XGB
	XCHG	—XCHG D1 D2	(D1) ← → (D2)		
Data	XCHGP	—XCHGP D1 D2	(= -/	0	0
Exchange	DXCHG	DXCHG D1 D2	(D1+1, D1) ← → (D2+1, D2)	Ö	O
	DXCHGP	DXCHGP D1 D2			
Group Data	GXCHG	GXCHG D1 D2 N	(D1) (D2) I	0	0
Exchange	GXCHGP	GXCHGP D1 D2 N		Ò	O
Higher/Lower Byte	SWAP	SWAP D	(D) Upper Byte Lower Byte	0	0
Exchange	SWAPP	SWAPP D	(D) Lower Byte Upper Byte))
Group Byte	GSWAP	—GSWAP D N	Exchanges Higher/Lower	0	0
Exchange	GSWAPP	GSWAPP D N	Byte of Words N starting from D		9

9) BIN operation instruction

Classification Designations		Symbol	Description	Support	
Olabbilloalibil	Designations		Бозоприон	XGK	XGB
	ADD	— ADD S1 S2 D	(S1)+(S2) → (D)		
Integer Addition	ADDP	ADDP S1 S2 D		. 0	0
(Signed)	DADD	— DADD S1 S2 D	(S1+1,S1)+(S2+1,S2)		Ü
	DADDP	— DADDP S1 S2 D	——→ (D+1,D)		
	SUB		(S1)-(S2) → (D)		
Integer Subtraction	SUBP		(61) (62)	. 0	0
(Signed)	DSUB		(S1+1,S1)-(S2+1,S2)		0
	DSUBP	— DSUBP S1 S2 D	——→ (D+1,D)		
	MUL		(0.1)		
Integer Multiplication	MULP	- MULP S1 S2 D	(S1)×(S2) → (D+1,D)	. 0	0
(Signed)	DMUL		(S1+1,S1)×(S2+1,S2)		0
	DMULP	- DMULP S1 S2 D	→ (D+3,D+2,D+1,D)		
	DIV	— DIV S1 S2 D	$(S1) \div (S2) \longrightarrow (D)$ Quotient $(D+1)$ Remainder		
Integer Division	DIVP		(S1)÷(S2) → (D+1) Remainder	. 0	0
(Signed)	DDIV	— DDIV S1 S2 D	(S1+1,S1)÷(S2+1,S2)		O
	DDIVP	— DDIVP S1 S2 D	(D+1,D) Quotient (D+3,D+2) Remainder		
	ADDU	ADDU S1 S2 D	(S1)+(S2) → (D)		
Integer Addition	ADDUP	ADDUP S1 S2 D	(31)+(32)	_	
(Unsigned)	DADDU	— DADDU S1 S2 D	(S1+1,S1)+(S2+1,S2)	0	0
	DADDUP	— DADDUP S1 S2 D	———→ (D+1,D)		
	SUBU		(S1)−(S2)		
Integer Subtraction	SUBUP	- SUBUP S1 S2 D			
(Unsigned)	DSUBU	— DSUBU S1 S2 D	(S1+1,S1)-(S2+1,S2)	0	0
	DSUBUP		——→(D+1,D)		
	MULU		(S1)×(S2) → (D+1,D)		
Integer	MULUP	MULUP S1 S2 D	(01)(02)		
Multiplication (Unsigned)	DMULU	- DMULU S1 S2 D	(S1+1,S1)×(S2+1,S2)	0	0
	DMULUP	DMULUP S1 S2 D	(S1+1,S1)*(S2+1,S2) (D+3,D+2,D+1,D)		

9) BIN operation instruction (continued)

Classification	Designations	I Symbol I Description F		Suppo	ort
Classification	Designations	Gymbol	Description	XGK	XGB
	DIVU	— DIVU S1 S2 D	(S1)÷(S2) (D) Quotient		
Integer Division	DIVUP	DIVUP S1 S2 D	(S1+1,S1)÷(S2+1,S2)		
(Unsigned)	DDIVU	— DDIVU S1 S2 D		0	0
	DDIVUP	DDIVUP S1 S2 D	(D+1,D) Quotient (D+3,D+2) Remainder		
	RADD	RADD S1 S2 D	(\$1+1,\$1)+(\$2+1,\$2)		
Real Number	RADDP	RADDP S1 S2 D	——→ (D+1,D)	0	0
Addition	LADD	— LADD S1 S2 D	(\$1+3,\$1+2,\$1+1,\$1)	0	Ö
	LADDP	-LADDP S1 S2 D	+(S2+3,S2+2,S2+1,S2) → (D+3,D+2,D+1,D)		
	RSUB	-RSUB S1 S2 D	(S1+1,S1)-(S2+1,S2)		
Real Number	RSUBP	RSUBP S1 S2 D	——→ (D+1,D)	0	0
Subtraction	LSUB	LSUB S1 S2 D	(S1+3,S1+2,S1+1,S1)	0	O
	LSUBP	LSUBP S1 S2 D	-(S2+3,S2+2,S2+1,S2) → (D+3,D+2,D+1,D)		
	RMUL	-RMUL S1 S2 D	(S1+1,S1)×(S2+1,S2)		
Real Number	RMULP	-RMULP S1 S2 D	——→(D+1,D)	0	0
Multiplication	LMUL	-LMUL S1 S2 D	(\$1+3,\$1+2,\$1+1,\$1)		O
	LMULP	-LMULP S1 S2 D	×(S2+3,S2+2,S2+1,S2) (D+3,D+2,D+1,D)		
	RDIV	RDIV S1 S2 D	(S1+1,S1)÷(S2+1,S2)		
Real Number	RDIVP	-RDIVP S1 S2 D	———→ (D+1,D)	0	0
Division	LDIV	— LDIV S1 S2 D	(\$1+3,\$1+2,\$1+1,\$1)	0	O
	LDIVP	LDIVP S1 S2 D	÷(S2+3,S2+2,S2+1,S2)		
String	\$ADD		Connects S1 String with S2 String		
Addition	\$ADDP	\$ADDP S1 S2 D	to save in D	0	0
Croup Addition	GADD	GADD S1 S2 D N	(S1) (S2) (D)		
Group Addition	GADDP	GADDP S1 S2 D N	+ = = <u></u>	0	0
Group	GSUB		(S1) (S2) (D)	-	
Subtraction	GSUBP	GSUBP S1 S2 D N	- = ■ • • • • • • • • • • • • • • • • • • •	0	0

10) BCD operation instruction

Classification	Designations	Symbol	Description	Support	
				XGK	XGB
BCD Addition	ADDB	ADDB S1 S2 D	(S1)+(S2) → (D)		
	ADDBP	- ADDBP S1 S2 D		0	0
	DADDB	— DADDB S1 S2 D	(\$1+1,\$1)+(\$2+1,\$2)		O
	DADDBP	— DADDBP S1 S2 D	——→ (D+1,D)		
BCD Subtraction	SUBB		(S1)-(S2) → (D)	0	0
	SUBBP	—SUBBP S1 S2 D			
	DSUBB	— DSUBB S1 S2 D	(S1+1,S1)−(S2+1,S2) → (D+1,D)		
	DSUBBP	— DSUBBP S1 S2 D			
BCD Multiplication	MULB		(S1)×(S2) → (D+1,D)	0	0
	MULBP	MULBP S1 S2 D			
	DMULB	- DMULB S1 S2 D	(S1+1,S1)×(S2+1,S2) → (D+3,D+2,D+1,D)		
	DMULBP	- DMULBP S1 S2 D			
BCD Division	DIVB	— DIVB S1 S2 D	$(S1) \div (S2) \longrightarrow (D) \text{ Quotient}$ $(D+1) \text{ Remainder}$	0	0
	DIVBP	— DIVBP S1 S2 D			
	DDIVB	— DDIVB S1 S2 D	(S1+1,S1)÷(S2+1,S2) (D+1,D) Quotient (D+3,D+2) Remainder		
	DDIVBP	DDIVBP S1 S2 D			

11) Logic operation instruction

Classification	Designations	Symbol	Description	Basic Steps	Page
Logic Multiplication	WAND	WAND S1 S2 D	Word AND (S1) ∧ (S2)(D)	0	0
	WANDP	WANDP S1 S2 D			
	DWAND	- DWAND S1 S2 D	DWord AND (S1+1,S1) ∧ (S2+1,S2) (D+1,D)		
	DWANDP	DWANDP S1 S2 D			
Logic Addition	WOR		Word OR (S1) V (S2)(D)	0	0
	WORP	WORP S1 S2 D			
	DWOR	— DWOR S1 S2 D	DWord OR (S1+1,S1) V (S2+1,S2) (D+1,D)		
	DWORP				
Exclusive OR	WXOR	WXOR S1 S2 D	Word Exclusive OR (S1) ✓ (S2) ———— (D)	0	0
	WXORP	WXORP S1 S2 D			
	DWXOR	DWXOR S1 S2 D	DWord Exclusive OR		
	DWXORP	DWXORP S1 S2 D	(S1+1,S1) <u>V</u> (S2+1,S2) (D+1,D)		
Exclusive NOR	WXNR	WXNR S1 S2 D	Word Exclusive NOR (S1) (S2) (D)	0	0
	WXNRP	WXNRP S1 S2 D			
	DWXNR	DWXNR S1 S2 D	DWord Exclusive NOR (S1+1,S1)¥(S2+1,S2) (D+1,D)		
	DWXNRP	DWXNRP S1 S2 D			
Group Logic Operation	GWAND	GWAND S1 S2 D N	(S1) (S2) = (D) N	0	0
	GWANDP	GWANDP S1 S2 D N			
	GWOR		(S1) V (S2) = (D) N	0	0
	GWORP	GWORP S1 S2 D N			
	GWXOR	GWXOR S1 S2 D N	(S1) (S2) = (D) N	0	0
	GWXORP	GWXORP S1 S2 D N			
	GWXNR	GWXNR S1 S2 D N	(S1) (S2) (D) N	0	0
	GWXNRP				

12) Data process instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
	BSUM	-BSUM S D	b15 b0 S		
Dit Charle	BSUMP		1's number D	_	
Bit Check	DBSUM	DBSUM S D	b31 b15 b0 S S	0	0
	DBSUMP	BSUMP			
Bit Reset	BRST	-BRST D N	Poseta N Pita (starting from D) to 0		
Dit Reset	BRSTP	-BRSTP D N	Resets in bits (starting from D) to 0	0	0
	ENCO	-ENCO S D n	1		
Encode	ENCOP	-ENCOP S D n		0	0
	DECO	— DECO SDn	S D		
Decode	DECOP	— DECOP SDn		0	0
Data Disconnect &	DIS	— DIS			
	DISP	— DISP SDn	5 : D+N-1	0	0
Connect	UNI	— UNI S D n	D+1	O	
	UNIP	-UNIP SDn	D+N-1 : SY V		
	WTOB	-WTOB SDn	h00 Higher D+1	0	
Word/ Byte	WTOBP		S+N-1 Higher Lower h00 Lower		0
Conversion	BTOW	-BTOW S D n	D+1 h00 Higher		
	BTOWP	-BTOWP SDn			
I/O	IORF	IORF S1 S2 S3	Right after masking I/O data (located	0	0
Refresh	IORFP	IORFP S1 S2 S3		Ŭ	ŭ
	SCH	SCH S1 S2 D N			
Data	SCHP	SCHP S1 S2 D N	and saves the first identical valued	0	0
Search	DSCH	DSCH S1 S2 D N			
	DSCHP	DSCHP S1 S2 D N			
	MAX	-MAX SDn	Saves the max value in D among N		
Max. Value	MAXP	MAXP S D n	words starting from S		0
Search	DMAX	— DMAX SDn	Saves the max value in D among N	o N	
	DMAXP	— DMAXP SDn	double words starting from S		

12) Data process instruction (continued)

Classification	Designatio	SVIIIDOI	Description	Support	
Ciassilleation	ns	Gymbol	υσοσιημιστι	XGK	XGB
	MIN	MIN S D n	Saves the min value in D among N		
Min. Value	MINP	MINP S D n	words starting from S	0	0
Search	DMIN	- DMIN S D n	Saves the min value in D among N		O
	DMINP	- DMINP S D n	double words starting from S		
	SUM	SUM SDn	Adds up N words starting from S to		
Sum	SUMP	-SUMP S D n	save in D		0
Suili	DSUM	- DSUM S D n	Adds up N double words starting	0	0
	DSUMP	- DSUMP S D n	from S to save in D	s ·	
	AVE	—AVE SDn	Averages N words starting from S		
Avorago	AVEP		to save in D		0
Average	DAVE	— DAVE SDn	Averages N double words starting		O
	DAVEP	— DAVEP S D n	from S to save in D	3	
	MUX		S2 S1st data	0	
MUX	MUXP		N ↓ □ □ □		0
IVIOX	DMUX		S2+1 S2 S1st data D+1 D		0
	DMUXP	- DMUXP S1 S2 D N	N D+1 D		
Data	DETECT	- DETECT S1 S2 D N	Detects N data from S1, to save the first value larger than S2 in D, and	0	0
Detect	DETECTP	- DETECTP S1 S2 D N	the extra number in D+1	0	0
Ramp Signal Output	RAMP		Saves linear-changed value in D1 during n3 scanning of initial value n1 to final n2 and present scanning number in D1+1, and changes D2 value to ON after completed	0	0
Data	SORT		S : Head Address of Sort Data n1 : Number of Words to sort n1+1 : Sorting Method		0
Align	SORTP		n2: Operation number per Scan D1 : ON if complete D2 : Auxiliary Area	0	J

13) Data table process instruction

Classification	Designations Symbol		Description	Support	
Classification	Designations	Symbol	Description	XGK	XGB
Data	FIWR	FIWR S D	Adds S to the last of Data Table D ~		
Write	FIWRP	FIWRP S D	D+N, and increases Data Table Length(N) saved in D by 1	0	0
First-input	FIFRD	-FIFRD S D	Moves first data, S+1 of Data Table S ~ S+N to D (pull 1 place after origin		
Data Read	FIFRDP	FIFRDP S D	deleted) and decreases Data Table Length(N) saved in D by 1 S	0	0
Last-Input Data	FILRD	-FILRD SD	Moves last data, S+N of Data Table S ~ S+N to D (origin deleted) and	0	C
Read	put S ~ S+N to D (origin deleted) and decreases Data Table Length(N)	0)		
Data	FIINS	-FINS SDn	Adds S to 'N'th place of Data Table D ~ D+N (origin data pulled by 1), and		
Insert	FIINSP	-FINSP S D n	increases Data Table Length(N) saved in D by 1	0	0
Data	FIDEL	-FDEL S D n	Deletes 'N'th data of Data Table S ~ S+N (pull 1 place) and decreases	0	C
Pull	FIDELP	FDELP S D n	Data Table Length(N) saved in D by 1		0

14) Display instruction

Classification	Designations Symbol	Description	Support		
Classification	Designations	Symbol	Description	XGK	XGB
7 Segment	SEG	SEG S D Z	Converts S Data to 7-Segment as		
Display	SEGP	SEGP S D Z	adjusted in Z Format so to save in D	0	O

15) String Process instruction

Classification	Designations	Symbol	Description	Sup	port
Ciassilication	Designations	Зушьог	Description	XGK	XGB
	BINDA	BINDA S D	Converts S of 1-word BIN value to Decimal ASCII Cord to save in		
Convert to Decimal	BINDAP	BINDAP S D	starting D	0	0
ASCII Cord	DBINDA	- DBINDA S D	Converts S of 2-word BIN value to Decimal ASCII Cord to save in	Ü	Ü
	DBINDAP	- DBINDAP S D	starting D		
	BINHA	BINHA S D	Converts S of 1-word BIN value to Hexadecimal ASCII Cord to save		
Convert to Hexadecimal	BINHAP	BINHAP S D	in starting D		
ASCII Cord	DBINHA	— DBINHA S D	Converts S of 2-word BIN value to Hexadecimal ASCII Cord to save in	0	0
	DBINHAP	— DBINHAP S D	starting D		
	BCDDA	BCDDA S D	Converts S of 1-word BCD to ASCII		
Convert BCD to Decimal	BCDDAP	BCDDAP S D	Cord to save in starting D	0	_
ASCII Cord	DBCDDA	— DBCDDA S D	Converts S of 2-word BCD to ASCII		0
	DBCDDAP	DBCDDAP S D	Cord to save in starting D		
	DABIN	— DABIN S D	Converts S S+2,S+1,S's Decimal		
Convert	DABINP	DABINP S D	ASCII Cord to BIN to save in D		
Decimal ASCII to BIN	DDABIN	— DDABIN S D	Converts S+5~S's Decimal ASCII Cord to BIN value to save in D+1 &	0	0
	DDABINP	DDABINP S D	D D		
	HABIN	HABIN S D	Converts S+1,S's Hexadecimal ASCII		
Convert	HABINP	HABINP S D	Cord to BIN value to save in D	_	_
Hexadecimal ASCII to BIN	DHABIN	— DHABIN S D	Converts S+3~S's Hexadecimal ASCII	0	0
	DHABINP	— DHABINP S D	Cord to BIN to save in D		
	DABCD	— DABCD S D	Converts S+1,S's Decimal ASCII		
Convert	DABCDP	DABCDP S D	Cord to BCD to save in D		
Decimal ASCII to BCD	DDABCD	DDABCD S D	Converts S+3~S's Decimal ASCII	0	0
	DDABCDP	DDABCDP S D	Cord to BCD to save in D		
String	LEN	LEN S D	Saves String Length with S starting		
Length Detect	LENP	LENP S D	in D	0	0

15) String process instruction (continued)

Classification Designations Symbol		Description	Support		
Ciassilication	Designations	Зушьы		XGK	XGB
	STR		Adjusts S2 saved word data to S1 saved place		
Convert BIN16/32 to	STRP		number to convert to String and save in D	0	0
String	DSTR	DSTR	Adjusts S2 saved double word data to S1 saved		O
	DSTRP	— DSTRP S1 S2 D	place number to convert to String and save in D		
Convert String to	VAL		Adjusts S saved string to number to save in word		
	VALP	VALP S D1 D2	D1 and saves the place number in D2		
BIN16/32	DVAL	DVAL	Adjusts S saved string to number to save in double	0	0
	DVALP	DVALP S D1 D2	word D1 and saves the place number in D2		
	RSTR	RSTR S1 S2 D	Adjusts Floating decimal point point Real Number		
Convert Real Number to String	RSTRP	RSTRP S1 S2 D	Data (S1: number, S2: places) to String format to save in D		X
	LSTR	LSTR	Adjusts Floating decimal point point Double Real	0	^
	LSTRP	LSTRP S1 S2 D	Number Data (S1:number, S2:places) to String format to save in D		
	STRR	-STRR S D	Converts String S to Floating decimal point point Real		
Convert String to Real	STRRP	STRRP S D	Number Data to save in D	- 0	V
Number	STRL	-STRL S D	Converts String S to Floating decimal point		Х
	STRLP	STRLP S D	point Double Real Number Data to save in D		
ASCII Conversion	ASC	ASC S D cw	Converts BIN Data to ASCII in Nibble unit,	0	
ASCII Conversion	ASCP	ASCP S D cw	based on cw's format from S to save in D	0	0
	HEX	HEX S D N	Converts 2N ASCII saved in N words from S in byte		
HEX Conversion	HEXP	HEXP S D N	unit to Nibble unit of Hexadecimal BIN so to save in D	0	0
String Extract from	RIGHT	RIGHT S D N	Extracts n string from S string's final letter to save	0	0
Right	RIGHTP	RIGHTP S D N	in starting D	0	0
String Extract from Left	LEFT	LEFT S D N	Extracts n string from S string's first letter to save	0	0
Onling Extract Holli Left	LEFTP	LEFTP S D N	in starting D	0	9
String Random Extract	MID	MID S1 S2 D	Extracts string which conforms to S2 condition	0	0
Sanig Nandom Extract	MIDP	MIDP S1 S2 D -	among S1 string to save in starting D	<u> </u>	J

15) String process instruction (continued)

Classification	Designations	Symbol	Description	Basic Steps	Page
String Random	REPLACE	REPLACE S1 D S2	Processes S1 String as applicable to S2 Condition to	0	0
Replace	REPLACEP	REPLACEP S1 D S2	save in D String	0	0
Otalia as Fin al	FIND	FIND S1 S2 D N	Finds identical String to S2 in S1 ~ N data to save the	_	
String Find	FINDP	FINDP S1 S2 D N	absolute position in D	0	0
	RBCD		Adjusts Floating decimal point point Real Number Data S1 to		
Parse Real	RBCDP		S2 place to convert to BCD, and then to save in D		V
Number to BCD	LBCD	LBCD S1 S2 D	Adjusts Floating decimal point point Double Real Number	0	Х
	LBCDP	- LBCDP S1 S2 D	Data S1 to S2 place to convert to BCD, and then to save in D		
	BCDR	BCDR S1 S2 D	Adjusts BCD Data S1 to S2 place to convert to Floating		
Convert BCD	BCDRP	BCDRP S1 S2 D	decimal point point Real Number, and then to save in D		
Data to Real Number	BCDL		Adjusts BCD Data S1 to S2 place to convert to Floating	0	Х
	BCDLP	BCDLP S1 S2 D	decimal point point Double Real Number, and then to save in D		

16) Special function instruction

Classification	Designations	Symbol	Description	Basic Steps	Page
CIN On a ration	SIN	-SIN SD	CIN(C+1 C) (D+1 D)	_	
SIN Operation COS Operation TAN Operation TRAD Conversion Angle Conversion COS COS COS COS COS COS COS COS COS CO	SINP	SINP S D	SIN(3+1,3)(U+1,U)	0	0
cos	cos	—cos sd	000(0.1.0) (0.1.0)		
Operation	COSP	—COSP SD	CUS(S+1,S) (U+1,U)	0	0
TANIO "	TAN	—TAN SD	TAN(S+1,S) (D+1,D)		
TAN Operation	TANP	TANP S D		0	0
RAD	RAD	-RAD SD	(S+1,S) (D+1,D)		
Conversion	RADP	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	0	0	
Angle	DEG	— DEG S D	· · · · · · · · · · · · · · · · · · ·		
Conversion	DEGP	DEGP S D	Converts radian to angle	0	0
Square Root	SQRT	— SQRT SD		_	_
Öperation	SQRTP	SQRTP S D	$\sqrt{(S+1,S)} \longrightarrow (D+1,D)$	0	0

17) Data control instruction

Classification	Designations	Symbol	Description	Basic Steps	Page
	LIMIT	LIMIT S1 S2 S3 D			
Limit	LIMITP	- LIMITP S1 S2 S3 D	If S1 < S2, then D = S2 If S2 < S1 < S3, then		
Control	DLIMIT	— DLIMIT S1 S2 S3 D	D = S1 If S3 < S1, then D = S3	0	0
	DLIMITP	LIMIT			
1	DZONE				
Dead-zone	DZONEP	DZONEP S1 S2 S3 D	D = S1+S2-S2(S3/100)	_	
Control	DDZONE	DDZONE S1 S2 S3 D	D = (S3/100)S1 If S1 < S2, then	0	0
	DDZONEP	DDZONEP S1 S2 S3 D	2 - 31 - 32 - 32 (33, 133)		
	VZONE		$\begin{array}{c} D = S1\text{-}S2+S2(S3/100) \\ \text{If } -S2(S3/100) & $		
Vertical-zone	VZONEP	VZONEP S1 S2 S3 D			
Control	DVZONE	DVZONE S1 S2 S3 D		0	0
	DVZONEP	DVZONEP S1 S2 S3 D	D = S1+S2-S2(S3/100)		
	PIDRUN	PIDRUN N	Operates PID Loop N	0	0
	PIDPAUSE	PIDPAUSE N		0	Х
Built-in PID Control Instruction	PIDPRMT	PIDPRMT S N	(SV(word) / Ts(word) / Kp(real)	0	Х
Limit Control Dead-zone Control Vertical-zone Control	PIDAT	PIDRUN N	Start of PID loop Auto-tuning	Х	0
	PIDCAS	PIDPRMT S N	Start of PID loop cascade operation	Х	0
	PIDHBD	PIDPRMT S N		Х	0

18) Time related instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Date/Time Data	DATERD	— DATERD D	Reads PLC Time to save in D ~ D+6	0	Х
Read	DATERDP	— DATERDP D	(Yr/Mn/Dt/Hr/Mn/Sd/Day)	0	^
Date/Time Data	DATEWR	— DATEWR S	Input S ~ S+6's Time Data in PLC	0	Х
Write	DATEWRP	— DATEWRP S	(Yr/Mn/Dt/Hr/Mn/Sd/Day)	0	^
Time Data	ADDCLK	ADDCLK S1 S2 D	Adds S1 ~ S1+2 & S2 ~ S2+2 Time	0	X
Increase	ADDCLKP	ADDCLKP S1 S2 D	Data to save in D ~ D+2 in Time Data format (Hr/Mn/Sd)	O	^
Time Data	SUBCLK	SUBCLK S1 S2 D	Extracts S2 ~ S2+2's Time Data from S1 ~ S1+2 to save in D ~ D+2 in	0	Х
Decrease	SUBCLKP	SUBCLKP S1 S2 D	Time Data format (Hr/Mn/Sd))	^
	SECOND	SECOND S D	Converts Time Data S ~ S+2 to	0	Х
Time Data	SECONDP	SECONDP S D	seconds to save in double word D	0	^
Format Conversion	HOUR	HOUR SD	Converts the seconds saved in double word S to Hr/Mn/Sd to save		Х
	HOURP	HOURP S D	in D ~ D+2	0	^

19) Divergence instruction

Classification	Designations	Symbol	Description	Support	
Classification	Designations	Зушьы	Description	XGK	XGB
Divergence	JMP	JMP LABEL	Jumps to LABEL location	0	0
Instruction	LABEL	LABEL ()	Jumps and designates the location to move to	0	0
	CALL	CALL LABEL	Calls Function applicable to LABEL		
Subroutine	CALLP	CALLP LABEL	Calls Fullction applicable to EABEL		0
Call Functional	SBRT	SBRT LABEL	Designates Function to be called by CALL	0	0
	RET	RET	RETURN		

20) Loop instruction

Classification [Designations Symbol	Description	Support		
Classification		Symbol	Description	XGK	XGB
	FOR	FOR N	Operates FOR~NEXT section n times		0
Loop Instruction	NEXT	NEXT	Operates FOR~NEXT Section II times	0	0
	BREAK	BREAK	Escapes from FOR~NEXT section	0	0

21) Flag instruction

Classification Designat	Designations	Symbol	Description	Sup	port
	Designations	Symbol	Description	XGK	XGB
Carry	STC	—STC	Carry Flag (F0112) SET)	0
Flag Set, Reset	CLC	—clc	Carry Flag (F0112) RESET	0	O
Error Flag Clear	CLE	—CLE	Error Latch Flag (F0115) RESET	0	0

22) System instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Error Display	FALS	— FALS n	Self Diagnosis (Error Display)	0	0
Scan Cluck	DUTY	OUTY D n1 n2	On during n1 Scan, Off during n2 Scan	0	0
Time Cluck	TFLK	TFLK D1 S1 S2 D2	On during S1 set time, Off during S2 set time	0	0
WDT	WDT	— WDT	Watch Dag Timor Class	0	0
Initialize	WDTP	— WDTP	Watch Dog Timer Clear	0	0
Output Control	OUTOFF	OUTOFF	All Output Off	0	0
Operation Stop	STOP	— STOP	Finishes applicable scan to end PLC Operation	0	0
Emergent Operation Stop	ESTOP	— ESTOP	Ends PLC operation right after Instruction executed	0	0

23) Interrupt related instruction

Classification	Designations	ignations Symbol Description		Support	
Classification	Designations	Syllibol	Description	XGK	XGB
All Channels	EI	—EI	All Channels Interrupt allowed	0	0
Interrupt Setting	DI		All Channel Interrupt prohibited		
Individual Channel	EIN	—EIN N	Individual Channel Interrupt allowed		0
Interrupt Setting	DIN	— DIN N	Individual Channel Interrupt prohibited	0	0

24) Sign reversion instruction

Classification	Designations	Symbol	Description	Sup XGK °	port
Classification	Designations	Symbol	Description	XGK	XGB
	NEG	MEG D	Saves D value again in D with 2's		
2's	NEGP	NEGP D	complement taken		0
complement	DNEG	— DNEG D	Saves (D+1,D) value again in (D+1,D)	0	O
Real Number Data Sign	DNEGP	— DNEGP D	with 2's complement taken		
	RNEG	RNEG D	to save again	0	0
	RNEGP	RNEGP D			
Reverse	LNEGR	— LNEG D	Reverses D Double Real Number Sign then to save again		
	LNEGP	LNEGP D			
	ABS	— ABS D	Converte D highest Bit to 0		
Absolute Value	ABSP	— ABSP D	Converts D highest Bit to 0		
Operation	DABS	— DABS D	Converts (D+1,D)		0
	DABSP	— DABSP D	highest Bit to 0		

25) File related instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Block	RSET	RSET S	Changes Block Number of file register		×
Conversion	RSETP	RSETP S	Changes Block Number of file register to S Number EMOV S1S2D Transfers S2 word data in S1 Block to D EDMOV S1S2D Transfers S2+1, S2 double word data in S1 Block to D+1, D	0	^
Flash Word Date	EMOV	EMOV S1 S2 D	Transfers S2 word data in S1 Block		
Word Data Transfer EMO\	EMOVP	-EMOVP S1 S2 D	to D	o	X
Flash Double Word	EDMOV	EDMOV S1 S2 D	·		^
Data Transfer	EDMOVP	EDMOVP S1 S2 D			
Block Read	EBREAD	- EBREAD S1 S2	Reads Flash Memory Block	0	Х
Block Write	EBWRITE	EBWRITE S1 S2	Writes Flash Memory Block	0	Х
Block Compare	EBCMP	- EBCMP S1 S2 D1 D2	Compares R Area's Bank with Flash Area's Block	0	Х

Appendix 4.4 Special/Communication Instruction

1) Communication module related instruction

Classification	Designations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Station No. Set	P2PSN	P2PSN n1 n2 n3	Sets opposite station No. for P2P Communication. n1:P2P No., n2:Block, n3:Station No.	0	Х
Read Area Set (WORD)	P2PWRD		Sets word data Read Area n1:P2P No., n2:Block, n3:Variable sequence, n4:Variable Size, n5:Device	0	Х
Write Area Set (WORD)	P2PWWR		Sets word data Write Area n1:P2P No., n2:Block, n3:Variable sequence, n4:Variable Size, n5:Device	0	Х
Read Area Set (BIT)	P2PBRD		Sets bit data Read Area n1:P2P No., n2:Block, n3:Variable sequence, n4: Variable Size, n5:Device	0	Х
Write Area Set (BIT)	P2PBWR		Sets bit data Write Area n1:P2P No., n2:Block, n3:Variable sequence,n4:Variable Size, n5:Device	0	Х

2) Special module common instruction

Classification	Designations	Symbol	Description	Support	
	Designations	Symbol	Description	XGK	XGB
Special Module Read/Write	GET	GET SISDN	Reads data of special module memory is installed on		0
	GETP	GETP SI S D N		0	0
	PUT		Writes data on special module		
	PUTP	PUTP SI S1 S2 N	memory is installed on	0	0

3) Exclusive positioning instruction

Classification	Designations	Symbol	Description	Su	pport
Classification	Designations	Зупівої	Description	XGK	XGB
Return to Origin Point	ORG	ORG sl ax	Instructions Positioning Module's ax axis installed on sl slot to return to Origin Point	0	0
Floating Origin Point	FLT	FLT sl ax	Instructions Positioning Module's ax axis installed on sl slot to set Floating Origin Point	0	0
Direct Start	DST	-DST slax n1 n2 n3 n4 n5	Instructions Positioning Module's ax axis installed on sl slot to start directly with Target Position(n1), Target Speed(n2), Dwell Time(n3), M Code(n4) & Control Word(n5)	0	0
Indirect Start	IST	[IST slax n	Instructions Positioning Module's ax axis installed on sl slot to start n step indirectly	0	0
Linear Interpolation	LIN	LIN SI ax n1 n2	Instructions Positioning Module's ax axis installed on sl slot to let n2 axes operate n1 step by Linear Interpolation	0	0
Circular Interpolation	CIN	— CIN SI ax n1 n2 −	Instructions Positioning Module's ax axis installed on sl slot to let n2 axes operate n1 step by Circular Interpolation	0	х
Simultaneous Start	SST	-SST sl ax n1 n2 n3 n4	Instructions Positioning Module's ax axis installed on sl slot to let n4 axes operate n1(X), n2(Y), n3(Z) steps by Simultaneous Start	0	0
Speed/Position Control Switch	VTP	VTP sl ax	Instructions Positioning Module's ax axis installed on sl slot to switch Speed to Position Control	0	0
Position/Speed Control Switch	PTV	PTV sl ax	Instructions Positioning Module's ax axis installed on sl slot to switch Position to Speed Control	0	0
Decelerated Stop	STP		Instructions Positioning Module's ax axis installed on sl slot to stop as decelerated.	0	0
Skip	SKP	SKP SI ax	Instructions Positioning Module's ax axis installed on sl slot to skip	0	Х
Position Synchronization	SSP	— SSP sl ax n1 n2 n3	Instructions Positioning Module's ax axis installed on sl slot to do Position Sync with main axis of n3, n1 sync-positioned and n2 step operated	0	0
Speed Synchronization	SSS	— SSS sl ax n1 n2 n3	Instructions Positioning Module's ax axis installed on sl slot to do Speed Sync with main axis of n3, n1 master and n2 slave	0	0
Position Override	POR	POR SI ax n	Instructions Positioning Module's ax axis installed on sl slot to override Position to change the target position to n	0	0

4) Exclusive position control instruction (continued)

Classification	Docianations	Symbol	Description	Sup	port
Classification	Designations	Symbol	Description	XGK	XGB
Speed Override	SOR	SOR slax n	Instructions Positioning Module's ax axis installed on sl slot to override Speed to change the target speed to n	0	0
Position specified Speed Override	PSO	PSO sl ax n	Instructions Positioning Module's ax axis installed on sl slot to override position specified speed to change the target speed to n2 from n1 position	0	0
Continuous Operation	NMV	NMV sl ax	Instructions Positioning Module's ax axis installed on sl slot to operate continuously to n step	0	Х
Inching	INCH	INCH sl ax n	Instructions Positioning Module's ax axis installed on sl slot to inch to n position	0	0
Return to Position Previous to Manual Operation	RTP	RTP sl ax	Instructions Positioning Module's ax axis installed on sl slot to return to position previous to manual operation	0	Х
Operation Step Change	SNS	SNS slax n	Instructions Positioning Module's ax axis installed on sl slot to change operation step to n	0	0
Repeated Operation Step Change	SRS	SRS slax n	Instructions Positioning Module's ax axis installed on sl slot to change repeated operation step to n	0	Х
M Code Off	MOF	MOF sl ax	Instructions Positioning Module's ax axis installed on sl slot to make M code off	0	0
Present Position Change	PRS	PRS slax n	Instructions Positioning Module's ax axis to change present position to n	0	0
Zone Allowed	ZOE	ZOE si ax	Allows zone output of Positioning Module installed on sl slot	0	Х
Zone Prohibited	ZOD	ZOD sl ax	Prohibits zone output of Positioning Module installed on sl slot	0	Х
Encoder Value change	EPRS	EPRS slax n	Changes Encoder Value of Positioning Module installed on sl slot to n	0	Х
Teaching	TEA	TEA sl ax n1 n2 n3 n4	Changes n1 step's target position or speed of Positioning Module's ax axis installed on sl slot	0	Х
Teaching Array	TEAA	TEAA si ax n1 n2 n3 n4	Changes multiple target positions or speed of Positioning Module's ax axis installed on sl slot	0	Х
Emergent Stop	EMG	EMG sl ax	Instructions Positioning Module installed on sl slot to perform Emergent Stop	0	0

5) Exclusive position control instruction (continued)

Classification	Designations	Symbol	Description	Sup	port
Ciassilication	Designations	Symbol	Description	XGK	XGB
Error Reset	CLR	CLR slax n	Resets Error originated from Positioning Module's ax axis installed on sl slot	0	0
Error History Reset	ECLR	ECLR SI ax	Deletes Error History originated from Positioning Module's ax axis installed on sl slot	0	Х
Point Operation	PST	PST slax n	Performs Point Operation of Positioning Module's ax axis installed on sl slot	0	Х
Basic Parameter Teaching	ТВР	TBP sl ax n1 n2	Changes n2 to n1 among basic parameters of Positioning Module's ax axis installed on sl slot	0	Х
Extended Parameter Teaching	TEP	TEP sl ax n1 n2	Changes n2 to n1 among extended parameters of Positioning Module's ax axis installed on sl slot	0	Х
Return to Origin Point Parameter Teaching	THP	—THP sl ax n1 n2	Changes n2 to n1 among returned parameters to origin point of Positioning Module's ax axis installed on sl slot	0	Х
Manual Operation Parameter Teaching	TMP	TMP sl ax n1 n2	Changes n2 to n1 among manual operation parameters of Positioning Module's ax axis installed on sl slot	0	Х
Input Signal Parameter Teaching	TSP	—TSP slax n	Changes input signal parameter of Positioning Module's ax axis installed on sl slot to the value set in n1	0	Х
Common Parameter Teaching	TCP	TCP sl ax n1 n2	Changes n2 to n1 among common parameters of Positioning Module installed on sl slot	0	Х
Parameter Save	WRT		Instructions Positioning Module's ax axis installed on sl slot to save present parameter of n axis in flash ROM.	0	0
Present State Read	SRD	SRD slax D	Reads and saves present state of Positioning Module's ax axis installed on sl slot in D area of CPU	0	Х
Point Operation Step Write	PWR	— PWR SI ax S n1	Writes value of S area of CPU on point operation step area of Positioning Module's ax axis installed on sl slot in	0	X
Plural Teaching Data Write	TWR	—TWR SI ax S n1	Writes n value of S area of CPU on plural teaching dada area of Positioning Module's ax axis installed on sl slot in	0	Х

Warranty

1. Warranty Period

The product you purchased will be guaranteed for 18 months from the date of manufacturing.

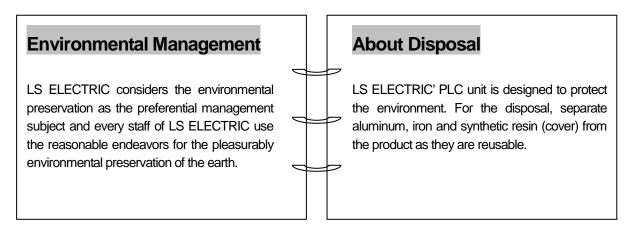
2. Scope of Warranty

Any trouble or defect occurring for the above-mentioned period will be partially replaced or repaired. However, please note the following cases will be excluded from the scope of warranty.

- (1) Any trouble attributable to unreasonable condition, environment or handling otherwise specified in the manual,
- (2) Any trouble attributable to others' products,
- (3) If the product is modified or repaired in any other place not designated by the company,
- (4) Due to unintended purposes
- (5) Owing to the reasons unexpected at the level of the contemporary science and technology when delivered.
- (6) Not attributable to the company; for instance, natural disasters or fire
- 3. Since the above warranty is limited to PLC unit only, make sure to use the product considering the safety for system configuration or applications.

Environmental Policy

LS ELECTRIC Co., Ltd supports and observes the environmental policy as below.





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Specifications in this instruction manual are subject to change without notice due to continuous products development and improvement.

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